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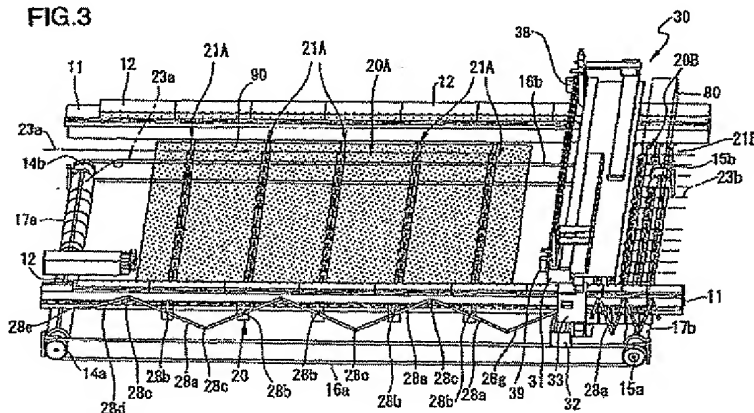
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(54) **SUBSTRATE-CUTTING SYSTEM, SUBSTRATE-PRODUCING APPARATUS,  
SUBSTRATE-SCRIBING METHOD, AND SUBSTRATE-CUTTING METHOD**

(57) A clamping device (50) is installed on a stand (10) with a hollow rectangular parallelepiped shape such that at least one place at a side edge portion of a mother board transported in the stand (10) is clamped. A pair of substrate-cutting devices for cutting the mother substrate, clamped by the clamping device (50), from its upper face and lower face is provided on a scribing

device guide body (30). The scribing device guide body (30) is reciprocally movable along one side of the hollow rectangular parallelepiped. The pair of substrate-cutting devices is installed so as to be movable along the direction perpendicular to the movement direction of the scribing device guide body (30). The mother substrate clamped by the clamping device is supported by a substrate-supporting device (20).

FIG.3



## Description

### TECHNICAL FIELD

[0001] The present invention relates to a substrate cutting system and a substrate cutting line system used for cutting mother substrates of various materials, including mother substrates such as glass substrates used for display panels of liquid crystal display apparatuses and the like, and more particularly, a substrate cutting system, a substrate manufacturing apparatus, a substrate scribing method, and a substrate cutting method which can be preferably used for cutting bonded mother substrates formed by bonding a pair of brittle material substrates to each other.

### BACKGROUND ART

[0002] Display panels of the liquid crystal display apparatuses and the like are usually made of glass substrates which are brittle material substrates. The liquid crystal display apparatuses includes display panels formed by bonding a pair of glass substrates with an appropriate space therebetween and enclosing liquid crystal into the space.

[0003] For manufacturing such display panels, a process to cut out a plurality of display panels of a bonded mother substrate by cutting the bonded mother substrate which is obtained by bonding mother glass substrates is performed. A scribing apparatus used for cutting bonded mother substrates is disclosed in Publication for Utility Model Opposition No. 59-22101.

[0004] Figure 93 is a schematic view showing a structure of the scribing apparatus. A scribing apparatus 950 includes tables 951 for respectively putting a side edge portion of a bonded mother substrate 908 thereon. On the tables 951, clamp members 952 for clamping the side edge portions of the bonded mother substrate 908 are attached. The scribing apparatus 950 includes a pair of cutter heads 953 and 954 respectively provided above and below the bonded mother substrate 908. The cutter heads 953 and 954 oppose each other with the bonded mother substrate 908 interposed there between.

[0005] In the scribing apparatus 950 having such a structure, when the bonded mother substrate 908 is fixed to the tables 951 with the clamp members 952, a front surface and a back surface of the bonded mother substrate 908 are scribed at the same time by the pair of cutter heads 953 and 954 to form scribe lines.

[0006] However, in such a scribing apparatus 950, a breaking apparatus for cutting the bonded mother substrate 908 on which the scribe lines are formed is separately required. Further, for cutting the bonded mother substrate 908 by a breaking apparatus, it is necessary to reverse the bonded mother substrate 908 (to turn the substrate upside down) after cutting one of the mother substrates of the bonded mother substrate 908 for cut-

ting another substrate. For cutting display panels out of the bonded mother substrate 908, a complicated line system has to be established.

[0007] For cutting display panels out of the bonded mother substrate 908 by using such a scribing apparatus 950, a complicated line system having a footprint few times larger than that of the scribing apparatus 950 has to be established. This is one of the reasons increasing the manufacturing cost of display panels.

[0008] Further, in the scribing apparatus 950 shown in Figure 93, the bonded mother substrate 908 is scribed from both front surface and back surface at the same time. However, the process direction is limited to one direction, and cross scribing (scribing along directions such that the scribe lines are orthogonal to each other) is impossible.

[0009] This means that another scribing apparatus is necessary for cross-scribing. There is a problem that the scribing process efficiency for the bonded mother substrate 908 is significantly low.

[0010] Moreover, there is a problem that the process cannot be performed along two directions which are orthogonal to each other in one setting when the mother substrate is cut from both the front surface and the back surface by using an apparatus similar to the above-described scribing apparatus 950.

[0011] The present invention is to solve such problems and the object thereof is to provide a substrate cutting system and a substrate cutting system which has a small foot print and a compact structure, and which can efficiently cut various types of mother substrates.

### DISCLOSURE OF THE INVENTION

[0012] A substrate cutting system according to the present invention is characterized by comprising: a hollow parallelepiped mounting structure; a clamp device attached to the mounting structure so as to clamp at least one portion of a side edge of a substrate carried into the mounting structure; a pair of substrate cutting devices for cutting the substrate from an upper surface side and a lower surface side of the substrate clamped by the clamping device; and a scribing device guide body which is movable back and forth along one side of the hollow parallelepiped mounting structure and to which the pair of substrate cutting devices are attached so as to be movable along a direction orthogonal to the moving direction.

[0013] The present invention is further characterized by comprising a substrate supporting device for supporting the substrate clamped by the clamping device.

[0014] The present invention is further characterized by comprising a first substrate supporting portion provided on one side in the moving direction of the scribing device guide body.

[0015] The present invention is further characterized in that the first substrate supporting portion includes a plurality of first substrate supporting units which can

move parallel along the moving direction of the scribing device guide body, the first substrate supporting units being moved so as to apart from each other as the scribing device guide body moves in one direction and being moved so as to approach each other as the scribing device guide body moves in other direction.

**[0016]** The present invention is further characterized in that, in the first substrate supporting units, a plurality of first supporting belts respectively arranged along the moving direction of the scribing device guide body are supported, and the substrate is supported in a horizontal fashion by the first supporting belts by moving the first substrate supporting units so as to apart from each other.

**[0017]** The present invention is further characterized by comprising first winding means for winding the first supporting belts by moving the first substrate supporting units so as to approach each other.

**[0018]** The present invention is further characterized in that, in the first substrate supporting units, a substrate upward/downward moving device for lifting the substrate above the first supporting belts so that the substrate is clamped by the clamp device is provided.

**[0019]** The present invention is further characterized in that the first substrate supporting portion includes a plurality of first substrate supporting units which move parallel along the moving direction of the scribing device guide body, the first substrate supporting units being moved with the scribing device guide body as the scribing device guide body moves in one direction.

**[0020]** The present invention is further characterized in that the first substrate supporting units comprises a plurality of belts for supporting the substrate.

**[0021]** The present invention is further characterized by comprising at least one clutch unit for selectively rotating the plurality of belts in accordance with the movement of the scribing device guide body.

**[0022]** The present invention is further characterized in that the substrate supporting device further comprises second substrate supporting portion provided on the other side in the moving direction of the scribing device guide body.

**[0023]** The present invention is further characterized in that the second substrate supporting portion includes a plurality of second substrate supporting units which move parallel along the moving direction of the scribing device guide body, the second substrate supporting units being moved so as to approach each other in the movement in one direction and being moved so as to apart from each other in the movement in other direction.

**[0024]** The present invention is further characterized in that, in the second substrate supporting units, a plurality of second supporting belts respectively arranged along the moving direction of the scribing device guide body are supported, and the substrate is supported in a horizontal fashion by the second supporting belts by moving the second substrate supporting units so as to

apart from each other.

**[0025]** The present invention is further characterized by comprising second winding means for winding the second supporting belts by moving the second substrate supporting units so as to approach each other.

**[0026]** The present invention is further characterized in that the second substrate supporting portion includes a plurality of second substrate supporting units which move parallel along the moving direction of the scribing device guide body, the second substrate supporting units being moved with the scribing device guide body as the scribing device guide body moves in one direction.

**[0027]** The present invention is further characterized in that the second substrate supporting units comprises a plurality of belts for supporting the substrate.

**[0028]** The present invention is further characterized by comprising at least one clutch unit for selectively rotating the plurality of belts in accordance with the movement of the scribing device guide body.

**[0029]** The present invention is further characterized in that a or the substrate cutting devices comprises a cutter head for transmitting pressure to the substrate using a servo motor for a cutter wheel.

**[0030]** The present invention is further characterized by comprising a steam unit portion for spraying steam on front and back surfaces of the substrate having scribe lines carved thereon at a or the substrate cutting devices.

**[0031]** The present invention is further characterized in that the steam unit portion includes substrate drying means for drying front and back surfaces of the substrate.

**[0032]** A substrate cutting system according to claim 10, characterized by comprising a substrate carry-out device for taking out the substrate which has been cut at the steam unit portion.

**[0033]** The present invention is further characterized in that the substrate carrying device includes a carrying robot comprising: substrate holding means for holding the substrate; substrate rotation means for rotating the substrate holding means holding the substrate around a first axis vertical to the substrate; and means for rotating the substrate rotation means around a second axis which is different from the first axis vertical to the substrate held by the substrate holding means.

**[0034]** The present invention is further characterized by comprising substrate inversion means for inverting the substrate carried by the substrate carrying device upside down.

**[0035]** The present invention is further characterized by comprising a positioning unit portion for positioning the substrate.

**[0036]** The present invention is further characterized by comprising a carrying unit for carrying the substrate scribed by the scribing device guide body to a steam unit portion.

**[0037]** The present invention is further characterized

by comprising removal means for removing unnecessary portion of the cut substrate.

[0038] The present invention is further characterized in that the plurality of belts are strained between a frame on a substrate carry-in side and a frame on a substrate carry-out side, the plurality of belts sinking below the scribing device guide body or coming up from below the scribing device guide body during the first substrate supporting portion is moving.

[0039] The present invention is further characterized in that the plurality of belts are strained between a frame on a substrate carry-in side and a frame on a substrate carry-out side, the plurality of belts sinking below the scribing device guide body or coming up from below the scribing device guide body during the second substrate supporting portion is moving.

[0040] The present invention is further characterized in that the substrate is a bonded mother substrate formed by bonding a pair of mother substrates.

[0041] A substrate manufacturing apparatus according to the present invention is characterized in that a chamfering system for chamfering end surfaces of the cut substrate is connected to the above substrate cutting system.

[0042] The present invention is further characterized in that an inspection system for inspecting functions of the cut substrate is connected.

[0043] A substrate scribing method for forming scribe lines on an upper surface and a lower surface of a substrate according to the present invention is characterized in that: scribe line formation means for forming a vertical crack along a thickness direction of the substrate oppose each other, and the scribe lines are continuously formed by the scribe formation means without being apart from the substrate.

[0044] The present invention is further characterized in that three or more linear scribe lines are formed by the scribe line formation means, a closed curve being formed by all the scribe lines which has been formed.

[0045] The present invention is further characterized in that the scribe line formation means form a closed curve having a rectangular shape.

[0046] The present invention is further characterized in that the scribe line formation means is a cutter wheel tip having a disc shape and having a blade edge for rotating on a surface of the substrate in an outer periphery.

[0047] The present invention is further characterized in that the cutter wheel tip has a plurality of protrusions formed in a blade edge in a predetermined pitch.

[0048] The present invention is further characterized in that sub-scribe lines along at least two formed scribe lines are formed by the cutter wheel tip after at least two scribe lines are formed by the cutter wheel tip.

[0049] The present invention is further characterized in that the sub-scribe lines are formed continuously after the at least two scribe lines formed on the substrate without separating the cutter wheel tip from a surface of the substrate.

[0050] The present invention is further characterized in that the cutter wheel tip forms one scribe line, moves on the surface drawing a circular trace, and then, forms the other scribe line.

5 [0051] The present invention is further characterized in that, when the cutter wheel tip moves on the substrate drawing a circular trace, pressure to the substrate is reduced compared to pressure to the substrate when the scribe lines are being formed.

10 [0052] A substrate cutting method according to the present invention is characterized in that a scribing method for forming scribe lines on an upper surface and a lower surface of the substrate comprises the steps of: forming a main scribe line along a line to be cut on the substrate by opposing scribe line formation means for forming a vertical crack along a thickness direction of the substrate; and forming a supplementary scribe line along the main scribe line with a predetermined space apart from the formed main scribe line.

15 [0053] The present invention is further characterized in that the supplementary scribe line is formed with a space of 0.5 mm to 1.0 mm apart from the main scribe line.

20 [0054] The present invention is further characterized in that the main scribe line is formed by a vertical crack which extends to 80% or more of a thickness direction of the substrate from the substrate surface.

25 [0055] The present invention is further characterized in that the main scribe line is formed by a vertical crack which extends to 90% or more of a thickness direction of the substrate from the substrate surface.

30 [0056] The present invention is further characterized in that the main scribe line is formed by a cutter wheel having a disc shape which rotates on the substrate surface, the cutter wheel protruding outward so as to have a center portion of an outer periphery in a width direction which has a shape of letter V with an obtuse angle, a plurality of protrusions with a predetermined height being provided across the entire circumferential with a predetermined pitch in a portion having the obtuse angle.

35 [0057] The present invention is further characterized in that a formation direction of main scribe line and a formation direction of supplementary scribe line by the cutter wheel are opposite to each other, and the cutter wheel continuously form the main scribe line and the supplementary scribe line in contact with the substrate surface.

40 [0058] The present invention is further characterized in that the main scribe line and the supplementary scribe line are formed with an appropriate space from at least one end portion of the line to be cut.

45 [0059] Further a substrate cutting method for cutting a substrate having scribe lines formed respectively on an upper surface and a lower surface of the substrate is characterized in that: the upper surface and the lower surface of the substrate are heated for cutting the substrate.



## BRIEF DESCRIPTION OF THE DRAWINGS

[0060]

Figure 1 is a schematic perspective view showing an example of a substrate cutting system according to Embodiment 1 of the present invention.

Figure 2 is a schematic perspective view of the substrate cutting system according to Embodiment 1 of the present invention viewed from another direction.

Figure 3 is a perspective view of an important part of the substrate cutting system according to Embodiment 1 of the present invention.

Figure 4 is a perspective view for illustrating operations of a substrate supporting device of the substrate cutting system according to Embodiment 1 of the present invention.

Figure 5 is a cross-sectional view of an important part of the substrate cutting system according to Embodiment 1 of the present invention.

Figure 6 is a schematic perspective view of an important part of the substrate cutting system according to Embodiment 1 of the present invention which is enlarged.

Figure 7 is a schematic perspective view of another important part of the substrate cutting system according to Embodiment 1 of the present invention which is enlarged.

Figure 8 is a perspective view of a first substrate supporting unit provided in the substrate supporting device of the substrate cutting system according to Embodiment 1 of the present invention.

Figure 9 is a front view of a substrate upward/downward moving device in the first substrate supporting unit with a part thereof being broken.

Figure 10 is a side view showing structures of connection arms attached to at least one end portion of the first substrate supporting units.

Figure 11 is a front view of the substrate upward/downward moving device shown in Figure 9 with a part thereof being broken.

Figure 12 is a perspective view of the substrate upward/downward moving device with a part thereof being broken.

Figure 13 is a perspective view for showing struc-

tures of clamp device provided in the substrate cutting system.

Figure 14 is a perspective view for showing an operation of the clamp device.

Figure 15 is a side view showing an example of a cutter head provided in the substrate cutting device in the substrate cutting system according to Embodiment 1 of the present invention.

Figure 16 is a front view showing an important part of the cutter head.

Figure 17 is a front view showing another example of the cutter head provided in the substrate cutting device in the substrate cutting system according to Embodiment 1 of the present invention.

Figure 18 is a schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 1 of the present invention.

Figure 19 is a schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 1 of the present invention.

Figure 20 is a schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 1 of the present invention.

Figure 21 is a cross sectional view of a substrate for illustrating the principle of a substrate cutting method according to the present invention.

Figure 22 is a plan view of a substrate showing a scribe pattern for the substrate for illustrating an example of the substrate cutting method according to the present invention.

Figure 23 is a plan view of a substrate showing a scribe pattern for the substrate for illustrating another example of the substrate cutting method according to the present invention.

Figure 24 is a partial plan view showing a scribe pattern for the substrate for illustrating yet another example of the substrate cutting method according to the present invention.

Figure 25 is a plan view showing a scribe pattern for the substrate for illustrating yet another example of the substrate cutting method according to the present invention.

Figure 26 is a plan view of a substrate showing a scribe pattern for the substrate for illustrating yet another example of the substrate cutting method ac-

according to the present invention.

Figure 27 is a partial plan view of a substrate showing a scribe pattern for the substrate for illustrating yet another example of the substrate cutting method according to the present invention.

Figure 28 is a plan view of a substrate showing a scribe pattern for the substrate for illustrating yet another example of the substrate cutting method according to the present invention.

Figure 29 is a plan view for illustrating yet another example of the substrate cutting method according to the present invention.

Figure 30 is a plan view of a substrate showing a scribe pattern for the substrate for illustrating yet another example of the substrate cutting method according to the present invention.

Figure 31 is a schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 1 of the present invention.

Figure 32 is a schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 1 of the present invention.

Figure 33 is a front view of an important part of a steam unit portion of the substrate cutting system according to Embodiment 1 of the present invention.

Figure 34 is a partial cross-sectional side view showing a structure of a steam unit in the steam unit portion.

Figure 35 is a diagram for showing a scribe pattern for scribing a substrate in a substrate cutting system according to Embodiment 2 of the present invention.

Figure 36 is a diagram for showing another scribe pattern for scribing a substrate in the substrate cutting system according to Embodiment 1 of the present invention.

Figure 37 is a diagram for showing yet another scribe pattern for scribing a substrate in the substrate cutting system according to Embodiment 1 of the present invention.

Figure 38 is a schematic perspective view for showing an example of the substrate cutting system according to Embodiment 2 of the present invention.

Figure 39 is a schematic perspective view of the

substrate cutting system viewed from another direction.

Figure 40 is a schematic perspective view of an important part of the substrate cutting system which is enlarged.

Figure 41 is a schematic perspective view of another important part of the substrate cutting system which is enlarged.

Figure 42 includes: portion (a) schematically showing structure of a carrying robot of a substrate carrying apparatus; and portion (b) illustrating an operation of the carrying robot.

Figure 43 is a side view of a first substrate supporting unit provided in a substrate supporting device of the substrate cutting system.

Figure 44 is a front view of the first substrate supporting unit viewed from a scribing device guide body side of the substrate cutting system.

Figure 45 is a schematic diagram showing a structure of a clutch unit provided in a substrate supporting portion of the substrate cutting system.

Figure 46 is a side view of the clutch unit.

Figure 47 is a front view of an important part of a steam unit portion of the substrate cutting system according to Embodiment 2 of the present invention when viewed from a substrate carry-in side.

Figure 48 is a partial cross-sectional side view showing a structure of a steam unit in the steam unit portion.

Figure 49 is a perspective view for showing a clamp device provided in the substrate cutting system according to Embodiment 2 of the present invention and illustrating an operation thereof.

Figure 50 is a perspective view for showing a clamp device provided in the substrate cutting system according to Embodiment 2 of the present invention and illustrating an operation thereof.

Figure 51 is a side view showing an example of a cutter head included in a substrate cutting device of the substrate cutting system according to Embodiment 2 of the present invention.

Figure 52 is a front view of a major part of the cutter head.

Figure 53 is a front view showing another example

of the cutter head included in the substrate cutting device of the substrate cutting system according to Embodiment 2 of the present invention.

Figure 54 is a schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 2 of the present invention. 5

Figure 55 is a schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 2 of the present invention. 10

Figure 56 is a diagram for showing a scribe pattern for scribing a substrate in the substrate cutting system according to Embodiment 2 of the present invention. 15

Figure 57 is a diagram for showing another scribe pattern for scribing a substrate in the substrate cutting system according to Embodiment 2 of the present invention. 20

Figure 58 is a diagram for showing yet another scribe pattern for scribing a substrate in the substrate cutting system according to Embodiment 2 of the present invention. 25

Figure 59 is a schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 2 of the present invention. 30

Figure 60 is a schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 2 of the present invention. 35

Figure 61 is a cross-sectional view of a substrate for illustrating a principle of a substrate cutting method according to the present invention.

Figure 62 is a plan view of a substrate showing a scribe pattern of the substrate for illustrating an example of the substrate cutting method according to the present invention. 40

Figure 63 is a plan view of a substrate showing a scribe pattern of the substrate for illustrating another example of the substrate cutting method according to the present invention. 45

Figure 64 is a partial plan view of a substrate showing a scribe pattern of the substrate for illustrating yet another example of the substrate cutting method according to the present invention. 50

Figure 65 includes: portions (a) and (b) providing plan view of a substrate showing a scribe pattern of the substrate for illustrating yet another example of the substrate cutting method according to the 55

present invention.

Figure 66 is a plan view of a substrate showing a scribe pattern of the substrate for illustrating yet another example of the substrate cutting method according to the present invention.

Figure 67 is a partial plan view of a substrate showing a scribe pattern of the substrate for illustrating yet another example of the substrate cutting method according to the present invention.

Figure 68 is a plan view of a substrate showing a scribe pattern of the substrate for illustrating yet another example of the substrate cutting method according to the present invention.

Figure 69 is a plan view for illustrating yet another example of the substrate cutting method according to the present invention.

Figure 70 is a plan view of a substrate showing a scribe pattern of the substrate for illustrating yet another example of the substrate cutting method according to the present invention.

Figure 71 is a schematic perspective view showing an example of a substrate cutting system according to Embodiment 3 of the present invention in whole.

Figure 72 is a schematic plan view showing the substrate cutting system.

Figure 73 is a schematic side view showing the substrate cutting system.

Figure 74 is a schematic perspective view showing a positioning unit portion of the substrate cutting system according to Embodiment 3 of the present invention.

Figure 75 is a schematic plan view of a lift conveyer portion of the substrate cutting system according to Embodiment 3 of the present invention.

Figure 76 is a side view of a third substrate supporting unit of the lift conveyer portion.

Figure 77 is a schematic view for illustrating a panel terminal separation portion of the substrate cutting system according to Embodiment 3 of the present invention.

Figure 78 is a partial schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 3 of the present invention.

Figure 79 is a partial schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 3 of the present invention.

Figure 80 is a partial schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 3 of the present invention.

Figure 81 is a partial schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 3 of the present invention.

Figure 82 is a partial schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 3 of the present invention.

Figure 83 is a partial schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 3 of the present invention.

Figure 84 is a schematic perspective view showing an example of a substrate cutting system according to Embodiment 4 of the present invention.

Figure 85 is a schematic perspective view of a first substrate supporting unit of a substrate supporting device of the substrate cutting system.

Figure 86 is a side view for illustrating an operation of the substrate supporting device of the substrate cutting system.

Figure 87 is a schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 4 of the present invention.

Figure 88 is a schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 4 of the present invention.

Figure 89 is a schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 4 of the present invention.

Figure 90 is a schematic plan view for illustrating an operation of the substrate cutting system according to Embodiment 4 of the present invention.

Figure 91 is a schematic view showing an example of a structure of a substrate manufacturing apparatus according to the present invention using the substrate cutting system according to Embodiments 1 to 4.

Figure 92 is a schematic view showing another example of a structure of a substrate manufacturing apparatus according to the present invention using the substrate cutting system according to Embodiments 1 to 4.

Figure 93 is a front view showing a structure of a conventional scribing apparatus.

## 10 BEST MODE FOR CARRYING OUT THE INVENTION

[0061] Hereinafter, embodiments of the present invention will be described in detail with reference to the drawings.

<Embodiment 1>

[0062] Figures 1 and 2 are perspective views schematically showing an entire structure of an example of a substrate cutting system according to Embodiment 1 of the present invention from different directions. Figure 3 is a perspective view schematically showing a structure of an important part of the system. Figure 4 is a perspective view for illustrating an operation. Figure 5 is a cross-sectional view of the important part.

[0063] In the present invention, "substrates" include mother substrates cut into a plurality of substrates and also include single plates of metal substrates such as steel sheets, woodplates, plastic substrates and ceramic substrate, semiconductor substrates, and brittle material substrates such as glass substrates. Furthermore, the "substrates" are not limited to such single plates, but also includes bonded substrates formed by bonding pairs of substrates and laminated substrates formed by laminating pairs of substrates.

[0064] For example, when panel substrates of a liquid crystal display apparatus in which a pair of glass substrates are bonded to each other (bonded substrate for display panel substrates) are manufactured, a substrate cutting system according to the present invention cuts a bonded mother substrate 90 which is formed by bonding a pair of mother glass substrates to each other into a plurality of panel substrates (bonded substrate for display panel substrates).

[0065] The substrate cutting system includes a hollow mounting structure 10 having a parallelepiped shape. On the mounting structure 10, a pair of main frames 11 are located along a longitudinal direction. In the mounting structure 10, a substrate supporting device 20 (see Figures 3 and 4) for supporting the bonded mother substrate 90 to be carried to the substrate cutting system by a carrying robot, carrying belt or the like in a horizontal manner is located.

[0066] Further, as shown in Figure 5, in the mounting structure 10, a clamp device 50 for holding a substrate held in a horizontal manner by substrate upward/downward moving device 40 (see Figure 8) provided in the substrate supporting device 20 (a first substrate sup-

porting unit 21A) in a horizontal manner is provided. The substrate supporting device 20 is not shown in Figure 5. Further, on the main frames 11, scribing device guide body 30 is provided so as to be movable along the longitudinal direction of the main frames 11. The scribing device guide body 30 includes an upper guide rail 31 extending along a direction orthogonal to the main frames 11 above the main frames 11 and a lower guide rail 32 extending along the upper guide rail 31 below the main frames 11. The upper guide rail 31 and the lower guide rail 32 are formed so as to move integrally along the main frames 11.

[0067] Figure 6 is a schematic perspective view showing near the upper guide rail 31 in the scribing device guide body 30. To the upper guide rail 31, upper portion substrate cutting device 60 is attached so as to be movable along the upper guide rail 31. Figure 7 is a schematic perspective view showing near the lower guide rail 32 in the scribing device guide body 30. To the lower guide rail 32, lower portion substrate cutting device 70 is attached so as to be movable along the lower guide rail 32.

[0068] The upper portion substrate cutting device 60 and the lower portion substrate cutting device 70 respectively move back and forth along the upper guide rail 31 and the lower guide rail 32 by linear motors. To the upper guide rail 31 and the lower guide rail 32, stators of the linear motors are respectively attached. To the upper portion substrate cutting device 60 and the lower portion substrate cutting device 70, movers of the linear motors are respectively attached. The upper portion substrate cutting device 60 and the lower portion substrate cutting device 70 cut glass substrates on upper and lower sides of the bonded mother substrate 90 held by the clamp device 50 in a horizontal manner and also supported by the substrate supporting device 20 for assisting holding the substrates.

[0069] In one end portion of the scribing device guide body 30, a first optical device 38 for taking an image of a first alignment mark of the bonded mother substrate 90 held by the clamp device 50 and supported by the substrate supporting device 20 is provided so as to be movable along the scribing device guide body 30. In the other end portion of the scribing device guide body 30, a second optical device 39 for taking an image of a second alignment mark provided on the bonded mother substrate 90 is provided so as to be movable along the scribing device guide body 30.

[0070] As shown in Figures 3 and 4, the substrate supporting device 20 includes a first substrate supporting portion 20A located on a side, to which substrates are to be carried, of the scribing device guide body 30 for supporting the bonded mother substrate 90 to be carried into the mounting structure 10 (see Figure 2), and a second substrate supporting portion 20B located on a side, from which substrates are carried out, of the scribing device guide body 30 for supporting the bonded mother substrate 90 after the bonded mother substrate

90 is cut and the panel substrates are sequentially carried out of the mounting structure 10. In the mounting structure 10, the first substrate supporting portion 20A side is a substrate carry-in side, the second substrate supporting portion 20B side is a carry-out side.

[0071] In the main frames 11 of the mounting structure 10, stators 12 of linear motors for moving the scribing device guide body 30 are respectively provided on upper surfaces of the main frames 11 along the longitudinal direction of the main frames 11. The stators 12 are respectively formed to have a flat hollow parallelepiped shape with external side surfaces opened. Thus, cross-sections thereof have squared "C" shape. In the stators, movers (not shown) of the linear motors attached to the scribing device guide body 30 are inserted so as to be movable along the main frames 11.

[0072] In the stators 12, a plurality of permanent magnets are respectively located along the longitudinal directions with the magnetic poles of the permanent magnets adjacent to each other are reversed. The movers are respectively formed of electromagnets. By sequentially switching magnetic poles of the electromagnets forming the movers, the movers slide respectively along the stators 12.

[0073] As shown in Figure 4, the movers of the linear motors are attached to inner side surfaces of coupling plates 33 for coupling end surfaces of the upper guide rail 31 and the lower guide rail 32 to each other. The movers are driven in synchronization and slid with respect to the stators 12.

[0074] Between the main frames 11 in the mounting structure 10 (see Figure 2), a substrate carry-out device 80 (see Figure 3) for carrying out panel substrates out of the bonded mother substrate 90 bridges. The substrate carry-out device 80 is located on the substrate carry-out side with respect to the scribing device guide body 30, and end portions thereof slide along guide rails 19 (see Figure 5) respectively provided on the main frames 11 by the linear motors. In this case, the linear motors are formed by inserting movers (not shown) of the linear motors respectively attached to the end portions of the substrate carry-out device 80 into the linear motor stators 12 respectively provided on the main frames 11.

[0075] The substrate carry-out device 80 includes an adsorption portion (not shown) for suction-adsorbing panel substrates cut out of the bonded mother substrate 90. The entire substrate carry-out device 80 is slid to the substrate carry-out side with the panel substrate adsorbed by the adsorption portion, and the panel substrates are carried out from the mounting structure 10.

[0076] As shown in Figures 3 and 4, in end portions of one of the main frames 11, i.e., an end portion on the substrate carry-in side and an end portion on the substrate carry-out side of one main frame 11, a first carry-in pulley 14a and a first carry-out pulley 15a are respectively provided. Further, in an end portion on the substrate carry-in side and an end portion on the substrate

carry-out side of the other main frame 11, a second carry-in pulley 14b and a second carry-out pulley 15b are respectively provided. A first transmission belt 16a loops around the first carry-in pulley 14a and the first carry-out pulley 15a located along one main frame 11. A second transmission belt 16b loops around the second carry-in pulley 14b and the second carry-out pulley 15b located along the other main frame 11.

[0077] Between the first carry-in pulley 14a and the second carry-in pulley 14b located in the end portion on the substrate carry-in side, a carry-in side winding drum 17a is provided in a concentric fashion with the first carry-in pulley 14a and the second carry-in pulley 14b. The carry-in side winding drum 17a is coupled to the first carry-in pulley 14a around which the first transmission belt 16a loops. When the first carry-in pulley 14a rotates, the carry-in side winding drum 17a integrally rotates in the same direction. The second carry-in pulley 14b provided in the other end portion of the carry-in side winding drum 17a can rotate freely with respect to the carry-in side winding drum 17a.

[0078] Between the first carry-out pulley 15a and the second carry-out pulley 15b located in the end portion on the substrate carry-out side, a carry-out side winding drum 17b is provided in a concentric fashion with the first carry-out pulley 15a and the second carry-out pulley 15b. The carry-out side winding drum 17b is coupled to the second carry-out pulley 15b around which the second transmission belt 16b loops. When the second carry-out pulley 15b rotates, the carry-out side winding drum 17b integrally rotates in the same direction. The first carry-out pulley 15a provided in the other end portion of the carry-out side winding drum 17b can rotate freely with respect to the carry-out side winding drum 17b.

[0079] The first transmission belt 16a located along one of the main frames 11 of the mounting structure 10 is coupled to an end portion of the respective scribing device guide body 30. Thus, when the scribing device guide body 30 moves toward the substrate carry-in side, the first transmission belt 16a moves and the first carry-in pulley 14a and the first carry-out pulley 15a around which the first transmission belt 16a loops rotate in the same direction. The rotation of the first carry-in pulley 14a causes the carry-in side winding drum 17a to rotate integrally with the first carry-in pulley 14a in the same direction. In such a case, the carry-out side winding drum 17b located in the concentric fashion with the second carry-out pulley 15b is not rotated and only the first carry-out pulley 15a is rotated since the first carry-out pulley 15a and the carry-out side winding drum 17b are not coupled to each other.

[0080] On the other hand, when the scribing device guide body 30 moves toward the substrate carry-out side, the first transmission belt 16a moves and the first carry-in pulley 14a and the first carry-out pulley 15a around which the first transmission belt 16a loops rotate in the same direction. Thus, the carry-in side winding

drum 17a rotates in the same direction as the first carry-in pulley 14a. However, in such a case, as described above, the carry-out side winding drum 17b located on the substrate carry-out side does not rotate.

[0081] The first substrate supporting portion 20A and the second substrate supporting portion 20B of the substrate supporting device 20 respectively have five first substrate supporting units 21A and second substrate supporting units 21B. The first substrate supporting units 21A and the second substrate supporting units 21B are respectively formed to have a linear shape along the direction orthogonal to the main frames 11.

[0082] Figure 8 is a perspective view of one of the first substrate supporting units 21A provided in the first substrate supporting portion 20A. The first substrate supporting unit 21A has a support main body 21a elongated linearly along the direction orthogonal to the main frames 11. To end portions of the support main body 21a, connection plates 21b extended upward in a direction vertical to the support main body 21a are attached. In upper end portions of the connection plates 21b, sliders 21c, which slidably engage substrate supporting unit guide rails 13 (see Figure 5) provided on outer side surfaces of the main frames 11, are provided. The sliders 21c slide along the substrate supporting unit guide rails 13. Thus, the first substrate supporting units 21A move along the main frames 11.

[0083] On each of the first substrate supporting units 21A, for example, six pairs of guide rollers 21d are provided with a predetermined space therebetween in the direction orthogonal to the main frames 11, and the substrate upward/downward moving device 40 is provided between a pair of guide rollers 21d.

[0084] Figure 9 is a front view of a pair of the guide rollers 21d provided in the first substrate supporting units 21A of the first substrate supporting portion 20A and the substrate upward/downward moving device 40 provided between the guide rollers 21d with a part of the substrate upward/downward moving device 40 being broken. The guide rollers 21d are supported so as to be rotatable at upper edge portions of roller supporting members 21e vertically supported by the support main bodies 21a with the roller axes thereof are in a horizontal manner along the direction orthogonal to the main frames 11.

[0085] Among five first substrate supporting units 21A which form the first substrate supporting portion 20A, the guide rollers 21d provided on the first substrate supporting units 21A are provided at the same position of the support main body 21a. Thus, the guide rollers 21d provided on one of the first substrate supporting units 21A and the guide rollers 21d provided on the adjacent first substrate supporting unit 21A are arranged in a line along the main frames 11. The guide rollers 21d of all the first substrate supporting units 21A which are lined along the main frames 11 together support one first supporting belt 23a.

[0086] As shown in Figures 3 and 4, each of the first



supporting belts 23a has one end portion fixed in place on the substrate carry-in side of the mounting structure 10. Each of the first supporting belts 23a is supported by the guide rollers 21d of all the first substrate supporting units 21A which are lined along the main frames 11 in the first substrate supporting portion 20A. The first supporting belts 23a respectively loop around the guide rollers 21d provided on the first substrate supporting units 21A nearest to the scribing device guide body 30. The first supporting belts 23a pass below the guide rollers 21d of all the first substrate supporting units 21A lined along the main frames 11 in the first substrate supporting portion 20A and are pulled toward the substrate carry-in side. The first supporting belts 23a are respectively wound to the carry-in side winding drum 17a between the first carry-in pulley 14a and the second carry-in pulley 14b located in the end portion on the substrate carry-in side.

[0087] The first substrate supporting units 21A adjacent to each other are coupled to each other by connection arms 28a respectively attached to end portions of the first substrate supporting units 21A. Figure 10 is a side view showing the structure of the connection arms 28a attached to at least one end portion of the first substrate supporting units 21A. It is preferable that the connection arms 28a are attached to both end portions of the first substrate supporting units 21A. The connection arms 28a have center portions rotatably attached to the connection plates 21b attached to end portions of the support main bodies 21a in the first substrate supporting units 21A by attachment pins 28b. End portions of the connection arms 28a attached to the first substrate supporting units 21A adjacent to each other are rotatably attached to each other by a connection pin 28c.

[0088] The connection arm 28a attached to the first substrate supporting unit 21A located nearest to the end portion on the substrate carry-out side has its end portion which is different from the end portion coupled to the adjacent first substrate supporting unit 21A rotatably attached to one end portion of a rotation arm 28d by a connection pin 28c. The rotation arm 28d has the other end portion rotatably attached to the main frames 11 by a fixing pin 28e.

[0089] The connection arm 28a attached to the first substrate supporting unit 21A located to be nearest to the scribing device guide body 30 has its end portion which is different from the end portion coupled to the adjacent first substrate supporting unit 21A rotatably attached to one end portion of a rotation arm 28g by a connection pin 28c. The rotation arm 28g has the other end portion rotatably attached to the scribing device guide body 30 by a fixing pin 28f.

[0090] In the first substrate supporting portion 20A having the structure as described above, when the scribing device guide body 30 slides toward the substrate carry-out side, the first substrate supporting unit 21A provided near the scribing device guide body 30 integrally slides in the same direction. Then, each of the

first substrate supporting units 21A slides toward the end portion on the substrate carry-out side with a space apart from the adjacent first substrate supporting unit 21A in the sliding direction in turn. Thus, all the first substrate supporting units 21A are arranged across the longitudinal direction of the mounting structure 10 with predetermined spaces therebetween.

[0091] In this case, the scribing device guide body 30 slides toward the substrate carry-out side, and thus, the first transmission belt 16a moves, the first carry-in pulley 14a rotates, and the carry-in side winding drum 17a rotates. Thus, the first substrate supporting units 21A move integrally with the scribing device guide body 30, and the all the first supporting belts 23a wound to the carry-in side winding drum 17a are drawn out.

[0092] As described above, when all the first substrate supporting units 21A in the first substrate supporting portion 20A are arranged across the entire region of the longitudinal direction of the mounting structure 10 with predetermined spaces therebetween, the bonded mother substrate 90 is placed on abut members 48 (see Figure 9) of the substrate upward/downward moving device 40 provided on the first substrate supporting units 21A.

[0093] On the other hand, in the first substrate supporting portion 20A, when the scribing device guide body 30 slides toward the substrate carry-in side, the first substrate supporting unit 21A provided near the scribing device guide body 30 integrally slides in the same direction. Then, each of the first substrate supporting units 21A slides toward the end portion on the substrate carry-in side becoming closer to the adjacent first substrate supporting unit 21A in the sliding direction. Thus, all the first substrate supporting units 21A become close to each other in the end portion on the substrate carry-in side.

[0094] In this case, as described above, the scribing device guide body 30 slides toward the substrate carry-in side, and thus, the first transmission belt 16a moves, the first carry-in pulley 14a rotates, and the carry-in side winding drum 17a rotates integrally with the first carry-in pulley 14a. Thus, the first supporting belts 23a supported by the guide rollers 21d of the first substrate supporting units 21A are wound to the carry-in side winding drum 17a.

[0095] When the first substrate supporting units 21A slide in the end portion on the substrate carry-in side to the state where they are close to each other with the bonded mother substrate 90 being held by the clamp device 50 and supported on the first supporting belts 23a, the first supporting belts 23a are wound by the carry-in side winding drum 17a as the first substrate supporting units 21A slide. Thus, there is no possibility that the first supporting belts 23a are in sliding contact with a bottom surface of the bonded mother substrate 90.

[0096] The second substrate supporting portion 20B located on the substrate carry-out side with respect to the scribing device guide body 30 also has, for example,

five second substrate supporting units **21B**. The second substrate supporting units **21B** provided in the second substrate supporting portion **20B** have similar structures as the first substrate supporting units **21A** of the first substrate supporting portion **20A** except for that the substrate upward/downward moving device **40** is not provided. In the second substrate supporting portion **20B**, each of second supporting belts **23b** is respectively supported by the guide rollers **21d** in all the second substrate supporting units **21B** which are lined along the main frames **11**.

[0097] Each of the second supporting belts **23b** has an end portion located in the end portion on the substrate carry-out side fixed in place on the mounting structure **10**. The second supporting belts **23b** loop around the guide rollers **21d** provided in the second substrate supporting unit **21B** which is closest to the scribing device guide body **30**, pass below the guide rollers **21d** of all the second substrate supporting units **21B** lined along the main frames **11** in the second substrate supporting portion **20B**, and wound to the carry-out side winding drum **17b** provided between the first carry-out pulley **15a** and the second carry-out pulley **15b** on the substrate carry-out side.

[0098] In the second substrate supporting portion **20B**, movers (not shown) which form linear motors with the stators **12** provided on the main frames **11** are respectively provided in end portions in the longitudinal direction of the second substrate supporting unit **21B** located closest to the scribing device guide body **30**. The movers are respectively inserted into the stators **12**. The movers slide inside the stators **12** to cause the second substrate supporting unit **21B** close to the scribing device guide body **30** independently slides along the main frames **11** separately from the scribing device guide body **30**.

[0099] Further, the second substrate supporting unit **21B** close to the scribing device guide body **30** is coupled to the second transmission belt **16b**. Thus, when the second substrate supporting unit **21B** slides along the main frames **11**, the second transmission belt **16b** is moved.

[0100] As described above, the second carry-out pulley **15b** around which the second transmission belt **16b** loops is coupled to the carry-out side winding drum **17b**. Thus, when the second substrate supporting units **21B** attached to the second transmission belt **16b** is slid toward the substrate carry-out side, the second transmission belt **16b** moves in the same direction and the second carry-out pulley **15b** rotates, the carry-out side winding drum **17b** rotates and the all the second supporting belts **23b** attached to the carry-out side winding drum **17b** are wound to the carry-out side winding drum **17b**.

[0101] In the second substrate supporting portion **20B**, second substrate supporting units **21B** adjacent to each other are coupled to each other by connection arms **28a** respectively attached to the end portions of

the second substrate supporting units **21B**. Center portions of the connection arms **28a** are rotatably attached to the second substrate supporting units **21B**. The end portions of the connection arms **28a** attached to the second substrate supporting units **21B** adjacent to each other are rotatably attached to each other. The connection arm **28a** attached to the second substrate supporting unit **21B** provided to be closest to the substrate carry-out side has its end portion opposite to the end portion attached to the adjacent second substrate supporting unit **21B** rotatably attached to the main frames **11**. Further, the connection arm **28a** attached to the second substrate supporting unit **21B** close to the scribing device guide body **30** has one end portion rotatably attached to the second substrate supporting unit **21B** and the other end portion attached to an end portion of a connection arm **28a** attached to the adjacent second substrate supporting unit **21B**.

[0102] In the second substrate supporting portion **20B** having such a structure, when the second substrate supporting unit **21B** close to the scribing device guide body **30** slides toward the substrate carry-in side, each of the second substrate supporting units **21B** slide toward the end portion on the substrate carry-in side while being separated from the adjacent second substrate supporting unit **21B** in the sliding direction. Thus, all the second substrate supporting units **21B** are arranged across the approximately entire region in the longitudinal direction of the mounting structure **10** with predetermined spaces therebetween.

[0103] In this case, the second substrate supporting unit **21B** close to the scribing device guide body **30** slides toward the substrate carry-in side, and thus, the second transmission belt **16b** moves, the second carry-out pulley **15b** rotates and the carry-out side winding drum **17b** rotates. Thus, the second substrate supporting units **21B** around which the second supporting belts **23b** loop move and the all the second supporting belts **23b** wound to the carry-out side winding drum **17b** are drawn out.

[0104] As described above, when all the first substrate supporting units **21A** of the first substrate supporting portion **20A** are located across approximately entire region of the longitudinal direction of the mounting structure **10** with predetermined spaces therebetween, the bonded mother substrate **90** is placed on the abut members **48** (see Figure 9) of the substrate upward/downward moving device **40** provided on the first substrate supporting units **21A**.

[0105] Thereafter, when the bonded mother substrate **90** is positioned, the positioned bonded mother substrate **90** is held by the clamp device **50** and also supported by first supporting belts **23a** of the first substrate supporting portion **20A**.

[0106] In this state, cutting of the bonded mother substrate **90** is started by the upper portion substrate cutting device **60** and the lower portion substrate cutting device **70** provided on the scribing device guide body **30**. As

the scribing device guide body 30 moves toward the substrate carry-in side, each of the first substrate supporting units 21A of the first substrate supporting portion 20A slides to the end portion on the substrate carry-in side while becoming closer to the adjacent first substrate supporting unit 21A in the sliding direction. Further, each of the second substrate supporting unit 21B of the second substrate supporting portion 20B slides toward the end portion on the substrate carry-in side while being separated from the adjacent second substrate supporting unit 21B in the sliding direction. Thus, the bonded mother substrate 90 while being out is also supported by the second supporting belts 23b of the second substrate supporting portion 20B.

[0107] When cutting of the bonded mother substrate 90 is finished, all the second substrate supporting units 21B of the second substrate supporting portion 20B are arranged across approximately entire region of the longitudinal direction of the mounting structure 10 with predetermined spaces therebetween, and the bonded mother substrate 90 is supported by the second supporting belts 23b.

[0108] Thus, when all the second substrate supporting units 21B of the second substrate supporting portion 20B are arranged across approximately entire region of the longitudinal direction of the mounting structure 10 with predetermined spaces therebetween, cut bonded mother substrate 90' (mill end) is supported on the second supporting belts 23b supported by the guide rollers 21d provided on the second substrate supporting units 21B after all the panel substrates are carried out by the substrate carry-out device 80.

[0109] Thereafter, the out bonded mother substrate 90' is released from being held by the clamp device 50 and the second substrate supporting unit 21B close to the scribing device guide body 30 slides toward the end portion on the substrate carry-out side. Thus, each of the second substrate supporting units 21B slides toward the end portion on the substrate carry-out side while becoming closer to the adjacent second substrate supporting unit 21B in the sliding direction, and all the second substrate supporting units 21B become close to each other in the end portion on the substrate carry-out side.

[0110] In this case, as described above, the second substrate supporting unit 21B close to the scribing device guide body 30 slides toward the substrate carry-out side and the second transmission belt 16b moves. Then, the second carry-out pulley 15b rotates and the carry-out side winding drum 17b rotates integrally with the second carry-out pulley 15b. Thus, the second supporting belts 23b supported by the guide rollers 21d of the second substrate supporting units 21B are wound to the carry-out side winding drum 17b. The means for winding the first supporting belts 23a and the second supporting belts 23b is not limited to those rotating the carry-in side winding drum 17a and the carry-out side winding drum 17b by moving the scribing device guide body 30 and the second substrate supporting units 21B

as described above.

[0111] For example, a turning force may be applied in a direction to wind supporting belts to the winding drum all the time, and the scribing device guide body 30 and the second substrate supporting units 21B may be moved by a force stronger than the turning force.

[0112] Further, a mechanism for winding the first supporting belts 23a of the first substrate supporting portion 20A and the second supporting belts 23b of the second substrate supporting portion 20B described above may include a device for applying tension to the first supporting belts 23a and the second supporting belts 23b appropriately in accordance with the size of the device.

[0113] The carry-in pulleys 14a and 14b and the carry-out pulleys 15a and 15b may include a clutch for coupling and decoupling the winding drums 17a and 17b as necessary.

[0114] As described above, since the second substrate supporting units 21B slide toward the end portion on the substrate carry-out side, and thus, the guide rollers 21d provided on the second substrate supporting units 21B slid in the same direction, the second supporting belts 23b are sequentially brought into a non-contact state without being in sliding contact with the bottom surface of the cut bonded mother substrate 90'. The supports of the cut bonded mother substrate 90' by the second supporting belts 23b are sequentially released. When all the second substrate supporting units 21B become close to each other in the end portion on the substrate carry-out side, the out bonded mother substrate 90' (mill end) is not supported by the first supporting belts 23a any more and drops downward. In this case, the cut bonded mother substrate 90' dropped downward (mill end and outlet) is guided by a guiding plate arranged in a slanted state and is accommodated within a cullet accommodation box.

[0115] Figure 11 is a front view of the substrate upward/downward moving device 40 provided in the first substrate supporting units 21A of the first substrate supporting portion 20A with apart of the substrate upward/downward moving device 40 being broken. Figure 12 is a perspective view thereof. On each of the first substrate supporting units 21A provided in the first substrate supporting portion 20A, the substrate upward/downward moving device 40 is provided between a pair of guide rollers 21d. The substrate upward/downward moving device 40 includes a moving cylinder 41 attached to the support main body 21a of the first substrate supporting units 21A in a vertical fashion and positioning cylinders 42 located on both sides of the moving cylinder 41 in a vertical fashion. The second substrate supporting units 21B provided in the second substrate supporting portion 20B do not include such a substrate upward/downward moving device.

[0116] A piston rod 41a of the moving cylinder 41 is made to move upward, and a sliding member 43 is attached to a tip portion of the piston rod 41a. The sliding member 43 includes sliding portions 43a having a pipe

shape which are provided on side so as to locate on both sides of the moving cylinder 41, and a connection portion 43b having a plate shape which couples the sliding portions 43a. The center portions of the sliding portions 43a are attached to the tip portion of the piston rod 41a of the moving cylinder 41.

[0117] The positioning cylinders 42 provided on both sides of the moving cylinder 41 have similar structures. Respective piston rods 42a are made to move upward. To the tip portions of the piston rods 42a, guide rods 44 are coupled co-axially. The guide rods 44 are inserted through the sliding portions 43a of the sliding member 43 with appropriate spaces therebetween. In lower parts of the sliding portions 43a, slide bushings 47 which are in smooth sliding contact with the guide rods 44 inserted through the sliding portions 43a are provided.

[0118] To the lower end portions of the guide rods 44, set collars 45 having a disc shape are attached in a fitted state. On the set collars 45, buffer members 46 having a disc shape which are formed of polyurethane rubber are attached in a fitted state. The set collars 45 are at predetermined positions respectively close to the positioning cylinders 42 when the piston rods 42a of the positioning cylinders 42 are retracted into the positioning cylinders 42 to the innermost position.

[0119] On the connection portion 43b of the sliding member 43, a fixing table 43c is provided. On the fixing table 43c, the abut member 48 which abuts the bottom surface of the bonded mother substrate when the bonded mother substrate 90 is carried to the substrate cutting system by carrying means such as a carrying robot, carrying belt, or the like. The abut member 48 includes an abut main body 48a having a disc shape, and an axis portion 48b vertically extended from the center portion of the abut main body 48a. A lower end portion of the axis portion 48b is inserted through an upper surface portion of the fixing table 43c. To the axis portion 48b of the abut member 48, a coil spring 48c is fitted so as to position between the abut main body 48a of the abut member 48 and an upper surface of the fixing table 43c. Furthermore, a plurality of coil springs 48c are provided around the axis portion 48b between the abut main body 48a of the abut member 48 and the upper surface of the fixing table 43c. The coil springs 48c apply forces to the abut main body 48a in upward direction. The abut main body 48a is supported in a horizontal fashion by the coil springs 48c.

[0120] In the substrate upward/downward moving device 40 having such a structure, all the moving cylinders 41 provided in the first substrate supporting portion 20A are driven integrally and all the positioning cylinders 42 are driven integrally. When the piston rods 41a of the moving cylinders 41 are retracted to the innermost position, the abut main bodies 48a of the abut members 48 are at retraction positions which are below the upper end portion of the guide rollers 21d. Thus, at such retraction positions, the abut main bodies 48a of the abut members 48 are positioned below the bonded mother

substrate 90 supported by the first supporting belts 23a in the first substrate supporting portion 20A.

[0121] When the piston rods 41a of the moving cylinders 41 moves out to the uppermost position, the abut main bodies 48a of the abut members 48 are at support positions above the upper end portions of the guide rollers 21d, protruded upward by a predetermined height from the first supporting belts 23a. In such a case, the positioning cylinders 42 are not driven. Therefore, when the piston rods 41a of the moving cylinders 41 move out, the sliding members 43 attached to the piston rods 41a slide along the guide rods 44. When the piston rods 41a of the moving cylinders 41 moves out to the uppermost position, the abut main bodies 48a of the abut members 48 are at positions above the first supporting belts 23a. The bonded mother substrate 90 is placed on and supported by the abut main bodies 48a of the abut members 48.

[0122] The moving cylinder 41 is formed to have the piston rod 41a moved out by a predetermined amount such that the abut main body 48a of the abut member 48 is at a predetermined intermediate position protruded upward by a predetermined height from the first supporting belts 23a with the bonded mother substrate 90 being held. In this case, the moving cylinder 41 is driven such that the piston rod 41a of the moving cylinder 41 which has been moved out to the uppermost position is retracted after the piston rods 42a of the positioning cylinders 42 are made to move out by predetermined amounts. In this way, the set collars 45 attached to the guide rods 44 coupled to the piston rods 42a are at the predetermined positions and the sliding portions 43a of the sliding member 43 abut the set collars 45 via the buffer members 46 by the moving cylinder 41 so that the sliding member 43 is at a predetermined height position. This causes the abut main body 48a of the abut member 48 to be at a predetermined height position and the bonded mother substrate 90 supported by the abut main body 48a is placed at that position.

[0123] In the axis portion 48b of the abut member 48, a through hole 48d is formed. Through the through hole via a joint 48e, gas, for example, compressed air, nitrogen, He or the like is to be blown out.

[0124] The second substrate supporting units 21B provided in the second substrate supporting portion 20B does not have a substrate upward/downward moving device 40 having such a structure.

[0125] The structure of the substrate upward/downward moving device 40 as described above is merely an example used in the substrate cutting system of the present invention, and the structure is not limited to such a structure. As long as the substrate upward/downward moving device 40 can receive and support the bonded mother substrate 90 carried to the substrate cutting system of the present invention by a carrying robot, carrying belt or the like inside the substrate cutting system, it may have any structure.

[0126] The mounting structure 10 includes a position-

ing device (not shown) for positioning the bonded mother substrate 90 supported at an intermediate portion by all the substrate upward/downward moving devices 40 provided in the first substrate supporting portion 20A.

[0127] The positioning device includes, for example, a plurality of positioning pins (not shown) along one of the main frames 11 and along a direction orthogonal to the main frame 11 with predetermined spaces therebetween. For the positioning pins arranged along one of the main frames 11, pushers (not shown) for pushing a side edge of the bonded mother substrate 90 which opposes the positioning pins supported at the intermediate position. For the positioning pins arranged in a direction orthogonal to the main frame 11, pushers (not shown) for pushing an opposing side edge of the bonded mother substrate 90 are provided.

[0128] Further, for example, when the positioning device for performing positioning of the bonded mother substrate 90 immediately before transportation to the substrate cutting system of the present invention is provided separately from the substrate cutting system, a positioning device within the substrate cutting system may be omitted.

[0129] Further, the positioning device within the substrate cutting system is not limited to the positioning pins and pushers as described above. It may be any kind of devices as long as it can provide a constant position of the bonded mother substrate 90 in the substrate cutting system.

[0130] Furthermore, the mounting structure 10 includes the clamp device 50 for clamping the bonded mother substrate 90 which is supported at the intermediate position by all the substrate upward/downward moving devices 40 provided in the first substrate supporting portion 20A and pushed against the positioning pins so as to be positioned. For example, as shown in Figure 5, the clamp device 50 includes a plurality of clamp members 51 attached to one of the main frames 11 with predetermined spaces therebetween in a longitudinal direction so as to clamp a side edge of the positioned bonded mother substrate 90 along the main frame 11, and a plurality of clamp members 51 arranged along the direction orthogonal to the main frames 11 with a predetermined spaces therebetween for clamping a side edge of the positioned bonded mother substrate 90 on the substrate carry-in side.

[0131] Figure 13 is a perspective view for showing a plurality of clamp members 51 provided on one of the main frames 11. Figure 14 is a perspective view for showing an operation thereof. The clamp members 51 have similar structures to each other. Each of the clamp members 51 includes a casing 51a attached to the main frame 11 and a pair of upper and lower rotation arms 51b attached to the casing 51a so as to be rotatable from a vertical position to a horizontal position. Each of the rotation arms 51b can rotate having one end portion as a center. The end portions to be the center of rotation are located close to each other. A tip portion of the upper

rotation arm 51b locates above the rotation center in the vertical position. A tip portion of the lower rotation arm 51b locates below the rotation center in the vertical position. The rotation arms 51b respectively rotate by 90 degrees toward the bonded mother substrate 90, and thus, the rotation arms 51b are in horizontal positions opposing each other.

[0132] To the tip portions of the rotation arms 51b, clamp portions 51c which respectively abut the upper surface or the lower surface of the bonded mother substrate 90 are attached. The clamp portions 51c are formed of elastic body. The rotation arms 51b are integrally rotated from the vertical position to the horizontal position and from the horizontal position to the vertical position. When the rotation arms 51b are rotated to the horizontal position, the clamp portions 51c attached to the tip portions of the rotation arms 51b clamp the bonded mother substrate 90.

[0133] The clamp members 51 arranged along a direction orthogonal to the main frames 11 have similar structures. These clamp members 51 are also driven integrally. After the side edges orthogonal to each other of the bonded mother substrate 90 are clamped by the plurality of clamp members 51, all the clamp members 51 sink below, and the bonded mother substrate 90 is supported by the first supporting belts 23a of the first substrate supporting portion 20A.

[0134] The structures of the clamp device 50 and the clamp members 51 as described above are merely examples used in the substrate cutting system of the present invention, and the structures are not limited to such structures. The clamp device 50 and the clamp members 51 may have any kind of structures as long as they can grip or hold the side edges of the bonded mother substrate 90. When the substrate size is small, the substrate can be held by clamping one position of the side edge of the substrate, and the substrate can be cut without causing a defect in the substrate.

[0135] As shown in Figure 6, the upper portion substrate cutting device 60 is attached to the upper guide rail 31 in the scribing device guide body 30. As shown in Figure 7, the lower portion substrate cutting device 70 having the similar structure as the upper portion substrate cutting device 60 but inverted upside down is attached to the lower guide rail 32. As described above, the upper portion substrate cutting device 60 and the lower portion substrate cutting device 70 respectively slide along the upper guide rail 31 and the lower guide rail 32 by the linear motors.

[0136] For example, in the upper portion substrate cutting device 60 and the lower portion substrate cutting device 70, a cutter wheel 62a for scribing the upper glass substrate of the bonded mother substrate 90 is rotatably attached to a tip holder 62b, and the tip holder 62b is rotatably attached to a cutter head 62c having an axis in a direction vertical to the surface of the bonded mother substrate 90 held by the clamp device 50. The cutter head 62c is movable along a direction vertical to



the surface of the bonded mother substrate by driving means which is not shown. The cutter wheel **62a** is appropriately loaded by energizing means which is not shown.

[0137] The cutter wheel **62a** held by the tip holder **62b** may have a blade edge protruded so as to have a center portion in a width direction of a shape of letter V with an obtuse angle and may have protrusions of a predetermined height formed on the blade edge with predetermined pitches in a circumferential direction as disclosed in Japanese Laid-Open Publication No. 9-188534.

[0138] The lower portion substrate cutting device **70** provided on the lower guide rail **32** has a structure similar to the upper portion substrate cutting device **60** but inverted upside down. A cutter wheel **62a** of the lower portion substrate cutting device **70** (see Figure 7) is arranged so as to oppose the cutter wheel **62a** of the upper portion substrate cutting device **60**.

[0139] The cutter wheel **62a** of the upper portion substrate cutting device **60** are pressed onto a surface of the bonded mother substrate **90** and rotated by the above-described energizing means and moving means of the cutter head **62c**. The cutter wheel **62a** of the lower portion substrate cutting device **70** is pressed onto a back surface of the bonded mother substrate **90** and rotated by the above-described energizing means and moving means of the cutter head **62c**. By moving the upper portion substrate cutting device **60** and the lower portion substrate cutting device **70** in the same direction at the same time, the bonded mother substrate **90** is out.

[0140] It is preferable that the cutter wheel **62a** is rotatably supported by a cutter head **65** using a servo motor disclosed in WO 03/011777.

[0141] Figure 15 shows a side view of an exemplary cutter head **65** using a servo motor. Figure 16 is a front view of the main part of the cutter head **65**. A servo motor **65b** is held between a pair of side walls **65a** in an inverted state. In the lower part of the side walls **65a**, a holder maintaining assembly **65c** having a shape of letter L when viewed from side is rotatably provided via a spindle **65d**. On the front portion of the holder maintaining assembly **65c** (the right hand part in Figure 16), the tip holder **62b** for rotatably supporting the cutter wheel **62a** via an axis **65e**. Flat bevel gears **65f** are respectively attached to the rotation axis of the servo motor **65b** and the spindle **65d** so as to engage each other. With such a structure, by rotating the servo motor **65b** in normal or inverted direction, the holder maintaining assembly **65a** performs an elevating operation having the spindle **65d** as a fulcrum and the cutter wheel **62a** moves up and down. The cutter head **65** itself is included in the upper portion substrate cutting device **60** and/or lower portion substrate cutting device **70**.

[0142] Figure 17 is a front view showing another example of a cutter head using a servo motor. In this example, the rotation axis of the servo motor **65b** is directly connected to the holder maintaining assembly **65c**.

[0143] The cutter heads of Figures 15 and 17 moves

the cutter wheel **62a** for positioning by rotating the servo motor by position control. Such a cutter head controls a rotation torque which acts to bring back the position of the cutter wheel **62a** to the position which has been previously set to the servo motor **65b** when the position is moved from the set position, and transmits a scribing pressure to a brittle material substrate during scribing operation in which the cutter head is moved in the horizontal direction to form scribe lines on the bonded mother substrate **90**. In other words, the servo motor **65b** controls the position of the cutter wheel **62a** in a vertical direction and also serves as energizing means for the cutter wheel **62a**.

[0144] By using the cutter head including the servo motor as described above, the rotation torque of the servo motor can be corrected while the bonded mother substrate **90** is being scribed instantly in accordance with the change in a scribing pressure due to a variance in resistance applied to the cutter wheel **62a**. Thus, stable scribing is performed and scribe lines with high quality can be formed.

[0145] A cutter head including a mechanism to periodically change the pressure to the bonded mother substrate **90** by a scribing cutter by vibrating the scribing cutter such as a diamond point cutter and/or cutter wheel for scribing the bonded mother substrate **90** may also effectively applied to the cutting of the mother substrate by the substrate cutting system of the present invention.

[0146] The structures of the upper portion substrate cutting device **60** and the lower portion substrate cutting device **70** are not limited to the above-described structures. The devices may have any kind of structures as long as they process the front and back surfaces of the substrate to out the substrate.

[0147] For example, the upper portion substrate cutting device **60** and the lower portion substrate cutting device **70** may be a device for cutting the mother substrate by using laser light, a dicing saw, a cutting blade, a diamond cutter, or the like.

[0148] When the mother substrate is a metal substrate such as steel sheet, wood plate, a plastic substrate, and a brittle material substrate such as ceramics substrate, glass substrate, semiconductor substrate or the like, a scribing device for cutting the mother substrate by using, for example, laser light, a dicing saw, a cutting blade, a diamond cutter, or the like may be used.

[0149] Furthermore, the upper portion substrate cutting device **60** and the lower portion substrate cutting device **70** may further include cutting assistance means for assisting in the cutting of the substrate. The cutting assistance means may be, for example, means for pressing a roller or the like to the substrate, or means for warming (heating) the substrate by spraying compressed air to the substrate or blowing hot air to the substrate.

[0150] In the above example, the upper portion substrate cutting device **60** and the lower portion substrate



cutting device 70 have the same structure. However, they may have different structures depending upon the cutting pattern of the substrate and cutting conditions for the substrate.

[0151] The operation of the substrate cutting system having such a structure will be explained with reference mainly to an example in which a bonded substrate formed by bonding large-scale glass plates is cut.

[0152] For cutting the bonded mother substrate 90 formed by bonding large-scale glass substrates to each other into a plurality of panel substrates 90a (see Figure 19), first, as shown in Figure 18, all the second substrate supporting units 21B of the second substrate supporting portion 20B in the substrate supporting device 20 are moved toward the end portion on the substrate carry-out side, and the scribing device guide body 30 is also moved toward the end portion on the substrate carry-out side. When the scribing device guide body 30 is moved to the end portion on the substrate carry-out side, all the first substrate supporting units 21A on the carry-in side of the first substrate supporting portion 20A in the substrate supporting device 20 are arranged across approximately entire region of the mounting structure 10 with predetermined spaces therebetween.

[0153] Then, moving cylinders 41 of all the substrate upward/downward moving devices 40 provided in the first substrate supporting units 21A are driven in synchronization, and the respective piston rods 41a move upward. Thus, the abut main bodies 48a of the abut members 48 are at the positions for receiving the bonded mother substrate which is protruded above relative to the first supporting belts 23a.

[0154] In such a state, the bonded mother substrate 90 is carried to the substrate cutting system from the end portion on the substrate carry-in side by a carrying conveyer, a carrying robot or the like. The bonded mother substrate 90 is supported by the abut main bodies 48a of the abut members 48 in all of the substrate upward/downward moving devices 40 in the first substrate supporting device 20A.

[0155] When the bonded mother substrate 90 is supported by the abut main bodies 48a of the abut members 48, a pair of positioning cylinders 42 in each of the substrate upward/downward moving devices 40 are driven and the piston rod 42a moves out by a predetermined amount. Then, the moving cylinders 41 of all the substrate upward/downward moving devices 40 are driven in synchronization and the respective piston rods 41a retract downward. Thus, the set collars 45 attached to guide rods 44 coupled to the piston rods 42a are at the predetermined position, and the sliding portions 43a of the sliding member 43 abut the set collars 45 via the buffer members 46. Accordingly, the abut main bodies 48a of the abut members 48 provided in the substrate upward/downward moving devices 40 are at the intermediate positions above the first supporting belts 23a by a predetermined height, and the bonded mother substrate 90 supported by the abut main bodies 48a in a

horizontal fashion is positioned at the intermediate position above the first supporting belts 23a.

[0156] In such a state, compressed air is blown out from the through holes 48d of the abut members 48 to slightly lift the bonded mother substrate 90 from the abut main bodies 48a. The bonded mother substrate 90 supported by the abut main bodies 48a in a horizontal fashion is pressed by a pressure which is not shown so that it abut the positioning pins (not shown) arranged along one of the main frames 11 and also pressed by a pressure which is not shown so that it abut the positioning pins (not shown) arranged along the direction orthogonal to the main frame 11. In this way, the bonded mother substrate 90 slightly lifted from the abut main bodies 48a in a horizontal fashion is positioned to a predetermined position within the mounting structure 10 in the substrate cutting system.

[0157] Then, as shown in Figure 19, the bonded mother substrate 90 supported by the abut main bodies 48a in a horizontal fashion has its side edge along the one of the main frames 11 clamped by the clamp members 51 of the clamp device 50. The side edge of the bonded mother substrate 90 on the substrate carry-in side edge is clamped by the clamp members 51 arranged on the substrate carry-in side so as to be orthogonal to the main frames 11.

[0158] When the side edges of the bonded mother substrate 90 which are orthogonal to each other are respectively clamped by the clamp device 50, the moving cylinder 41 and a pair of the positioning cylinders 42 of each of the substrate upward/downward moving devices 40 provided in the first substrate supporting units 21A are driven to retract the piston rods 41a and 42a. The abut main bodies 48a of the abut members 48 are at retracted position below the first supporting belts 23a. Accordingly, the clamp members clamping the side edges of the bonded mother substrate 90 sink approximately at the same time due to the weight of the bonded mother substrate itself. Thus, the bonded mother substrate 90 is supported supplementarily by the first supporting belts 23a.

[0159] In such a state, the scribing device guide body 30 slide toward the substrate carry-in side so as to be a predetermined position on a side edge near the bonded mother substrate 90 clamped by the clamp device 50 in a horizontal fashion. The first optical device 38 and the second optical device 39 provided on the scribing device guide body 30 move along the guide body 30 from waiting positions. Thus, the images of the first alignment mark and the second alignment mark provided on the bonded mother substrate 90 are taken.

[0160] In this example, since the scribing device guide body 30 slides, the first substrate supporting unit 21A in the substrate supporting device 20 which is close to the scribing device guide body 30 slides toward the end portion on the substrate carry-in side, and the second substrate supporting units 21B in the second substrate supporting portion 20B which is close to the scribing device

guide body 30 slides toward the end portion on the substrate carry-in side.

[0161] Next, based on the results of taking the images of the first alignment mark and the second alignment mark, angle of the bonded mother substrate 90 supported by the clamp device 50 in a horizontal fashion in a direction along the scribing device guide body 30, cutting start position and cutting end position by a calculation using an operation process device which is not shown. Based on the calculated results, the scribing device guide body 30 is moved with the upper portion substrate cutting device 60 and the lower portion substrate cutting device 70 to cut the bonded mother substrate 90.

[0162] In this example, as shown in Figure 20, the cutter wheels 62a respectively opposing the front surface and the back surface of the bonded mother substrate 90 are pressed onto the front back surfaces and rotated. Thus, scribe lines are formed on the front surface and the back surface of the bonded mother substrate 90.

[0163] At this time, as shown in Figure 21, the cutter wheels 62a are pressed and rotated on an upper mother substrate 91 and a lower mother substrate 92 of the bonded mother substrate 90 along lines to be cut on the mother substrates 91 and 92 for scribing the mother substrates 91 and 92. Thus, vertical cracks Vm along thickness directions of the mother substrates 91 and 92 are sequentially formed along the lines to be cut, and main scribe lines MS are formed. The vertical cracks Vm are formed such that they extend by 80% or more of the thickness of the mother substrates 91 and 92, and more preferably, 90% or more from surfaces of the mother substrates 91 and 92.

[0164] Thereafter, in the area outside the panel substrates obtained by cutting the mother substrates 91 and 92, the mother substrates 91 and 92 are scribed by pressing and rotating the cutter wheels 62a along the main scribe lines MS on the mother substrates 91 and 92 with spaces of about 0.5 to 1.0 mm apart from the main scribe lines MS. In this way, vertical cracks Vs along the thickness directions of the mother substrates 91 and 92 are sequentially formed along the main scribe lines MS to form supplementary scribe lines SS.

[0165] At this time, the cutter wheels 62a presses and rotates on the surfaces of the mother substrates 91 and 92, and the blades thereof cut into the surfaces of the mother substrates 91 and 92. Thus, a compressed force is applied to the surfaces of the mother substrates 91 and 92 and the compressed force has influence on the surface portions of the vertical cracks Vm in the main scribe lines MS which have been already formed. In this example, the vertical cracks Vm forming the main scribe lines MS are formed to extend by 80% or more of the thickness of the mother substrates 91 and 92. Thus, when the surface portion of the mother substrates 91 and 92 are compressed, the vertical cracks Vm of the main scribe lines MS have gaps on the surface portions of the mother substrates 91 and 92 compressed and gaps on bottom portions are widened. Therefore, the

vertical cracks Vm are elongated toward the bonded surface of the mother substrates 91 and 92. When the vertical cracks Vm reach the bonded surface of the mother substrates 91 and 92 and the vertical cracks Vm reach the bonded surface of the mother substrates 91 and 92 across the entirety of the main scribe lines MS, the bonded mother substrate 90 is cut along the main scribe lines MS.

[0166] It is preferable that the supplementary scribe lines SS are formed with spaces of about 0.5 to 1.0 mm apart from the main scribe lines MS. When the spaces between the supplementary scribe lines SS and the main scribe lines MS are smaller than 0.5 mm, a large compression force is applied to the surface portion of the vertical cracks Vm forming the main scribe lines MS, and damage such as chip may occur in the surface side end portions of the vertical cracks Vm. On the other hand, when the space is larger than 1.0 mm, the compression force applied to the vertical cracks Vm on the main scribe lines MS is not enough, and the vertical cracks Vm may not reach the bonded surface of the mother substrates 91 and 92.

[0167] As described above, by forming double scribe lines of the main scribe lines MS and the supplementary scribe lines SS with predetermined spaces, a plurality of panel substrates 90a are cut out of the bonded mother substrate 90.

[0168] Figure 22 is a diagram for illustrating a scribe pattern for cutting panel substrates 90a out of the bonded mother substrate 90 by using such double scribe lines of the main scribe lines MS and the supplementary scribe lines SS. The cutter wheels 62a of the upper portion substrate cutting device 60 and the lower portion substrate cutting device 70 run along side edges of the substrate carry-out side of two panel substrates 90a on the substrate carry-out side of the bonded mother substrate 90, and a double scribe line (main scribe line MS1 and supplementary scribe line SS1) is formed on the side edges of the substrate carry-out side of the two panel substrates 90a.

[0169] Then, main scribe line MS2 and supplementary scribe line SS2 are formed along the side edges of the substrate carry-in side of the two panel substrates 90a on the substrate carry-out side of the bonded mother substrate 90. When the side edges of the substrate carry-out side and the substrate carry-in side of the two panel substrates 90a on the substrate carry-out side of the bonded mother substrate 90 are cut, the scribing device guide body 30 slides toward the substrate carry-out side so that the cutter wheels 62a locate on the side edge portion located on the substrate carry-out side of the bonded mother substrate 90. Then, the upper portion substrate cutting device 60 and the lower portion substrate cutting device 70 slide along the upper guide rail 31 and the lower guide rail 32 so that the cutter wheels 62a of the upper portion substrate cutting device 60 and the lower portion substrate cutting device 70 are on an extension of the side edge of the panel substrate

**90a** on the substrate carry-out side and close to a frame **11A** of the main frames **11**, which is close to the main frame **11**. Along the extension of the side edge, a double scribe line (main scribe line **MS3** and supplementary scribe line **SS3**) is formed, and the side edge close to the frame **11A** of the panel substrate **90a** on the substrate carry-out side and close to the frame **11A** of the main frames **11** is cut.

**[0170]** Then, double scribe lines (main scribe lines **MS4** to **MS6** and supplementary scribe lines **SS4** to **SS6**) are formed in parallel with the frame **11A** in a similar manner. Thus, side edges of the panel substrates **90a** located on the substrate carry-out side in a direction along the frame **11A** are respectively cut.

**[0171]** Thereafter, regarding two other panel substrates **90a** along the upper guide rail **31** and the lower guide rail **32**, side edges of the panel substrates **90a** are out by forming double scribe lines (main scribe lines **MS7** to **MS12** and supplementary scribe lines **SS7** to **SS12**) along side edges of the panel substrates **90a**.

**[0172]** In the above description, an example where double scribe lines are individually formed has been explained. However, the present invention is not limited to such a method. As long as the double scribe lines are formed along the side edges of the panels **90a**, any method may be used. For example, double scribe lines may be formed on the side edges of the panel substrates **90a** by using one scribe line.

**[0173]** Figure **23** is a plan view for illustrating a scribe pattern for cutting panel substrates **90a** out of the bonded mother substrate **90** by using double scribe lines of the main scribe lines **MS** and the supplementary scribe lines **SS**. In this example, the mother substrates **91** and **92** of the bonded mother substrate **90** are cut along first to eighth lines to be out **D1** through **D8** in this order to become four panel substrates **90a** arranged in two rows and two columns.

**[0174]** The first line to be out **D1** corresponds to side edges of two panel substrates **90a** in a first row along a row direction (horizontal direction), and is spaced apart from a side edge of the bonded mother substrate **90** along the row direction by a predetermined space. The second line to be cut **D2** corresponds to side edges of the two panel substrates **90a** in the first row, which are close to the panel substrate **90a** in a second row. The third line to be out **D3** corresponds to side edges of two panel substrates **90a** in the second row which are close to the panel substrates **90a** in the first row, and is spaced apart from the second line to be out **D2** by 2 to 4 mm. The fourth line to be cut **D4** corresponds to side edges of the two panel substrates **90a** in the second row in a row direction (horizontal direction), and is spaced apart from the other side edges of the bonded mother substrate **90** along the row direction by a predetermined space.

**[0175]** The fifth line to be cut **D5** corresponds to side edges of two panel substrates **90a** in a first column along the column direction (vertical direction), and is spaced

apart from one side edge of the bonded mother substrate **90** along the column direction. The sixth line to be cut **D6** corresponds to the side edges of the two panel substrates **90a** in the first column, which are close to panel substrates **90a** in a second column. The line to be cut **D7** corresponds to side edges of the two panel substrates **90a** in the second column, which are close to the panel substrates **90a** in the first column, and is spaced apart from the sixth line to be cut **D6** by 2 to 4 mm. The line to be cut **D8** corresponds to the side edges of the two panel substrates **90a** in the second column along the column direction (vertical direction), and is spaced apart from the other side edges of the bonded mother substrate **90** along the column direction by a predetermined space.

**[0176]** For cutting such a bonded mother substrate **90**, first, the cutter wheels **62a** are pressed and rotated along, for example, the first to fourth lines to be out **D1** to **D4** in this order. Thus, first to fourth main scribe lines **MS13** to **MS16** are formed by vertical cracks having depths of 90% or more of the thicknesses of the mother substrates **91** and **92** from the surface of the upper and lower mother substrates **91** and **92** of the bonded mother substrate **90**.

**[0177]** In this state, the cutter Wheels **62a** are pressed and rotated along the fifth line to be cut **D5**. Thus, fifth main scribe line **MS17** is formed along the fifth line to be out **D5**.

**[0178]** Thereafter, sixth to eighth main scribe lines **MS18** to **MS20** are formed along the sixth through eighth lines to be out **D6** to **D8** in this order by pressing and rotating the cutter wheels **62a** along the sixth through eighth lines to be cut **D6** to **D8** in turn in a similar manner.

**[0179]** After the first through eighth main scribe lines **MS13** to **MS20** are formed as such, first supplementary scribe line **SS13** is formed along the first main scribe line **MS13** by pressing and rotating the cutter wheels **62a** in a side edge portion of the bonded mother substrate **90**, which is on opposite side of the panel substrates **90a** with respect to the first main scribe line **MS13**, with a space of about 0.5 to 1.0 mm from the first main scribe line **MS13**. Thus, vertical cracks on the first main scribe line **MS13** extend toward the bonded surface of the mother substrates **91** and **92** of the bonded mother substrate **90** and reach the bonded surface of the mother substrates **91** and **92**. Such a phenomena occurs across entirety of the first main scribe line **MS13**, and the bonded mother substrate **90** is out along the first main scribe line **MS13**.

**[0180]** Next, a second supplementary scribe line **SS14** is formed along the second main scribe line **MS14** by the cutter wheels **62a** in an area opposite to the panel substrates **90a** with respect to the second main scribe line **MS14**, with a space of about 0.5 to 1.0 mm from the second main scribe line **MS14**. Thus, vertical cracks on the second main scribe line **MS14** extend toward the bonded surface of the mother substrates **91** and **92** of the bonded mother substrate **90** from the surfaces of the

mother substrates **91** and **92** of the bonded mother substrate **90**, and the vertical cracks reach the bonded surface of the mother substrates **91** and **92** across the entirety of the second main scribe line **MS14**. In this way, the bonded mother substrate **90** is out along the second main scribe line **MS14**.

**[0181]** Along the third main scribe line **MS15** and the fourth main scribe line **MS16**, third supplementary scribe line **SS15** and a fourth supplementary scribe line **SS16** are respectively formed on the side opposite to the panel substrates **90a**. Thus, the bonded mother substrate **90** is sequentially cut along the third main scribe line **MS15** and the fourth main scribe line **MS16**.

**[0182]** Thereafter, along the fifth to eighth main scribe lines **MS17** to **MS20**, fifth to eighth supplementary scribe lines **SS17** to **SS20** are formed on the side opposite to the panel substrates **90a** respectively between the first main scribe line **13** and the second main scribe line **MS14**, and between the third main scribe line **MS15** and the fourth main scribe line **MS16**. Thus, the bonded mother substrate **90** are out along the fifth to eighth main scribe lines **MS17** to **MS20** and unnecessary portions are removed. As a result, fourpanel displays **90a** can be obtained.

**[0183]** In this example, the first to eighth main scribe lines **MS13** to **MS20** are formed between end surfaces of the bonded mother substrate **90**, more specifically, formed across the entirety of the lines to be out **D1** to **D8** formed across one end surface of the bonded mother substrate **90b** to the opposing other end surface. Further, the first to eighth supplementary scribe lines **SS13** to **SS20** are respectively formed across the end surface or one out surface which has been cut to the opposing other end surface or the other cut surface.

**[0184]** The present invention is not limited to the method in which the first to eighth main scribe lines **MS13** to **MS20** are formed across the entirety of the lines to be out **D1** to **D8** formed between the end surfaces of the bonded mother substrate **90**, the first to fourth supplementary scribe lines **SS13** to **SS16** across the one end surface of the bonded mother substrate **90** and the opposing other end surface, and the fifth to the eighth supplementary scribe lines **SS17** to the **SS20** are formed across one out surface of the bonded mother substrate **90** to the opposing other cut surface. As shown in Figure 24, positions spaced apart from the one end surface of the mother glass substrate **10** by about 0.2 to 0.5 mm may be the start positions of the first to eighth main scribe lines **MS13** to **MS20**, and similarly, positions in front of the other end surfaces by about 0.2 to 0.5 mm may be end portions of the first to eighth main scribe lines **MS13** to **MS20**.

**[0185]** In this example, when the cutter wheels **62a** are pressed and rotated on the mother substrates **91** and **92** of the bonded mother substrate **90** to perform scribing for forming the first to eighth main scribe lines **MS13** to **MS20**, vertical cracks extend in back and front directions of the scribing direction with respect to the

scribing start positions. Thus, the first to eighth main scribe lines **MS13** to **MS20** to be formed reach one end surface of the mother substrates **91** and **92** of the bonded mother substrate **90**.

**[0186]** Similarly, even though the scribing end positions of the first to eighth main scribe lines **MS13** to **MS20** are in front of the other end surface of the mother substrates **91** and **92** of the bonded mother substrate **90**, since the vertical cracks in the mother substrates **91** and **92** extend in the scribing direction, the first to eighth main scribe lines **MS13** to **MS20** to be formed reach the other end surface of the mother substrates **91** and **92**.

**[0187]** This shows that it is not necessary to form first to eighth supplementary scribe lines **SS13** to **SS20** across one end surface or one cut surface which has been cut of the mother substrates **90** and **91** to the opposing other end surface or the opposing other cut surface. As shown in Figure 24, positions appropriately spaced apart from one end surface or the one out surface which has been cut of the mother substrates **91** and **92** of the bonded mother substrate **90** by 0.2 to 0.5 mm may be start positions of the first to eighth supplementary scribe lines **SS13** to **SS20**. Similarly, positions in front of the other end surface or cut surface by about 0.2 to 0.5 mm may be end positions of the first to eighth supplementary scribe lines **SS13** to **SS20**.

**[0188]** Furthermore, one of the first to eighth main scribe lines **MS13** to **MS20** and the first to eighth supplementary scribe lines **SS23** to **SS20** may be formed across the one end surface or one out surface which has been cut of the mother substrates **91** and **92** of the bonded mother substrate to the other end surface or the other out surface of the mother substrates **91** and **92**, and the other of the first to eighth main scribe lines **MS13** to **MS20** and the first to eighth supplementary scribe lines **SS13** to **SS20** may be formed across the position appropriately space apart from the one end surface or one cut surface which has been cut of the mother substrates **91** and **92** of the bonded mother substrate **90** to positions in front of the other end surface or the other cut surface of the mother substrates **91** and **92**.

**[0189]** Figure 25 is a plan view for illustrating another scribe pattern for cutting the panel substrates **90a** out of the bonded mother substrate **90**. In this scribing method, first and second main scribe lines **MS13** and **MS14** are formed by the cutter wheels **162a**, along first and second lines to be out **D1** and **D2** on the bonded mother substrate **90** along the horizontal direction are respectively formed by vertical cracks which extend to 90% or more of the thicknesses of the mother substrates **91** and **92** from the surfaces of the mother substrates **91** and **92** of the bonded mother substrate **90**. Thereafter, in the area between the first and second main scribe lines **MS13** and **MS14**, fifth main scribe line **MS17** along the fifth line to be cut **D5** along the vertical direction is formed by the cutter wheels **62a**, and fifth supplementary scribe lines **SS17** is formed on the side opposite to the panel substrates **90a** being spaced apart from the fifth main scribe

line MS17 by about 0.5 to 1.0 mm.

[0190] In this example, the fifth main scribe line MS17 and the fifth supplementary scribe line SS17 respectively cross the first and second main scribe lines MS13 and MS14. The fifth main scribe line MS17 runs over the second main scribe line MS14 and then is inverted by 180 degrees to form the fifth supplementary scribe line SS17 so that the fifth main scribe line MS17 and the fifth supplementary scribe line SS17 are formed continuously with one scribing.

[0191] Thereafter, similarly, in the area between the first and second main scribe lines MS13 and MS14, sixth scribe line MS18 is formed by the cutter wheels 62a along sixth line to be cut D8, and then is inverted to form sixth supplementary scribe line SS18 on the side opposite to the panel substrates 90a. Further, seventh main scribe line MS19 and seventh supplementary scribe lines SS19, and eighth main scribe line MS20 and eighth supplementary scribe lines SS20 are formed similarly in turn. Since the fifth to eighth main scribe lines MS17 to MS20 and the fifth to eighth supplementary scribe lines SS17 to SS20 pass across the first and second main scribe lines MS13 and MS14, it is ensured that vertical cracks forming the first and second main scribe lines MS13 and MS14 reach the bonded surface of the mother substrates 91 and 92 of the bonded mother substrate 90 across the entirety of the first and second main scribe lines MS13 and MS14, and a pair of the panel substrates 90a are obtained.

[0192] Before the substrate is cut into the pair of the panel substrates 90a at this point, an area of the bonded mother substrate 90 which has not been cut is referred to a second substrate portion 90c.

[0193] Next, as shown in portion (b) of Figure 25, on the second substrate portion 90c cut by the second main scribe line MS14, the cutter wheels 62a are pressed and rotated along the lines to be cut D3 and D4 on the bonded mother substrate 90 along the vertical direction, and third and fourth main scribe lines MS15 and MS16 are formed by vertical cracks extended to 90% or more of the thicknesses of the mother substrates 91 and 92 from the surfaces of the mother substrates 91 and 92 of the bonded mother substrate 90. Thereafter, in the area between the third and fourth main scribe lines MS15 and MS16, ninth main scribe line MS21 and fifth supplementary scribe line SS21 along ninth line to be cut D9 along the vertical direction, tenth main scribe line MS22 and tenth supplementary scribe line SS22 along the tenth line to be cut D10, eleventh main scribe line MS23 and eleventh supplementary scribe line SS23 along the eleventh line to be cut D11, and twelfth main scribe line MS24 and twelfth supplementary scribe line SS24 along the twelfth line to be cut D12 are sequentially formed outside the panel substrates 90a so as to cross the third and fourth main scribe lines MS15 and MS16. Thus, the second substrate portion 90c is cut, and a pair of panel substrates 90a are cut.

[0194] It is not necessary that the fifth to twelfth sup-

plementary scribe lines SS21 to SS24 cross the first and third main scribe lines MS13 and MS15. For example, as shown in Figure 26, positions in front of the first and third main scribe lines MS13 and MS15 by about 0.2 to 0.5 mm may be end portions of the fifth to twelfth supplementary scribe lines SS17 to SS24. In such a case, vertical cracks forming the fifth to twelfth supplementary scribe lines SS17 to SS24 also extend in the scribing direction. The fifth to twelfth main scribe lines MS17 to MS24 are cut across the entirety of the main scribe lines MS17 to MS24.

[0195] In the case where the scribe lines are formed to cross each other for cutting the substrate as described above, as shown in Figure 27, first, the main scribe lines MS13 to MS16 are formed along the first to fourth lines to be cut D1 to D4, and then, the fifth main scribe line MS17 and the fifth supplementary scribe line SS17, the sixth main scribe line MS18 and the sixth supplementary scribe line SS18, the seventh main scribe line MS19 and the seventh supplementary scribe line SS19, and the eighth main scribe line MS20 and the eighth supplementary scribe line SS20 are formed to respectively cross the first main scribe line MS13 and fourth main scribe line MS16 such that the main scribe lines and the supplementary scribe lines are formed continuously with one scribing by inverting the line by 180 degrees after they cross over the fourth main scribe line MS16.

[0196] Figure 28 is a schematic plan view for illustrating a scribing pattern for cutting the panel substrates 90a out of the bonded mother substrate 90 by using double scribe lines of main scribe lines MS and supplementary scribe lines SS. First, four scribe lines along lines to be scribed S1 to S4 with respect to the panel substrates 90a (hereinafter, four linear scribe lines across the entire circumferences of the panel substrates 90a will be referred to as main scribe line DS1) are formed. Then, outside the panel substrates 90a with respect to the main scribe line DS1, four linear sub-scribe line DS2 in parallel to the main scribe line DS1 spaced apart from the main scribe line DS1 by about 0.5 to 1 mm.

[0197] As described above, when the sub-scribe line DS2 is formed with a space of about 0.5 to 1 mm apart from the main scribe line DS1, a stress is applied to a horizontal direction which is orthogonal to the formation direction of the scribe lines on a surface of the bonded mother substrate 90 when the sub-scribe line S2 is formed. Thus, a compression force is applied to surface portions of the vertical cracks which form the main scribe line DS1 which has been already formed. When the compression force is applied to the surface portion of the vertical cracks forming the main scribe line DS1 as such, a reaction force is applied in a direction to widen the width of the vertical cracks forming the main scribe line DS1. In this way, the vertical cracks extend in the thickness direction of the bonded mother substrate 90 and the vertical cracks reach the bonded surface of the mother substrates 91 and 92 of the bonded mother sub-



strate.

[0198] In this example, as shown in Figure 29, sub-scribe line DS2 may be formed continuously after the main scribe line DS1 without separating the cutter wheels 62a from the front and back surfaces of the bonded mother substrate 90 after the main scribe line DS1 is formed.

[0199] Furthermore, when scribe lines are first formed along lines to be scribed S1 and S2, and then scribe lines are continuously formed along lines to be scribed S4 and S2, as shown in Figure 30, the sub-scribe line DS2 may be formed after the main scribe line DS1 is formed.

[0200] As described above, by forming the double scribe line of the main scribe line MS and supplementary scribe line SS with a predetermined space a plurality of panel substrates 90a are cut out of the bonded mother substrate 90.

[0201] Then, the scribing device guide body 30 slides as shown in Figure 31. Thus, each of the first substrate supporting units 21A of the first substrate supporting portion 20A slides toward the substrate carry-in side such that the space with the adjacent first substrate supporting unit 21A becomes smaller.

[0202] In the above description, an example in which double scribe lines are individually formed has been explained. However, the present invention is not limited to such an example. As long as double scribe lines are formed along the side edges of the display bonded substrates 90a, any method may be used. For example, double scribe lines are formed on one scribe line panel substrates 90a.

[0203] Further, as a method for cutting the substrate, a method in which double scribe lines are formed on the bonded mother substrates where the glass substrates, which is a type of brittle material substrate, are bonded as mother substrates has been described. However, the present invention is not limited to this. When the mother substrate is a metal substrate such as steel sheet, wood plate, a plastic substrate, and a brittle material substrate such as ceramics substrate, glass substrate, semiconductor substrate or the like, a method for cutting the mother substrate by using, for example, laser light, a dicing saw, a cutting blade, a diamond cutter, or the like may be used.

[0204] Furthermore, the substrates include, besides mother substrate, a bonded substrate formed by bonding the same type of mother substrates, a bonded mother substrate formed by bonding different types of mother substrates, and a substrate formed by laminating mother substrates.

[0205] In this way, as the panel substrates 90a from the bonded mother substrate 90 are sequentially cut and made to be removable from the bonded mother substrate 90, substrate carry-out device 80 slides and the panel substrates 90a are sequentially adsorbed by the substrate carry-out device 80 and carried out of the mounting structure 10.

[0206] When the cutting of the panel substrates 90a is finished and all the out panel substrates 90a are carried out of the mounting structure 10, as shown in Figure 31, the scribing device guide body 30 slides to the position closest to the end portion on the substrate carry-in side. Thus, all the first substrate supporting units 21A in the first substrate supporting portion 20A are arranged to be close to each other in the end portion on the substrate carry-in side of the mounting structure 10. At this time, the second substrate supporting unit 21B located to be the closest to the scribing device guide body 30 in the second substrate supporting portion 20B moves in accordance with movement of the scribing device guide body 30. Thus, all the second substrate supporting units 21B in the second substrate supporting portion 20B are arranged to have a predetermined space across the entirety below the cut bonded mother substrate 90'.

[0207] Then, as shown in Figure 32, when all the panel substrates 90a are carried out from the bonded mother substrate 90, the out bonded mother substrate 90' which has become a frame since all the panel substrates 90a are carried out is released from clamping by the clamp members 51. Then, the second substrate supporting unit 21B closest to the scribing device guide body 30 slides toward the end portion on the substrate carry-out side. Thus, the second supporting belts 23b supporting the out bonded mother substrate 90' sequentially release the support of the cut bonded mother substrate 90'. Clamping by the clamp members 51 is released, and the cut bonded mother substrate 90' drops downward, is guided by the guide plate to be accommodated in the cullet accommodation box.

[0208] Further, instead of the above-described scribing methods for forming double scribe lines, a device for warming (heating) the bonded substrate 90 by spraying compressed air to the front and back surfaces of the bonded mother substrate 90 or blowing hot air to the front and back surfaces of the bonded mother substrate 90 may be provided on the substrate carry-out side of the scribing device guide body 30 as a device for cutting the bonded mother substrate 90 after the scribing process.

[0209] Figure 33 is a front view of important parts of a steam unit portion 75 as viewed from the substrate carry-in side. Six steam units 76 are attached to an upper steam unit attachment bar 77 and six steam units 76 are attached to a lower steam unit attachment bar 78 with a gap GA spaced apart from the upper six steam units 76. The gap GA is adjusted so as to allow the bonded mother substrate 90 to pass through the gap when the steam units 76 move toward the substrate carry-in side.

[0210] After the steam unit portion 75 arranged on the substrate carry-out side of the scribing device guide body 30 is scribed by the scribing device guide body 30, the bonded mother substrate 90 which has been already scribed and is clamped (held) by the clamp device 50



and supported by the second substrate supporting portion 20B slides (moves) toward the substrate carry-in side so as to pass through the gap between a plurality of upper and lower steam units 76 of the steam unit portion.

[0211] Figure 34 is a partial cross-sectional side view showing the structures of the steam units 76. Each of the steam units 76 is mostly made of an aluminum material, and a plurality of heaters 76a are embedded in a vertical direction. When an opening/closing valve (not shown) which can be opened or closed automatically is opened, water flows into the steam unit 76 from a water supply port 76b and heated by the heaters 76a. The supplied water is vaporized and becomes steam. The steam is blown to the surface of the mother substrate through a conducting hole 76c and from a spray nozzle 76d.

[0212] Further, on the carry-out side of the upper steam unit attachment bar 77, an air knife 71 for removing water which remains on the surface of the bonded mother substrate 90 after the steam is blown to the upper surface of the bonded mother substrate 90 is attached.

[0213] The lower steam unit attachment bar 78 also includes the steam units 76 and the air knife 71 similar to those attached to the upper steam unit attachment bar 77.

[0214] The cutter wheel 62a of the upper portion substrate cutting device 60 and the cutter wheels 62a of the lower portion substrate cutting device 70 generate vertical cracks in the portions of the glass substrates where the cutter wheels 62a rotated, and a scribe line 95 is formed. Since protrusions are formed in a predetermined pitch in peripheral edges of the blade edges of the cutter wheels 62a, vertical cracks having the length of about 90% of the thickness of the glass substrate in the thickness direction are formed in the glass substrates.

[0215] Further, a scribing method using a cutter head including a mechanism for periodically changing (vibrating) a pressure to the bonded mother substrate 90 by a scribe cutter such as a diamond point cutter, cutter wheel or the like for scribing the bonded mother substrate 90 may be effectively applied to the cutting of the bonded mother substrate 90 by the substrate cutting system of the present invention.

[0216] As the method for scribing the front and back surfaces of the bonded mother substrate 90, a conventional method as shown in Figure 35, in which scribe lines are formed in turn along lines to be scribed S1 to S4 along a vertical direction, which is a narrow side direction of the bonded mother substrate 90, and then scribe lines are formed in turn along lines to be scribed S5 to S8 along the horizontal direction, which is wide side direction, may be used in general.

[0217] Beside the above-described scribing method, a scribing method as shown in Figure 36 may be preferably used for the substrate cutting system of the present invention. In Figure 20, four panel substrates

90a are formed from one bonded mother substrate 90.

[0218] The bonded mother substrate 90 has a rectangular shape. Four panel substrates 90a are obtained by forming two panel substrates 90a along the longitudinal direction of the bonded mother substrate 90 and forming two panel substrates 90a along the width direction which is orthogonal to the longitudinal direction. Each of the panel substrates 90a is formed with an appropriate space apart from the adjacent panel substrate 90a and from side edges along the longitudinal direction and side edges of the width direction of the bonded mother substrate 90.

[0219] By having the cutter wheel 62a of the upper portion substrate cutting device 60 and the cutter wheel 62a of the lower portion substrate cutting device 70 oppose each other, and are pressed and rotated at the same time, scribe lines across the entire circumference are formed on the front and back surface of the bonded mother substrate 90 for each of the cut substrates 90a one by one in turn.

[0220] In this example, first, scribe line is formed along one linear line to be scribed S1 along the side edges parallel to the longitudinal direction of the bonded mother substrate 90 for the panel substrate 90a to be scribed. More specifically, the cutter wheels 62a of the cutter heads 62c are pressed and rotated on the bonded mother substrate 90 along the line to be scribed S1.

[0221] In Figure 37, it is shown that the scribe start point by the cutter wheels 62a is a position on the bonded mother substrate 90 (a position for internal cut). However, it may be a position near the outside of the end surface of the bonded mother substrate 90 along the line to be scribed S1 (a position for external cut).

[0222] When the scribe line is formed along the line to be scribed S1 by a vertical crack which extends across the entirety of the thickness direction, the scribing device guide body 30 is moved to Y direction and the upper portion substrate cutting device 60 and the lower portion substrate cutting device 70 are moved in X direction at the same time such that the cutter wheels 62a revolves around the vertical axis by 270 degrees to form a circular trace having a radius of about 1 mm (a corner portion A in Figure 37).

[0223] When the cutter wheels 62a are revolving, the pressure of the cutter wheels 62a to the bonded mother substrate 90 is reduced so that there is no deep vertical crack formed on the bonded mother substrate 90. When the thickness of the bonded substrate 90 is 0.7 mm, the depth of the vertical crack formed in the bonded mother substrate 90 when the cutter wheels 61a is revolving is about 100 to 200  $\mu\text{m}$ .

[0224] When the cross-scribing is performed by the cutter wheels 62a as shown in Figure 35, a chip tends to be generated in the bonded mother substrate 90 at cross points of the scribe lines formed when scribing is performed in first direction and scribing is performed in second direction.

[0225] Since a vertical cracks which almost extends

to the thickness of the bonded mother substrate **90** has been already formed when scribing is performed in the first direction, the mother glass substrate **90** sinks in front of the first scribe line when the cutter wheels **62a** reach near the scribe line in the first direction while scribing in the second direction and such a chip may be generated when the cutter wheels **62a** run on the glass substrates along the scribe line in the first direction at a crossing portion of the scribe line in the first direction and a scribe line in the second direction.

[0226] In the scribing method as shown in Figure 36, the cutter wheels **62a** revolve and cross the scribe line which has been already formed along the line to be scribed **S1** with the pressure to the bonded mother substrate **90** being reduced. Thus, a part of the bonded mother substrate **90** does not sink before the scribing lines cross each other, and thus, it is possible to prevent a chip from occurring in the bonded mother substrate **90** when the scribing lines cross each other.

[0227] When travel direction of the cutter wheels **62a** revolve by 270 degrees and the cutter wheels **62a** are along the linear line to be scribed **S2** along the width direction of the panel substrates **90a** which are orthogonal to the line to be scribed **S1**, the cutter wheels **62a** are pressed and rotated along the line to be scribed **S2**. Thus, the scribe line is formed by a vertical crack which extends across the entirety of the thickness direction along the line to be scribed **S2**.

[0228] Then, again, the cutter wheels **62a** revolve by 270 degrees to a direction orthogonal to the line to be scribed **S2** while forming a circular trace having a radius of about 1 mm in corner portion **B** without separating the cutter wheels **62a** from the front and back surfaces of the bonded mother substrate **90**. Thus, the cutter wheels **62a** are along the line to be scribed **S3** and form the scribe line by a vertical crack which extends across the entirety of the thickness direction along the line to be scribed **S3**. Furthermore, again, the cutter wheels **62a** revolve by 270 degrees to a direction orthogonal to the line to be scribed **S3** while forming a circular trace having a radius of about 1 mm in corner portion **C** without separating the cutter wheels **62a** from the front and back surfaces of the bonded mother substrate **90**. Thus, the cutter wheels **62a** are along the line to be scribed **S4** and form the scribe line by a vertical crack which extends across the entirety of the thickness direction along the line to be scribed **S4**.

[0229] In this way, a closed curve including four linear scribe lines is formed around a panel substrate **90a**. Then, for example, for forming the panel substrate **90a** adjacent in the longitudinal direction of the bonded mother substrate **90**, a closed curve including four linear scribe lines is formed across the entire circumference of the panel substrate **90a** similarly. Then, closed curves including four linear scribe lines are formed across the entire circumferences for each of the remaining pair of the panel substrates **90a** in turn.

[0230] Besides the above-described scribing method,

a scribing method as shown in Figure 37 can be preferably used in the substrate cutting system of the present invention. In Figure 37, four panel substrates **90a** are formed from one bonded mother substrate **90**.

5 [0231] In the scribing method shown in Figure 37, scribe lines along lines to be scribed **S1** and **S2** which are orthogonal to each other on the panel substrates **90a** are formed in the method as described above. For forming the scribe line along the line to be scribed **S1**,  
10 the cutter wheels **62a** is positioned outside the end surface of the bonded mother substrate **90** and the scribe line along the line to be scribed **S1** is continuously formed therefrom.

[0232] A chip which may be generated when the cutter wheels **62a** run on the front and back surfaces of the bonded mother substrate **90** at the start of scribing does not affect the panel substrates **90a** to become products.

[0233] Then, the cutter wheels **62a** revolve by 270 degrees to a direction orthogonal to the line to be scribed **S1** while forming a circular trace in the corner portion **A**. Thus, the cutter wheels **62a** are along the line to be scribed **S2** and form the scribe line by a vertical crack which extends across most of the entirety of the thickness direction along the line to be scribed **S2**.

25 [0234] Then, the cutter wheels **62a** are temporarily separated from the surface of the bonded mother substrate **90**, and the scribe lines along the lines to be scribed **S3** and **S4** in a direction orthogonal to the line to be scribed **S1** are formed in this order. In this case, a chip which may be generated when the cutter wheels  
30 **62a** run on the front and back surfaces of the bonded mother substrate **90** at the start of scribing does not affect the panel substrates **90a** to become products.

[0235] In this way, four linear scribe lines are formed around the panel substrate **90a**. Then, for example, for forming the panel substrate **90a** adjacent in the longitudinal direction of the bonded mother substrate **90**, four linear scribe lines are formed across the entire circumference of the panel substrate **90a** similarly. Then,  
35 closed curves including four linear scribe lines are formed across the entire circumferences for each of the remaining pair of the panel substrates **90a** in turn.

[0236] After the scribe lines are formed on the bonded mother substrate by the above-described scribing method, the steam unit portion **75** moves toward the substrate carry-in side and blows the steam entirely on the front and back surfaces of the bonded mother substrate **90** on which the scribe lines are carved to completely cut the bonded mother substrate **90**. At the same time,  
40 the water remaining on the front and back surfaces of the bonded mother substrate **90** after the steam is blown thereto is removed by the air knife **71**.

[0237] By blowing the steam onto the entire front and back surface of the bonded mother substrate **90** having the scribe lines carved thereon, the scribe lines formed by the cutter wheel tips **62a** experience volume expansion since the front and back surface portions of the bonded mother substrate **90** are heated. In this way, ver-  
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tical cracks extend from the surface of the upper and lower mother substrates of the bonded mother substrate 90 toward the bonded surface, and the bonded mother substrate 90 is completely cut.

[0238] In the above description of the operations of the substrate cutting system according to the present invention, an example in which the mother glass substrate formed by bonding glass substrates is out has been described. However, the present invention is not limited to this. For example, operations different from the above description may be performed depending on the types of the substrates to be cut or in order to enhance the functionalities of the devices which form the substrate cutting system.

#### <Embodiment 2>

[0239] Figures 38 and 39 are schematic perspective view showing another example of the embodiment of the substrate cutting system according to the present invention in whole as viewed from different directions.

[0240] In the present invention, "substrates" include mother substrates cut into a plurality of substrates and also include single plates of metal substrates such as steel sheets, wood plates, plastic substrates and ceramic substrate, semiconductor substrates, and brittle material substrates such as glass substrates. Furthermore, the "substrates" are not limited to such single plates, but also includes bonded substrates formed by bonding pairs of substrates and laminated substrates formed by laminating pairs of substrates.

[0241] The substrate cutting system according to the present invention cut the bonded mother substrate 90 formed by bonding a pair of mother glass substrates to each other into a plurality of panel substrates (display panel bonded substrates) for producing, for example, panel substrates (display panel bonded substrates) of the liquid crystal display apparatus which are bonded to each other.

[0242] Regarding a substrate cutting system 100 according to Embodiment 2, a side on which a first substrate supporting portion 120A is located is referred to as a substrate carry-in side and a side on which a substrate carry-out device 180 is located is referred to as a substrate carry-out side in the following description. In the substrate cutting system 100, a direction in which the substrates are carried (substrate flowing direction) is +Y direction from the substrate carry-in side to the substrate carry-out side. The direction in which the substrates are carried is a direction orthogonal to a scribing device guide body 130 in a horizontal fashion and the scribing device guide body 130 is provided along X direction.

[0243] The substrate cutting system 100 includes a hollow mounting structure 110 having a parallelepiped shape. On an upper surface of the mounting structure 110, four pillars 114 are provided, and a main frame 111 of a frame is located on the pillars 114. On the upper surface of the mounting structure 110, a substrate sup-

porting device 120 for supporting the bonded mother substrate 90 to be carried to the substrate cutting system 100 by a carrying robot in a horizontal manner is located.

[0244] As shown in Figure 38, the substrate supporting device 120 includes a first substrate support portion 120A located on the substrate carry-in side of the substrate cutting system 100 for supporting the bonded mother substrate 90 to be carried into the main frame 111, and a second substrate supporting portion 120B located on the substrate carry-out side of the substrate cutting system 100 for supporting the bonded mother substrate 90 after the bonded mother substrate 90 is cut and the display panels are sequentially carried out of the substrate cutting system. In the mounting structure 110, the first substrate supporting portion 120A side is a substrate carry-in side, the second substrate supporting portion 120B side is a carry-out side.

[0245] Further, as shown in Figure 39, on the mounting structure 110, a clamp device 150 for holding a substrate held in a horizontal manner by the substrate supporting device 120 (a first substrate supporting unit 121A) in a horizontal manner is provided. Further, as shown in Figure 38, on the upper surface of the mounting structure 110, scribing device guide body 130 is provided so as to be movable along frames 111A and 111B in the longitudinal direction of the main frame 111. The scribing device guide body 130 includes an upper guide rail 131 extending along X direction orthogonal to frames 111A and 111B in the longitudinal direction of the main frame 111 above the main frame 111 and a lower guide rail 132 extending along the upper guide rail 131 below the main frame 111. The upper guide rail 131 and the lower guide rail 132 are formed so as to move integrally along the frames 111A and 111B in the longitudinal direction (Y direction) of the main frame 111.

[0246] Figure 40 is a schematic perspective view showing near the upper guide rail 131 in the scribing device guide body 130. To the upper guide rail 131, upper portion substrate cutting device 160 is attached so as to be movable along the upper guide rail 131. Figure 41 is a schematic perspective view showing near the lower guide rail 132 in the scribing device guide body 130. To the lower guide rail 132, lower portion substrate cutting device 170 is attached so as to be movable along the lower guide rail 132.

[0247] The upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 respectively move back and forth along the upper guide rail 131 and the lower guide rail 132 by linear motors. To the upper guide rail 131 and the lower guide rail 132, stators of the linear motors are respectively attached, and to the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170, movers of the linear motors are respectively attached. The upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 cut glass substrates on upper and lower sides of the bonded mother

substrate **90** held by the clamp device **150** in a horizontal manner and also supported by the substrate supporting device **120** for assisting holding the mother substrates.

[0248] In one end portion of the scribing device guide body **130**, a first optical device **138** for taking an image of a first alignment mark of the bonded mother substrate **90** held by the clamp device **150** and supported by the substrate supporting device **120** is provided so as to be movable along the scribing device guide body **130**. In the other end portion of the scribing device guide body **130**, a second optical device **139** for taking an image of a second alignment mark provided on the bonded mother substrate **90** is provided so as to be movable along the scribing device guide body **130**.

[0249] Stators **112** of linear motors for moving the scribing device guide body **130** are respectively provided on the upper surface of the mounting structure **110** along the frames **111A** and **111B** in the longitudinal direction of the main frame **111**. The stators **112** are respectively formed to have a flat hollow parallelepiped shape with external side surfaces opened. Thus, cross-sections thereof have squared "C" shape. In the stators, movers (not shown) of the linear motors are inserted into guide bases **115** for holding pillars **128** for supporting both ends of the scribing device guide body **130** so as to be movable along the frames **111A** and **111B** in the longitudinal direction of the main frame **111**.

[0250] In the stators **112**, a plurality of permanent magnets are respectively located along the longitudinal directions with the magnetic poles of the permanent magnets adjacent to each other are reversed. The movers are respectively formed of electromagnets. By sequentially switching magnetic poles of the electromagnets forming the movers, the movers slide respectively along the stators **112**.

[0251] As shown in Figures **38** and **39**, both ends of the scribing device guide body **130** having the end surfaces of the upper guide rail **131** and the lower guide rail **132** coupled to each other by a connection plate **133** are supported by the pillars **128**. The pillars **128** are supported on upper surfaces of the guide bases **115**. The movers are respectively attached to the guide bases **115**. The movers are driven in synchronization and slid along the stators **112**.

[0252] Above the mounting structure **110** on the carry-out side, a carrying robot **240** for carrying out display panels cut out of the bonded mother substrate **90**, and the substrate carry-out device **180** provided for allowing the carrying robot **240** to move in X direction which is orthogonal to the frames **111A** and **111B** in the longitudinal direction of the main frame **111** are located on the substrate carry-out side with respect to the scribing device guide body **130**. End portions of substrate carry-out device guides **181** slide by linear motors via supporting members **182** along the guide rails **113** provided on the upper surface of the mounting structure **110**. The linear motors in this example are formed by inserting movers (not shown) attached to the portions of the substrate car-

ry-out device **180** into the stators **112** respectively provided on the upper surface of the mounting structure **110**.

[0253] The carrying robot **240** of the substrate carry-out device **180** includes an adsorption portion (not shown) for suction-adsorbing panel substrates cut out of the bonded mother substrate **90**. The entire substrate carry-out device **180** is slid to the substrate carry-out side with the panel substrate adsorbed by the adsorption portion, and out display panels are carried out from the mounting structure **110**.

[0254] The portion (a) of Figure **42** is a schematic view showing the structure of the carrying robot **240** in the substrate carry-out device **180**. The carrying robot **240** is attached to the substrate carry-out device guides **181** and is movable in a direction along the substrate carry-out device guides **181** (X direction) by a moving mechanism formed by combining driving means of the linear motors or servo motors and linear guides.

[0255] The carrying robot **240** includes two servo motors **240a** and **240m**. The servo motor **240a** is coupled to a driving shaft **240b**. A first pulley **240c** and a second pulley **240e** are integrally attached, and are respectively attached to the driving shaft **240b** via bearings and cut from the rotation of the driving shaft **240b**. An end portion of an arm **240f** is integrally attached to the driving shaft **240b**, and the arm **240f** is rotated by the driving shaft **240b** having the driving shaft **240b** as the center. On a tip portion of the arm **240f**, a rotation shaft **240g** is rotatably supported. The rotation shaft **240g** penetrates through the arm **240f**, and a third pulley **240h** is integrally attached to one end portion thereof. A belt **240i** such as, for example, a timing belt is hung between the second pulley **240e** and the third pulley **240h**.

[0256] Furthermore, fourth pulley **240n** is attached to a rotation axis of the servo motor **240m**. A belt **240p** such as, for example, a timing belt is hung between the fourth pulley **240n** and the first pulley **240c**. Thus, rotation of the servo motor **240m** is transmitted to the first pulley **240c** via the belt **240**, further transmitted to the third pulley **240h** via the belt **240i**, and the rotation shaft **240g** rotates.

[0257] To the other end portion of the rotation shaft **240g**, a center portion of an adsorption pad attachment plate **240j** is integrally attached. On the lower surface of the adsorption pad attachment plate **240j**, adsorption pads **240k** for adsorbing the substrates out by the substrate cutting system **100** by using a sucking mechanism which is not shown.

[0258] The carrying robot **240** having such a structure can carry substrates to a device in next step with the directions of the substrates in a horizontal manner but varying in angle directions with the minimum movement of the arm **240f**. This is achieved by setting rotation directions and rotation angles of the servo motor **240a** and the servo motor **240m**.

[0259] When the cut substrates are carried, the cut substrates are held by adsorption pads by sucking, and

the entire carrying robot 240 is temporarily lifted by a moving mechanism (not shown). Then, the substrates are carried to a device in next step, and the entire carrying robot 240 is moved down again by the moving mechanism (not shown) and placed in a previously decided state in a predetermined position in the next step.

[0260] Next, the example of changing the direction of the cut substrates by using the carrying robot 240 having such a structure by, for example, 90° will be described with reference to the portion (b) of Figure 42.

[0261] When the adsorption pads 240k attached to the adsorption pad attachment plate 240j are adsorbed to the cut substrates 93, the entire carrying robot 240 is lifted by the moving mechanism. The servo motor 240a is driven, and the driving shaft 240b is rotated by 90 degrees in counterclockwise direction as viewed from the substrate side. When the driving shaft 240b is rotated by 90 degrees, the arm 240f is rotated by 90 degrees in the counterclockwise direction as viewed from the substrate side having the driving shaft 240b as a center. Thus, the adsorption pad attachment plate 240j rotatably supported by the tip portion of the arm 240f via the rotation shaft 240g is rotated in counterclockwise direction as viewed from the substrate side having the driving shaft 240b as the center together with the arm 240f. In this case, the rotation shaft 240g attached to the adsorption pad attachment plate 240j is also rotated having the driving shaft 240b as the center.

[0262] At this time, the rotation of the servo motor 240m is transmitted to the first pulley 240c via the belt 240p, and further transmitted to the third pulley 240h via the belt 240i. Thus, the rotation shaft 240g is rotated by 180° in clockwise direction. The adsorption pad attachment plate 240j attached to the rotation shaft 240g also rotates by 180° in clockwise direction having the rotation shaft 240g as the center. Thus, the adsorption pad attachment plate 240j rotates by 180 degrees in clockwise direction as viewed from the substrate side having the rotation shaft 240g as the center while it is rotated by 90 degrees in counterclockwise direction as viewed from the substrate side having the driving shaft 240b as the center. As a result, as shown in the portion (b) of Figure 42, the cut substrate 93 adsorbed by the adsorption pads 240k are rotated by 90 degrees in clockwise direction when viewed from the substrate side with a relatively small space having the rotation center position being moved.

[0263] As shown in Figure 38, the first substrate supporting portion 120A and the second substrate supporting portion 120B of the substrate supporting device 120 respectively includes, for example, five first substrate supporting units 121A and second substrate supporting units 121B which are movable in a direction same as the moving direction of the scribing device guide body 130. The first substrate supporting units 121A and the second substrate supporting units 121B are arranged linearly along the direction parallel to the frames 111A and 111B in the longitudinal direction of the main frame

111 (Y direction) respectively on the substrate carry-in side and the substrate carry-out side of the scribing device guide body 130.

[0264] Figure 43 is a side view of one of the first substrate supporting units 121A provided in the first substrate supporting portion 120A. The first substrate supporting unit 121A has a pillar 145 provided on the surface of the guide base 115 held by a moving unit of the pair of guide rails 113 provided on the upper surface of the mounting structure 110, and has a supporting member 143 parallel to Y direction along the frames 111A and 111B in the longitudinal direction of the main frame 111 above the pillar 145. Two unit attachment members 141 and 142 extending in X direction orthogonal to the frames 111A and 111B of the main frame 111 on the supporting member 143 are attached to junction members 146 and 147.

[0265] A plurality of first substrate supporting units 121A (five in the present embodiment) are arranged with a predetermined spaces therebetween, and move in Y direction along the frames 111A and 111B of the main frame 111 together with the scribing device guide body 130.

[0266] Each of the first substrate supporting units 121A has a support main body 121a elongated linearly along a direction parallel to the main frame 111 (Y direction), and timing pulleys 121c and 121d for guiding a timing belt 121e are respectively attached to end portions of the support main body 121a. The timing belt 121e is rotated when clutches described below rotate a driving timing pulley 121b in connection with a driving axis.

[0267] A mechanism for moving the timing belt 121e of the first substrate supporting unit 121A having above-described structure will be described with reference to Figures 44, 45 and 46. Figure 44 is a front view of the plurality of (five) first substrate supporting units 121A provided in the first substrate supporting portion 120A as viewed from the side of the scribing device guide body 130. Figure 45 is a schematic view showing a structure of a clutch unit 210. Figure 46 is a side view of the clutch unit 210.

[0268] As shown in Figure 44, the driving timing pulleys 121b included in the support main bodies 121a of the first substrate supporting units 121A are coupled to a rotation driving shaft 149 provided in parallel to X direction which is orthogonal to the frames 111A and 111B in the longitudinal direction of the main frame 111. Both ends of the rotation driving shaft 149 are connected to the clutch units 210. Whether the rotation driving shaft 149 rotate or not rotate depends upon a connection state of a clutch in the clutch unit 210 with a driving axis. More specifically, when the clutch in the clutch unit is coupled with a driving axis 222, the rotation driving shaft 149 rotates. When the clutch is decoupled from the driving axis 222, the rotation driving shaft 149 is not rotated.

[0269] On the bottom surface of the frames 111A and 111B in the longitudinal direction of the main frame 111,



a rack **111a** for rotating a pinion **211** of the clutch unit **110** is attached along the longitudinal direction of the frames **111A** and **111B**.

[0270] The pinion **211** of the clutch unit **210** is coupled to one end of an axis **223**. To the other end of the axis **223**, a timing pulley **212** for a timing belt **219** is coupled.

[0271] To one end of the driving axis **222**, a timing pulley **215** is coupled. The timing belt **219** is hung between the timing pulley **212** and the timing pulley **215** via the two idlers **213** and **214**, and rotation of the axis **223** is transmitted to the driving axis **222**.

[0272] To the other end of the driving axis **222**, clutch **216** such as an air clutch is attached. When compressed air is put into the clutch **216**, the driving axis **222** and a driven axis **224** are coupled. When putting compressed air into the clutch **216** is stopped and the air pressure inside the clutch **216** becomes atmospheric pressure, the coupling between the driving axis **222** and the driven axis **224** is blocked.

[0273] To the end portion of the driven axis **224** which is not jointed to the clutch **216**, a timing pulley **217** is coupled. A timing belt **221** is hung between the timing pulley **217** and a timing pulley **218** on one end of the rotation driving shaft **149** to which the driving timing pulley **121b** included in the support main body **121a** of the first substrate supporting units **121A** is coupled.

[0274] As shown in Figure 44, a mechanism for moving the timing belts **121e** by rotating the driving timing pulleys **121b** of the five first substrate supporting units **121A** provided in the first substrate supporting portion **120A** (clutch unit **210**) is also provided on the frame **111B** side in the longitudinal direction of the main frame **111**.

[0275] As described above, the pillar **145** on the frame **111A** side which supports five first substrate supporting units **121A** and the pillar **145** on the frame **111B** side are held by the guide bases **115**, and are coupled such that they move integrally with the guide bases **115** for holding the pillars **128** for supporting both ends of the scribing device guide body **130**. To the guide bases **115** which support the pillars **128**, movers (not shown) of the linear motors are attached. Thus, by driving the linear motors, the scribing device guide body **130** is moved toward the substrate carry-in side, and five first substrate supporting units **121A** of the first substrate supporting portion **120A** are moved toward the substrate carry-in side.

[0276] When the scribing device guide body **130** is moved, the pinion **211** of the clutch unit **210** on the frame **111A** side and the pinion **211** of the clutch unit **210** on the frame **111B** side, which are engaged with the racks **111a** attached along the frames **111A** and **111B**, are rotated.

[0277] For rotating the driving timing pulleys **121b** of the first substrate supporting units **121A** and moving the timing belts **121e**, clutches on both sides of the frames **111A** and **111B** may be coupled to the respective driving axes **222**, or the clutch on one of the frames **111A**

and **111B** may be coupled to the driving axes **222**.

[0278] The second substrate supporting portion **120B** of the substrate supporting device **120** includes, for example, five second substrate supporting units **121B** which are movable in the same direction as the moving direction of the scribing device guide body **342**. The second substrate supporting units **121B** have similar structures as those of the first substrate supporting units **121A**, and supported by the pillar **145** on the frame **111A** side and the pillar **145** on the frame **111B** side so as to be attached in an inverted direction with respect to Y direction to provide an arrangement symmetrical with respect to the scribing device guide body **130**. The respective pillars are supported by the guide bases **115**.

[0279] The pillar **145** on the frame **111A** side and the pillar **145** on the frame **111B** side which support five first substrate supporting units **121A** are held by the guide bases **115**. The pillar **145** on the frame **111A** side and the pillar **145** on the frame **111B** side which supports five second substrate supporting units **121B** are held by the guide bases **115**. Further, they are coupled such that they integrally move with the guide bases **115** for supporting pillars which support both ends of the scribing device guide body **130**. Since the movers (not shown) of the linear motors are attached to the guide bases **115** for holding the pillars **128** which support both ends of the scribing device guide body **130**, the scribing device guide body **130** is moved toward the substrate carry-in side by driving the linear motor, and the five first substrate supporting units **121A** of the first substrate supporting portion **120A** and the five second substrate supporting units **121B** of the second substrate supporting portion **120B** also move toward the substrate carry-in side.

[0280] On the frame **111A** side and the frame **111B** side of the second substrate supporting portion **120B**, clutch units **210** similar to those in the first substrate supporting portion **120A** are provided. When the scribing device guide body **130** is moved, the pinion **211** of the clutch unit **210** on the frame **111A** side and the pinion **211** of the clutch unit **210** on the frame **111B** side, which are engaged with the racks **111a** attached along the frames **111A** and **111B**, are rotated.

[0281] For rotating the driving timing pulleys **121b** of the second substrate supporting units **121B** and moving the timing belts **121e**, clutches on both sides of the frames **111A** and **111B** may be coupled to the respective driving axes **222**, or the clutch on one of the frames **111A** and **111B** may be coupled to the driving axes **222**.

[0282] As shown in Figure 38, above the mounting structure **110** on the substrate carry-out side, a steam unit portion **260** for completely cutting the bonded mother substrate **90** which is not completely cut after the scribing process is located on the substrate carry-out side with respect to the second substrate supporting portion **120B** and the substrate carry-in side with respect to the substrate carry-out device **180**.

[0283] The steam unit portion **260** includes an upper



steam unit attachment bar 262 for attaching a plurality of steam units 261 for spraying steam to the upper mother substrate of the bonded mother substrate 90 and a lower steam unit attachment bar 263 for attaching a plurality of steam units 261 for spraying steam on the lower mother substrate of the bonded mother substrate 90 attached to a pillar 264 on the frame 111A side and a pillar 264 on the frame 111B side along X direction which is orthogonal to the frames 111A and 111B.

[0284] Along the guide rails 113 provided on the upper surface of the mounting structure 110, the pillars 264 on the frame 111A and 111B sides slide by the linear motors. In this case, the linear motors are formed by inserting movers (not shown) of the linear motors respectively attached to the steam unit portion 260 into the linear motor stators 112 respectively provided on the upper surface of the mounting structure 110.

[0285] Figure 47 is a front view of important parts of a steam unit portion 260 as viewed from the substrate carry-in side. Six steam units 261 are attached to the upper steam unit attachment bar 262 and six steam units 261 are attached to the lower steam unit attachment bar 263 with a gap GA spaced apart from the upper six steam units 261. The gap GA is adjusted so as to allow the bonded mother substrate 90 to pass through the gap GA when the steam unit portion 260 moves toward the substrate carry-in side.

[0286] Figure 48 is a partial cross-sectional side view showing the structures of the steam units 261. Each of the steam units 261 is mostly made of an aluminum material, and a plurality of heaters 261a are embedded in a vertical direction. When an opening/closing valve (not shown) which can be opened or closed automatically is opened, water flows into the steam unit 261 from a water supply port 261b and heated by the heaters 261a. The supplied water is vaporized and becomes steam. The steam is blown to the surface of the mother substrate through a conducting hole 261c and from a spray nozzle 261d.

[0287] Further, on the carry-out side of the upper steam unit attachment bar 262, an air knife 265 for removing water which remains on the surface of the bonded mother substrate 90 after the steam is blown to the upper surface of the bonded mother substrate 90 is attached.

[0288] The lower steam unit attachment bar 263 also includes the steam units 261 and the air knife 165 similar to those attached to the upper steam unit attachment bar 262.

[0289] When the bonded mother substrate 90 is placed on the first substrate supporting portion 120A, and the bonded mother substrate 90 is positioned, the positioned bonded mother substrate 90 is held by the clamp device 150 and also supported by the timing belts 221e of the first substrate supporting units 121A.

[0290] In this state, cutting of the bonded mother substrate 90 is started by the upper portion substrate cutting device 160 and the lower portion substrate cutting de-

vice 170 provided on the scribing device guide body 130 after the clutches of four clutch units 210 of the first substrate supporting portion 120A and the second substrate supporting portion 120B are coupled to the driving axes 222. As the scribing device guide body 130 moves toward the substrate carry-in side, the first substrate supporting portion 120A slides toward the substrate carry-in side. Further, second substrate supporting portion 120B slides toward the substrate carry-in side. While the scribing device guide body 130 is moving toward the substrate carry-in side, the timing belts 121e of the first substrate supporting units 121A of the first substrate supporting portion 120A and the timing belts 121e of the second substrate supporting units 121B of the second substrate supporting portion 120B rotate at the same rate as the moving speed of the scribing device guide body 130 and moves the bonded mother substrate 90 in the substrate carry-out direction. The bonded mother substrate 90 being out is supported by the timing belts 121e of the first substrate supporting units 121A of the first substrate supporting portion 120A and the timing belts 121e of the second substrate supporting units 121B of the second substrate supporting portion 120B. [0291] However, while the scribing device guide body 130 is being moved, the timing belts 121e of the first substrate supporting units 121A of the first substrate supporting portion 120A and the timing belts 121e of the second substrate supporting units 121B of the second substrate supporting portion 120B try to move the bonded mother substrate 90 in a direction opposite to the moving direction of the scribing device guide body 130 at a rate same as the moving speed of the scribing device guide body 130. Thus, the bonded mother substrate 90 does not actually move, and the bonded mother substrate 90 is supported while being held by the clamp device 150 without the timing belts 121e of the first substrate supporting units 121A of the first substrate supporting portion 120A and the timing belts 121e of the second substrate supporting units 121B of the second substrate supporting portion 120B being in sliding contact with the bonded mother substrate 90.

[0292] When cutting of the bonded mother substrate 90 is finished, the bonded mother substrate 90 is supported by the timing belts 121e of all the second substrate supporting units 121B of the second substrate supporting portion 120B.

[0293] With the bonded mother substrate 90 being supported by the timing belts 121e of the second substrate supporting units 121B, the steam unit portion 260 moves toward the substrate carry-in side, and sprays steam on the entire front and back surfaces of the bonded mother substrate 90 having the scribe lines carved. Thus, the vertical cracks are extended by thermal stress, and the bonded mother substrate 90 is completely out. At the same time, water remaining on the front and back surfaces of the bonded mother substrate 90 after spraying steam is removed by the air knives 265.

[0294] Thereafter, all the display panels cut from the

bonded mother substrate **90** on the timing belts **121e** of all the second substrate supporting units **121B** of the second substrate supporting portion **120B** are carried out by the carrying robot **240** of the substrate carry-out device **180**, and thus, a out bonded mother substrate **90'** (mill end) is supported.

[0295] Then, the substrate carry-out device **180** and the steam unit portion **260** moves toward the end portion on the substrate carry-out side.

[0296] Thereafter, the scribing device guide body **130**, the second substrate supporting portion **120B**, and the first substrate supporting portion **120A** are slid toward the substrate carry-out side. At this time, timing belts **121e** of the first substrate supporting units **121A** of the first substrate supporting portion **120A** and the timing belts **121e** of the second substrate supporting units **121B** of the second substrate supporting portion **120B** rotates as if they move the bonded mother substrate **90** in the substrate carry-in direction at the same rate as the moving speed of the scribing device guide body **130**.

[0297] Thus, the timing belts **121e** of the first substrate supporting units **121A** and the timing belts **121e** of the second substrate supporting units **121B** are sequentially brought into a non-contact state without being in sliding contact from the lower surface of the cut bonded mother substrate **90'**. The supports of the out bonded mother substrate **90'** by the timing belts **121e** are sequentially released. Then, support of the out bonded mother substrate **90'** (mill end) by the clamp device **150** is released and the cut bonded mother substrate **90'** (mill end) drops downward. In this case, the out bonded mother substrate **90'** dropped downward (mill end and cullet) is guided by a guiding plate arranged in a slanted state and is accommodated within a cullet accommodation box.

[0298] The mounting structure **110** includes a positioning device (not shown) for positioning the bonded-mother substrate **90** supported by the first substrate supporting portion **120A**. The positioning device includes, for example, a plurality of positioning pins (not shown) the frame **111B** of the main frame **111** and along a direction orthogonal to the frame **111B** with predetermined spaces therebetween. For the positioning pins arranged along the frame **111B**, pushers (not shown) for pushing a side edge of the bonded mother substrate **90** which opposes the positioning pins. For the positioning pins arranged in a direction orthogonal to the frame **111B**, pushers (not shown) for pushing an opposing side edge of the bonded mother substrate **90** are provided.

[0299] Further, for example, when the positioning device for performing positioning of the bonded mother substrate **90** immediately before transportation to the substrate cutting system of the present invention is provided separately from the substrate cutting system, a positioning device within the substrate cutting system may be omitted.

[0300] Further, the positioning device within the sub-

strate cutting system is not limited to the positioning pins and pushers as described above. It may be any kind of devices as long as it can provide a constant position of the bonded mother substrate **90** in the substrate cutting system.

[0301] Furthermore, above the mounting structure **110**, the clamp device **150** for clamping the bonded mother substrate **90**, which is supported by the first substrate supporting portion **120A** and pushed against the positioning pins so as to be positioned, is provided. For example, as shown in Figure **39** the clamp device **150** includes a plurality of clamp members **151** attached to the frame **111B** of the main frame **111** with predetermined spaces therebetween in a longitudinal direction so as to clamp a side edge of the positioned bonded mother substrate **90** along the frame **111B**, and a plurality of clamp members **151** arranged along the direction orthogonal to the main frame **111** with a predetermined spaces therebetween for clamping a side edge of the positioned bonded mother substrate **90** on the substrate carry-in side.

[0302] Figures **49** and **50** are perspective views for showing a plurality of clamp members **151** provided on the frame **111B** of the main frames **11**, and for illustrating an operation thereof. The clamp members **151** have similar structures to each other. Each of the clamp members **151** includes a casing **151a** attached to the frame **111B** of the main frame **111** and a pair of upper and lower rotation arms **151b** attached to the casing **151a** so as to be rotatable from a vertical position to a horizontal position. Each of the rotation arms **151b** can rotate having one end portion as a center. The end portions to be the center of rotation are located close to each other. As shown in Figure **49**, a tip portion of the upper rotation arm **151b** locates above the rotation center in the vertical position. A tip portion of the lower rotation arm **151b** locates below the rotation center in the vertical position. The rotation arms **151b** respectively rotate by **90** degrees toward the bonded mother substrate **90**, and thus, the rotation arms **151b** are in horizontal positions opposing each other.

[0303] To the tip portions of the rotation arms **151b**, clamp portions **151c** which respectively abut the upper surface and the lower surface of the bonded mother substrate **90** are attached. The clamp portions **151c** are formed of elastic body. The rotation arms **151b** are integrally rotated from the vertical position to the horizontal position and from the horizontal position to the vertical position. When the rotation arms **151b** are rotated to the horizontal position, as shown in Figure **50**, the clamp portions **151c** attached to the tip portions of the rotation arms **151b** clamp the bonded mother substrate **90**.

[0304] The clamp members **151** arranged along a direction orthogonal to the frame **111B** of the main frame **111** have similar structures. These clamp members **151** are also driven integrally. After the side edges orthogonal to each other of the bonded mother substrate **90** are

clamped by the plurality of clamp members 151, all the clamp members 151 sink below, and the bonded mother substrate 90 is supported by the timing belts 121e of the first substrate supporting portion 120A.

[0305] Further, in the above-described the arrangement of the clamp device 150, the clamp device 150 for holding the bonded mother substrate 90 is provided on the substrate carry-in side in a direction orthogonal to the frame 111A and the frame 111B of the main frame 111. However, even when the clamp device 150 is provided only on the frame 111B, the bonded mother substrate 90 can be held without causing damage in the substrates.

[0306] The structures of the clamp device 150 and the clamp members 151 as described above are merely examples used in the substrate cutting system of the present invention, and the structures are not limited to such structures. The clamp device 150 and the clamp members 151 may have any kind of structures as long as they can grip or hold the side edges of the bonded mother substrate 90. When the substrate size is small, the substrate can be held by clamping one position of the side edge of the substrate, and the substrate can be cut out without causing a defect in the substrate.

[0307] As shown in Figure 40, the upper portion substrate cutting device 160 is attached to the upper guide rail 131 in the scribing device guide body 130. As shown in Figure 41, the lower portion substrate cutting device 170 having the similar structure as the upper portion substrate cutting device 160 but inverted upside down is attached to the lower guide rail 132. As described above, the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 respectively slide along the upper guide rail 131 and the lower guide rail 132 by the linear motors.

[0308] For example, in the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170, a cutter wheel 162a for scribing the upper glass substrate of the bonded mother substrate 90 is rotatably attached to a tip holder 162b, and the tip holder 162b is rotatably attached to a cutter head 162c having an axis in a direction vertical to the surface of the bonded mother substrate 90 held by the clamp device 150. The cutter head 162c is movable along a direction vertical to the surface of the bonded mother substrate by driving means which is not shown. The cutter wheel 162a is appropriately loaded by energizing means which is not shown.

[0309] The cutter wheel 162a held by the tip holder 162b may have a blade edge protruded so as to have a center portion in a width direction of a shape of letter V with an obtuse angle and may have protrusions of a predetermined height formed on the blade edge with predetermined pitches in a circumferential direction as disclosed in Japanese Laid-Open Publication No. 9-188534.

[0310] The lower portion substrate cutting device 170 provided on the lower guide rail 132 has a similar struc-

ture as the upper portion substrate cutting device 160 but inverted upside down. A cutter wheel 162a of the lower portion substrate cutting device 170 (see Figure 41) is arranged so as to oppose the cutter wheel 162a of the upper portion substrate cutting device 160.

[0311] The cutter wheel 162a of the upper portion substrate cutting device 160 are pressed onto a surface of the bonded mother substrate 90 and rotated by the above-described energizing means and moving means of the cutter head 162c. The cutter wheel 162a of the lower portion substrate cutting device 170 is pressed onto a back surface of the bonded mother substrate 90 by the above-described energizing means and moving means of the cutter head 162c. By moving the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 in the same direction at the same time, the bonded mother substrate 90 is cut.

[0312] It is preferable that the cutter wheel 162a is rotatably supported by a cutter head 165 using a servo motor disclosed in WO 03/011777.

[0313] Figure 51 shows a side view of an exemplary cutter head 165 using a servo motor. Figure 52 is a front view of the main part of the cutter head 165. A servo motor 165b is held between a pair of side walls 165a in an inverted state. In the lower part of the side walls 165a, a holder maintaining assembly 165c having a shape of letter L when viewed from side is rotatably provided via a spindle 165d. On the front portion of the holder maintaining assembly 165c (the right hand part in Figure 52), the tip holder 162b for rotatably supporting the cutter wheel 162a via an axis 165e. Flat bevel gears 165f are respectively attached to the rotation axis of the servo motor 165b and the spindle 165d so as to engage each other. With such a structure, by rotating the servo motor 165b in normal or inverted direction, the holder maintaining assembly 165c performs an elevating operation having the spindle 165d as a fulcrum and the cutter wheel 162a moves up and down. The cutter head 165 itself is included in the upper portion substrate cutting device 160 and/or lower portion substrate cutting device 170.

[0314] Figure 53 is a front view showing another example of a cutter head using a servo motor. In this example, the rotation axis of the servo motor 165b is directly connected to the holder maintaining assembly 165c.

[0315] The cutter heads of Figures 51 and 53 moves the cutter wheel 162a for positioning by rotating the servo motor by position control. Such a cutter head controls a rotation torque which acts to bring back the position of the cutter wheel 162a to the position which has been previously set to the servo motor 165b. When the position is moved from the set position, and transmits a scribing pressure to a brittle material substrate during scribing operation in which the cutter head is moved in the horizontal direction to form scribe lines on the bonded mother substrate 90. In other words, the servo motor 165b controls the position of the cutter wheel 162a in a

vertical direction and also serves as energizing means for the cutter wheel 162a.

[0316] By using the cutter head including the servo motor as described above, the rotation torque of the servo motor can be corrected while the bonded mother substrate 90 is being scribed instantly in accordance with the change in a scribing pressure due to a variance in resistance applied to the cutter wheel 162a. Thus, stable scribing is performed and scribe lines with high quality can be formed.

[0317] A cutter head including a mechanism to periodically change the pressure to the bonded mother substrate 90 by a scribing cutter by vibrating the scribing cutter such as a diamond point cutter and/or cutter wheel for scribing the bonded mother substrate 90 may also effectively be applied to the cutting of the mother substrate by the substrate cutting system of the present invention.

[0318] The structures of the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 are not limited to the above-described structures. The devices may have any kind of structures as long as they process the front and back surfaces of the substrate to cut the substrate.

[0319] For example, the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 may be a device for cutting the mother substrate by using laser light, a dicing saw, a cutting blade, a diamond cutter, or the like. When the mother substrate is a metal substrate such as steel sheet, wood plate, a plastic substrate, and a brittle material substrate such as ceramics substrate, glass substrate, semiconductor substrate or the like, a scribing device for cutting the mother substrate by using, for example, laser light, a dicing saw, a cutting blade, a diamond cutter, or the like may be used.

[0320] Furthermore, the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 may further include cutting assistance means for assisting in the cutting of the substrate. The cutting assistance means may be, for example, means for pressing a roller or the like to the substrate, or means for warming (heating) the substrate by spraying compressed air to the substrate, irradiating the substrate with laser, or blowing hot air to the substrate.

[0321] In the above example, the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 have the same structure. However, they may have different structures depending upon the cutting pattern of the substrate and cutting conditions for the substrate.

[0322] The substrate cutting system having such a structure will be explained with reference mainly to an example in which a bonded substrate formed by bonding large-scale glass plates is cut.

[0323] For cutting the bonded mother substrate 90 formed by bonding large-scale glass substrates to each other into a plurality of panel substrates 90a (see Figure

55), first, as shown in Figure 54, the bonded mother substrate 90 is carried into the substrate cutting system by the carrying robot or the like from the end portion on the substrate carry-in side, and is placed on the timing belts 121e of all the second substrate supporting units 121A of the first substrate supporting portion 120A in a horizontal fashion.

[0324] In such a state, the bonded mother substrate 90 is pressed with a pressure which is not shown so as to abut positioning pins (not shown) arranged along the frame 111B of the main frame 111. The bonded mother substrate 90 is also pressed with a pressure which is not shown so as to abut positioning pins (not shown) arranged along a direction orthogonal to the frame 111B. In this way, the bonded mother substrate 90 is positioned at a predetermined position in the housing 110 in the substrate cutting system.

[0325] Then, as shown in Figure 54, the bonded mother substrate 90 has its side edge along the frame 111B of the main frames 111 clamped by the clamp members 151 of the clamp device 150. The side edge of the bonded mother substrate 90 on the substrate carry-in side is clamped by the clamp members 151 arranged on the substrate carry-in side so as to be orthogonal to the frame 111B.

[0326] When the side edges of the bonded mother substrate 90 which are orthogonal to each other are respectively clamped by the clamp device 150, the clamp members 151 clamping the side edges of the bonded mother substrate 90 sink approximately at the same time due to the weight of the bonded mother substrate 90 itself. Thus, the bonded mother substrate 90 is supported supplementarily by the timing belts 121c of all the first substrate supporting units 121A.

[0327] In such a state, the scribing device guide body 130 slide toward the substrate carry-in side so as to be at a predetermined position on a side edge near the bonded mother substrate 90 clamped by the clamp device 150 in a horizontal fashion after the clutches 216 of the four clutch units 210 of the first substrate supporting portion 120A and the second substrate supporting portion 120B are coupled to the driving axes. The first optical device 138 and the second optical device 139 provided on the scribing device guide body 130 move along the guide body 130 from waiting positions. Thus, the images of the first alignment mark and the second alignment mark provided on the bonded mother substrate 90 are taken.

[0328] Since the scribing device guide body 130 slides, the first substrate supporting portion 120A slides toward the substrate carry-in side, and second substrate supporting portion 120B slides toward the substrate carry-in side. The timing belts 121e of the first substrate supporting units 121A of the first substrate supporting portion 120A and the timing belts 121e of the second substrate supporting units 121B of the second substrate supporting portion 120B moves the bonded mother substrate 90 in a direction opposite to the moving direction

of the scribing device guide body 130 at the rate same as the moving speed of the scribing device guide body 130. Thus, the bonded mother substrate 90 is supported while being held by the clamp device 150 without the timing belts 121e of the first substrate supporting units 121A of the first substrate supporting portion 120A and the timing belts 121e of the second substrate supporting units 121B of the second substrate supporting portion 120B being in allding contact with the bonded mother substrate 90.

[0329] Next, based on the results of taking the images of the first alignment mark and the second alignment mark, angle of the bonded mother substrate 90 supported by the clamp device 150 in a horizontal fashion in a direction along the scribing device guide body 130, cutting start position and cutting end position by a calculation using an operation process device which is not shown. Based on the calculated results, the scribing device guide body 130 is moved with the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 to cut the bonded mother substrate 90 (Such an operation may be referred to as scribing or cutting by linear interpolation).

[0330] In this example, as shown in Figure 55, the cutter wheels 162a respectively opposing the front surface and the back surface of the bonded mother substrate 90 are pressed onto the front back surfaces and rotated. Thus, scribe lines are formed on the front surface and the back surface of the bonded mother substrate 90.

[0331] From the bonded mother substrate 90, for example, two panel substrates 90a in a column direction along the upper guide rail 132 and the lower guide rail 132 are out out for two columns. For cutting four panel displays 90a out of the bonded mother substrate 90, the cutter wheel 162a of the upper portion substrate cutting device 160 and the cutter wheel 162a of the lower portion substrate cutting device 170 are respectively pressed and rotated along the side edges of the panel substrates.

[0332] In this example, the cutter wheel 162a of the upper portion substrate cutting device 160 and the cutter wheels 162a of the lower portion substrate cutting device 170 generate vertical cracks in the portions of the glass substrates where the cutter wheels 162a rotated, and a scribe line 95 is formed. Since protrusions are formed in a predetermined pitch in peripheral edges of the blade edges of the cutter wheels 162a, vertical cracks having the length of about 90% of the thickness of the glass substrate in the thickness direction are formed in the glass substrates.

[0333] Further, a scribing method using a cutter head including a mechanism for periodically changing (vibrating) a pressure to the bonded mother substrate 90 by a scribe cutter such as a diamond point cutter, cutter wheel or the like for scribing the bonded mother substrate 90 may be effectively applied to the cutting of the bonded mother substrate 90 by the substrate cutting system of the present invention.

[0334] As the method for scribing the front and back surfaces of the bonded mother substrate 90, a conventional method as shown in Figure 56, in which scribe lines are formed in turn along lines to be scribed S1 to S4 along a vertical direction, which is a narrow side direction of the bonded mother substrate 90, and then scribe lines are formed in turn along lines to be scribed S5 to S8 along the horizontal direction, which is wide side direction, may be used in general.

[0335] Beside the above-described scribing method, a scribing method as shown in Figure 57 may be preferably used for the substrate cutting system of the present invention. In Figure 57, four panel substrates 90a are formed from one bonded mother substrate 90.

[0336] The bonded mother substrate 90 has a rectangular shape. Four panel substrates 90a are obtained by forming two panel substrates 90a along the longitudinal direction of the bonded mother substrate 90 and forming two panel substrates 90a along the width direction which is orthogonal to the longitudinal direction. Each of the panel substrates 90a is formed with an appropriate space apart from the adjacent panel substrate 90a and from side edges along the longitudinal direction and side edges of the width direction of the bonded mother substrate 90.

[0337] By having the cutter wheel 162a of the upper portion substrate cutting device 160 and the cutter wheel 162a of the lower portion substrate cutting device 170 oppose each other, and are pressed and rotated at the same time, scribe lines across the entire circumference are formed on the front and back surface of the bonded mother substrate 90 for each of the panel substrates 90a one by one in turn.

[0338] In this example, first, scribe line is formed along one linear line to be scribed S1 along the side edges parallel to the longitudinal direction of the bonded mother substrate 90 for the panel substrate 90a to be scribed. More specifically, the cutter wheels 162a of the cutter heads 62a are pressed and rotated on the bonded mother substrate 90 along the line to be scribed S1.

[0339] In Figure 58, it is shown that the scribe start point by the cutter wheels 162a is a position on the bonded mother substrate 90 (a position for internal out). However, it may be a position near the outside of the end surface of the bonded mother substrate 90 along the line to be scribed S1 (a position for external out).

[0340] When the scribe line is formed along the line to be scribed S1 by a vertical crack which extends across the entirety of the thickness direction, the scribing device guide body 30 is moved to Y direction and the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 are moved in X direction at the same time such that the cutter wheels 162a revolves around the vertical axis by 270 degrees to form a circular trace having a radius of about 1 mm (a corner portion A in Figure 58).

[0341] When the cutter wheels 162a are revolving, the pressure of the cutter wheels 162a to the bonded mother



substrate 90 is reduced so that there is no deep vertical crack formed on the bonded mother substrate 90. When the thickness of the bonded substrate 90 is 0.7 mm, the depth of the vertical crack formed in the bonded mother substrate 90 when the cutter wheels 162a is revolving is about 100 to 200  $\mu\text{m}$ .

[0342] When the cross-scribing is performed by the cutter wheels 162a as shown in Figure 56, a chip tends to be generated in the bonded mother substrate 90 at cross points of the scribe lines formed when scribing is performed in first direction and scribing is performed in second direction.

[0343] Since a vertical cracks which almost extends to the thickness of the bonded mother substrate 90 has been already formed when scribing is performed in the first direction, the mother glass substrate 90 sinks in front of the first scribe line when the cutter wheels 162a reach near the scribe line in the first direction while scribing in the second direction and such a chip may be generated when the cutter wheels 162a run on the glass substrates along the scribe line in the first direction at a crossing portion of the scribe line in the first direction and a scribe line in the second direction.

[0344] In the scribing method as shown in Figure 57, the cutter wheels 162a revolve and cross the scribe line which has been already formed along the line to be scribed S1 with the pressure to the bonded mother substrate 90 being reduced. Thus, a part of the bonded mother substrate 90 does not sink before the scribing lines cross each other, and thus, it is possible to prevent a chip from occurring in the bonded mother substrate 90 when the scribing lines cross each other.

[0345] When travel direction of the cutter wheels 162a revolve by 270 degrees and the cutter wheels 162a are along the linear line to be scribed S2 along the width direction of the panel substrates 90a which are orthogonal to the line to be scribed S1, the cutter wheels 162a are pressed and rotated along the line to be scribed S2. Thus, the scribe line is formed by a vertical crack which extends across the entirety of the thickness direction along the line to be scribed S2.

[0346] Then, again, the cutter wheels 162a revolve by 270 degrees to a direction orthogonal to the line to be scribed S2 while forming a circular trace having a radius of about 1 mm in corner portion B without separating the cutter wheels 162a from the front and back surfaces of the bonded mother substrate 90. Thus, the cutter wheels 62a are along the line to be scribed S3 and form the scribe line by a vertical crack which extends across the entirety of the thickness direction along the line to be scribed S3. Furthermore, again, the cutter wheels 162a revolve by 270 degrees to a direction orthogonal to the line to be scribed S3 while forming a circular trace having a radius of about 1 mm in corner portion C without separating the cutter wheels 162a from the front and back surfaces of the bonded mother substrate 90. Thus, the cutter wheels 162a are along the line to be scribed S4 and form the scribe line by a vertical crack which ex-

tends across the entirety of the thickness direction along the line to be scribed S4.

[0347] In this way, a closed curve including four linear scribe lines is formed around a panel substrate 90a. Then, for example, for forming the panel substrate 90a adjacent in the longitudinal direction of the bonded mother substrate 90, a closed curve including four linear scribe lines is formed across the entire circumference of the panel substrate 90a similarly. Then, closed curves including four linear scribe lines are formed across the entire circumferences for each of the remaining pair of the panel substrates 90a in turn.

[0348] Besides the above-described scribing method, a scribing method as shown in Figure 58 can be preferably used in the substrate cutting system of the present invention. In Figure 58, four panel substrates 90a are formed from one bonded mother substrate 90.

[0349] In the scribing method shown in Figure 58, scribe lines along lines to be scribed S1 and S2 which are orthogonal to each other on the panel substrates 90a are formed in the method as described above. For forming the scribe line along the line to be scribed S1, the cutter wheels 162a is positioned outside the end surface of the bonded mother substrate 90 and the scribe line along the line to be scribed S1 is continuously formed therefrom.

[0350] A chip which may be generated when the cutter wheels 162a run on the front and back surfaces of the bonded mother substrate 90 at the start of scribing does not affect the panel substrates 90a to become products.

[0351] Then, the cutter wheels 162a revolve by 270 degrees to a direction orthogonal to the line to be scribed S1 while forming a circular trace in the corner portion A. Thus, the cutter wheels 162a are along the line to be scribed S2 and form the scribe line by a vertical crack which extends across most of the entirety of the thickness direction along the line to be scribed S2.

[0352] Then, the cutter wheels 162a are temporarily separated from the surface of the bonded mother substrate 90, and the scribe lines along the lines to be scribed S3 and S4 in a direction orthogonal to the line to be scribed S1 are formed in this order. In this case, a chip which may be generated when the cutter wheels 162a run on the front and back surfaces of the bonded mother substrate 90 at the start of scribing does not affect the panel substrates 90a to become products.

[0353] In this way, four linear scribe lines are formed around the panel substrate 90a. Then, for example, for forming the panel substrate 90a adjacent in the longitudinal direction of the bonded mother substrate 90, four linear scribe lines are formed across the entire circumference of the panel substrate 90a similarly. Then, closed curves including four linear scribe lines are formed across the entire circumferences for each of the remaining pair of the panel substrates 90a in turn.

[0354] After the scribe lines are formed on the bonded mother substrate by the above-described scribing meth-



od, as shown in Figure 59, with the bonded mother substrate 90 on which the scribe line 95 is formed being supported by the timing belts 121e of the second substrate supporting units 121B, the steam unit portion 260 moves toward the substrate carry-in side and blows the steam entirely on the front and back surfaces of the bonded mother substrate 90 on which the scribe lines are carved to completely out the bonded mother substrate 90. At the same time, the water remaining on the front and back surfaces of the bonded mother substrate 90 after the steam is blown thereto is removed by the air knife 71.

[0355] By blowing the steam onto the entire front and back surface of the bonded mother substrate 90 having the scribe lines carved thereon, the scribe lines formed by the cutter wheels 162a experience volume expansion since the front and back surface portions of the bonded mother substrate 90 are heated. In this way, vertical cracks extend from the surface of the upper and lower mother substrates of the bonded mother substrate 90 toward the bonded surface, and the bonded mother substrate 90 is completely out.

[0356] Thereafter, as shown in Figure 59, all the panel substrates 90a out from the bonded mother substrate 90 on the timing belts 121e of all the second substrate supporting units 121B of the second substrate supporting portion 120B are carried out by the carrying robot 240 of the substrate carry-out device 180, and thus, a cut bonded mother substrate 90' (mill end) is supported.

[0357] Then, the substrate carry-out device 180 and the steam unit portion 260 moves toward the end portion on the substrate carry-out side.

[0358] Thereafter, as shown in Figure 60, the scribing device guide body 130, the second substrate supporting portion 120B, and the first substrate supporting portion 120A are slid toward the substrate carry-out side. At this time, timing belts 121e of the first substrate supporting units 121A of the first substrate supporting portion 120A and the timing belts 121e of the second substrate supporting units 121B of the second substrate supporting portion 120B rotates as if they move the bonded mother substrate 90 in the substrate carry-in direction at the same rate as the moving speed of the scribing device guide body 130.

[0359] Thus, the timing belts 121e of the first substrate supporting units 121A and the timing belts 121e of the second substrate supporting units 121B are sequentially brought into a non-contact state without being in sliding contact from the lower surface of the cut bonded mother substrate 90'. The supports of the cut bonded mother substrate 90' by the timing belts 221e are sequentially released. Then, support of the cut bonded mother substrate 90' (mill end) by the clamp device 150 is released and the out bonded mother substrate 90' (mill end) drops downward. In this case, the cut bonded mother substrate 90' dropped downward (mill end and cullet) is guided by a guiding plate arranged in a slanted state and is accommodated within a cullet accommoda-

tion box.

[0360] By employing the scribing method which will be described below as the scribing method by the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 of the scribing device guide body 130, a cutting process of the bonded substrate by the steam unit portion 260 may be omitted.

[0361] At this time, as shown in Figure 61, the cutter wheels 162a are pressed and rotated on an upper mother substrate 91 and a lower mother substrate 92 of the bonded mother substrate 90 along lines to be out on the mother substrates 91 and 92 for scribing the mother substrates 91 and 92. Thus, vertical cracks Vm along thickness directions of the mother substrates 91 and 92 are sequentially formed along the lines to be out, and main scribe lines MS are formed. The vertical cracks vm are formed such that they extend by 80% or more of the thickness of the mother substrates 91 and 92, and more preferably, 90% or more from surfaces of the mother substrates 91 and 92.

[0362] Thereafter, in the area outside the panel substrates obtained by cutting the mother substrates 91 and 92, the mother substrates 91 and 92 are scribed by pressing and rotating the cutter wheels 162a along the main scribe lines MS on the mother substrates 91 and 92 with spaces of about 0.5 to 1.0 mm apart from the main scribe lines MS. In this way, vertical cracks Vs along the thickness directions of the mother substrates 91 and 92 are sequentially formed along the main scribe lines MS to form supplementary scribe lines SS.

[0363] At this time, the cutter wheels 162a presses and rotates on the surfaces of the mother substrates 91 and 92, and the blades thereof cut into the surfaces of the mother substrates 91 and 92. Thus, a compressed force is applied to the surfaces of the mother substrates 91 and 92 and the compressed force has influence on the surface portions of the vertical cracks Vm in the main scribe lines MS which have been already formed. In this example, the vertical cracks Vm forming the main scribe lines MS are formed to extend by 80% or more of the thickness of the mother substrates 91 and 92. Thus, when the surface portion of the mother substrates 91 and 92 are compressed, the vertical cracks Vm of the main scribe lines MS have gaps on the surface portions of the mother substrates 91 and 92 compressed and gaps on bottom portions are widened. Therefore, the vertical cracks Vm are elongated toward the bonded surface of the mother substrates 91 and 92. When the vertical cracks Vm reach the bonded surface of the mother substrates 91 and 92 and the vertical cracks Vm reach the bonded surface of the mother substrates 91 and 92 across the entirety of the main scribe lines MS, the bonded mother substrate 90 is cut along the main scribe lines MS.

[0364] It is preferable that the supplementary scribe lines SS are formed with spaces of about 0.5 to 1.0 mm apart from the main scribe lines MS. When the spaces between the supplementary scribe lines SS and the

main scribe lines MS are smaller than 0.5 mm, a large compression force is applied to the surface portion of the vertical cracks Vm forming the main scribe lines MS, and damage such as chip may occur in the surface side end portions of the vertical cracks Vm. On the other hand, when the space is larger than 1.0 mm, the compression force applied to the vertical cracks Vm on the main scribe lines MS is not enough, and the vertical cracks Vm may not reach the bonded surface of the mother substrates 91 and 92.

[0365] As described above, by forming double scribe lines of the main scribe lines MS and the supplementary scribe lines SS with predetermined spaces, a plurality of panel substrates 90a are cut out of the bonded mother substrate 90.

[0366] Figure 62 is a diagram for illustrating a scribe pattern for cutting panel substrates 90a out of the bonded mother substrate 90 by using such double scribe lines of the main scribe lines MS and the supplementary scribe lines SS. The cutter wheels 162a of the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 run along side edges of the substrate carry-out side of two panel substrates 90a on the substrate carry-out side of the bonded mother substrate 90, and a double scribe line (main scribe line MS1 and supplementary scribe line SS1) is formed on the side edges of the substrate carry-out side of the two panel substrates 90a.

[0367] Then, main scribe line MS2 and supplementary scribe line SS2 are formed along the side edges of the substrate carry-in side of the two panel substrates 90a on the substrate carry-out side of the bonded mother substrate 90. When the side edges of the substrate carry-out side and the substrate carry-in side of the two panel substrates 90a on the substrate carry-out side of the bonded mother substrate 90 are cut, the scribing device guide body 130 slides toward the substrate carry-out side so that the cutter wheels 162a locate on the side edge portion located on the substrate carry-out side of the bonded mother substrate 90. Then, the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 slide along the upper guide rail 131 and the lower guide rail 132 so that the cutter wheels 162a of the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 are on an extension of the side edge of the panel substrate 90a on the substrate carry-out side and close to the frame 111A of the main frame 111, which is close to the main frame 111. Along the extension of the side edge, a double scribe line (main scribe line MS3 and supplementary scribe line SS3) is formed, and the side edge close to the frame 111A of the panel substrate 90a on the substrate carry-out side and close to the frame 111A of the main frame 111 is cut.

[0368] Then, double scribe lines (main scribe lines MS4 to MS6 and supplementary scribe lines SS4 to SS6) are formed in parallel with the frame 111A in a similar manner. Thus, side edges of the panel substrates

90a located on the substrate carry-out side in a direction along the frame 111A are respectively cut.

[0369] Thereafter, regarding two other panel substrates 90a along the upper guide rail 131 and the lower guide rail 132, side edges of the panel substrates 90a are cut by forming double scribe lines (main scribe lines MS7 to MS12 and supplementary scribe lines SS7 to SS12) along side edges of the panel substrates 90a.

[0370] In the above description, an example where double scribe lines are individually formed has been explained. However, the present invention is not limited to such a method. As long as the double scribe lines are formed along the side edges of the panels 90a, any method may be used. For example, double scribe lines may be formed on the side edges of the panel substrates 90a by using one scribe line.

[0371] Figure 63 is a plan view for illustrating a scribe pattern for cutting panel substrates 90a out of the bonded mother substrate 90 by using double scribe lines of the main scribe lines MS and the supplementary scribe lines SS. In this example, the mother substrates 91 and 92 of the bonded mother substrate 90 are cut along first to eighth lines to be cut D1 through D8 in this order to become four panel substrates 90a arranged in two rows and two columns.

[0372] The first line to be cut D1 corresponds to side edges of two panel substrates 90a in a first row along a row direction (horizontal direction), and is spaced apart from a side edge of the bonded mother substrate 90 along the row direction by a predetermined space. The second line to be cut D2 corresponds to side edges of the two panel substrates 90a in the first row, which are close to the panel substrate 90a in a second row. The third line to be cut D3 corresponds to side edges of two panel substrates 90a in the second row which are close to the panel substrates 90a in the first row, and is spaced apart from the second line to be cut D2 by 2 to 4 mm. The fourth line to be cut D4 corresponds to side edges of the two panel substrates 90a in the second row in a row direction (horizontal direction), and is spaced apart from the other side edges of the bonded mother substrate 90 along the row direction by a predetermined space.

[0373] The fifth line to be cut D5 corresponds to side edges of two panel substrates 90a in a first column along the column direction (vertical direction), and is spaced apart from one side edge of the bonded mother substrate 90 along the column direction. The sixth line to be cut D6 corresponds to the side edges of the two panel substrates 90a in the first column, which are close to panel substrates 90a in a second column. The line to be cut D7 corresponds to side edges of the two panel substrates 90a in the second column, which are close to the panel substrates 90a in the first column, and is spaced apart from the sixth line to be cut D6 by 2 to 4 mm. The line to be cut D8 corresponds to the side edges of the two panel substrates 90a in the second column along the column direction (vertical direction), and is spaced

apart from the other side edges of the bonded mother substrate 90 along the column direction by a predetermined space.

[0374] For cutting such a bonded mother substrate 90, first, the cutter wheels 162a are pressed and rotated along, for example, the first to fourth lines to be cut D1 to D4 in this order. Thus, first to fourth main scribe lines MS13 to MS16 are formed by vertical cracks having depths of 90% or more of the thicknesses of the mother substrates 91 and 92 from the surface of the upper and lower mother substrates 91 and 92 of the bonded mother substrate 90.

[0375] In this state, the cutter wheels 162a are pressed and rotated along the fifth line to be cut D5. Thus, fifth main scribe line MS17 is formed along the fifth line to be cut D5.

[0376] Thereafter, sixth to eighth main scribe lines MS18 to MS20 are formed along the sixth through eighth lines to be cut D6 to D8 in this order by pressing and rotating the cutter wheels 162a along the sixth through eighth lines to be cut D6 to D8 in turn in a similar manner.

[0377] After the first through eighth main scribe lines MS13 to MS20 are formed as such, first supplementary scribe line SS13 is formed along the first main scribe line MS13 by pressing and rotating the cutter wheels 162a in a side edge portion of the bonded mother substrate 90, which is on opposite side of the panel substrates 90a with respect to the first main scribe line MS13, with a space of about 0.5 to 1.0 mm from the first main scribe line MS13. Thus, vertical cracks on the first main scribe line MS13 extend toward the bonded surface of the mother substrates 91 and 92 of the bonded mother substrate 90 and reach the bonded surface of the mother substrates 91 and 92. Such a phenomena occurs across entirety of the first main scribe line MS13, and the bonded mother substrate 90 is cut along the first main scribe line MS13.

[0378] Next, a second supplementary scribe line SS14 is formed along the second main scribe line MS14 by the cutter wheels 162a in an area opposite to the panel substrates 90a with respect to the second main scribe line MS14, with a space of about 0.5 to 1.0 mm from the second main scribe line MS14. Thus, vertical cracks on the second main scribe line MS14 extend toward the bonded surface of the mother substrates 91 and 92 of the bonded mother substrate 90 from the surfaces of the mother substrates 91 and 92 of the bonded mother substrate 90, and the vertical cracks reach the bonded surface of the mother substrates 91 and 92 across the entirety of the second main scribe line MS14. In this way, the bonded mother substrate 90 is cut along the second main scribe line MS14.

[0379] Along the third main scribe line MS15 and the fourth main scribe line MS16, third supplementary scribe line SS15 and a fourth supplementary scribe line SS16 are respectively formed on the side opposite to the panel substrates 90a. Thus, the bonded mother substrate 90 is sequentially cut along the third main scribe

line MS15 and the fourth main scribe line MS16.

[0380] Thereafter, along the fifth to eighth main scribe lines MS17 to MS20, fifth to eighth supplementary scribe lines SS17 to SS20 are formed on the side opposite to the panel substrates 90a respectively between the first main scribe line MS13 and the second main scribe line MS14, and between the third main scribe line MS15 and the fourth main scribe line MS16. Thus, the bonded mother substrate 90 are cut along the fifth to eighth main scribe lines MS17 to MS20 and unnecessary portions are removed. As a result, four panel displays 90a can be obtained.

[0381] In this example, the first to eighth main scribe lines MS13 to MS20 are formed between end surfaces of the bonded mother substrate 90, more specifically, formed across the entirety of the lines to be cut D1 to D8 formed across one end surface of the bonded mother substrate 90b to the opposing other end surface. Further, the first to eighth supplementary scribe lines SS13 to SS20 are respectively formed across the end surface or one out surface which has been cut to the opposing other end surface or the other cut surface.

[0382] The present invention is not limited to the method in which the first to eighth main scribe lines MS13 to MS20 are formed across the entirety of the lines to be cut D1 to D8 formed between the end surfaces of the bonded mother substrate 90, the first to fourth supplementary scribe lines SS13 to SS16 across the one end surface of the bonded mother substrate 90 and the opposing other end surface, and the fifth to the eighth supplementary scribe lines SS17 to the SS20 are formed across one cut surface of the bonded mother substrate 90 to the opposing other cut surface. As shown in Figure 64, positions spaced apart from the one end surface of the mother glass substrate 10 by about 0.2 to 0.5 mm may be the start positions of the first to eighth main scribe lines MS13 to MS20, and similarly, positions in front of the other end surfaces by about 0.2 to 0.5 mm may be end portions of the first to eighth main scribe lines MS13 to MS20.

[0383] In this example, when the cutter wheels 162a are pressed and rotated on the mother substrates 91 and 92 of the bonded mother substrate 90 to perform scribing for forming the first to eighth main scribe lines MS13 to MS20, vertical cracks extend in back and front directions of the scribing direction with respect to the scribing start positions. Thus, the first to eighth main scribe lines MS13 to MS20 to be formed reach one end surface of the mother substrates 91 and 92 of the bonded mother substrate 90.

[0384] Similarly, even though the scribing end positions of the first to eighth main scribe lines MS13 to MS20 are in front of the other end surface of the mother substrates 91 and 92 of the bonded mother substrate 90, since the vertical cracks in the mother substrates 91 and 92 extend in the scribing direction, the first to eighth main scribe lines MS13 to MS20 to be formed reach the other end surface of the mother substrates 91 and 92.

[0385] This shows that it is not necessary to form first to eighth supplementary scribe lines SS13 to SS20 across one end surface or one out surface which has been out of the mother substrates 90 and 91 to the opposing other end surface or the opposing other out surface. As shown in Figure 64, positions appropriately spaced apart from one end surface or the one out surface which has been cut of the mother substrates 91 and 92 of the bonded mother substrate 90 by 0.2 to 0.5 mm may be start positions of the first to eighth supplementary scribe lines SS13 to SS20. Similarly, positions in front of the other end surface or cut surface by about 0.2 to 0.5 mm may be end positions of the first to eighth supplementary scribe lines SS13 to SS20.

[0386] Furthermore, one of the first to eighth main scribe lines MS13 to MS20 and the first to eighth supplementary scribe lines SS13 to SS20 may be formed across the one end surface or one cut surface which has been cut of the mother substrates 91 and 92 of the bonded mother substrate to the other end surface or the other cut surface of the mother substrates 91 and 92, and the other of the first to eighth main scribe lines MS13 to MS20 and the first to eighth supplementary scribe lines SS13 to SS20 may be formed across the position appropriately space apart from the one end surface or one cut surface which has been out of the mother substrates 91 and 92 of the bonded mother substrate 90 to positions in front of the other end surface or the other cut surface of the mother substrates 91 and 92.

[0387] Figure 65 is a plan view for illustrating another scribe patter for outting the panel substrates 90a out of the bonded mother substrate 90. In this scribing method, first and second main scribe lines MS13 and MS14 are formed by the cutter wheels 162a, along first and second lines to be out D1 and D2 on the bonded mother substrate 90 along the horizontal direction are respectively formed by vertical cracks which extend to 90% or more of the thicknesses of the mother substrates 91 and 92 from the surfaces of the mother substrates 91 and 92 of the bonded mother substrate 90. Thereafter, in the area between the first and second main scribe lines MS13 and MS14, fifth main scribe line MS17 along the fifth line to be cut D5 along the vertical direction is formed by the cutter wheels 162a, and fifth supplementary scribe lines SS17 is formed on the side opposite to the panel substrates 90a being spaced apart from the fifth main scribe line MS17 by about 0.5 to 1.0 mm.

[0388] In this example, the fifth main scribe line MS17 and the fifth supplementary scribe line SS17 respectively cross the first and second main scribe lines MS13 and MS14. The fifth main scribe line MS17 runs over the second main scribe line MS14 and then is inverted by 180 degrees to form the fifth supplementary scribe line SS17 so that the fifth main scribe line MS17 and the fifth supplementary scribe line SS17 are formed continuously with one scribing.

[0389] Thereafter, similarly, in the area between the first and second main scribe lines MS13 and MS14, sixth

scribe line MS18 is formed by the cutter wheels 162a along sixth line to be out D8, and then is inverted to form sixth supplementary scribe line SS18 on the side opposite to the panel substrates 90a. Further, seventh main scribe line MS19 and seventh supplementary scribe lines SS19, and eighth main scribe line MS20 and eighth supplementary scribe lines SS20 are formed similarly in turn. Since the fifth to eighth main scribe lines MS17 to MS20 and the fifth to eighth supplementary scribe lines SS17 to SS20 pass across the first and second main scribe lines MS13 and MS14, it is ensured that vertical cracks forming the first and second main scribe lines MS13 and MS14 reach the bonded surface of the mother substrates 91 and 92 of the bonded mother substrate 90 across the entirety of the first and second main scribe lines MS13 and MS14, and a pair of the panel substrates 90a are obtained.

[0390] Before the substrate is cut into the pair of the panel substrates 90a at this point, an area of the bonded mother substrate 90 which has not been out is referred to a second substrate portion 90c.

[0391] Next, as shown in portion (b) of Figure 65, on the second substrate portion 90c cut by the second main scribe line MS14, the cutter wheels 162a are pressed and rotated along the lines to be cut D3 and D4 on the bonded mother substrate 90 along the vertical direction, and third and fourth main scribe lines MS15 and MS16 are formed by vertical cracks extended to 90% or more of the thicknesses of the mother substrates 91 and 92 from the surfaces of the mother substrates 91 and 92 of the bonded mother substrate 90. Thereafter, in the area between the third and fourth main scribe lines MS15 and MS16, ninth main scribe line MS21 and fifth supplementary scribe line SS21 along ninth line to be cut D9 along the vertical direction, tenth main scribe line MS22 and tenth supplementary scribe line SS22 along the tenth line to be cut D10, eleventh main scribe line MS23 and eleventh supplementary scribe line SS23 along the eleventh line to be cut D11, and twelfth main scribe line MS24 and twelfth supplementary scribe line SS24 along the twelfth line to be cut D12 are sequentially formed outside the panel substrates 90a so as to cross the third and fourth main scribe lines MS15 and MS16. Thus, the second substrate portion 90c is cut, and a pair of panel substrates 90a are cut.

[0392] It is not necessary that the fifth to twelfth supplementary scribe lines SS21 to SS24 cross the first and third main scribe lines MS13 and MS15. For example, as shown in Figure 66, positions in front of the first and third main scribe lines MS13 and MS15 by about 0.2 to 0.5 mm may be end portions of the fifth to twelfth supplementary scribe lines SS17 to SS24. In such a case, vertical cracks forming the fifth to twelfth supplementary scribe lines SS17 to SS24 also extend in the scribing direction. The fifth to twelfth main scribe lines MS17 to MS24 are cut across the entirety of the main scribe lines MS17 to MS24.

[0393] In the case where the scribe lines are formed

to cross each other for cutting the substrate as described above, as shown in Figure 67, first, the main scribe lines MS13 to MS16 are formed along the first to fourth lines to be cut D1 to D4, and then, the fifth main scribe line MS17 and the fifth supplementary scribe line SS17, the sixth main scribe line MS18 and the sixth supplementary scribe line SS18, the seventh main scribe line MS19 and the seventh supplementary scribe line SS19, and the eighth main scribe line MS20 and the eighth supplementary scribe line SS20 are formed to respectively cross the first main scribe line MS13 and fourth main scribe line MS16 such that the main scribe lines and the supplementary scribe lines are formed continuously with one scribing by inverting the line by 180 degrees after they cross over the fourth main scribe line MS16.

[0394] Figure 68 is a schematic plan view for illustrating a scribing pattern for cutting the display panels 90a out of the bonded mother substrate 90 by using double scribe lines of main scribe lines MS and supplementary scribe lines SS. First, with the scribing method shown in Figure 57, four scribe lines along lines to be scribed S1 to S4 with respect to the panel substrates 90a (hereinafter, four linear scribe lines across the entire circumferences of the panel substrates 90a will be referred to as main scribe line DS1) are formed. Then, outside the panel substrates 90a with respect to the main scribe line DS1, four linear sub-scribe line DS2 in parallel to the main scribe line DS1 spaced apart from the main scribe line DS1 by about 0.5 to 1 mm.

[0395] As described above, when the sub-scribe line DS2 is formed with a space of about 0.5 to 1 mm apart from the main scribe line DS1, a stress is applied to a horizontal direction which is orthogonal to the formation direction of the scribe lines on a surface of the bonded mother substrate 90 when the sub-scribe line S2 is formed. Thus, a compression force is applied to surface portions of the vertical cracks which form the main scribe line DS1 which has been already formed. When the compression force is applied to the surface portion of the vertical cracks forming the main scribe line DS1 as such, a reaction force is applied in a direction to widen the width of the vertical cracks forming the main scribe line DS1. In this way, the vertical cracks extend in the thickness direction of the bonded mother substrate 90 and the vertical cracks reach the bonded surface of the mother substrates 91 and 92 of the bonded mother substrate.

[0396] In this example, as shown in Figure 69, sub-scribe line DS2 may be formed continuously after the main scribe line DS1 without separating the cutter wheels 162a from the front and back surfaces of the bonded mother substrate 90 after the main scribe line DS1 is formed.

[0397] Furthermore, as shown in Figure 58, when scribe lines are first formed along lines to be scribed S1 and S2, and then scribe lines are continuously formed along lines to be scribed S4 and S2, as shown in Figure

70, the sub-scribe line DS2 may be formed after the main scribe line DS1 is formed.

[0398] Further, as a method for cutting the substrate, a method in which double scribe lines are formed on the bonded mother substrates where the glass substrates, which is a type of brittle material substrate, are bonded as mother substrates has been described. However, the present invention is not limited to this. When the substrate is a metal substrate such as steel sheet, wood plate, a plastic substrate, and a brittle material substrate such as ceramics substrate, glass substrate, semiconductor substrate or the like, a method for cutting the substrate by using, for example, laser light, a dicing saw, a cutting blade, a diamond cutter, or the like may be used.

[0399] Furthermore, the substrates include, besides mother substrate, a bonded substrate formed by bonding the same type of mother substrates, a bonded mother substrate formed by bonding different types of mother substrates, and a substrate formed by laminating mother substrates.

#### <Embodiment 3>

[0400] Figure 71 is a schematic perspective view showing an example of another embodiment of the substrate cutting system according to the present invention in whole. Figure 72 is a plan view of the substrate cutting system. Figure 73 is a side view of the substrate cutting system. In the present invention, "substrates" include mother substrates cut into a plurality of substrates and also include single plates of metal substrates such as steel sheets, wood plates, plastic substrates and ceramic substrate, semiconductor substrates, and brittle material substrates such as glass substrates. Furthermore, the "substrates" are not limited to such single plates, but also includes bonded substrates formed by bonding pairs of substrates and laminated substrates formed by laminating pairs of substrates.

[0401] The substrate cutting system according to the present invention cut the bonded mother substrate 90 formed by bonding a pair of mother glass substrates to each other into a plurality of panel substrates (display panel bonded substrates) for producing, for example, panel substrates (display panel bonded substrates) of the liquid crystal display apparatus which are bonded to each other.

[0402] A substrate cutting system 300 according to Embodiment 3 includes a positioning unit portion 320, a scribe unit portion 340, a lift conveyer portion 360, a steam break unit portion 380, a substrate carrying unit portion 400, a panel inversion unit portion 420, and a panel terminal separation portion 440.

[0403] Regarding the substrate cutting system 300 according Embodiment 3, a side on which positioning unit portion 320 is located is referred to as a substrate carry-in side and a side on which the panel terminal separation portion 440 is located is referred to as a substrate carry-out side in the following description. In the



substrate cutting system **300**, a direction in which the substrates are carried (substrate flowing direction) is +Y direction from the substrate carry-in side to the substrate carry-out side. The direction in which the substrates are carried is a direction orthogonal to a scribing device guide body **342** of the scribe unit portion **340** in a horizontal fashion and the scribing device guide body **342** is provided along X direction.

[0404] The following description will be made with reference to an example in which the bonded mother substrate **90** is cut as a substrate. First, the bonded mother substrate **90** is carried into the positioning unit portion **320** by a carrying device (not shown) of the former step. Then, the positioning unit portion **320** places the bonded mother substrate **90** on a first substrate supporting portion **341A** of the scribe unit portion **340** and positions the bonded mother substrate **90** on the first substrate supporting portion **341A**.

[0405] As shown in Figure **74**, the positioning unit portion **320** includes: a guide bar **326** elongated along one side edge of a mounting structure **330**, which is provided along Y direction on the mounting structure **330** via pillars **328**; and a guide bar **327** elongated along the other side edge of the mounting structure **330** in parallel with the guide bar **326**. The positioning unit portion **320** further includes a guide bar **325** elongated along X direction provided on the mounting structure **330** via pillars **328** on the substrate carry-in side of the mounting structure **330** between the guide bar **326** and the guide bar **327**.

[0406] The guide bar **325** and the guide bar **326** respectively include a plurality of reference rollers **323** which will be criteria for positioning the bonded mother substrate **90**. The guide bar **327** includes a plurality of pushers **324** for pushing the bonded mother substrate **90** toward the reference rollers provided on the guide bar **326** for positioning the bonded mother substrate **90**.

[0407] Above the mounting structure **330**, a plurality of suction pad bases **321** are provided between the guide bar **326** and the guide bar **327** with predetermined spaces therebetween. The suction pad bases **321** are held by a moving device **322** provided on an upper surface of the mounting structure **330** on the guide bar **326** side and a moving device **322** provided on an upper surface of the mounting structure **330** on the guide bar **327** side.

[0408] The suction pad bases **321** include suction bases **321a**. Plurality of the suction bases **321a** receive the bonded mother substrate **90** from the carrying device (not shown) of the former step, and suck the bonded mother substrate **90** by sucking devices which are not shown for adsorption.

[0409] The first substrate supporting portion **341A** of the scribe unit portion **340** moves toward the substrate carry-in side and waits at the position of the positioning unit portion **320**. The plurality of suction pad bases **321** holding the bonded mother substrate **90** sink into the waiting first substrate supporting portion **341A** by mov-

ing devices **322**. Thus, the bonded mother substrate **90** is placed on the first substrate supporting portion **341A**.

[0410] The scribe unit portion **340** has a structure similar to that in the substrate cutting system **100** according to Embodiment 2 except for it does not include the substrate carry-out device **180** and the steam unit portion **260**. Other mechanical structure is similar to that of Embodiment 1.

[0411] The scribing device guide body **342** of the scribe unit portion **340** is coupled with the first substrate supporting portion **341A** and a second substrate supporting portion **341B**, and, as the scribing device guide body **342** moves in Y direction, the first substrate supporting portion **341A** and the second substrate supporting portion **341B** move in the same direction as the scribing device guide body **342** at the same time.

[0412] The first substrate supporting portion **341A** and the second substrate supporting portion **341B** respectively include a plurality of first substrate supporting units **344A** and a plurality of second substrate supporting units **344B** which are movable in the same direction as the moving direction of the scribing device guide body **342**. The first substrate supporting units **344A** and the second substrate supporting units **344B** are respectively formed linearly along a direction parallel to a frame **343A** and a frame **343B** (Y direction).

[0413] One of the first substrate supporting units **344A** provided in the first substrate supporting portion **341A** is similar to the first substrate supporting units **121A** shown in Figure **43** in Embodiment 2. Timing belts provided in the first substrate supporting units **344A** are rotated when clutch provided in the first substrate supporting portion **341A** is coupled with a driving axis.

[0414] A plurality of the first substrate supporting units **344A** are arranged with predetermined spaces therebetween, and move in Y direction along the frames **343A** and **343B** with the scribing device guide body **342**.

[0415] A mechanism for rotating the timing belts of the first substrate supporting units **344A** having such structures is similar to that shown in Figures **44** to **46** in Embodiment 2. The frames **111A** and **111B** in Figure **44** correspond to the frames **343A** and **343B** in Embodiment 3.

[0416] As shown in Figure **44**, clamp units including clutches for rotating timing belts by rotating driving timing pulleys of the plurality of first substrate supporting units **344A** provided in the first substrate supporting portion **341A** are provided on the sides of frames **343A** and **343B**.

[0417] As shown in Figure **73**, a pillar **345** on the frame **343A** side which supports the first substrate supporting units **344A** and a pillars **345** on the frame **343B** side are held by the guide bases **347**, and to the pillars **345** for supporting both ends of the scribing device guide body **342**, movers (not shown) of the linear motors are attached. Thus, by driving the linear motors, the scribing device guide body **342** is moved toward the substrate carry-in side, and a plurality of first substrate supporting



units **344A** of the first substrate supporting portion **341A** are moved toward the substrate carry-in side.

[0418] When the scribing device guide body **342** is moved, the pinion of the clutch unit on the frame **343A** side and the pinion of the clutch unit on the frame **343B** side, which are engaged with the racks attached as in Figure **45** along the frames **343A** and **343B**, are rotated.

[0419] For rotating the driving timing pulleys of the first substrate supporting units **344A** and moving the timing belts, clutches on both sides of the frames **343A** and **343B** may be coupled to the respective driving axes to which the rotation of the pinions is transmitted, or the clutch on one of the frames **343A** and **343B** may be coupled to the driving axes to which rotation of the pinions is transmitted.

[0420] The second substrate supporting portion **341B** includes a plurality of second substrate supporting units **344B** which are movable in the same direction as the moving direction of the scribing device guide body **342**. The second substrate supporting units **344B** have similar structures as those of the first substrate supporting units **344A**, and supported by the pillar **345** on the frame **343A** side and the pillar **345** on the frame **343B** side so as to be attached in an inverted direction with respect to Y direction to provide an arrangement symmetrical with respect to the scribing device guide body **342**. The respective pillars are supported by the guide bases **347**.

[0421] Since the movers (not shown) of the linear motors are attached to the guide bases **347** for holding the pillars **346** which support both ends of the scribing device guide body **342**, the scribing device guide body **342** is moved toward the substrate carry-in side by driving the linear motor, and a plurality of the second substrate supporting units **344B** of the second substrate supporting portion **341B** also move toward the substrate carry-in side.

[0422] On the frame **343A** side and the frame **343B** side of the second substrate supporting portion **341B**, clutch units similar to those in the first substrate supporting portion **341A** are provided. When the scribing device guide body **342** is moved, the pinion of the clutch unit on the frame **343A** side and the pinion of the clutch unit on the frame **343B** side, which are engaged with the racks attached along the frames **343A** and **343B**, are rotated.

[0423] For rotating the driving timing pulleys of the second substrate supporting units **344B** and moving the timing belts, clutches on both sides of the frames **343A** and **343B** may be coupled to the respective driving axes to which rotation of the pinions is transmitted, or the clutch on one of the frames **343A** and **343B** may be coupled to the driving axes to which rotation of the pinions is transmitted.

[0424] Furthermore, above the mounting structure **350**, the clamp device **351** for clamping the bonded mother substrate **90**, which is supported by the first substrate supporting portion **341A** and pushed against the positioning pins so as to be positioned, is provided. For

example, as shown in Figure **71**, the clamp device **351** includes a plurality of clamp devices **351** attached to the frame **343B** with predetermined spaces therebetween in a longitudinal direction so as to clamp a side edge of the bonded mother substrate **90** along the frame **343B**, and a plurality of clamp devices **351** arranged along the direction orthogonal to the frame **343B** with a predetermined spaces therebetween for clamping a side edge of the bonded mother substrate **90** on the substrate carry-in side.

[0425] The operation of each of the clamp devices **351** is as described with reference to Figures **49** and **50**, and thus, the description thereof is omitted.

[0426] Further, in the above-described the arrangement of the clamp device **351**, the clamp devices **351** for holding the bonded mother substrate **90** is provided on the substrate carry-in side in a direction orthogonal to the frame **343A** and the frame **343B**. However, even when the clamp device **351** is provided only on the frame **343B**, the bonded mother substrate **90** can be held without receiving damage.

[0427] The structure of the clamp devices **351** as described above is merely an example used in the substrate cutting system of the present invention, and the structures are not limited to such structures. The clamp device **150** and the clamp members **151** may have any kind of structures as long as they can grip or hold the side edges of the bonded mother substrate **90**. When the substrate size is small, the substrate can be held by clamping one position of the side edge of the substrate, and the substrate can be cut without causing a defect in the substrate.

[0428] As shown in Figure **40** of Embodiment **2**, the upper portion substrate cutting device **160** is attached to the upper guide rail **352** in the scribing device guide body **342**. The lower portion substrate cutting device **170** having the similar structure as the upper portion substrate cutting device **160** but inverted upside down as shown in Figure **41** of Embodiment **2** is attached to the lower guide rail **354**. The upper portion substrate cutting device **160** and the lower portion substrate cutting device **170** respectively slide along the upper guide rail **352** and the lower guide rail **353** by the linear motors.

[0429] For example, in the upper portion substrate cutting device **160** and the lower portion substrate cutting device **170**, a cutter wheel **162a** for scribing the upper glass substrate of the bonded mother substrate **90** similar to that shown in Figures **40** and **41** in Embodiment **2** is rotatably attached to a tip holder **162b**, and the tip holder **162b** is rotatably attached to a cutter head **162c** having an axis in a direction vertical to the front and back surfaces of the bonded mother substrate **90** held by the clamp devices **351**. The cutter head **162c** is movable along a direction vertical to the front and back surfaces of the bonded mother substrate by driving means which is not shown. The cutter wheel **162a** is appropriately loaded by energizing means which is not shown.

[0430] The cutter wheel **162a** held by the tip holder **162b** may have a blade edge protruded so as to have a center portion in a width direction of a shape of letter V with an obtuse angle and may have protrusions of a predetermined height formed on the blade edge with predetermined pitches in a circumferential direction as disclosed in Japanese Laid-Open Publication No. 9-188534.

[0431] The lower portion substrate cutting device **170** provided on the lower guide rail **353** has a similar structure as the upper portion substrate cutting device **160** but inversed upside down. A cutter wheel **162a** of the lower portion substrate cutting device **170** (see Figure 41) is arranged so as to oppose the cutter wheel **162a** of the upper portion substrate cutting device **160**.

[0432] The cutter wheel **162a** of the upper portion substrate cutting device **160** are pressed onto a surface of the bonded mother substrate **90** and rotated by the above-described energizing means and moving means of the cutter head **162c**. The cutter wheel **162a** of the lower portion substrate cutting device **170** is pressed onto a back surface of the bonded mother substrate **90** by the above-described energizing means and moving means of the cutter head **162c**. By moving the upper portion substrate cutting device **160** and the lower portion substrate cutting device **170** in the same direction at the same time, the bonded mother substrate **90** is cut.

[0433] It is preferable that the cutter wheel **162a** is rotatably supported by a cutter head **165** using a servo motor disclosed in WO 03/011777.

[0434] Figure 51 shows a side view of an exemplary cutter head **165** using a servo motor. Figure 52 is a front view of the main part of the cutter head **165**. A servo motor **165b** is held between a pair of side walls **165a** in an inverted state. In the lower part of the side walls **165a**, a holder maintaining assembly **165c** having a shape of letter L when viewed from side is rotatably provided via a spindle **165d**. On the front portion of the holder maintaining assembly **165c** (the right hand part in Figure 52), the tip holder **162b** for rotatably supporting the cutter wheel **162a** via an axis **165e**. Flat bevel gears **165f** are respectively attached to the rotation axis of the servo motor **165b** and the spindle **165d** so as to engage each other. With such a structure, by rotating the servo motor **165b** in normal or inverted direction, the holder maintaining assembly **165c** performs an elevating operation having the spindle **165d** as a fulcrum and the cutter wheel **162a** moves up and down. The cutter head **165** itself is included in the upper portion substrate cutting device **160** and/or lower portion substrate cutting device **170**.

[0435] Figure 53 is a front view showing another example of a cutter head using a servo motor. In this example, the rotation axis of the servo motor **165b** is directly connected to the holder maintaining assembly **165c**.

[0436] The cutter heads of Figures 51 and 53 moves the cutter wheel **162a** for positioning by rotating the ser-

vo motor by position control. Such a cutter head controls a rotation torque which acts to bring back the position of the cutter wheel **162a** to the position which has been previously set to the servo motor **165b** when the position is moved from the set position, and transmits a scribing pressure to a brittle material substrate during scribing operation in which the cutter head is moved in the horizontal direction to form scribe lines on the bonded mother substrate **90**. In other words, the servo motor **165b** controls the position of the cutter wheel **162a** in a vertical direction and also serves as energizing means for the cutter wheel **162a**.

[0437] By using the cutter head including the servo motor as described above, the rotation torque of the servo motor can be corrected while the bonded mother substrate **90** is being scribed instantly in accordance with the change in a scribing pressure due to a variance in resistance applied to the cutter wheel. Thus, stable scribing is performed and scribe lines with high quality can be formed.

[0438] A cutter head including a mechanism to periodically change the pressure to the bonded mother substrate **90** by a scribing cutter by vibrating the scribing cutter such as a diamond point cutter and/or cutter wheel for scribing the bonded mother substrate **90** may also effectively applied to the cutting of the mother substrate by the substrate cutting system of the present invention.

[0439] The structures of the upper portion substrate cutting device **160** and the lower portion substrate cutting device **170** are not limited to the above-described structures. The devices may have any kind of structures as long as they process the front and back surfaces of the substrate to cut the substrate.

[0440] For example, the upper portion substrate cutting device **160** and the lower portion substrate cutting device **170** may be a device for cutting the mother substrate by using laser light, a dicing saw, a cutting blade, a diamond cutter, or the like.

[0441] When the mother substrate is a metal substrate such as steel sheet, wood plate, a plastic substrate, and a brittle material substrate such as ceramics substrate, glass substrate, semiconductor substrate or the like, a scribing device for cutting the mother substrate by using, for example, laser light, a dicing saw, a cutting blade, a diamond cutter, or the like may be used.

[0442] Furthermore, the upper portion substrate cutting device **160** and the lower portion substrate cutting device **170** may further include cutting assistance means for assisting in the cutting of the substrate. The cutting assistance means may be, for example, means for pressing a roller or the like to the substrate, or means for warming (heating) the substrate by spraying compressed air to the substrate, irradiating the substrate with laser, or blowing hot air to the substrate.

[0443] In the above example, the upper portion substrate cutting device **160** and the lower portion substrate cutting device **170** have the same structure. However,

they may have different structures depending upon the cutting pattern of the substrate and cutting conditions for the substrate.

[0444] The lift conveyer portion 360 is a device for carrying the scribed bonded mother substrate 90 which is placed on the plurality of second substrate supporting units 344B of the second substrate supporting portion 241B to the steam break unit portion 380 after the bonded mother substrate 90 is scribed by the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 of the scribing device guide body 342 of the scribe unit portion 340, and then, clamping of the bonded mother substrate 90 by the clamp devices 351 is released.

[0445] Figure 75 is a plan view of the lift conveyer portion 360. Figure 76 is a side view of third substrate supporting units 361 which form the lift conveyer portion 360.

[0446] Each of the third substrate supporting units 361 has a support main body 361a elongated linearly along a direction parallel to the frames 343A and 343B (Y direction), and timing pulleys 361c and 361d for guiding a timing belt 361e are respectively attached to end portions of the support main body 361a. A driving timing pulley 361b is coupled to a rotation axis to which rotation of a rotation motor 367 is transmitted by a belt 368, and rotates the timing belt 361e.

[0447] A plurality of the third substrate supporting units 361 are arranged in the lift conveyer portion 360 with predetermined spaces therebetween. The plurality of the third substrate supporting units 361 are held to a holding frame 362 via pillars 365 such that a plurality of the second substrate supporting units 344B of the second substrate supporting portion 341B of the scribe unit portion 340 are inserted between the spaces.

[0448] A center portion of each of the frames 362a of the holding frames 362 on the frame 343A side and the frame 343B side includes a cylinder 366. The main body of the cylinder 366 is jointed to an upper surface of mounting structure 370, and a rod of the cylinder 366 is jointed to each of the frames 362a of the holding frames 362. On both sides of each of the frames 362a of the holding frames 362, guide shafts 364 are provided, and respectively inserted into linear guides 363 provided on the upper surface of the mounting structure 370.

[0449] The scribed bonded mother substrate 90, which is placed on the plurality of second substrate supporting units 344B of the second substrate supporting portion 241B after the bonded mother substrate 90 is scribed by the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 of the scribing device guide body 342 of the scribe unit portion 340, and then, clamping (holding) of the bonded mother substrate 90 by the clamp devices 351 is released, is placed on the plurality of the third substrate supporting units 361 and is moved to a predetermined position in upstream (+Z direction) along a vertical direction by driving the cylinders 366. Then, by rotating

the rotation motor 367 and moving the timing belt 361e, the bonded mother substrate 90 is moved to the steam break unit portion 380.

[0450] The steam break unit portion 380 has similar structure as the steam unit portion 260 shown in Figure 47 in Embodiment 2 except that it is fixed instead of moving along Y direction.

[0451] The steam break unit portion 380 includes an upper steam unit attachment bar 381 for attaching a plurality of steam units 384 for spraying steam to the upper mother substrate 91 of the bonded mother substrate 90 and a lower steam unit attachment bar 382 for attaching a plurality of steam units 384 for spraying steam on the lower mother substrate 92 of the bonded mother substrate 90 attached to pillars 383 along X direction parallel to the scribing device guide body 342.

[0452] The pillars 383 of the scribe unit portion 340 on the frame 343A side and the frame 343B side are respectively jointed to the upper surface of the mounting structure 370. On the substrate carry-out side of the steam break unit portion 380, a belt conveyer 385 for supporting and carrying the completely out bonded mother substrate 90 after steam is sprayed on the front and back surfaces of the bonded mother substrate 90 from the steam units 384, which is, for example, a rotating belt having a sheet shape, is provided.

[0453] The rotation moving speed of the belt conveyer 385 provided on the substrate carry-out side of the steam break unit portion 380 is set to be substantially the same as the rotation moving speed of the timing belt 361e of the plurality of the third substrate supporting units 361 of the lift conveyer portion 360, and they move in synchronization.

[0454] The steam break unit portion 380 has similar structure as the steam unit portion 260 shown in Figure 47 in Embodiment 2. A plurality of steam units 384 are attached to the upper steam unit attachment bar 381 and a plurality of steam units 384 are attached to the lower steam unit attachment bar 382 with a gap GA spaced apart from the upper plurality of steam units 384. The gap GA is adjusted so as to allow the bonded mother substrate 90 to pass through the gap GA.

[0455] The structures of the steam units 384 are similar as those of the steam units 261 shown in Figure 48 in Embodiment 2. Each of the steam units 384 is mostly made of an aluminum material, and a plurality of heaters 261a are embedded in a vertical direction. When an opening/closing valve (not shown) which can be opened or closed automatically is opened, water flows into the steam unit 261 from a water supply port 261b and heated by the heaters 261a. The supplied water is vaporized and becomes steam. The steam is blown to the surface of the mother substrate through a conducting hole 261c and from a spray nozzle 261d.

[0456] Further, on the carry-out side of the upper steam unit attachment bar 381, an air knife 386 for removing water which remains on the surface of the mother substrate 90 after the steam is blown to the upper

surface of the mother substrate 90 is attached.

[0457] The lower steam unit attachment bar 382 also includes the steam units 384 and the air knife 385 similar to those attached to the upper steam unit attachment bar 382.

[0458] The scribed bonded mother substrate 90 which is placed on the plurality of second substrate supporting units is placed on the third substrate supporting units 361 and is moved to a predetermined position above along the vertical direction (Y direction). Then, the belt conveyer 385 provided on the steam break unit portion 380 on the substrate carry-out side is moved at the substantially same rotation moving speed as that of the timing belts 361e of the plurality of the third substrate supporting units 361. Thus, the scribed bonded mother substrate 90 passes through the steam break unit portion 380, is out into panel substrates 90a, and is to be supported by the belt conveyer 385.

[0459] The substrate carrying unit portion 400 is a device for taking up a moving or stopped panel substrate 90a which has passed through the steam break unit portion 380, has been cut into panel substrates 90a, and is to be supported by the belt conveyer 385, and placing on a panel holding portion 422 of an inverted carrying robot 421 of panel inversion unit portion 420.

[0460] Above the mounting structure 370 and mounting structure 430 of the substrate carrying unit portion, a substrate carry-out device guide 401 for allowing the carrying robot 410 for carrying out the panel substrates cut out of the bonded mother substrate 90 to move in X direction parallel to the steam break unit portion 380 and the scribing device guide body 342, which is a direction orthogonal to Y direction, that is a substrate flowing direction. The substrate carrying unit portion 400 has both end portions of the substrate carry-out device guide 401 slide via supporting members 404 by linear motors along guides 403 respectively provided on the upper surfaces of the mounting structure 370 and 430 via pillars 402 on the frame 343A side and the frame 343B side. In this case, the linear motors are formed by inserting movers (not shown) of the linear motors respectively attached to the supporting members 404 into the stators respectively provided on the guides 403.

[0461] The carrying robot 410 includes an adsorption portion (not shown) for suction-adsorbing panel substrates 90a out of the bonded mother substrate 90. The carrying robot 410 is slid to the substrate carry-out side with the panel substrate 90a adsorbed by the adsorption portion. Thus, the panel substrate 90a is placed on the panel holding portion 422 of the inverted carrying robot 421 of the panel inversion unit portion 420.

[0462] Since the structure of the carrying robot 410 of the substrate carrying unit portion 400 is similar to that of the carrying robot 240 shown in Figure 42 in Embodiment 2, the detailed description thereof is omitted. The carrying robot 410 is attached to the substrate carry-out device guide 401, and is made movable in a direction along the substrate carry-out device guide 401 (X direc-

tion) by a moving mechanism formed by combining driving means of a linear motor or servo motor and a linear guide.

[0463] For carrying the panel substrates 90a cut out of the bonded mother substrate 90 by the carrying robot 410, the cut panel substrates 90a are held by adsorption pads of the carrying robot 410 by sucking with a sucking mechanism which is not shown, and the entire carrying robot 410 is temporarily lifted by a moving mechanism (not shown). Then, the substrates are carried to the inverted carrying robot 421 of the panel inversion unit portion 420 in next step, and the entire carrying robot 410 is moved down again by the moving mechanism (not shown) and placed in a previously decided state in a predetermined position of the panel holding portion 422 of the inverted carrying robot 421 of the panel inversion unit portion 420 in the next step.

[0464] The panel inversion unit portion 420 includes the inverted carrying robot 421. The panel inversion unit portion 420 receives the panel substrates 90a from the carrying robot 410 of the substrate carrying unit portion 400 and inverts the panel substrates 90a upside down to place on a separation table 441 on the panel terminal separation portion 440.

[0465] The panel holding portion 422 of the inverted carrying robot 421 includes, for example, a plurality of adsorption pads, and is held so as to be rotatable with respect to a robot main body 423 of the inverted carrying robot 421.

[0466] Regarding the panel substrates 90a placed on the separation table 441 of the panel terminal separation portion 440 by the inverted carrying robot 421, unnecessary portions 99 of the panel substrates 90a are separated from the panel substrates 90a by an unnecessary portion removal mechanism 442 provided near the side edge portions of the separation table 441 as shown in Figure 77, for example, by an insertion robot (not shown).

[0467] As shown in Figure 77, the unnecessary portion removal mechanism 442 is formed by arranging a plurality of removal roller portions 442a respectively having a pair of the rollers 442b opposing each other along a side edge of the separation table 441 with a predetermined pitch. The opposing rollers 442b provided in the provided in the removal roller portions 442a are energized in directions to approach each other. The unnecessary portion 99 of the upper substrate of the panel substrate 90a and a lower side edge of the panel substrate 90a are inserted between the rollers 442b by the insertion robot (not shown). The rollers 442b rotate only in one direction of the insertion direction into the rollers 442b of the panel substrate 90a. A pair of opposing rollers 442b are respectively set to rotate in the reversed direction.

[0468] The substrate cutting system of Embodiment 3 having such a structure will be explained with reference mainly to an example in which a bonded substrate formed by bonding large-scale glass plates is out.

[0469] For cutting the bonded mother substrate 90 formed by bonding large-scale glass substrates to each other into a plurality of panel substrates 90a (see Figure 55), the bonded mother substrate 90 is received and adsorbed by a plurality of suction bases 321a provided on a plurality of suction pad bases 321 of the positioning unit portion 320 of Embodiment 3 from the carrying device (not shown) of the former step.

[0470] The four clutches of the first substrate supporting portion 341A and the second substrate supporting portion 341B of the scribe unit portion 340 release connection with driving axes such that timing pulleys for rotating the timing belts of the first substrate supporting units 344A and the second substrate supporting units 344B (such an operation is referred to as switching off a clutch in the following description).

[0471] As shown in Figure 78, the first substrate supporting portion 341A moves toward the substrate carry-in side with the scribing device guide body 342 and the second substrate supporting portion 341B with the clutches switched off, and waits at the positioning unit portion 320.

[0472] Then, as shown in Figure 79, a plurality of the suction pad bases 321 holding the bonded mother substrate 90 sinks into the first substrate supporting portion 341A in awaiting state by a moving device 322. Then, adsorption state of the bonded mother substrate by the plurality of adsorption pads is released to place the bonded mother substrate 90 on the first substrate supporting portion 341A.

[0473] As described above, with the bonded mother substrate 90 being placed on the first substrate supporting portion 341A, and with the four clutches of the first substrate supporting portion 341A and the second substrate supporting portion 341B being switched off, the first substrate supporting portion 341A slightly moves toward the substrate carry-in side together with the scribing device guide body 342 and the second substrate supporting portion 341B, and abut the side edge of the bonded mother substrate 90 on the substrate carry-in side against a plurality of the reference rollers 323 provided in the guide bar 325 of the positioning unit portion 320.

[0474] After the side edge of the bonded mother substrate 90 on the substrate carry-in side abuts against a plurality of the reference rollers 323 provided in the guide bar 325 of the positioning unit portion 320, the pushers 324 of the guide bar 327 of the positioning unit portion 320 pushes the bonded mother substrate 90 toward the reference rollers 323 of the guide bar 326. The side edge of the bonded mother substrate 90 on the guide bar 326 side abuts the reference rollers 323 provided in the guide bar 326. Thus, the bonded mother substrate 90 is positioned in the first substrate supporting portion 341A of the scribe unit portion 340.

[0475] Then, with the pushing of the bonded mother substrate 90 toward the reference rollers 323 of the guide bar 326 by the pushers 324 of the guide bar 327

of the positioning unit portion 320 being released and the four clutches of the first substrate supporting portion 341A and the second substrate supporting portion 341B being switched off, the first substrate supporting portion 341A moves together with the scribing device guide body 342 and the second substrate supporting portion 341B. After the bonded mother substrate 90 is moved to the position to be held by the clamp devices 351, the side edge portions of the bonded mother substrate 90 are clamped by the clamp devices 351.

[0476] When the side edges of the bonded mother substrate 90 which are orthogonal to each other are respectively clamped by the clamp device 351, the clamp members 151 clamping the side edges of the bonded mother substrate 90 sink approximately at the same time due to the weight of the bonded mother substrate itself. Thus, the bonded mother substrate 90 is supported supplementarily by the timing belts of all the first substrate supporting units 344A.

[0477] As shown in Figure 80, in such a state where the side edges of the bonded mother substrate 90 which are orthogonal to each other are respectively clamped by the clamp device 351 and supported by the first substrate supporting units 344A, the four clutches of the first substrate supporting portion 341A and the second substrate supporting portion 341B of the scribe unit portion 340 are coupled to the driving axes such that timing pulleys for rotating the timing belts of the first substrate supporting units 344A and the second substrate supporting units 344B rotate (such an operation will be referred to switching on a clutch in the following description).

[0478] After the clutches of the four clutch units of the first substrate supporting portion 341A and the second substrate supporting portion 341B are switched on, the scribing device guide body 342 slides toward the substrate carry-in side so as to be at a predetermined position on a side edge of the bonded mother substrate 90 clamped by the clamp devices 351 in a horizontal fashion on the substrate carry-out side. The first optical device and the second optical device provided on the scribing device guide body 342 move along the guide body 342 from waiting positions. Thus, the images of the first alignment mark and the second alignment mark provided on the bonded mother substrate 90 are taken.

[0479] Since the scribing device guide body 342 slides, the first substrate supporting portion 341A slides toward the substrate carry-in side, and second substrate supporting portion 341B slides toward the substrate carry-in side. The timing belts of the first substrate supporting units 344A of the first substrate supporting portion 341A and the timing belts of the second substrate supporting units 344B of the second substrate supporting portion 341B moves the bonded mother substrate 90 in a direction opposite to the moving direction of the scribing device guide body 342 at the rate same as the moving speed of the scribing device guide body 342. Thus, the bonded mother substrate 90 does not move, and while being held by the clamp devices 351, the bonded



mother substrate 90 is supported without being in sliding contact with the timing belts of the first substrate supporting units 344A of the first substrate supporting portion 341A and the timing belts of the second substrate supporting units 344B of the second substrate supporting portion 341B.

[0480] Next, based on the results of taking the images of the first alignment mark and the second alignment mark, angle of the bonded mother substrate 90 supported by the clamp devices 351 in a horizontal fashion in a direction along the scribing device guide body 342, cutting start position and cutting end position by a calculation using an operation process device which is not shown. Based on the calculated results, the scribing device guide body 342 is moved with the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 to cut the bonded mother substrate 90 (Such an operation may be referred to as scribing or cutting by linear interpolation).

[0481] In this example, the cutter wheels 162a respectively opposing the front surface and the back surface of the bonded mother substrate 90 are pressed on to the front back surfaces and rotated. Thus, scribe lines 95 are formed on the front surface and the back surface of the bonded mother substrate 90.

[0482] Figure 81 is a diagram showing the second substrate supporting portion 341B supporting the bonded mother substrate when the scribe lines 95 are formed in the side edge portions of four panel substrates 90a for cutting four panel substrates out of the bonded mother substrate 90 by pressing and rotating the cutter wheel 162a of the upper portion substrate cutting device 160 and the cutter wheel 162a of the lower portion substrate cutting device 170.

[0483] As shown in Figure 81, from the bonded mother substrate 90, for example, two panel substrates 90a in a column direction along the upper guide rail 352 and the lower guide rail 353 are cut out for two columns. For cutting four display panels 90a out of the bonded mother substrate 90, the cutter wheel 162a of the upper portion substrate cutting device 160 and the cutter wheel 162a of the lower portion substrate cutting device 170 are respectively pressed and rotated along the side edges of the display panels 90a.

[0484] In this example, the cutter wheel 162a of the upper portion substrate cutting device 160 and the cutter wheel 162a of the lower portion substrate cutting device 170 generate vertical cracks in the portions of the glass substrates where the cutter wheels 162a rotated, and a scribe line 95 is formed. Since protrusions are formed in a predetermined pitch in circumferential direction of the blade edges of the cutter wheels 162a, vertical cracks having the length of about 90% of the thickness of the glass substrate in the thickness direction are formed in the glass substrates.

[0485] Further, a scribing method using a cutter head including a mechanism for periodically changing a pressure to the bonded mother substrate 90 by a scribe cut-

ter by vibrating the scribe cutter such as a diamond point cutter, cutter wheel or the like for scribing the bonded mother substrate 90 may be effectively applied to the cutting of the bonded mother substrate 90 by the substrate cutting system of the present invention.

[0486] When the scribing process on the front and back surfaces of the bonded mother substrate 90 is finished and the bonded mother substrate 90 is in a state as shown in Figure 81, clamping (holding) of the bonded mother substrate 90 by the clamp devices 351 is released, and the clutches of the four clutch units of the second substrate supporting portion 241B are switched off while the bonded mother substrate 90 is being placed on the second substrate supporting portion 241B.

[0487] Thereafter, as shown in Figure 82, the second substrate supporting portion 341B carrying the scribed bonded mother substrate 90 moves toward the substrate carry-out side with the first substrate supporting portion 341A and the scribing device guide body 342, and moves to the position to be inserted into the spaces between a plurality of third substrate supporting units 361 arranged in the lift conveyer portion 360 with a predetermined spaces.

[0488] As a scribing method for forming scribe lines in side edge portions of the four panel substrates 90a for cutting four panel substrates out of the bonded mother substrate 90 by pressing and rotating the cutter wheel 162a of the upper portion substrate cutting device 160 and the cutter wheel 162a of the lower portion substrate cutting device 170, a scribing method shown in Figures 56 to 58 in Embodiment 2 may be effectively applied to the substrate cutting system according to Embodiment 3 instead of the scribing method shown in Figure 81.

[0489] A plurality of third substrate supporting units 361 are arranged in the lift conveyer portion 360 with predetermined spaces therebetween. As shown in Figure 76, the plurality of third substrate supporting units 361 are held by the holding frame 362 via the pillars 365 such that the plurality of the second substrate supporting units 344B of the second substrate supporting portion 341B of the scribe unit portion 340 are inserted into the spaces. As shown in Figure 83, the plurality of the third substrate supporting units 361 are arranged such that a surface of the timing belts 361e receiving the scribed bonded mother substrate 90 is lower than a surface of the second substrate supporting units 344B on which the scribed bonded mother substrate 90 is to be placed.

[0490] After the bonded mother substrate 90 is scribed by the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 of the scribing device guide body 342 of the scribe unit portion 340, clamping (holding) of the bonded mother substrate 90 by the clamp devices 351 is released. The scribed bonded mother substrate 90 placed on the plurality of the second substrate supporting units 344B of the second substrate supporting portion 241B is placed on the plurality of the third substrate supporting units



361 and moved to a predetermined position in upper direction (+Z direction) along vertical direction. Then, by rotating the rotation motor 367 and moving the timing belts 361e, the bonded mother substrate 90 is carried to the break unit portion 380.

[0491] The break unit portion 380 includes an upper steam unit attachment bar 381 for attaching a plurality of steam units 384 for spraying steam to the upper mother substrate 91 of the bonded mother substrate 90 and a lower steam unit attachment bar 382 for attaching a plurality of steam units 384 for spraying steam on the lower mother substrate 92 of the bonded mother substrate 90 attached to pillars 383 along X direction parallel to the scribing device guide body 342.

[0492] The rotation moving speed of the belt conveyer 385 provided on the substrate carry-out side of the steam break unit portion 380 is set to be substantially the same as the rotation moving speed of the timing belt 361e of the plurality of the third substrate supporting units 361 of the lift conveyer portion 360, and they move in synchronization. Thus, the scribed bonded mother substrate 90 passes through the break unit portion 380.

[0493] Further, on the carry-out side of the upper steam unit attachment bar 381, the air knife 386 is attached, and in the lower steam unit attachment bar 382, the steam units 384 and the air knife 385 similar to those attached to the upper steam unit attachment bar 382 are also provided. After the steam is blown to the front and back surfaces of the mother substrate 90, the water remaining on the front and back surfaces of the mother substrate 90 is completely removed.

[0494] After the scribed bonded mother substrate 90 is placed on the plurality of the third substrate supporting units 361 and moved to a predetermined position in upper direction (+Z direction) along vertical direction, the bonded mother substrate 90 is moved by the belt conveyer 385 provided in the steam break unit portion on the substrate carry-out side at the rotation moving speed substantially same as that of the timing belts 361e of the plurality of the third substrate supporting units 361. Then, the scribed bonded mother substrate 90 passes through the break unit portion 380. Thus, the bonded mother substrate 90 is cut and in a state to be supported by the belt conveyer 385.

[0495] A moving or stopped panel substrate 90a which has passed through the steam break unit portion 380, has been cut into panel substrates 90a, and is to be supported by the belt conveyer 385 is taken up by the carrying robot 410. Then, the panel substrate 90a is placed on a panel holding portion 422 of an inverted carrying robot 421 of panel inversion unit portion 420.

[0496] The inverted carrying robot 421 of panel inversion unit portion 420 receives the panel substrate 90a from the carrying robot 410 and inverts the panel substrate 90a upside down to place on a separation table 441 on the panel terminal separation portion 440.

[0497] Regarding the panel substrate 90a placed on the separation table 441 of the panel terminal separation

portion 440 by the inverted carrying robot 421, unnecessary portions 99 of the panel substrates 90a are separated from the panel substrates 90a by an unnecessary portion removal mechanism 442 provided near the side edge portions of the separation table 441 as shown in Figure 77, for example, by an insertion robot (not shown).

[0498] By employing the scribing method shown in Figures 61 to 70 in Embodiment 2 as the scribing method by the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 of the scribing device guide body 342, a cutting process of the bonded substrate 90 by the steam unit portion 380 may be omitted.

[0499] Further, as a method for cutting the substrate, a method in which double scribe lines are formed on the bonded mother substrates where the glass substrates, which is a type of brittle material substrate, are bonded as mother substrates has been described. However, the present invention is not limited to this. When the mother substrate is a metal substrate such as steel sheet, wood plate, a plastic substrate, and a brittle material substrate such as ceramics substrate, glass substrate, semiconductor substrate or the like, a method for cutting the substrate by using, for example, laser light, a dicing saw, a cutting blade, a diamond cutter, or the like may be used.

[0500] Furthermore, the substrates include, besides mother substrate, a bonded substrate formed by bonding the same type of mother substrates, a bonded mother substrate formed by bonding different types of mother substrates, and a substrate formed by laminating mother substrates.

#### <Embodiment 4>

[0501] Figure 84 is a schematic perspective view showing an example of another embodiment of the substrate cutting system according to the present invention in whole. In the present invention, "substrates" include mother substrates cut into a plurality of substrates and also include single plates of metal substrates such as steel sheets, wood plates, plastic substrates and ceramic substrate, semiconductor substrates, and brittle material substrates such as glass substrates. Furthermore, the "substrates" are not limited to such single plates, but also includes bonded substrates formed by bonding pairs of substrates and laminated substrates formed by laminating pairs of substrates.

[0502] The substrate cutting system according to the present invention cut the bonded mother substrate 90 formed by bonding a pair of mother glass substrates to each other into a plurality of panel substrates (display panel bonded substrates) for producing, for example, panel substrates (display panel bonded substrates) of the liquid crystal display apparatus which are bonded to each other.

[0503] A substrate cutting system 500 according to Embodiment 4 has a similar structure as Embodiment 2

except for that the substrate supporting device **120** in the substrate cutting system **100** in Embodiment 2 is replaced with the substrate supporting device **520** of Embodiment 4, and a plurality of supporting belts **550** are hung within the substrate cutting system according to Embodiment 4. Thus, the like parts in Embodiment 2 shown in Figure **84** are denoted by like reference numerals. Detailed description will be omitted.

**[0504]** Regarding the substrate cutting system **500** according Embodiment 4, a side on which the first substrate supporting device **520** is located is referred to as a substrate carry-in side and a side on which the substrate carrying device **180** is located is referred to as a substrate carry-out side in the following description. In the substrate cutting system **500** of the present invention, a direction in which the substrates are carried (substrate flowing direction) is +Y direction from the substrate carry-in side to the substrate carry-out side. The direction in which the substrates are carried is a direction orthogonal to a scribing device guide body **130** in a horizontal fashion and the scribing device guide body **130** is provided along X direction.

**[0505]** The first substrate supporting portion **520A** and second substrate supporting portion **520B** of the substrate supporting device **520** respectively includes, for example, five first substrate supporting units **521A** and second substrate supporting units **521B** which are movable in a direction same as the moving direction of the scribing device guide body **130**. The first substrate supporting units **521A** and the second substrate supporting units **521B** are formed to have linear shape along the direction parallel to the frames **111A** and **111B** in the longitudinal direction of the main frame **111** (Y direction).

**[0506]** Figure **86** is a side view of one of the first substrate supporting units **521A** provided in the first substrate supporting portion **520A**. The first substrate supporting unit **521A** has a support main body **521a** elongated linearly along the direction parallel to the main frame **111** (Y direction). On an upper portion of the support main body **521a**, a belt receiver **521b** for guiding the supporting belt **550** is provided. On the end portion of the support main body **521a** on the substrate carry-out side, pulleys **521c** and **521d** are attached. Further, on a lower central portion of the support main body **521a**, a cylinder **521h** is provided. A cylinder rod of the cylinder **521h** is jointed to a suction plate **521e**. On both lower end portions of the support main body **521a**, linear guides **521f** are provided. One end of each of the shafts **521g** which are inserted into the linear guides **521f** is jointed to the suction plate **521e**.

**[0507]** The suction plate **521e** moves to a position higher than the supporting belt **550** by driving the cylinder **521h**, and receives the bonded mother substrate **90** carried by the carrying device which is not shown from the former step to the first substrate supporting portion **420**, and sucks and adsorbs the bonded mother substrate **90** by a suction mechanism which is not shown to

place on the supporting belt **550** of the first substrate supporting unit **521A**.

**[0508]** The cylinder **521h** has a structure of a two-stage cylinder. By controlling a pattern to put compressed air into the cylinder by an electromagnetic valve which is not shown, the suction plate **521e** is selectively placed at the lowest position lower than the supporting belt **550** as shown in Figure **85**, the highest position for receiving the bonded mother substrate **90**, and the intermediate position for placing the bonded mother substrate **90** on the supporting belt **550**.

**[0509]** The pillars **145** are provided on the upper surface of the guide bases **115** held in the moving units of the pair of the guide rails **113** provided on the upper surface of the mounting structure **110**. Above the pillars **145**, the supporting members **143** are provided parallel to Y direction along the frames **111A** and **111B** of the main frame **111**. The support main bodies **121a** are respectively attached to two unit attachment members **41** and **42** bridging to the supporting members **143** in X direction orthogonal to the frames **111A** and **111B** of the main frame **111** via the junction members **146** and **147**.

**[0510]** Figure **85** shows the first substrate supporting unit **521A** as moved toward the substrate carry-in side with the scribing device guide body **130** and the second substrate supporting unit **521B**. As shown in the portion (a) of Figure **86**, the supporting belt **550** is connected to the main frame **111** on the substrate carry-in side is supported by the belt receiver **521b** of the first substrate supporting unit **521A**, hung over the pulleys **521c** and **521d** of the first substrate supporting unit **521A**, and hung over a lower pulley **551** of the first substrate supporting unit **521A** and a lower pulley **552** of the second substrate supporting unit **521B**. Then, the supporting belt **550** is hung over the pulleys **521d** and **521c** of the second substrate supporting unit **521B**; supported by the belt receiver of the second substrate supporting unit **521B**, and then connected to the main frame **111** on the substrate carry out side to have a tension.

**[0511]** The pillar **145** on the frame **111A** side and the pillar **145** on the frame **111B** side which support first substrate supporting units **521A** are held by the guide bases **115**. Since the movers (not shown) of the linear motors are attached to the guide bases **115** for holding the pillars **128** which support both ends of the scribing device guide body **130**, the scribing device guide body **130** is moved toward the substrate carry-in side by driving the linear motor, and the five first substrate supporting units **521A** of the first substrate supporting portion **520A** also move toward the substrate carry-in side.

**[0512]** A plurality of first substrate supporting units **521A** (five in the present embodiment) are arranged with a predetermined spaces therebetween, and move in Y direction along the frames **111A** and **111B** of the main frame **111** together with the scribing device guide body **130**.

**[0513]** The second substrate supporting portion **520B** of the substrate supporting device **520** respectively in-

cludes, for example, the second substrate supporting units **521B** which are movable in a direction same as the moving direction of the scribing device guide body **130**. The second substrate supporting units **521B** have similar structures as those of the first substrate supporting units **521A** except for that they do not include the suction plate **521e**, cylinder **521h** for moving the suction plate **521e**, linear guides **521f**, and shafts **521g**, and supported by the pillar **145** on the frame **111A** side and the pillar **145** on the frame **111B** side so as to be attached in an inverted direction with respect to Y direction to provide an arrangement symmetrical with respect to the scribing device guide body **130**. The respective pillars are supported by the guide bases **115**.

[0514] Since the movers (not shown) of the linear motors are attached to the guide bases **115** for holding the pillars **128** which support both ends of the scribing device guide body **130**, the scribing device guide body **130** is moved toward the substrate carry-in side by driving the linear motor, and the five second substrate supporting units **521B** of the second substrate supporting portion **520B** also move toward the substrate carry-in side.

[0515] As shown in the portion (b) of Figure **86**, when the first substrate supporting unit **521A** moves toward the substrate carry-in side with the scribing device guide body **130** and the second substrate supporting unit **521B**, the supporting belt **550** of the first substrate supporting unit **521A** sinks below the scribing device guide body **130**, and the supporting belt **550** of the second substrate supporting unit **521B** appears on the belt receiver **521b** of the second substrate supporting unit **521B** from below the scribing device guide body **130**.

[0516] Further, when the second substrate supporting unit **521B** moves toward the substrate carry-out side with the scribing device guide body **130** and the first substrate supporting unit **521A**, the supporting belt **550** of the second substrate supporting unit **521B** sinks below the scribing device guide body **130**, and the supporting belt **550** of the first substrate supporting unit **521A** appears on the belt receiver **521b** of the first substrate supporting unit **521A** from below the scribing device guide body **130**.

[0517] The operation of the substrate cutting system of Embodiment 4 having such a structure will be explained with reference mainly to an example in which a bonded substrate formed by bonding large-scale glass plates is cut.

[0518] For cutting the bonded mother substrate **90** formed by bonding large-scale glass substrates to each other into a plurality of panel substrates **90a** (see Figure **88**), first, as shown in Figure **87**, the bonded mother substrate **90** is carried into the substrate cutting system by the carrying robot or the like from the end portion on the substrate carry-in side, and is placed on the supporting belts **550** of all the second substrate supporting units **521A** of the first substrate supporting portion **520A** in a horizontal fashion.

[0519] In such a state, as in Embodiment 2, the bond-

ed mother substrate **90** is pressed with a pressure which is not shown so as to abut positioning pins (not shown) arranged along the frame **111B** of the main frame **111**. The bonded mother substrate **90** is also pressed with a pressure which is not shown so as to abut positioning pins (not shown) arranged along a direction orthogonal to the frame **111B**. In this way, the bonded mother substrate **90** is positioned at a predetermined position in the housing **110** in the substrate cutting system.

[0520] Then, as shown in Figure **87**, the bonded mother substrate **90** has its side edge along the frame **111B** of the main frames **111** clamped by the clamp members **151** of the clamp device **150**. The side edge of the bonded mother substrate **90** on the substrate carry-in side is clamped by the clamp members **151** arranged on the substrate carry-in side so as to be orthogonal to the frame **111B**.

[0521] When the side edges of the bonded mother substrate **90** which are orthogonal to each other are respectively clamped by the clamp device **150**, the clamp members **151** clamping the side edges of the bonded mother substrate **90** sink approximately at the same time due to the weight of the bonded mother substrate itself. Thus, the bonded mother substrate **90** is supported supplementarily by the supporting belt **550** of all the first substrate supporting units **521A**.

[0522] In such a state, the scribing device guide body **130** slide toward the substrate carry-in side so as to be at a predetermined position on a side edge of the bonded mother substrate **90** on the substrate carry-out side clamped by the clamp device **50** in a horizontal fashion. The first optical device **138** and the second optical device **139** provided on the scribing device guide body **130** move along the guide body **130** from waiting positions. Thus, the images of the first alignment mark and the second alignment mark provided on the bonded mother substrate **90** are taken.

[0523] Since the scribing device guide body **130** slides, the first substrate supporting portion **520A** slides toward the substrate carry-in side, and second substrate supporting portion **520B** slides toward the substrate carry-in side. At this time, the supporting belt **550** of the first substrate supporting unit **521A** on the scribing device guide body **130** side sinks below the scribing device guide body **130**, and the supporting belt **550** of the second substrate supporting unit **521B** appears on the belt receiver **521** of the second substrate supporting unit **521B**. Thus, the supporting belts **550** are not in sliding contact with the lower surface of the bonded mother substrate **90**.

[0524] Next, based on the results of taking the images of the first alignment mark and the second alignment mark, angle of the bonded mother substrate **90** supported by the clamp device **150** in a horizontal fashion in a direction along the scribing device guide body **130**, cutting start position and cutting end position by a calculation using an operation process device which is not shown. Based on the calculated results, the scribing de-

vice guide body 130 is moved With the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170 to cut the bonded mother substrate 90 (Such an operation may be referred to as scribing or cutting by linear interpolation).

[0525] In this example, as shown in Figure 88, the cutter wheels 162a respectively opposing the front surface and the back surface of the bonded mother substrate 90 are pressed onto the front back surfaces and rotated. Thus, scribe lines 95 are formed on the front surface and the back surface of the bonded mother substrate 90.

[0526] From the bonded mother substrate 90, for example, two panel substrates 90a in a column direction along the upper guide rail 132 and the lower guide rail 132 are cut out for two columns. For cutting four panel displays 90a out of the bonded mother substrate 90, the cutter wheel 162a of the upper portion substrate cutting device 160 and the cutter wheel 162a of the lower portion substrate cutting device 170 are respectively pressed and rotated along the side edges of the panel substrates.

[0527] In this example, the cutter wheel 162a of the upper portion substrate cutting device 160 and the cutter wheels 162a of the lower portion substrate cutting device 170 generate vertical cracks in the portions of the glass substrates where the cutter wheels 162a rotated, and a scribe line 95 is formed. Since protrusions are formed in a predetermined pitch in peripheral edges of the blade edges of the cutter wheels 162a, vertical cracks having the length of about 90% of the thickness of the glass substrate in the thickness direction are formed in the glass substrates.

[0528] Further, a scribing method using a cutter head including a mechanism for periodically changing a pressure to the bonded mother substrate 90 by a scribe cutter by vibrating the scribe cutter such as a diamond point cutter, cutter wheel or the like for scribing the bonded mother substrate 90 may be effectively applied to the cutting of the bonded mother substrate 90 by the substrate cutting system of the present invention.

[0529] As a scribing method for forming scribe lines in side edge portions of the four panel substrates 90a for cutting four panel substrates 90a out of the bonded mother substrate 90 by pressing and rotating the cutter wheel 162a of the upper portion substrate cutting device 160 and the cutter wheel 162a of the lower portion substrate cutting device 170, a scribing method shown in Figures 56 to 58 in Embodiment 3 may be effectively applied to the substrate cutting system according to Embodiment 3 beside the scribing method shown in Figure 81.

[0530] During a scribing process by the cutter wheels 162a of the upper portion substrate cutting device 160 and the lower portion substrate cutting device 170, all the first substrate supporting units 521A of the first substrate supporting portion 520A and all the second substrate supporting units 521B of the second substrate supporting portion 520B move to the substrate carry-in

side and the substrate carry-out side. When they move to the substrate carry-in side, the supporting belt 550 of the first substrate supporting unit 521A on the scribing device guide body 130 side sinks below the scribing device guide body 130, and the supporting belt 550 of the second substrate supporting unit 521B appears on the belt receiver 521 of the second substrate supporting unit 521B. When they move to the substrate carry-out side, the supporting belt 550 of the second substrate supporting unit 521B sinks below the scribing device guide body 130, and the supporting belt 550 of the first substrate supporting unit 521A appears on the belt receiver 521b of the first substrate supporting unit 521A from below the scribing device guide body 130. Thus, there is no possibility that the supporting belts 550 are in sliding contact with the lower surface of the bonded mother substrate 90.

[0531] After the scribe lines are formed on the bonded mother substrate by the above-described scribing method, as shown in Figure 89, with the bonded mother substrate 90 on which the scribe line 95 is formed being supported by the supporting belts 550 of the second substrate supporting units 521B, the steam unit portion 260 moves toward the substrate carry-in side and blows the steam entirely on the front and back surfaces of the bonded mother substrate 90 on which the scribe lines are carved to completely cut out the bonded mother substrate 90. At the same time, the water remaining on the front and back surfaces of the bonded mother substrate 90 after the steam is blown thereto is removed by the air knife 71.

[0532] By blowing the steam onto the entire front and back surface of the bonded mother substrate 90 having the scribe lines carved thereon, the scribe lines formed by the cutter wheels 162a experience volume expansion since the surface portions of the mother substrate 1 are heated. In this way, vertical cracks extend in the thickness direction of the mother substrate, and the bonded mother substrate 90 is completely cut.

[0533] Thereafter, as shown in Figure 89, all the panel substrates 90a cut out from the bonded mother substrate 90 on the supporting belts 550 of all the second substrate supporting units 521B of the second substrate supporting portion 520B are carried out by the carrying robot 240 of the substrate carry-out device 180, and thus, a cut bonded mother substrate 90' (mill end) is supported.

[0534] Then, the substrate carry-out device 180 and the steam unit portion 260 moves toward the end portion on the substrate carry-out side.

[0535] Thereafter, as shown in Figure 90, the scribing device guide body 130, the second substrate supporting portion 520B, and the first substrate supporting portion 520A are slid toward the substrate carry-out side. At this time, the supporting belt 550 of the second substrate supporting unit 521B on the scribing device guide body 130 side sinks below the scribing device guide body 130, and the supporting belt 550 of the first substrate

supporting unit **521A** appears on the belt receiver **521b** of the first substrate supporting unit **521A** from below the scribing device guide body **130**. Thus, the supporting belts **550** are not in sliding contact with the lower surface of the cut bonded mother substrate **90'** (mill end).

[0536] Thus, the supporting belts **550** of the first substrate supporting units **521A** and the supporting belts of the second substrate supporting units **521B** of the second substrate supporting portion **520** are sequentially brought into a non-contact state without being in sliding contact from the lower surface of the cut bonded mother substrate **90'**. The supports of the cut bonded mother substrate **90'** by the supporting belts **550** are sequentially released. Then, support of the out bonded mother substrate **90'** (mill end) by the clamp device **150** is released and the out bonded mother substrate **90'** (mill end) drops downward. In this case, the out bonded mother substrate **90'** dropped downward (mill end and cullet) is guided by a guiding plate arranged in a slanted state and is accommodated within a oullat accommodation box.

[0537] By employing the scribing method shown in Figures **61** to **70** in Embodiment 2 as the scribing method by the upper portion substrate cutting device **160** and the lower portion substrate cutting device **170** of the scribing device guide body **130**, a cutting process of the bonded mother substrate **90** by the steam unit portion **260** may be omitted.

[0538] Further, as a method for cutting the substrate, a method in which double scribe lines are formed on the bonded mother substrates where the glass substrates, which is a type of brittle material substrate, are bonded as mother substrates has been described. However, the present invention is not limited to this. When the mother substrate is a metal substrate such as steel sheet, wood plate, a plastic substrate, and a brittle material substrate such as ceramics substrate, glass substrate, semiconductor substrate or the like, a method for cutting the substrate by using, for example, laser light, a dicing saw, a cutting blade, a diamond outter, or the like may be used.

[0539] Furthermore, the substrates include, besides mother substrate, a bonded substrate formed by bonding the same type of mother substrates, a bonded mother substrate formed by bonding different types of mother substrates, and a substrate formed by laminating mother substrates.

<Embodiment 4>

[0540] A substrate manufacturing apparatus **901** shown in Figure **91** is obtained by connecting a substrate chamfering device **700** for chamfering end surfaces of the out substrates is connected to one of the substrate cutting systems **1**, **100**, **300** and **500** according to the present invention.

[0541] Substrate manufacturing apparatuses **902** and **903** shown in Figure **92** is obtained by further incorpo-

rating an inspection system for inspecting the size, conditions of the front and back surfaces and end surfaces and the like of the cut substrates and for inspecting the functions of the substrates into the above-described substrate manufacturing apparatus **901**.

[0542] In the above description of the operations of the substrate cutting systems according to Embodiments 2 to 4, examples in which the mother glass substrate formed by bonding glass substrates is out have been described. However, the present invention is not limited to these. For example, operations different from the above description may be performed depending on the types of the substrates to be cut or in order to enhance the functionalities of the devices which form the substrate cutting system.

[0543] In the above descriptions regarding Embodiments 1 to 4, the substrate cutting systems for cutting the bonded mother substrate formed by bonding glass substrates to each other into a plurality of display panels have been described. However, the substrate which can be applied to the present invention is not limited to this.

[0544] The substrates which can be applied to the present invention include metal substrates having the mother substrates such as steel sheets, wood plates, plastic substrates and ceramic substrate, semiconductor substrates, and brittle material substrates such as glass substrates. Furthermore, the substrates include bonded substrates formed by bonding the same type of mother substrates, bonded mother substrates formed by bonding different types of mother substrates, and substrates formed by laminating mother substrates.

#### INDUSTRIAL APPLICABILITY

[0545] The substrate cutting system according to the present invention, as described above, holds a substrate with clamp devices and supports with substrate supporting devices which slide as a cut guide body moves. Thus, it becomes possible to perform a cutting process in two directions orthogonal to each other at the same time from front and back surfaces of the substrate by setting the substrate once. This causes the entire system to be compact. Also, various substrates can be cut efficiently.

#### Claims

1. A substrate cutting system characterized by comprising:

a hollow parallelepiped mounting structure;  
a clamp device attached to the mounting structure so as to clamp at least one portion of a side edge of a substrate carried into the mounting structure;  
a pair of substrate cutting devices for cutting the substrate from an upper surface side and a low-



er surface side of the substrate clamped by the clamping device; and  
 a scribing device guide body which is movable back and forth along one side of the hollow parallelepiped mounting structure and to which the pair of substrate cutting devices are attached so as to be movable along a direction orthogonal to the moving direction.

2. A substrate cutting system according to claim 1, **characterized by** comprising a substrate supporting device for supporting the substrate clamped by the clamping device. 10
3. A substrate cutting system according to claim 2, **characterized by** comprising a first substrate supporting portion provided on one side in the moving direction of the scribing device guide body. 15
4. A substrate cutting system according to claim 3, **characterized in that** the first substrate supporting portion includes a plurality of first substrate supporting units which can move parallel along the moving direction of the scribing device guide body, the first substrate supporting units being moved so as to apart from each other as the scribing device guide body moves in one direction and being moved so as to approach each other as the scribing device guide body moves in other direction. 20 25
5. A substrate cutting system according to claim 4, **characterized in that**, in the first substrate supporting units, a plurality of first supporting belts respectively arranged along the moving direction of the scribing device guide body are supported, and the substrate is supported in a horizontal fashion by the first supporting belts by moving the first substrate supporting units so as to apart from each other. 30 35
6. A substrate cutting system according to claim 5, **characterized by** comprising first winding means for winding the first supporting belts by moving the first substrate supporting units so as to approach each other. 40 45
7. A substrate cutting system according to claim 4, wherein, in the first substrate supporting units, a substrate moving device for lifting the substrate above the first supporting belts so that the substrate is clamped by the clamp device is provided. 50
8. A substrate cutting system according to claim 3, **characterized in that** the first substrate supporting portion includes a plurality of first substrate supporting units which move parallel along the moving direction of the scribing device guide body, the first substrate supporting units being moved with the scribing device guide body as the scribing device 55

guide body moves in one direction.

9. A substrate cutting system according to claim 8, **characterized in that** the first substrate supporting units comprises a plurality of belts for supporting the substrate.
10. A substrate cutting system according to claim 9, **characterized by** comprising at least one clutch unit for selectively rotating the plurality of belts in accordance with the movement of the scribing device guide body.
11. A substrate cutting system according to claim 2, **characterized in that** the substrate supporting device further comprises second substrate supporting portion provided on the other side in the moving direction of the scribing device guide body.
12. A substrate cutting system according to claim 11, **characterized in that** the second substrate supporting portion includes a plurality of second substrate supporting units which move parallel along the moving direction of the scribing device guide body, the second substrate supporting units being moved so as to approach each other in the movement in one direction and being moved so as to apart from each other in the movement in other direction.
13. A substrate cutting system according to claim 12, **characterized in that**, in the second substrate supporting units, a plurality of second supporting belts respectively arranged along the moving direction of the scribing device guide body are supported, and the substrate is supported in a horizontal fashion by the second supporting belts by moving the second substrate supporting units so as to apart from each other.
14. A substrate cutting system according to claim 13, **characterized by** comprising second winding means for winding the second supporting belts by moving the second substrate supporting units so as to approach each other.
15. A substrate cutting system according to claim 11, **characterized in that** the second substrate supporting portion includes a plurality of second substrate supporting units which move parallel along the moving direction of the scribing device guide body, the second substrate supporting units being moved with the scribing device guide body as the scribing device guide body moves in one direction.
16. A substrate cutting system according to claim 15, **characterized in that** the second substrate supporting units comprises a plurality of belts for sup-



porting the substrate.

17. A substrate cutting system according to claim 16, **characterized by** comprising at least one clutch unit for selectively rotating the plurality of belts in accordance with the movement of the scribing device guide body.
18. A substrate cutting system according to claim 1, **characterized in that** a or the substrate cutting devices comprises a cutter head for transmitting pressure to the substrate using a servo motor for a cutter wheel.
19. A substrate cutting system according to claim 1, **characterized by** comprising a steam unit portion for spraying steam on front and back surfaces of the substrate having scribe lines carved thereon at a or the substrate cutting devices.
20. A substrate cutting system according to claim 19, **characterized in that** the steam unit portion includes substrate drying means for drying front and back surfaces of the substrate.
21. A substrate cutting system according to claim 19, **characterized by** comprising a substrate carry-out device for taking out the substrate which has been cut at the steam unit portion.
22. A substrate cutting system according to claim 21, **characterized in that** the substrate carrying device includes a carrying robot comprising: substrate holding means for holding the substrate; substrate rotation means for rotating the substrate holding means holding the substrate around a first axis vertical to the substrate; and means for rotating the substrate rotation means around a second axis which is different from the first axis vertical to the substrate held by the substrate holding means.
23. A substrate cutting system according to claim 21, **characterized by** comprising substrate inversion means for inverting the substrate carried by the substrate carrying device upside down.
24. A substrate cutting system according to claim 1, **characterized by** comprising a positioning unit portion for positioning the substrate.
25. A substrate cutting system according to claim 1, **characterized by** comprising a carrying unit for carrying the substrate scribed by the scribing device guide body to a steam unit portion.
26. A substrate cutting system according to claim 1, **characterized by** comprising removal means for removing unnecessary portion of the out substrate.
27. A substrate cutting system according to claim 5, **characterized in that** the plurality of belts are strained between a frame on a substrate carry-in side and a frame on a substrate carry-out side, the plurality of belts sinking below the scribing device guide body or coming up from below the scribing device guide body during the first substrate supporting portion is moving.
28. A substrate cutting system according to claim 9, **characterized in that** the plurality of belts are strained between a frame on a substrate carry-in side and a frame on a substrate carry-out side, the plurality of belts sinking below the scribing device guide body or coming up from below the scribing device guide body during the second substrate supporting portion is moving.
29. A substrate cutting system according to claim 1, **characterized in that** the substrate is a bonded mother substrate formed by bonding a pair of mother substrates.
30. A substrate manufacturing apparatus **characterized in that** a chamfering system for chamfering end surfaces of the cut substrate is connected to the substrate cutting system according to claim 1.
31. A substrate manufacturing apparatus **characterized in that** an inspection system for inspecting functions of the cut substrate is connected to the substrate cutting system according to claim 1.
32. A substrate manufacturing apparatus according to claim 19, **characterized in that** an inspection system for inspecting functions of the out substrate is connected.
33. A substrate scribing method for forming scribe lines on an upper surface and a lower surface of a substrate, **characterized in that:**  

scribe line formation means for forming a vertical crack along a thickness direction of the substrate oppose each other, and the scribe lines are continuously formed by the scribe formation means without being apart from the substrate.
34. A substrate scribing method according to claim 26, **characterized in that** three or more linear scribe lines are formed by the scribe line formation means, a closed curve being formed by all the scribe lines which has been formed.
35. A substrate scribing method according to claim 27, **characterized in that** the scribe line formation means form a closed curve having a rectangular shape.

36. A substrate scribing method according to claim 26, **characterized in that** the scribe line formation means is a cutter wheel tip having a disc shape and having a blade edge for rotating on a surface of the substrate in an outer periphery.

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37. A substrate scribing method according to claim 29, **characterized in that** the cutter wheel tip has a plurality of protrusions formed in a blade edge in a predetermined pitch.

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38. A substrate scribing method according to claim 30, **characterized in that** sub-scribe lines along at least two formed scribe lines are formed by the cutter wheel tip after at least two scribe lines are formed by the cutter wheel tip.

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39. A substrate scribing method according to claim 31, **characterized in that** the sub-scribe lines are formed continuously after the at least two scribe lines formed on the substrate without separating the cutter wheel tip from a surface of the substrate.

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40. A substrate scribing method according to claim 26, **characterized in that** the cutter wheel tip forms one scribe line, moves on the surface drawing a circular trace, and then, forms the other scribe line.

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41. A substrate scribing method according to claim 26, **characterized in that**, when the cutter wheel tip moves on the substrate drawing a circular trace, pressure to the substrate is reduced compared to pressure to the substrate when the scribe lines are being formed.

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42. A substrate cutting method **characterized in that** a scribing method for forming scribe lines on an upper surface and a lower surface of the substrate comprises the steps of:

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forming a main scribe line along a line to be cut on the substrate by opposing scribe line formation means for forming a vertical crack along a thickness direction of the substrate; and forming a supplementary scribe line along the main scribe line with a predetermined space apart from the formed main scribe line.

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43. A substrate cutting method according to claim 35, **characterized in that** the supplementary scribe line is formed with a space of 0.5 mm to 1.0 mm apart from the main scribe line.

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44. A substrate cutting method according to claim 35 or 36, **characterized in that** the main scribe line is formed by a vertical crack which extends to 80% or more of a thickness direction of the substrate from the substrate surface.

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45. A substrate cutting method according to claim 35, **characterized in that** the main scribe line is formed by a vertical crack which extends to 90% or more of a thickness direction of the substrate from the substrate surface.

46. A substrate cutting method according to claim 35, **characterized in that** the main scribe line is formed by a cutter wheel having a disc shape which rotates on the substrate surface, the cutter wheel protruding outward so as to have a center portion of an outer periphery in a width direction which has a shape of letter V with an obtuse angle, a plurality of protrusions with a predetermined height being provided across the entire circumferential with a predetermined pitch in a portion having the obtuse angle.

47. A substrate cutting method according to claim 39, **characterized in that** a formation direction of main scribe line and a formation direction of supplementary scribe line by the cutter wheel are opposite to each other, and the cutter wheel continuously form the main scribe line and the supplementary scribe line in contact with the substrate surface.

48. A substrate cutting method according to claim 35, **characterized in that** the main scribe line and the supplementary scribe line are formed with an appropriate space from at least one end portion of the line to be cut.

49. A substrate cutting method for cutting a substrate having scribe lines formed respectively on an upper surface and a lower surface of the substrate, **characterized in that:**

the upper surface and the lower surface of the substrate are heated for cutting the substrate.

#### Amended claims under Art. 19.1 PCT

1. (Amended) A substrate cutting system **characterized by** comprising:

a hollow parallelepiped mounting structure;  
a clamp device attached to the mounting structure so as to clamp at least one portion of a side edge of a substrate carried into the mounting structure;  
a pair of scribing devices including scribe line formation means respectively movable back and forth, which respectively scribe the substrate from an upper surface side and a lower surface side of the substrate clamped by the clamp device;  
a scribing device guide body which supports the scribing device, which is movable back and

forth along one side of the hollow parallelepiped mounting structure, and movably attached along a direction orthogonal to the moving direction of the scribe line formation means, a first substrate supporting portion for supporting a substrate provided on one side in the moving direction of the scribing device guide body; a second substrate supporting portion for supporting a substrate provided on the other side in the moving direction of the scribing device guide body:

a plurality of first substrate supporting units which are provided in the first substrate supporting portion and move along the moving direction of the scribing device guide body; and  
a plurality of second substrate supporting units which are provided in the second substrate supporting portion and move along the moving direction of the scribing device guide body, when the scribing device guide body moves, the first substrate supporting units and the second substrate supporting units support the substrate clamped by the clamp device without being in sliding contact.

2. (Cancelled)

3. (Cancelled)

4. (Amended) A substrate cutting system according to claim 1, **characterized in that** the first substrate supporting units are moved so as to apart from each other as the scribing device guide body moves in one direction and are moved so as to approach each other as the scribing device guide body moves in other direction.

5. (Amended) A substrate cutting system according to claim 4, **characterized in that**, in the first substrate supporting units, a plurality of first supporting belts respectively arranged along the moving direction of the scribing device guide body are supported, and the substrate is supported in a horizontal fashion by the first supporting belts by moving the first substrate supporting units so as to apart from each other.

6. A substrate cutting system according to claim 5, **characterized by** comprising first winding means for winding up the first supporting belts by moving the first substrate supporting units so as to approach each other.

7. A substrate cutting system according to claim 4,

wherein, in the first substrate supporting units, a substrate moving device for lifting the substrate above the first supporting belts so that the substrate is clamped by the clamp device is provided.

8. (Cancelled)

9. (Amended) A substrate cutting system according to claim 1, **characterized in that** the first substrate supporting units comprises a plurality of belts for supporting the substrate.

10. A substrate cutting system according to claim 9, **characterized by** comprising at least one clutch unit for selectively rotating the plurality of belts in accordance with the movement of the scribing device guide body.

11. (Cancelled)

12. (Amended) A substrate cutting system according to claim 11, **characterized in that** the second substrate supporting units are moved so as to approach each other in the movement in one direction and are moved so as to apart from each other in the movement in other direction.

13. A substrate cutting system according to claim 12, **characterized in that**, in the second substrate supporting units, a plurality of second supporting belts respectively arranged along the moving direction of the scribing device guide body are supported, and the substrate is supported in a horizontal fashion by the second supporting belts by moving the second substrate supporting units so as to apart from each other.

14. A substrate cutting system according to claim 13, **characterized by** comprising second winding means for winding the second supporting belts by moving the second substrate supporting units so as to approach each other.

15. (Cancelled)

16. (Amended) A substrate cutting system according to claim 1, **characterized in that** the second substrate supporting units comprises a plurality of belts for supporting the substrate.

17. A substrate cutting system according to claim 16, **characterized by** comprising at least one clutch unit for selectively rotating the plurality of belts in accordance with the movement of the scribing device guide body.

18. (Amended) A substrate cutting system according to claim 1, **characterized in that** a or the sub-

strate cutting devices comprises a cutter head for transmitting pressure to the substrate using a servo motor for a cutter wheel.

19. (Amended) A substrate cutting system according to claim 1, **characterized by** further comprising a steam unit portion for spraying steam on front and back surfaces of the substrate having scribe lines carved thereon.

20. A substrate cutting system according to claim 19, **characterized in that** the steam unit portion includes substrate drying means for drying front and back surfaces of the substrate.

21. A substrate cutting system according to claim 19, **characterized by** comprising a substrate carry-out device for taking out the substrate which has been cut at the steam unit portion.

22. A substrate cutting system according to claim 21, **characterized in that** the substrate carrying device includes a carrying robot comprising: substrate holding means for holding the substrate; substrate rotation means for rotating the substrate holding means holding the substrate around a first axis vertical to the substrate; and means for rotating the substrate rotation means around a second axis which is different from the first axis vertical to the substrate held by the substrate holding means.

23. (Amended) A substrate cutting system according to claim 21, **characterized by** comprising substrate inversion means for inverting the substrate carried by the substrate carrying device upside down.

24. A substrate cutting system according to claim 1, **characterized by** comprising a positioning unit portion for positioning the substrate.

25. A substrate cutting system according to claim 1, **characterized by** comprising a carrying unit for carrying the substrate scribed by the scribing device guide body to a steam unit portion.

26. A substrate cutting system according to claim 1, **characterized by** comprising removal means for removing unnecessary portion of the out substrate.

27. (Amended) A substrate cutting system according to claim 9, **characterized in that** the plurality of belts are strained between a frame on a substrate carry-in side and a frame on a substrate carry-out side, the plurality of belts sinking below the scribing device guide body or coming up from below the scribing device guide body during the first substrate supporting units are moving.

28. (Amended) A substrate cutting system according to claim 16, **characterized in that** the plurality of belts are strained between a frame on a substrate carry-in side and a frame on a substrate carry-out side, the plurality of belts sinking below the scribing device guide body or coming up from below the scribing device guide body during the second substrate supporting units are moving.

29. A substrate cutting system according to claim 1, **characterized in that** the substrate is a bonded mother substrate formed by bonding a pair of mother substrates.

30. (Amended) A substrate manufacturing apparatus **characterized by** comprising a chamfering system for chamfering end surfaces of the substrate out by the substrate cutting system according to claim 1.

31. (Amended) A substrate manufacturing apparatus **characterized by** comprising an inspection system for inspecting functions of the substrate out by the substrate cutting system according to claim 1.

32. (Amended) A substrate manufacturing apparatus according to claim 30, **characterized by** further comprising an inspection system for inspecting functions of the cut substrate.

33. (Amended) A substrate scribing method for forming scribe lines on an upper surface and a lower surface of a substrate, **characterized in that**:

when at least two scribe lines are formed by opposing scribe line formation means each other along lines to be scribed on the upper surface and the lower surface of the substrate, the scribe line formation means form a first scribe line, move on the substrate so as to draw a circular trace without being apart from the substrate, and then, form a second scribe line.

34. (Amended) A substrate scribing method according to claim 33, **characterized in that** three or more scribe lines are formed by the scribe line formation means, an area having a polygonal shape being formed by all the scribe lines which has been formed.

35. (Amended) A substrate scribing method according to claim 34, **characterized in that** the scribe line formation means form an area having a rectangular shape.

36. (Amended) A substrate scribing method according to claim 33, **characterized in that** the scribe line formation means is a cutter wheel having

a disc shape and having a blade edge for rotating on a surface of the substrate in an outer periphery.

37. (Amended) A substrate scribing method according to claim 36, **characterized in that** the cutter wheel has a plurality of protrusions formed in a blade edge in a predetermined pitch.

38. (Cancelled)

39. (Cancelled)

40. (Cancelled)

41. (Amended) A substrate scribing method according to claim 33, **characterized in that**, when the scribe formation means move on the substrate drawing a circular trace, pressure to the substrate is reduced compared to pressure to the substrate when the scribe lines are being formed.

42. (Amended) A substrate cutting method comprising the steps of:

forming a main scribe line along a line to be cut on an upper surface and a lower surface of a substrate; and  
forming a supplementary scribe line proximal to the formed main scribe line and approximately in parallel with the main scribe line,

wherein the substrate is cut along the main scribe line by formation of the supplementary scribe line.

43. (Amended) A substrate cutting method according to claim 42, **characterized in that** the supplementary scribe line is formed with a space of 0.5 mm to 1.0 mm apart from the main scribe line.

44. (Amended) A substrate cutting method according to claim 42 or 43, **characterized in that** the main scribe line is formed by a vertical crack which extends to at least 80% or more of a thickness direction of the substrate from the substrate surface.

45. (Cancelled)

46. (Amended) A substrate cutting method according to claim 42, **characterized in that** the main scribe line is formed by a cutter wheel having a disc shape which rotates on the substrate surface, the cutter wheel protruding outward so as to have a center portion of an outer periphery in a width direction which has a shape of letter V with an obtuse angle, a plurality of protrusions with a predetermined height being provided across the entire circumferential with a predetermined pitch in a portion

having the obtuse angle.

47. (Amended) A substrate cutting method according to claim 46, **characterized in that** a formation direction of the main scribe line and a formation direction of the supplementary scribe line by the cutter wheel are opposite to each other, and the cutter wheel continuously form the main scribe line and the supplementary scribe line in contact with the substrate surface.

48. (Amended) A substrate cutting method according to claim 42, **characterized in that** the main scribe line and/or the supplementary scribe line is formed with an appropriate space apart from at least one end portion of either of the lines.

49. (Amended) A substrate cutting method for cutting a substrate having scribe lines formed respectively on an upper surface and a lower surface of a substrate, **characterized in that**:

the upper surface and the lower surface of the substrate are sprayed with steam for cutting the substrate.

50. (Added) A substrate scribing method according to claim 42, **characterized in that**, when at least two main scribe lines are formed by the scribe line formation means, the scribe line formation means form a first main scribe line, move on the substrate so as to draw a circular trace without being apart from the substrate, form a second main scribe line, and then, form supplementary scribe lines along the at least two main scribe lines.

51. (Added) A substrate scribing method according to claim 50, **characterized in that** three or more main scribe lines are formed by the scribe line formation means, an area having a polygonal shape being formed by all the scribe lines which has been formed.

52. (Added) A substrate scribing method according to claim 51, **characterized in that** the scribe line formation means form an area having a rectangular shape.

53. (Added) A substrate scribing method according to claim 51, **characterized in that** the scribe formation means is a cutter wheel having a disc shape and having a blade edge rotated on a surface of the substrate in an outer periphery.

54. (Added) A substrate scribing method according to claim 53, **characterized in that** the cutter wheel has a plurality of protrusions formed in a blade edge in a predetermined pitch.



55. (Added) A substrate scribing method according to claim 50, **characterized in that**, when the scribe formation means move on the substrate drawing a circular trace, pressure to the substrate is reduced compared to pressure to the substrate when the main scribe lines are being formed.

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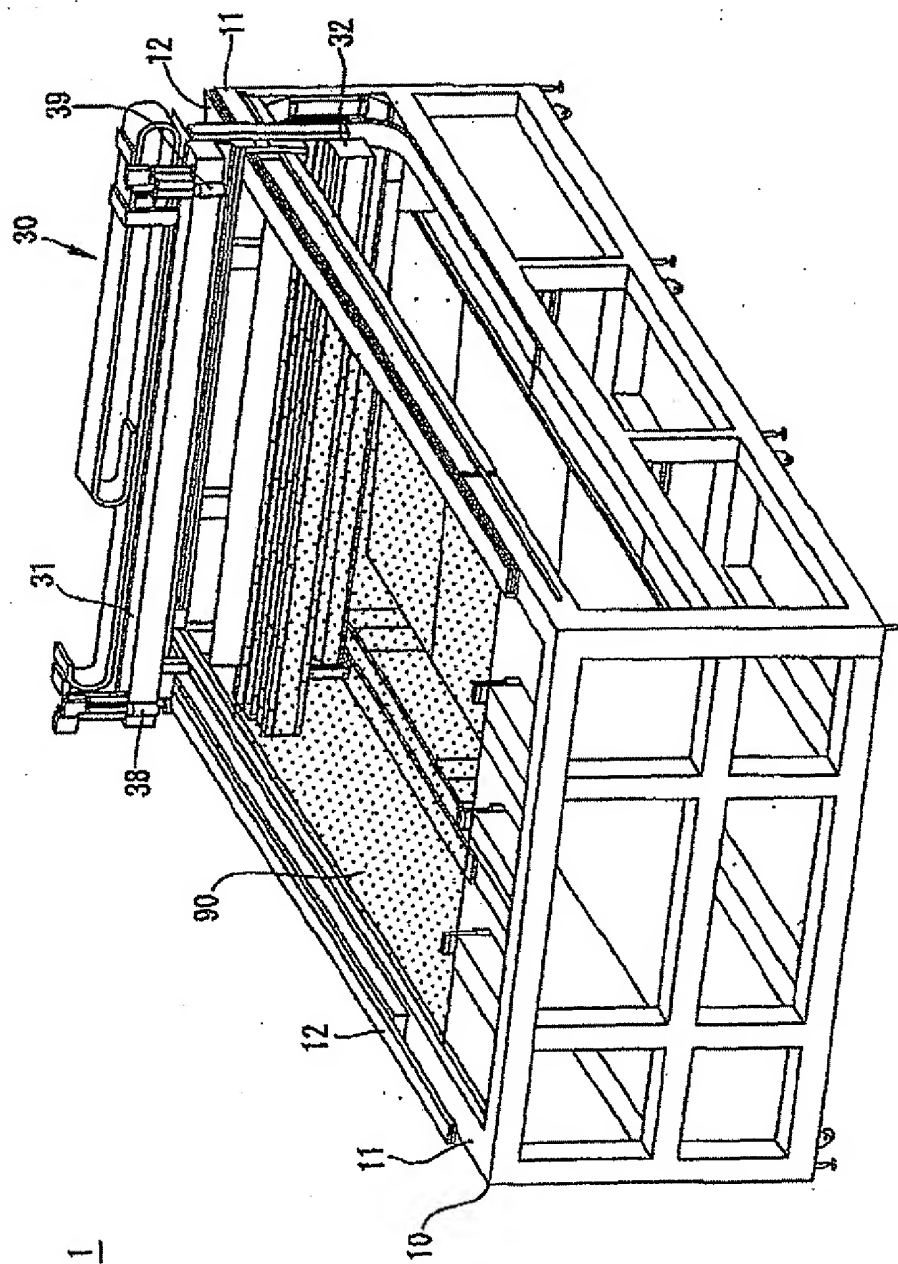
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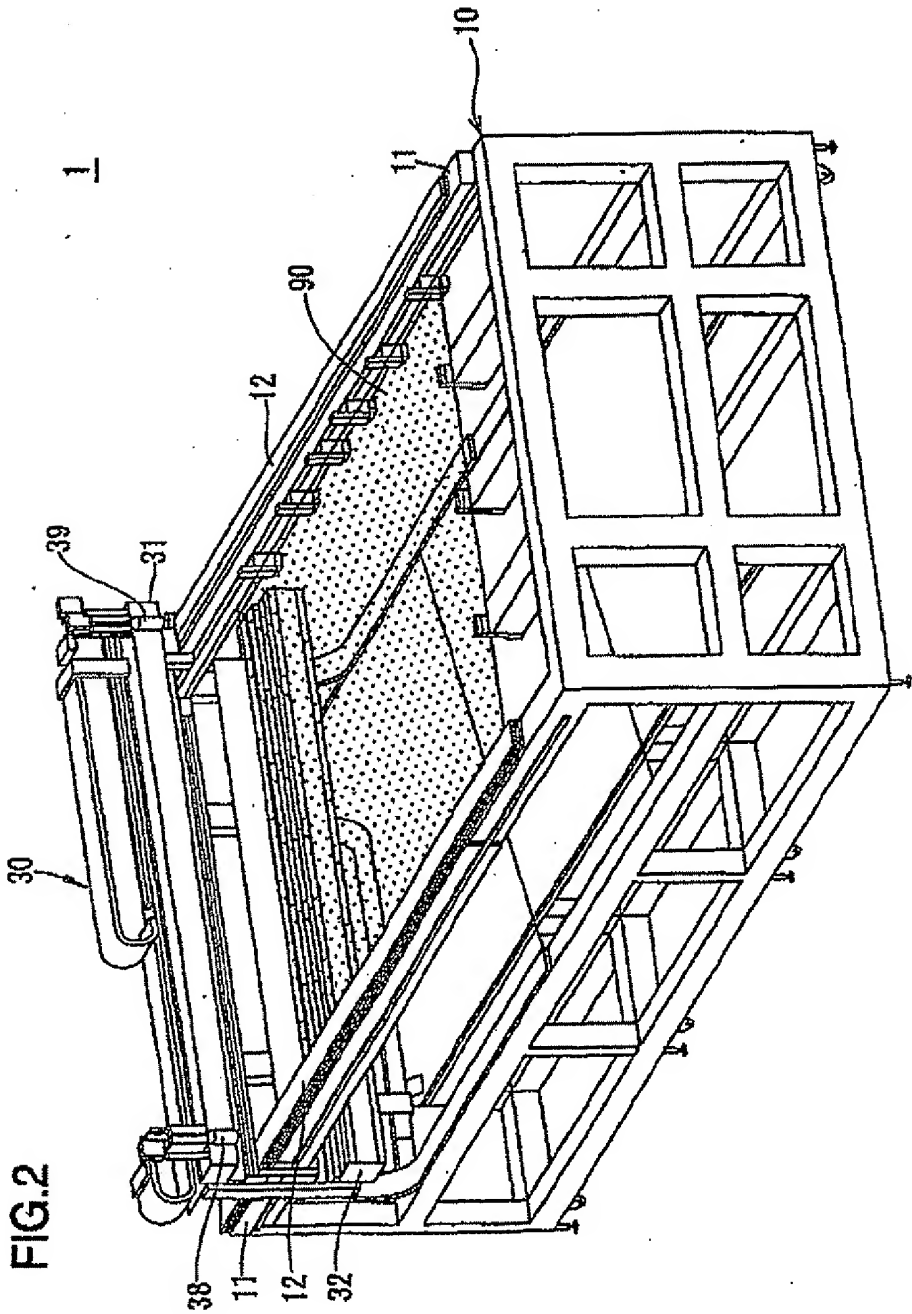
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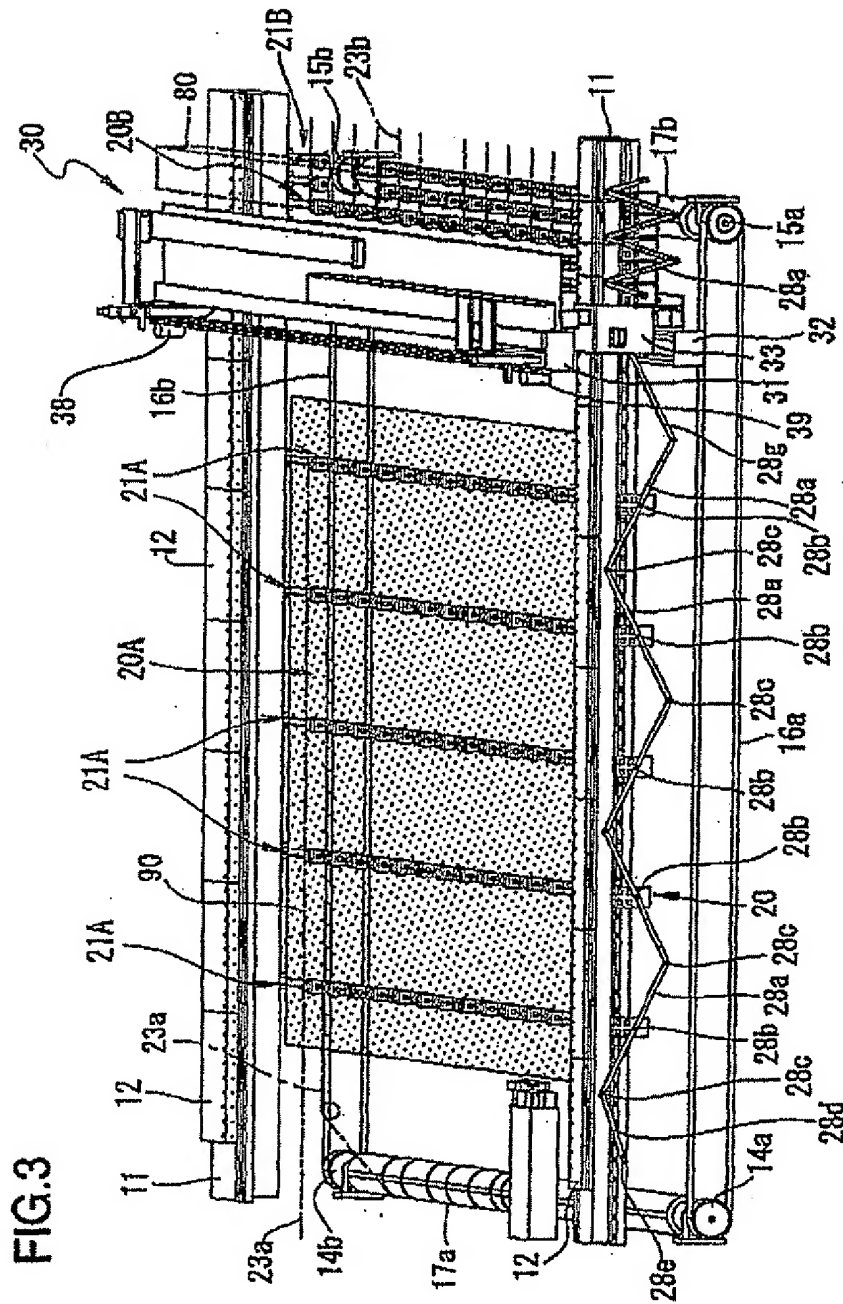
55

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FIG.1







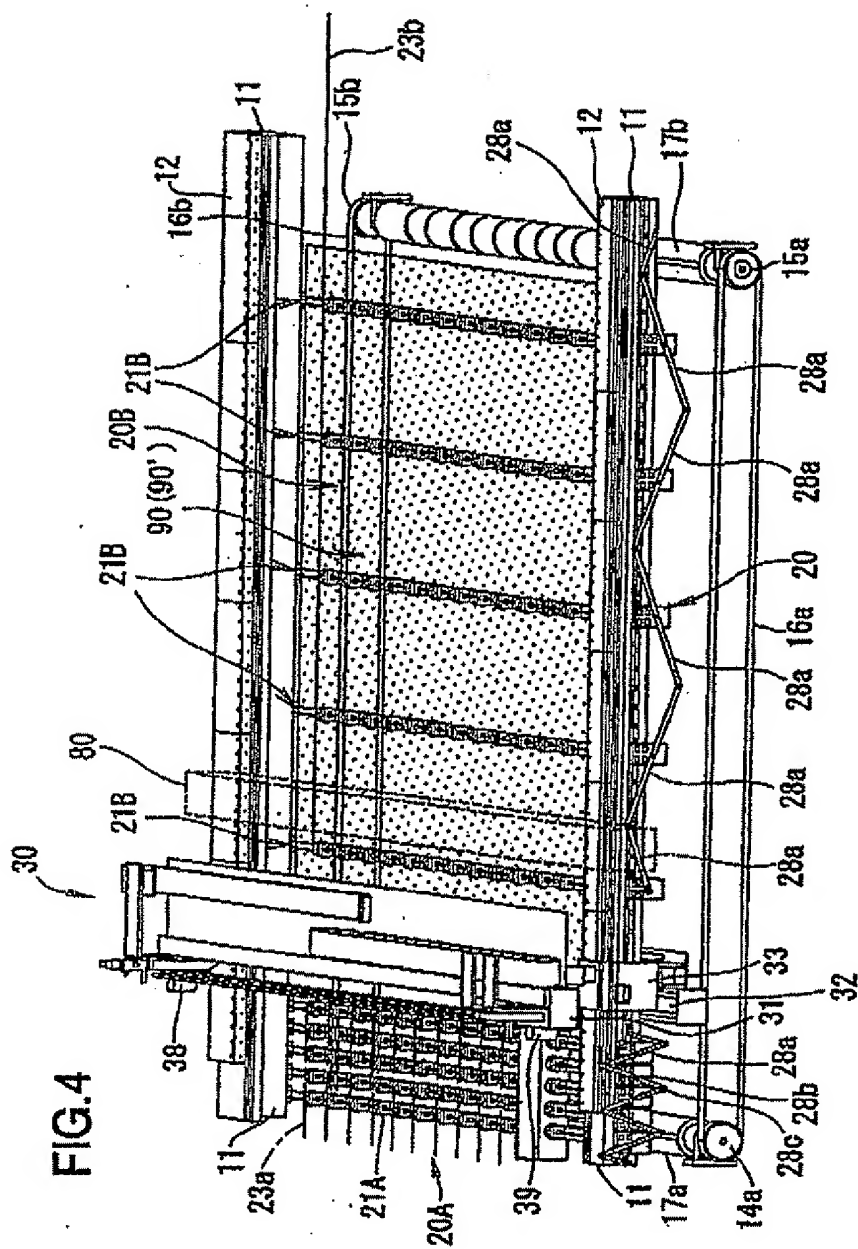




FIG.5

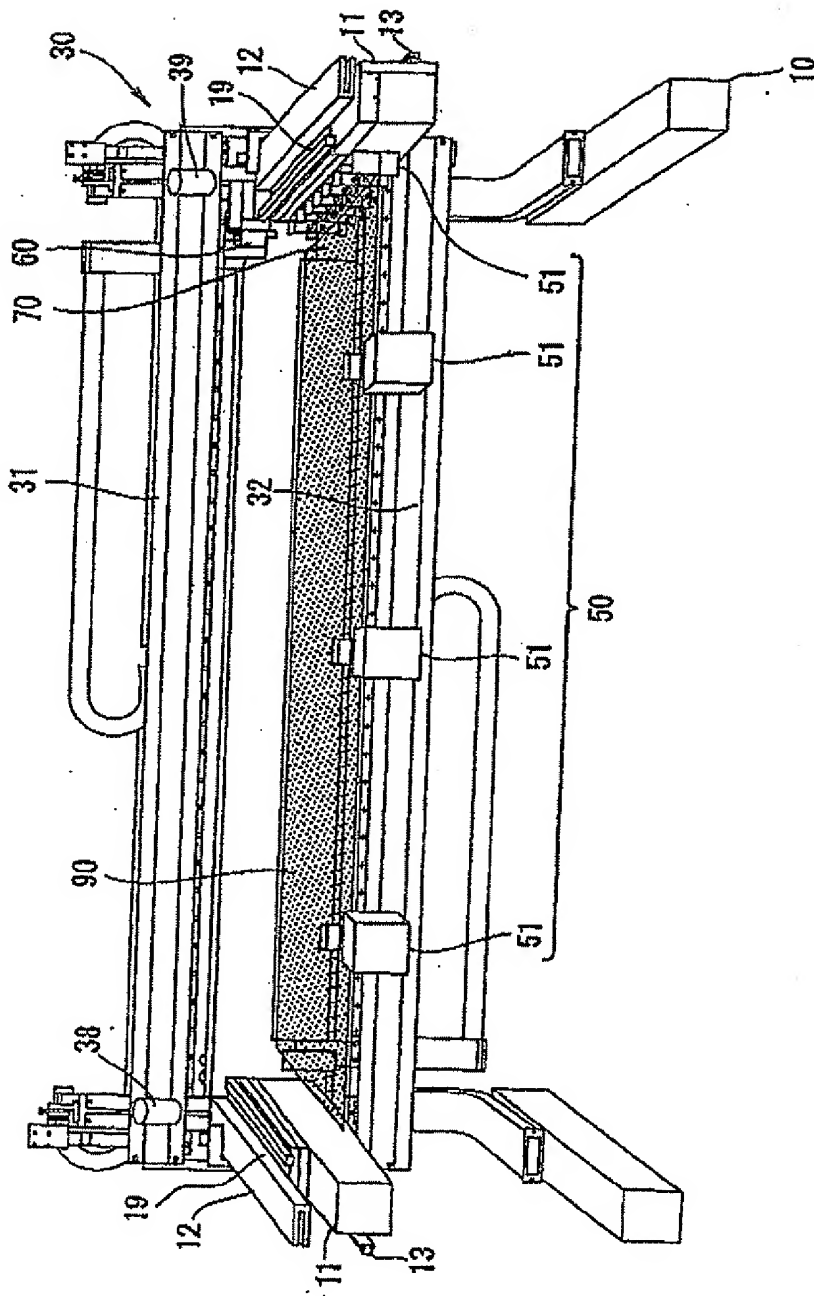


FIG.6

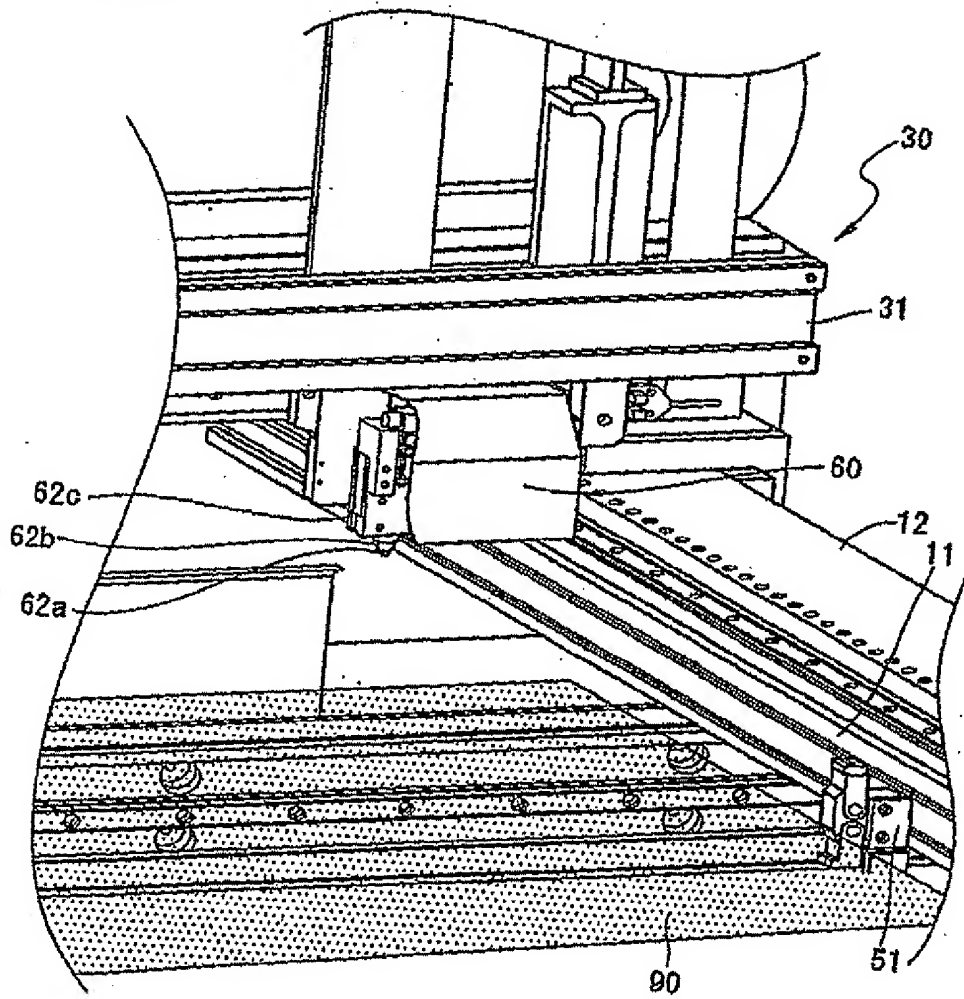
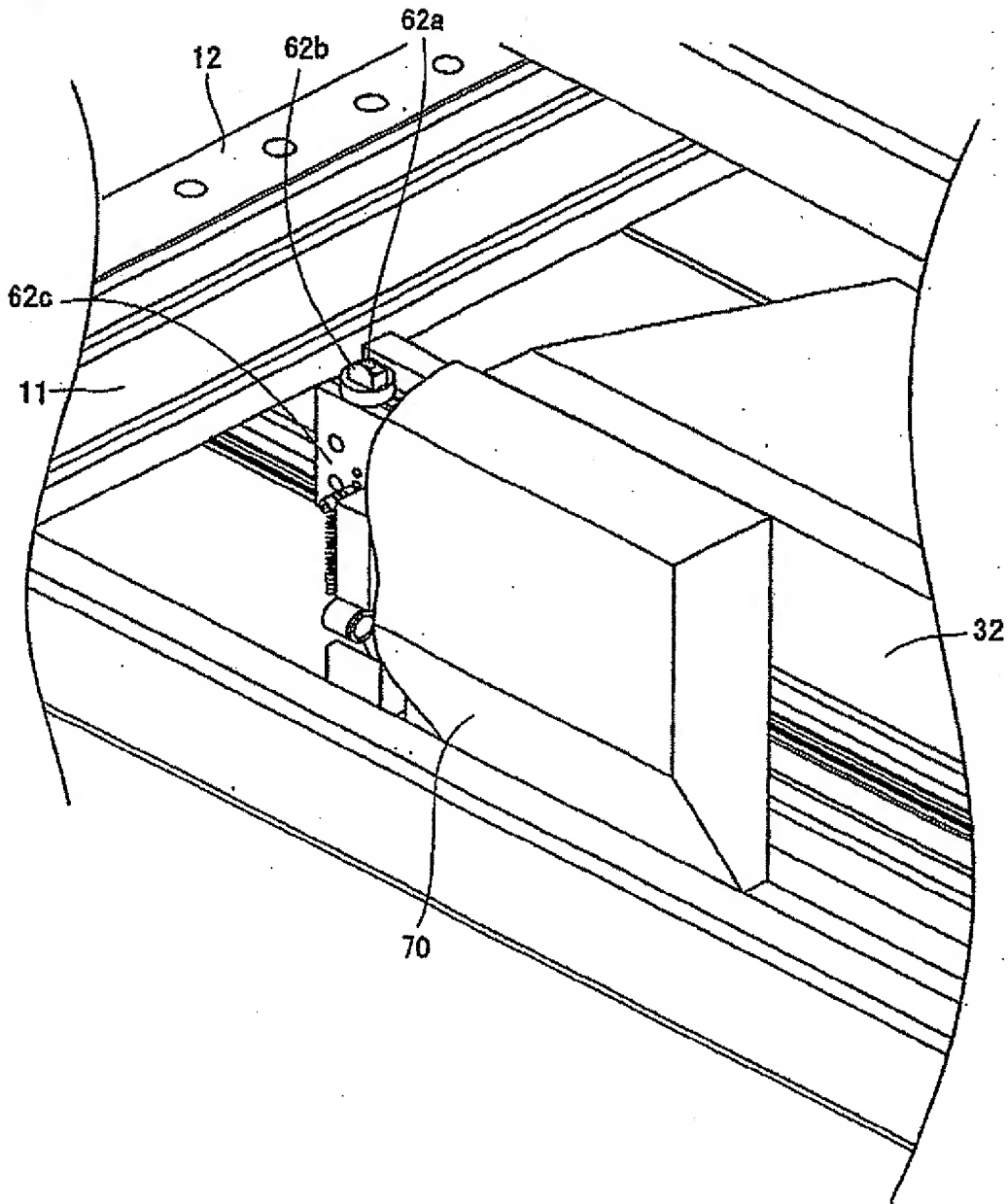


FIG. 7



**FIG. 8.**

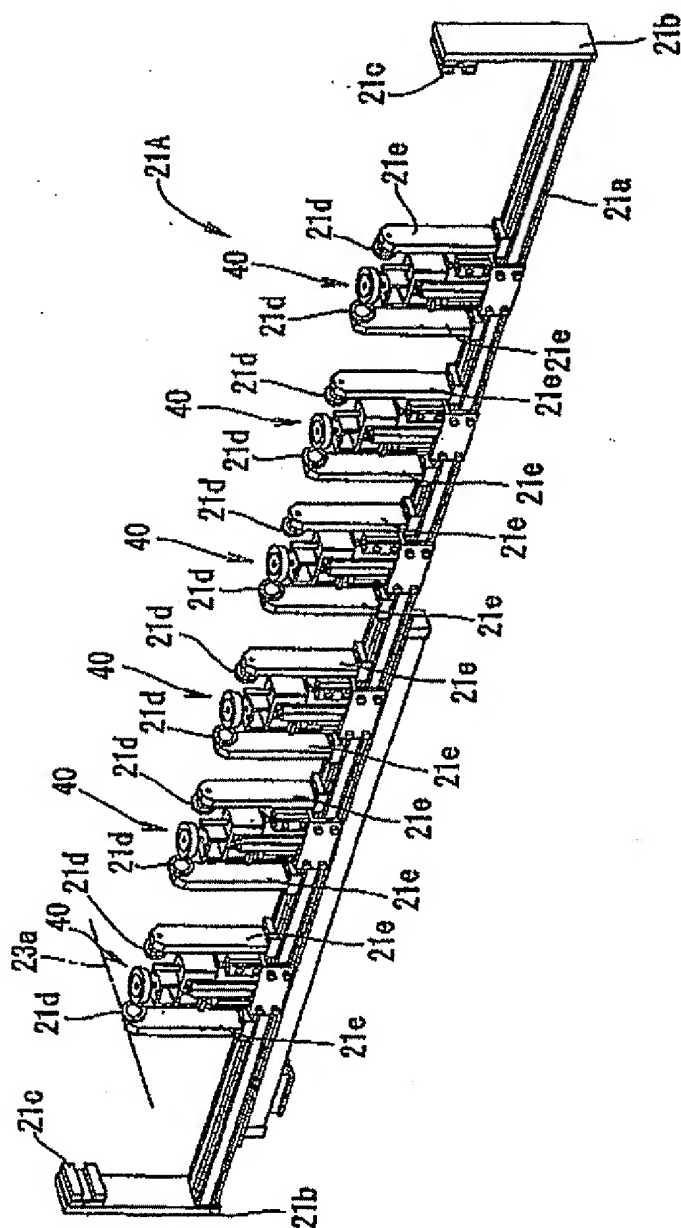


FIG.9

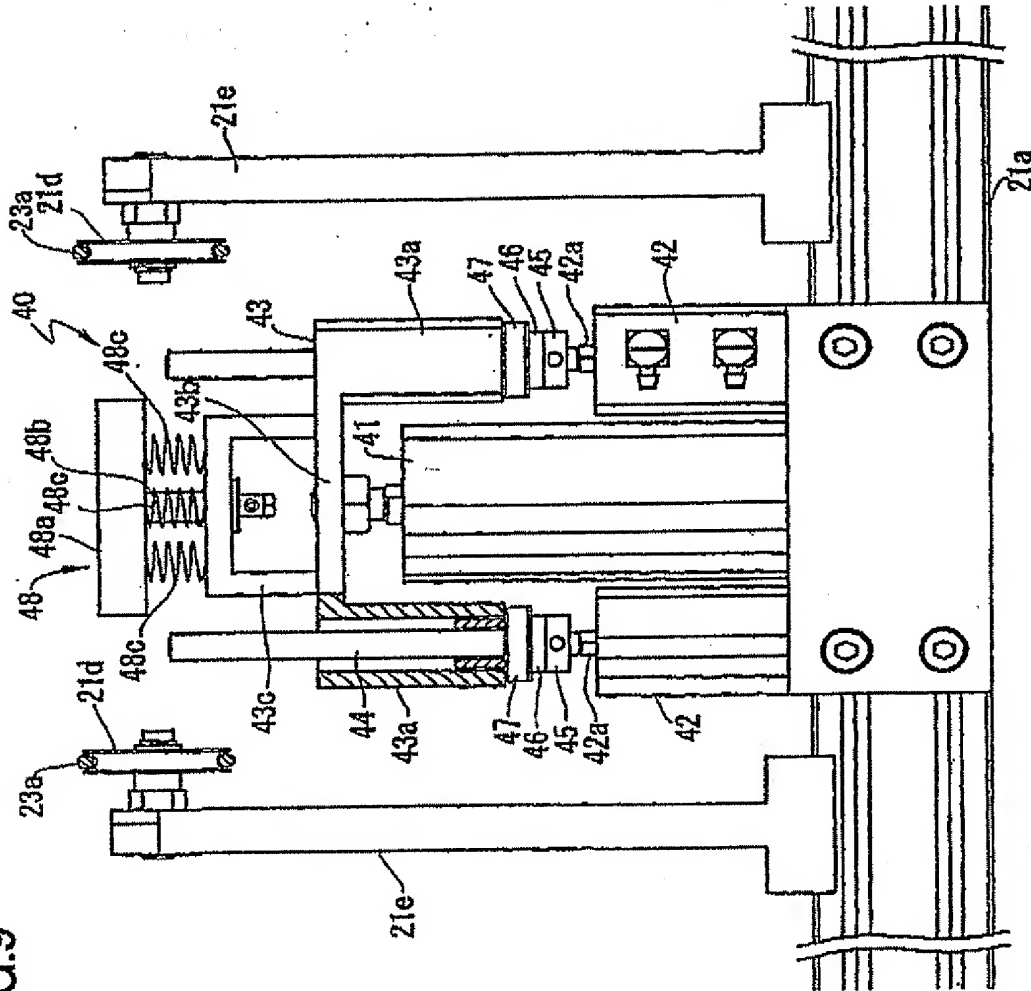
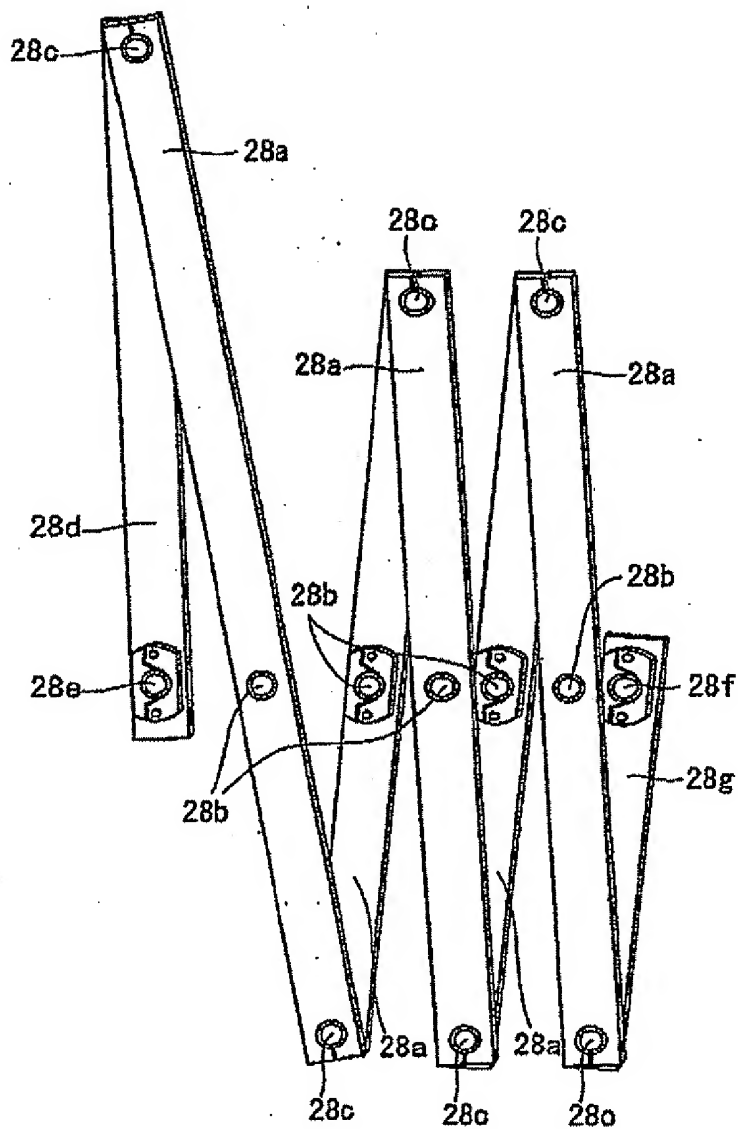




FIG.10



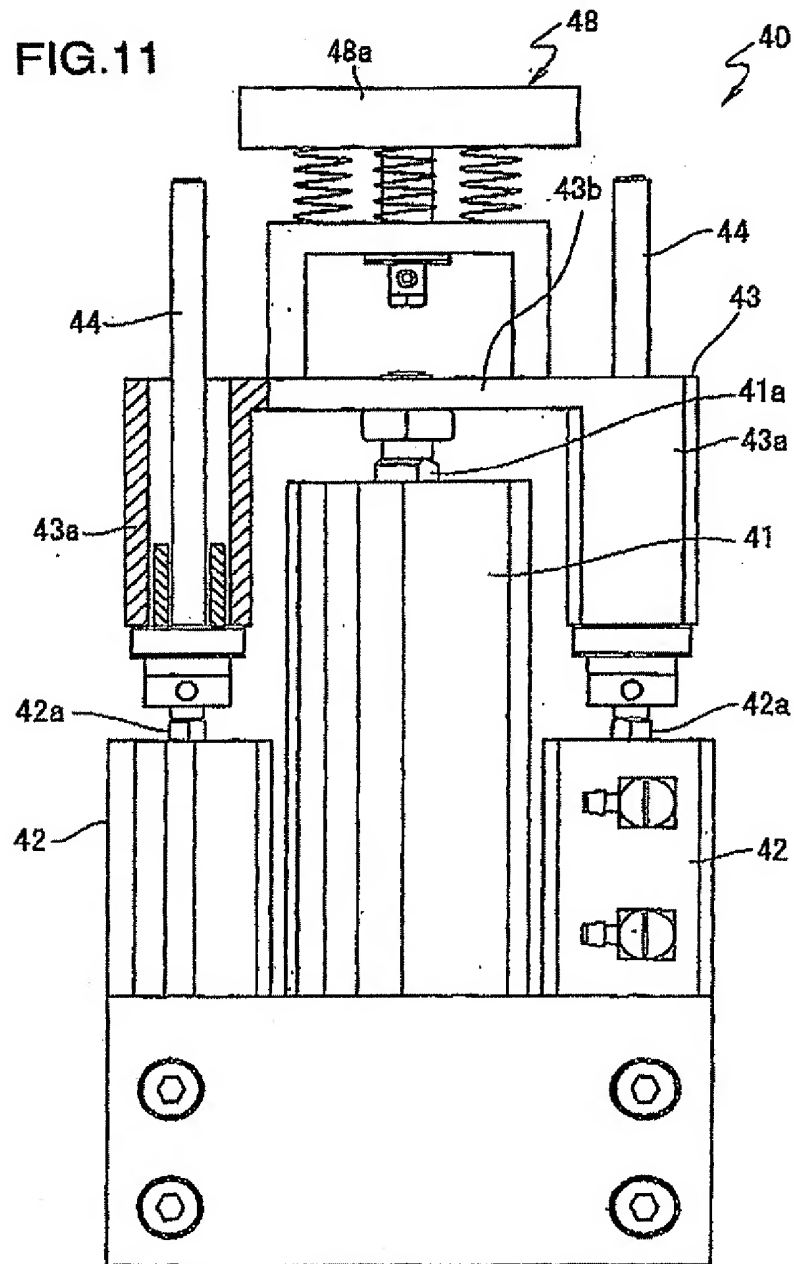


FIG.12

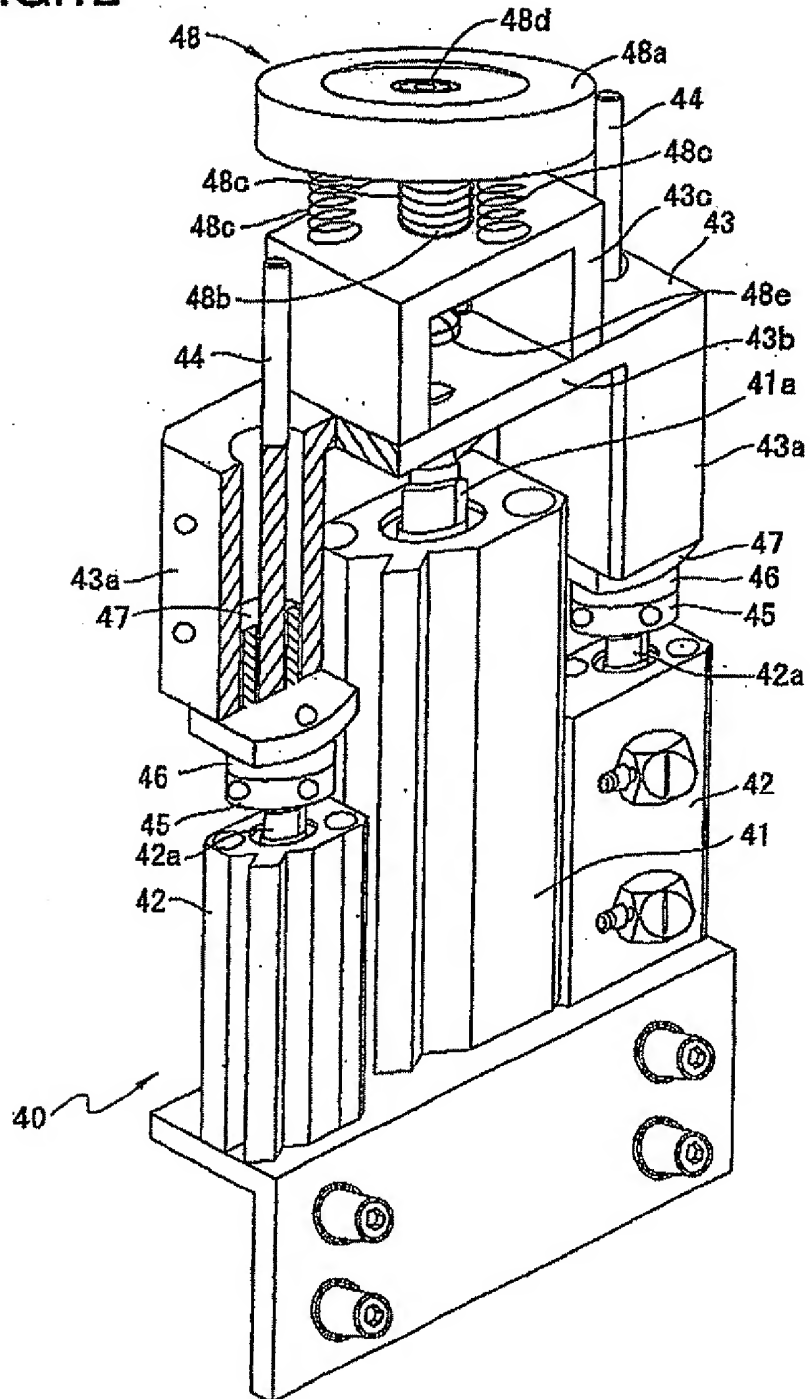
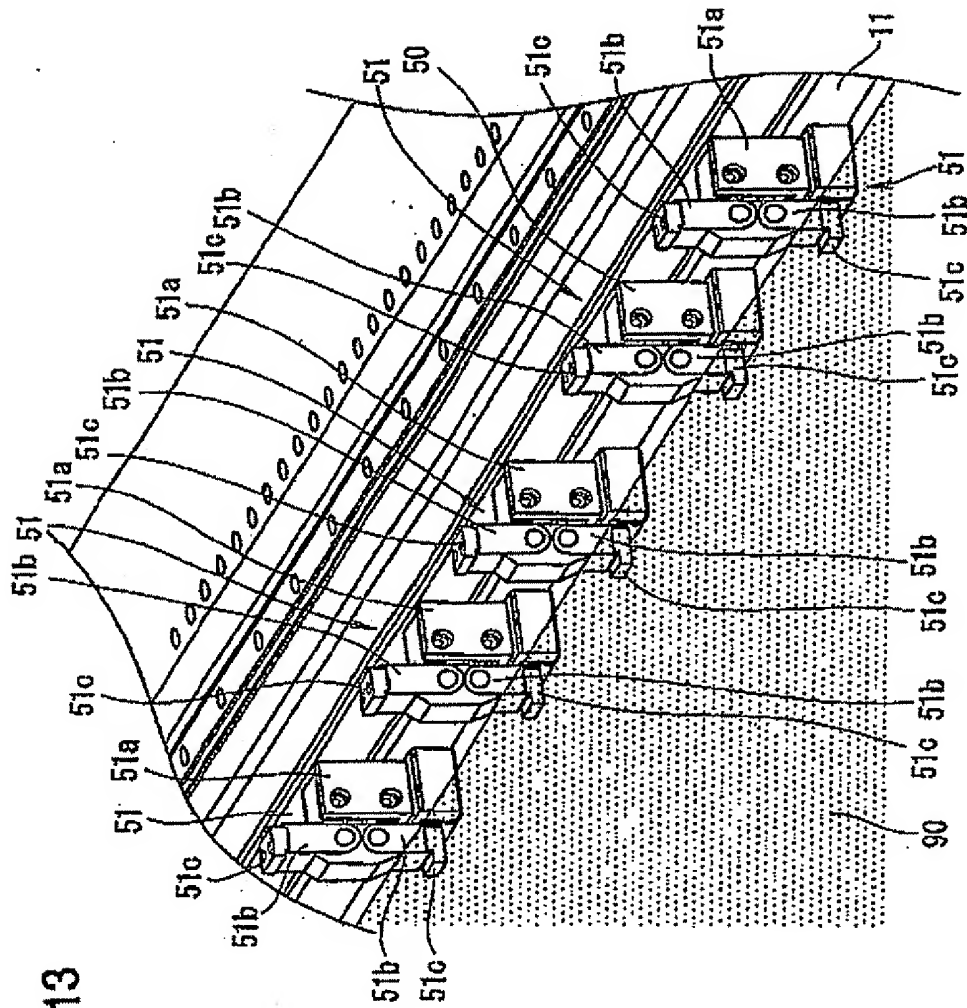


FIG.13



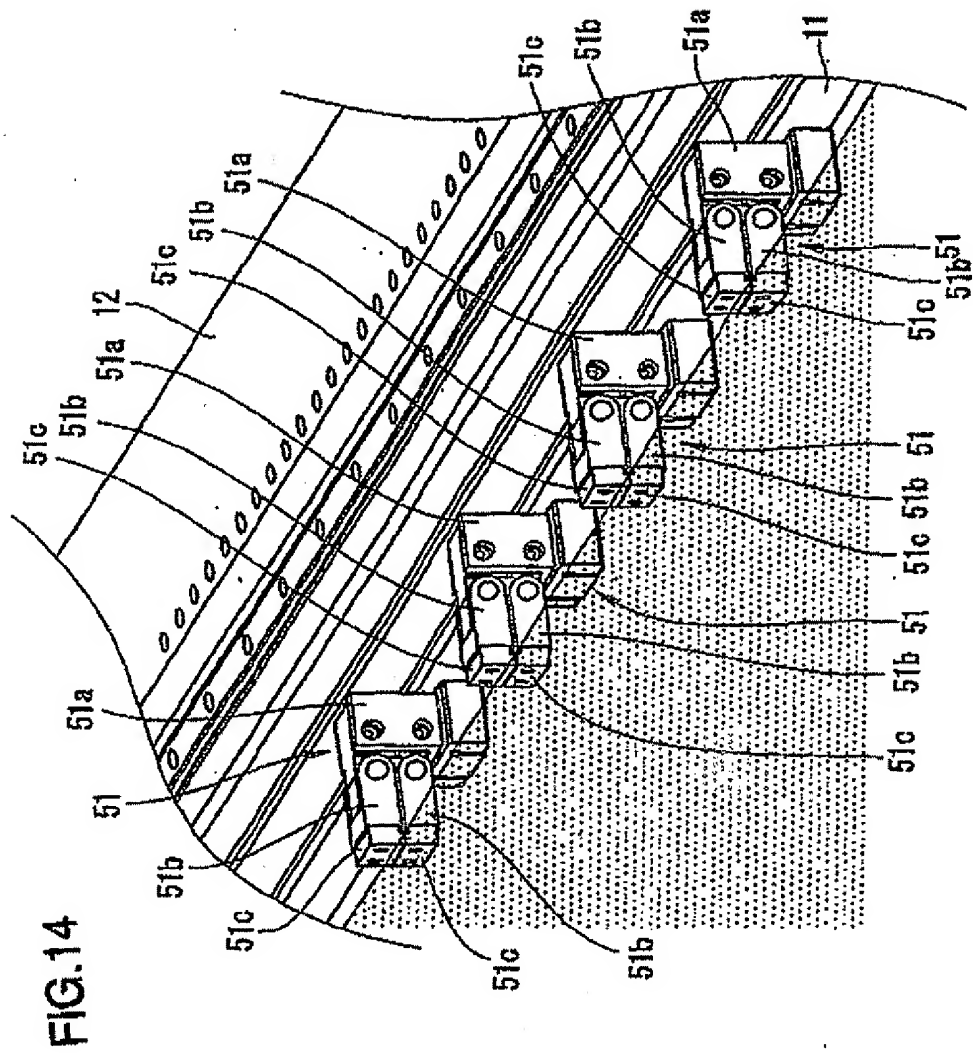




FIG.15

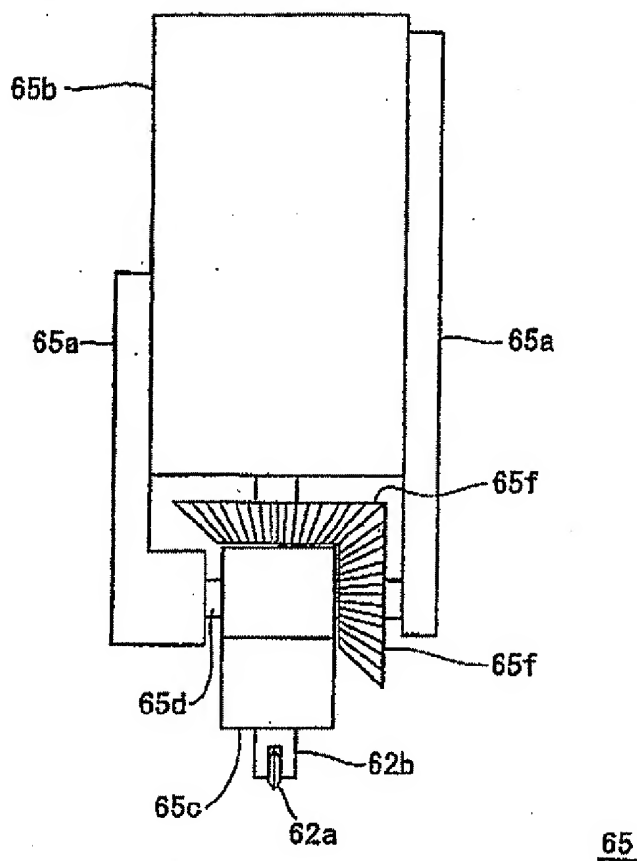


FIG.16

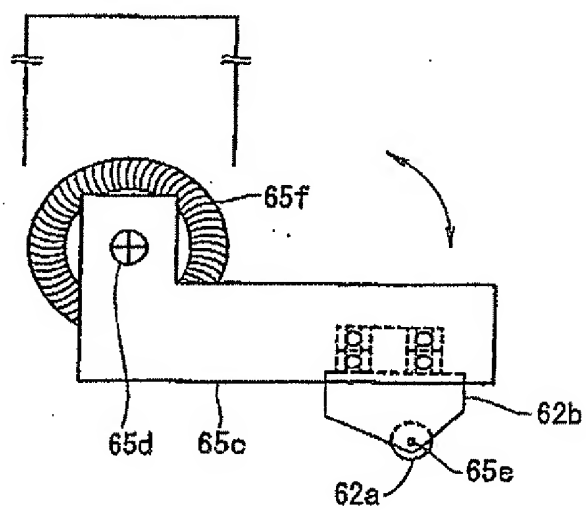


FIG.17

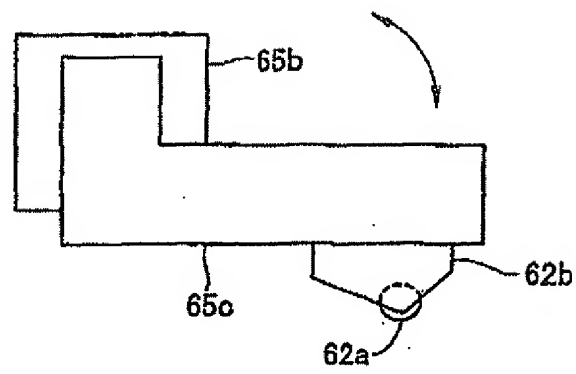


FIG.18

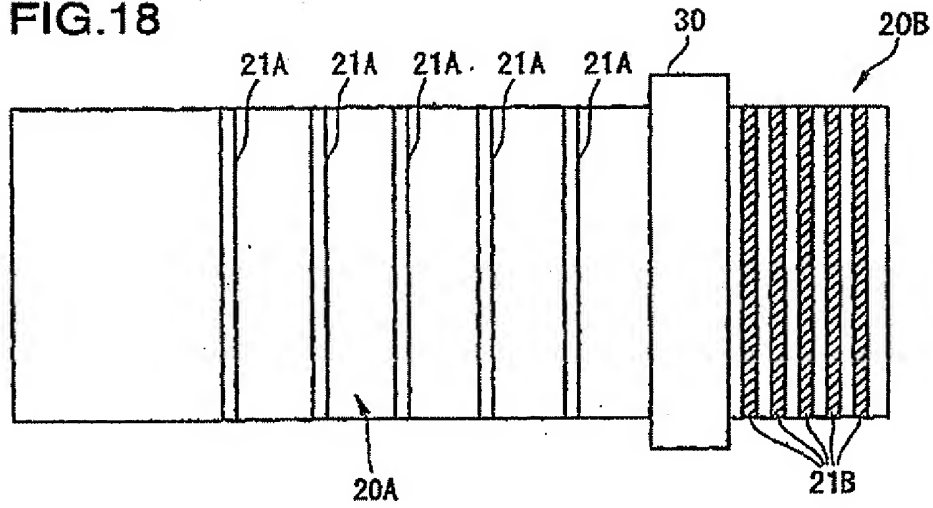


FIG.19

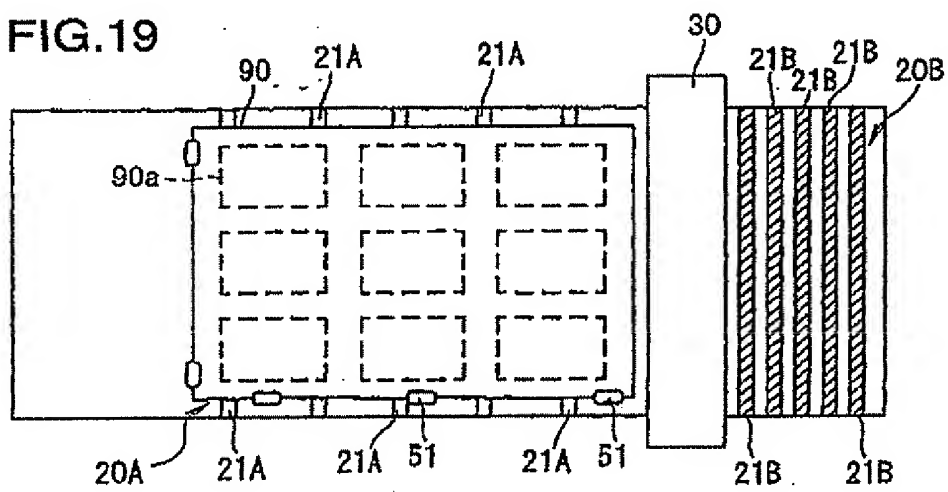


FIG.20

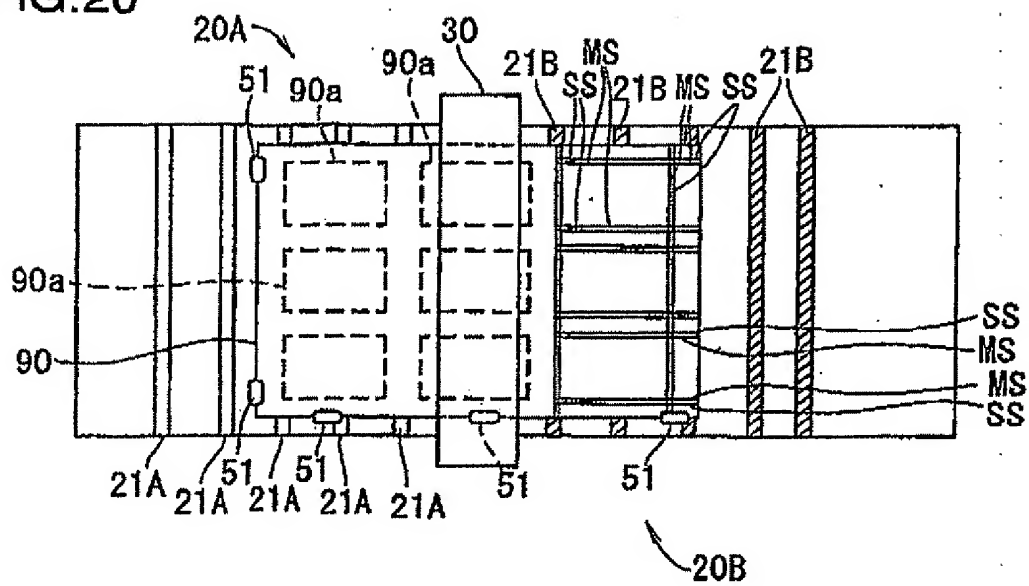


FIG.21

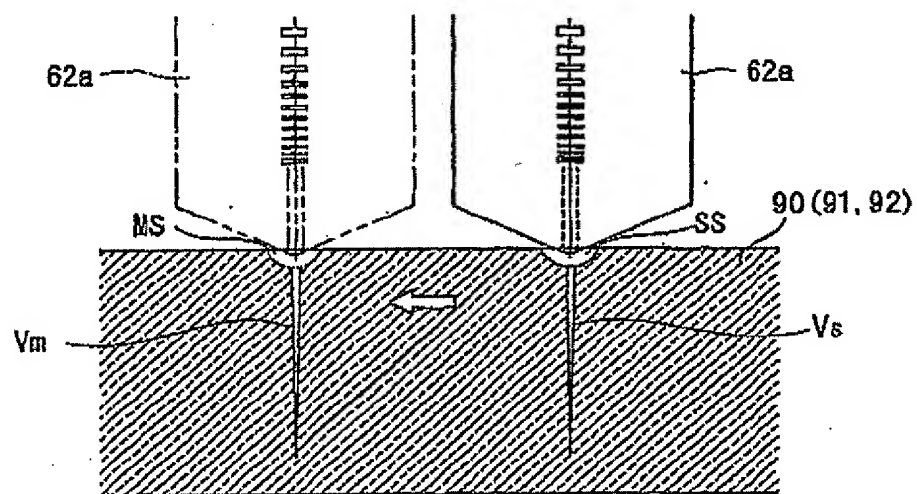


FIG.22

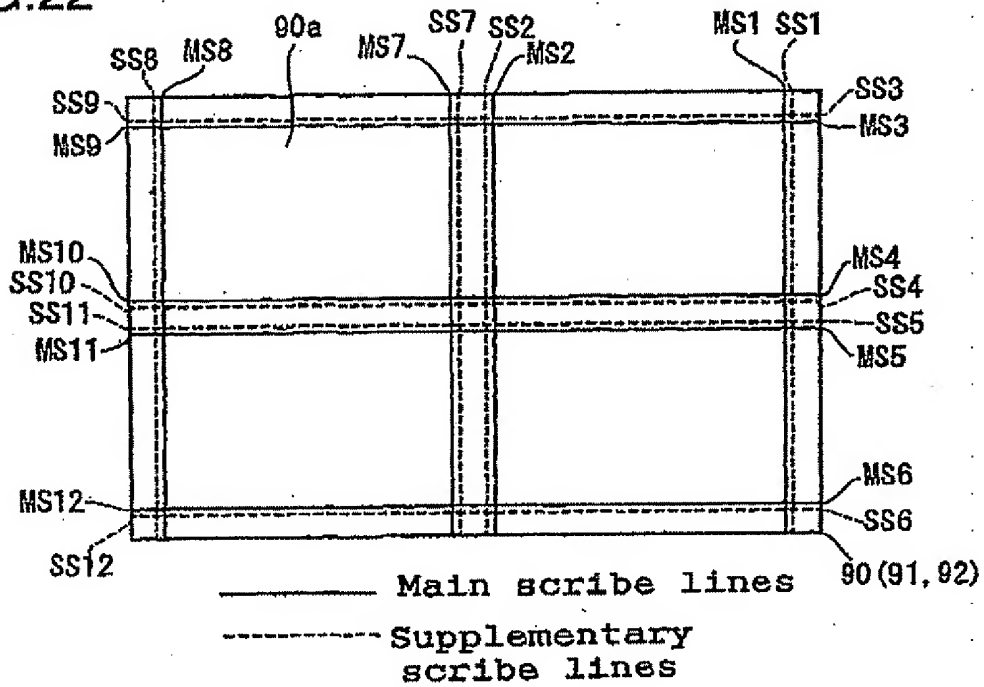


FIG.23

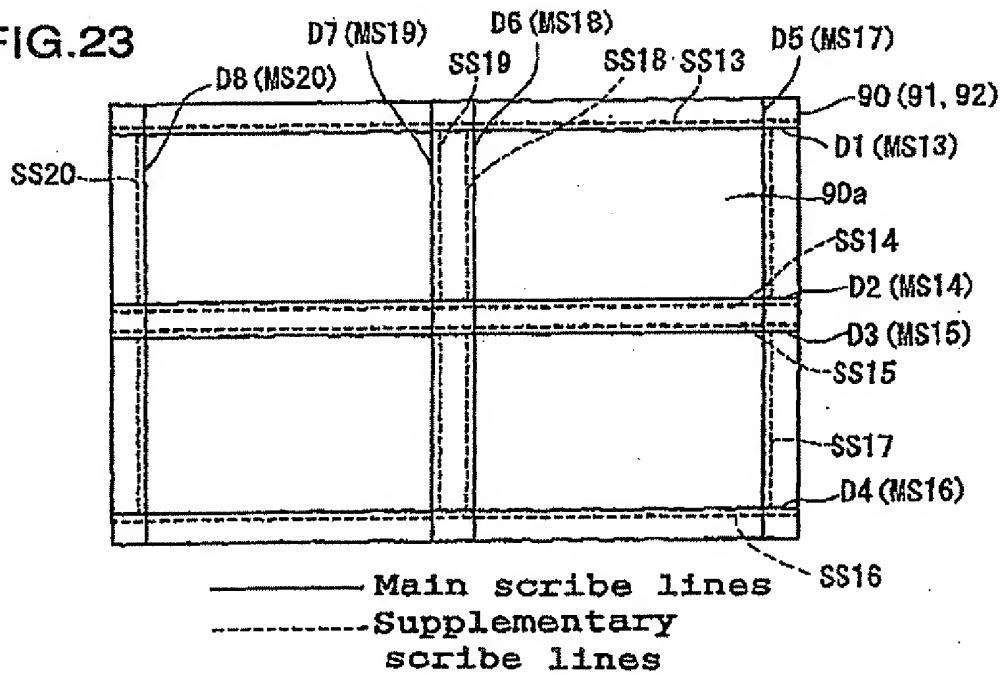




FIG.24

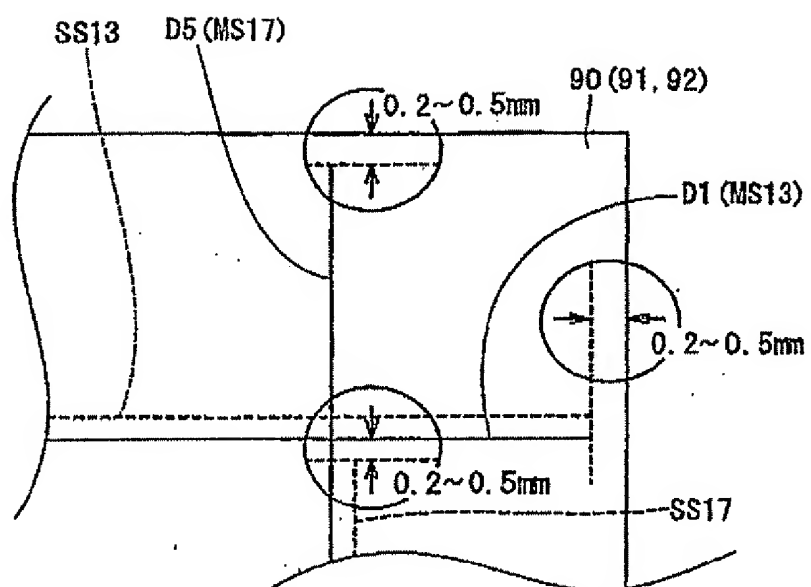


FIG.25

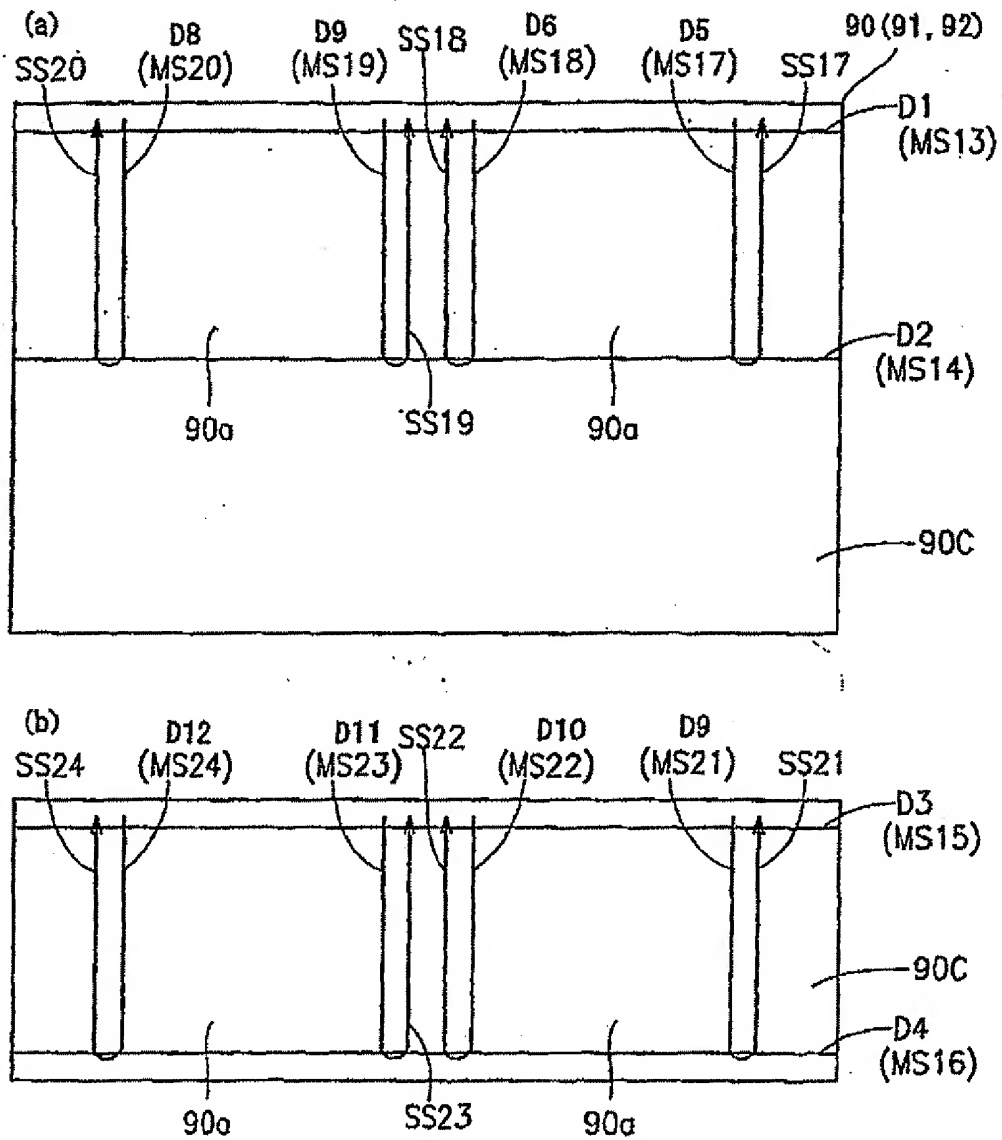


FIG.26

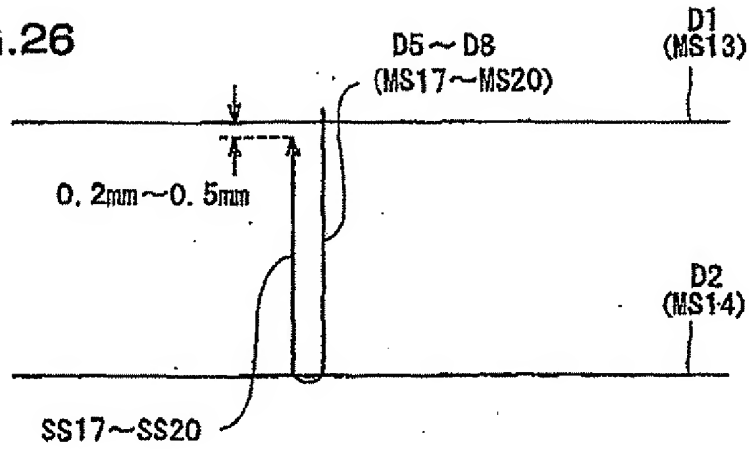


FIG.27

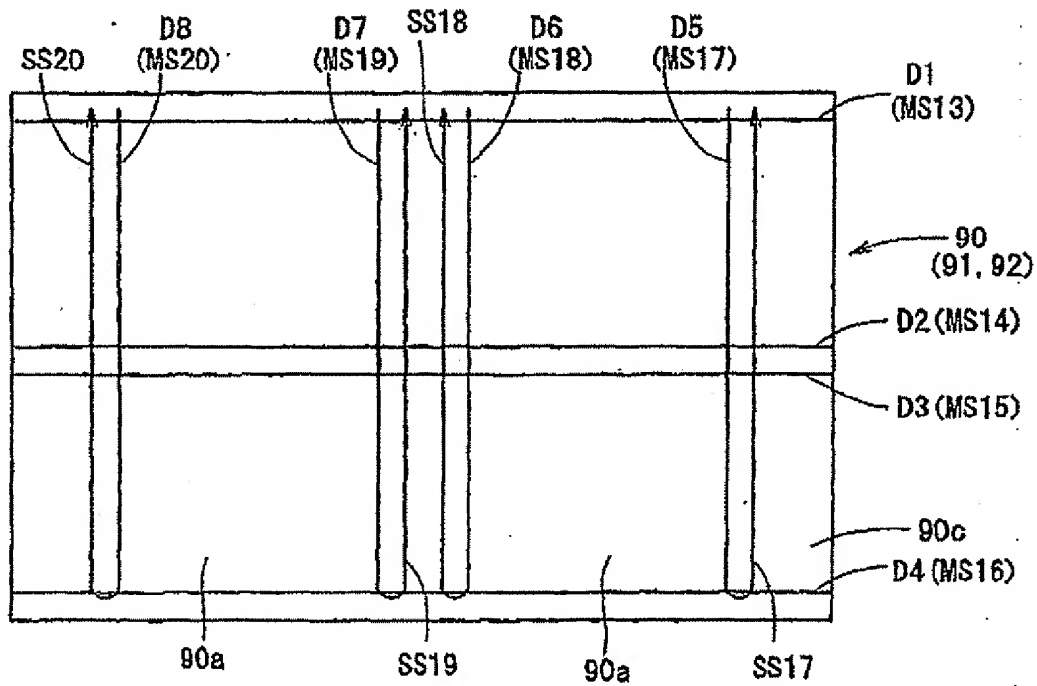


FIG.28

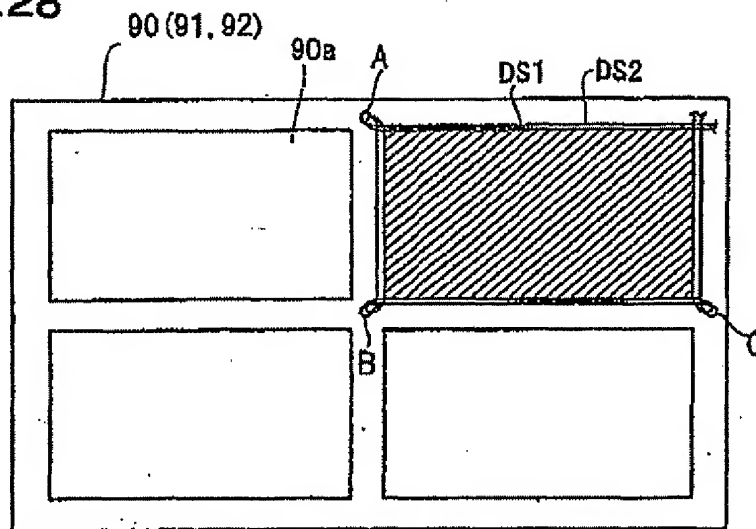


FIG.29

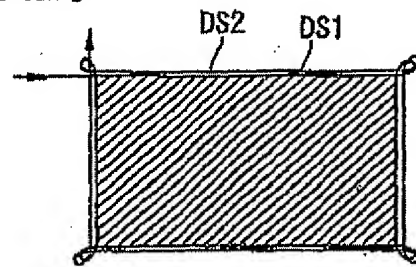


FIG.30

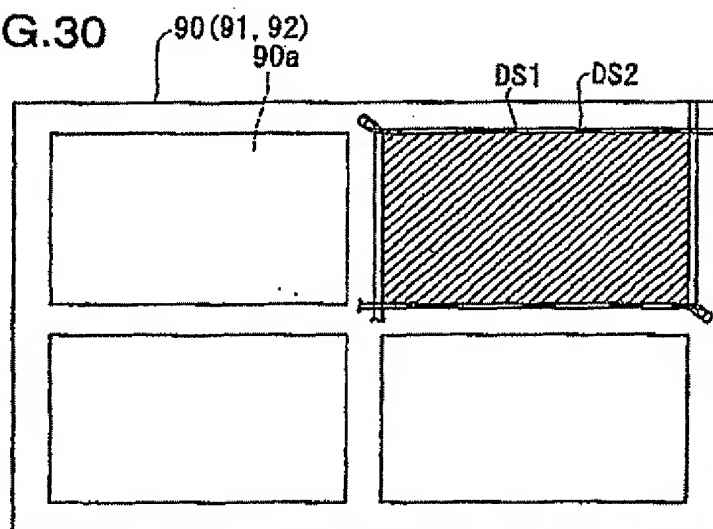


FIG.31

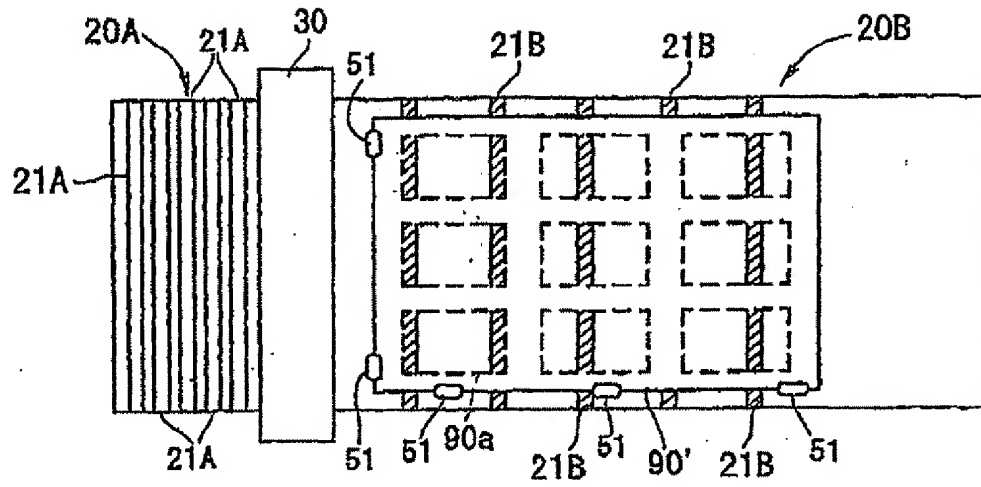
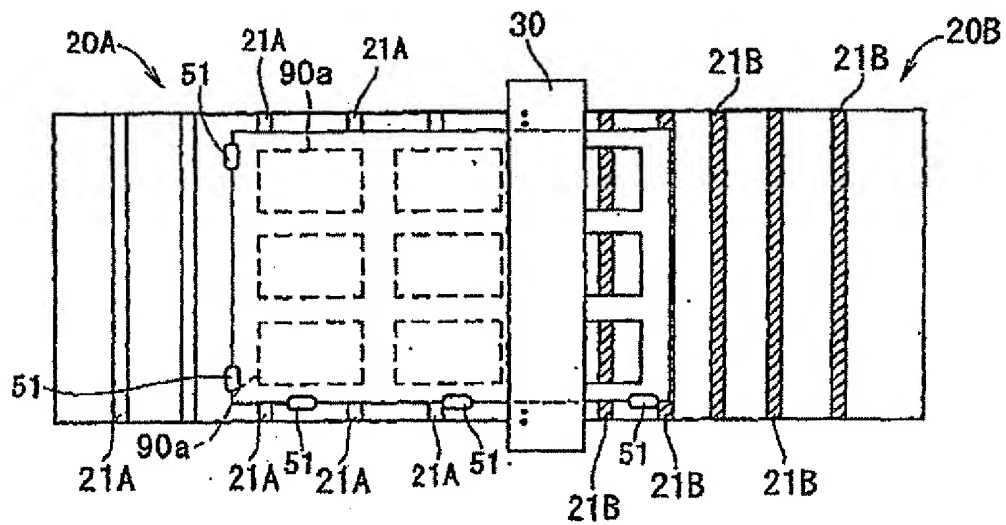


FIG.32





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FIG.33

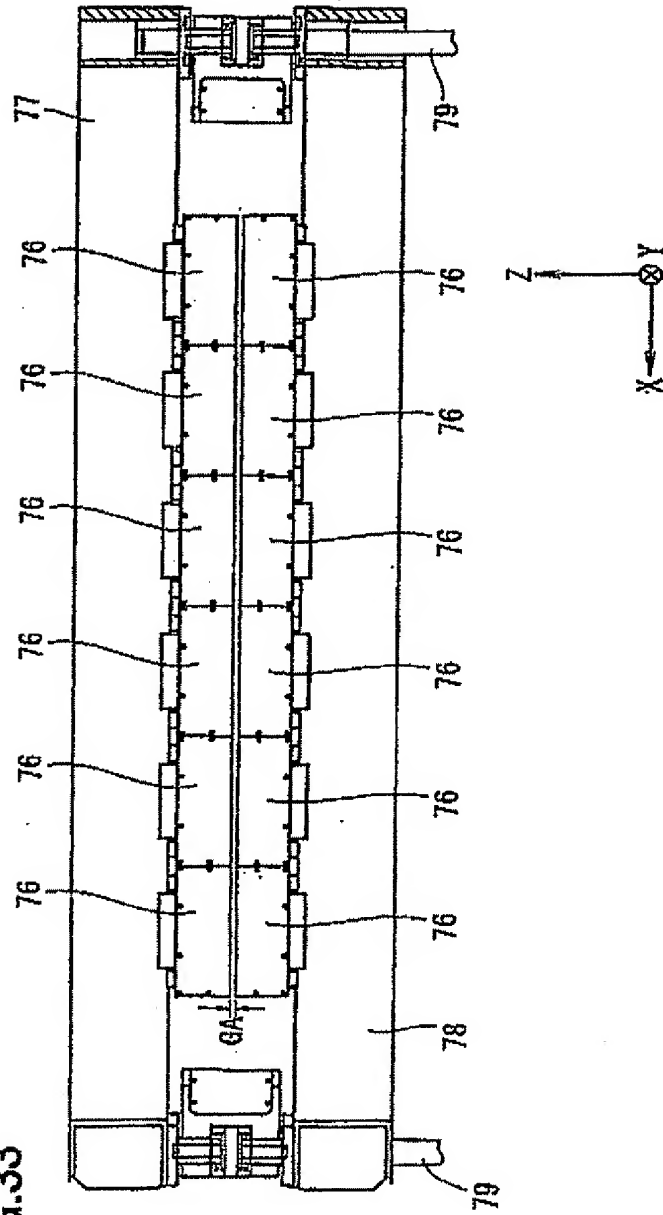


FIG.34

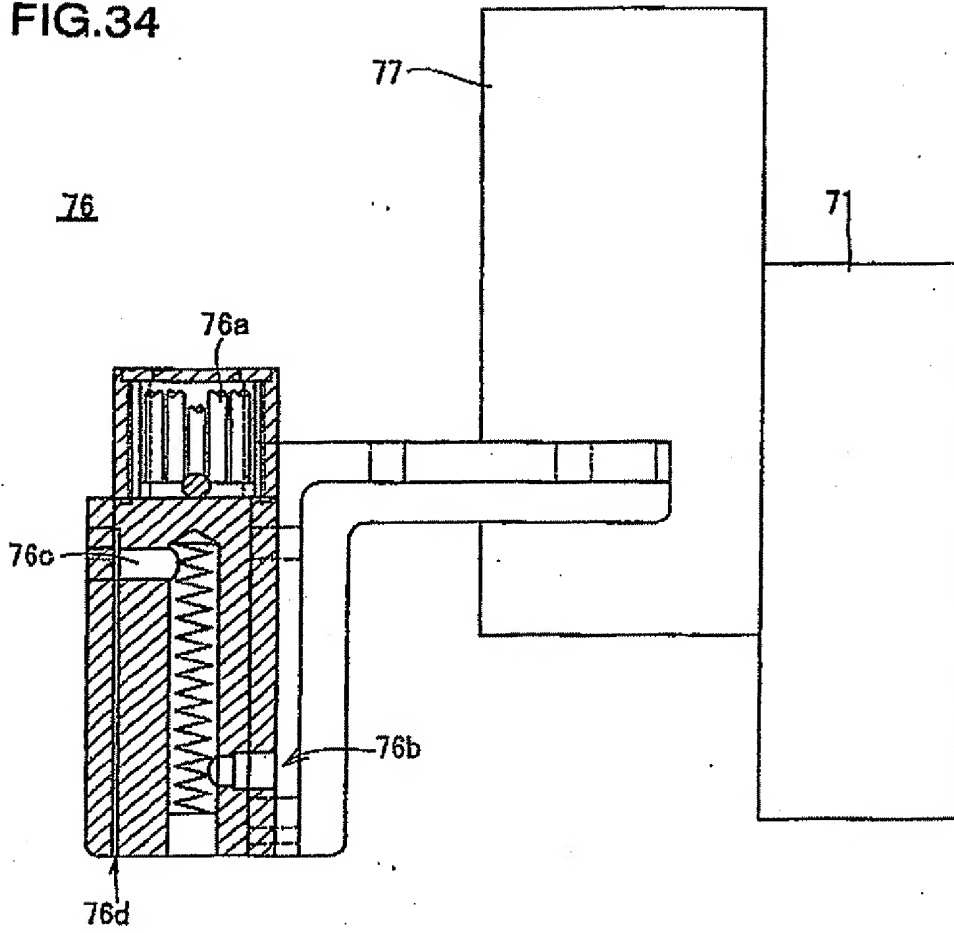


FIG.35

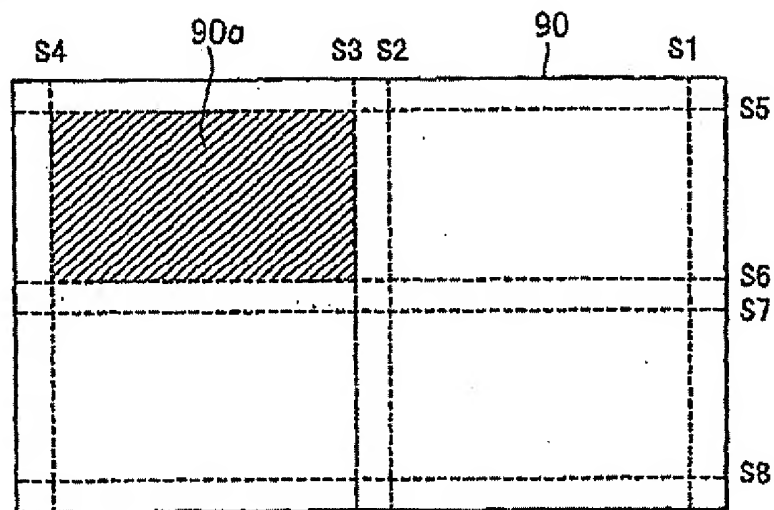


FIG.36

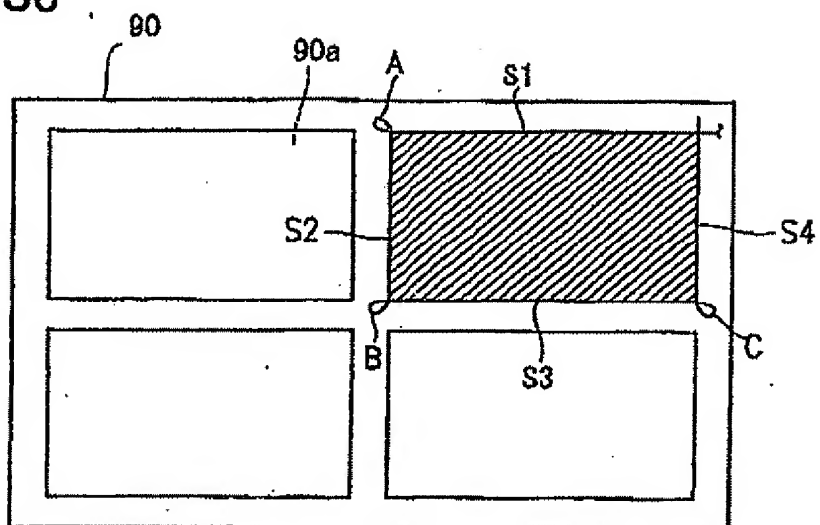
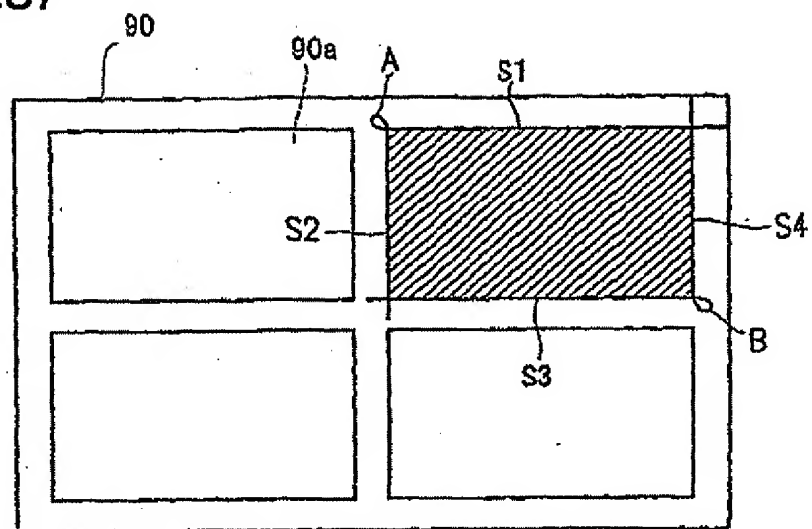
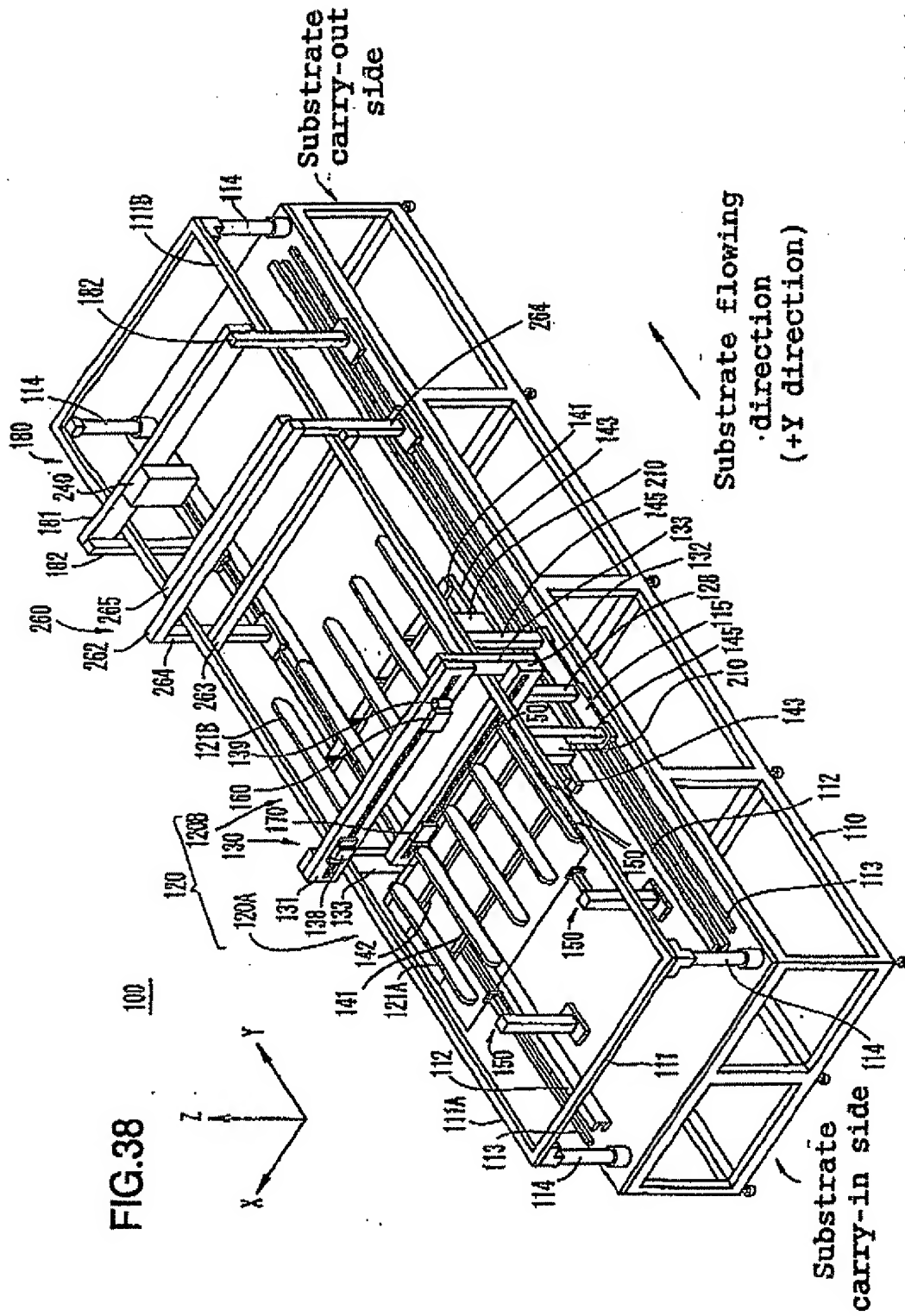


FIG.37







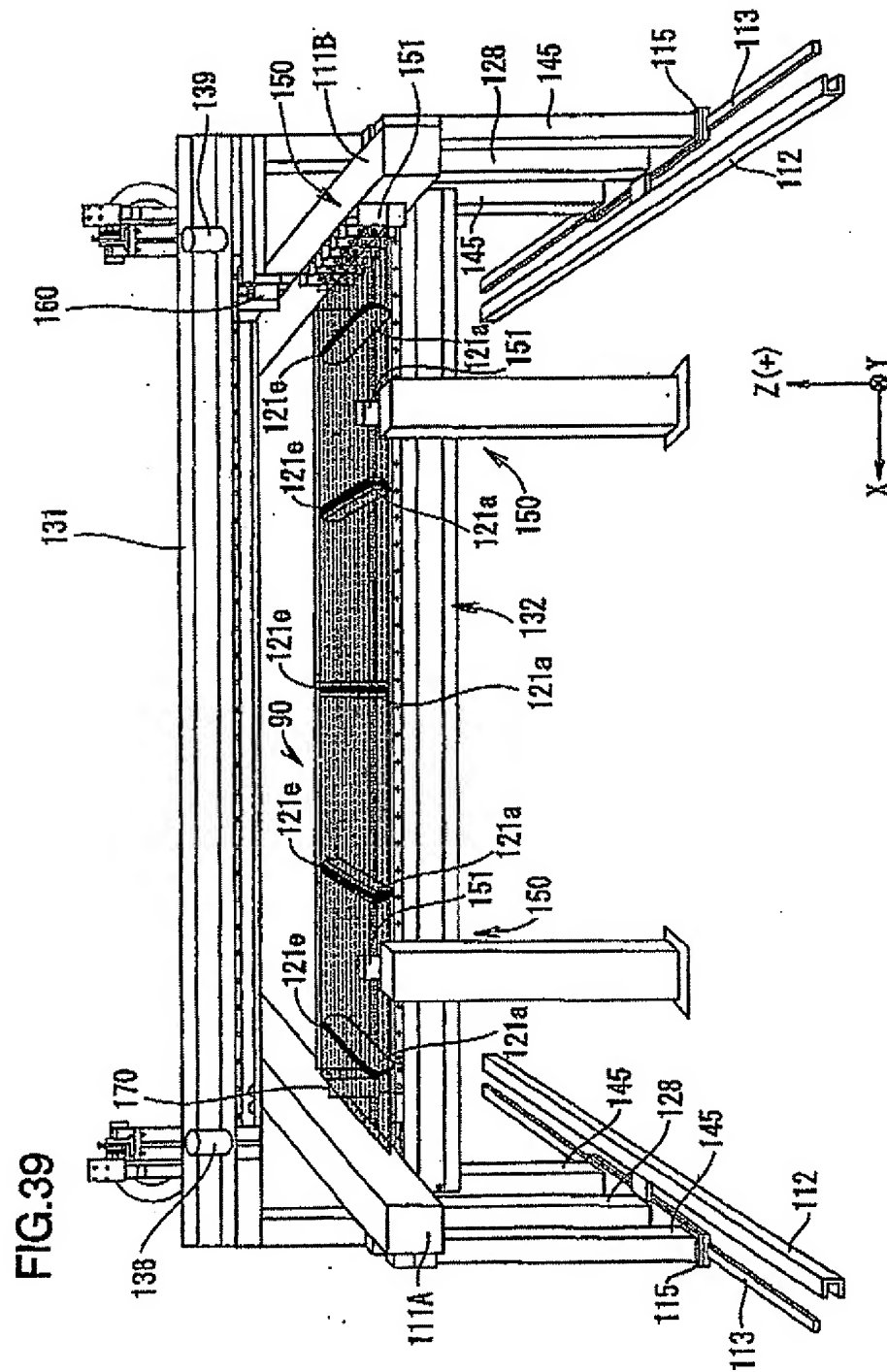


FIG.40

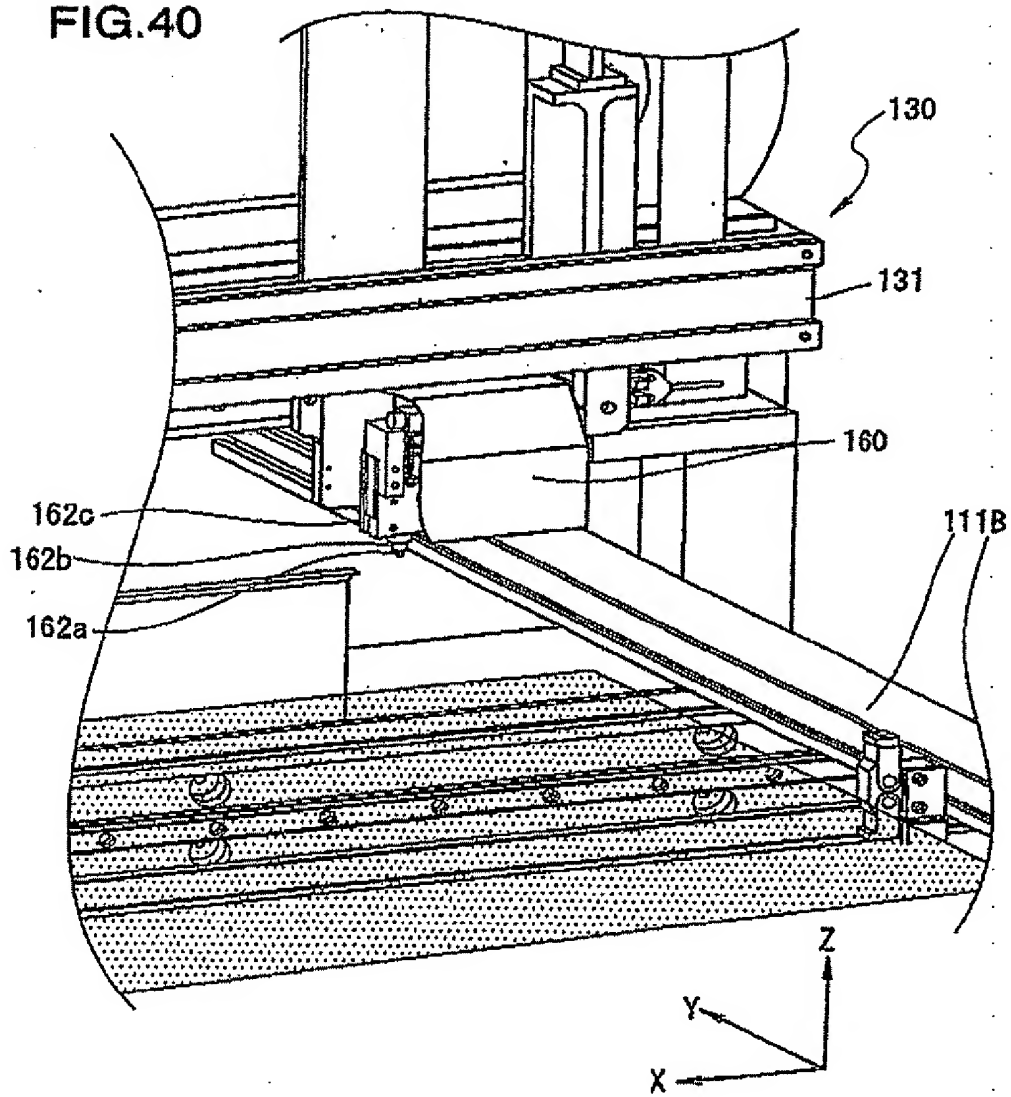


FIG.41

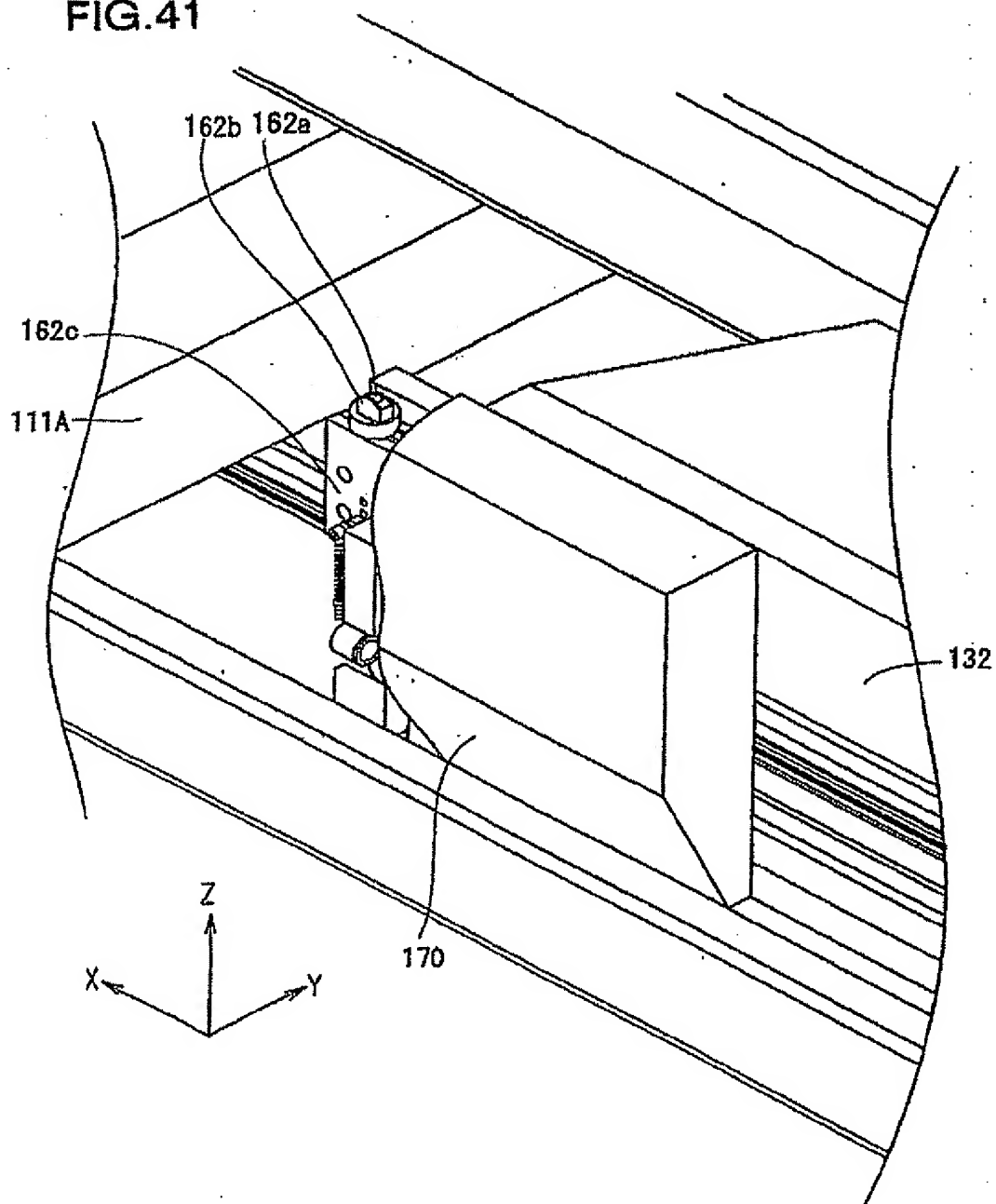
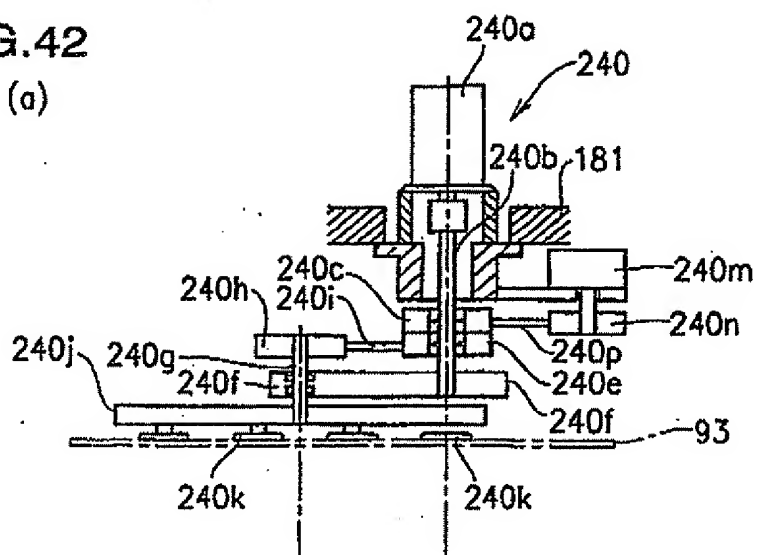


FIG. 42

(a)



(b)

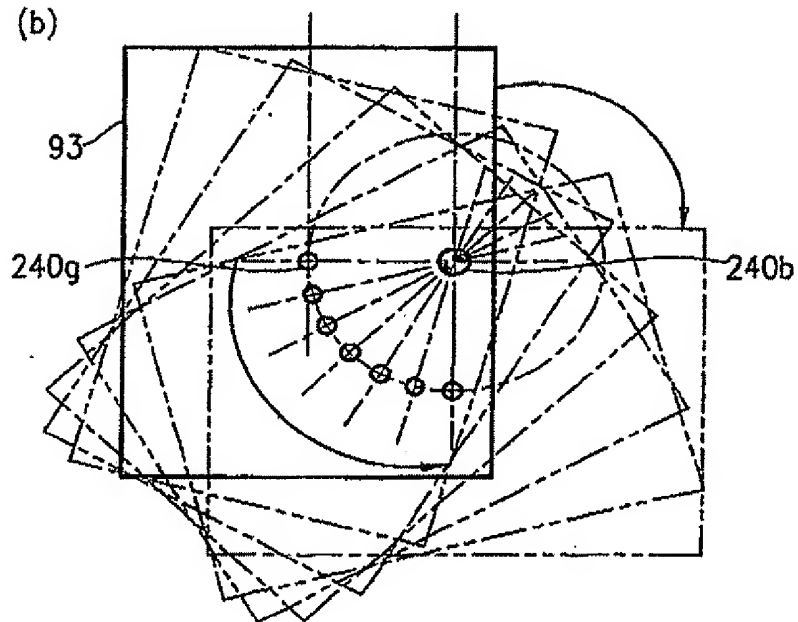


FIG.43

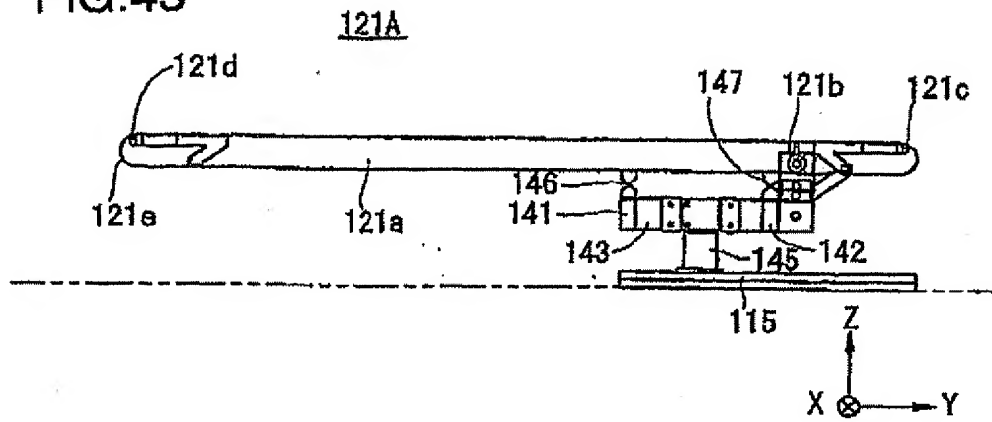


FIG.44

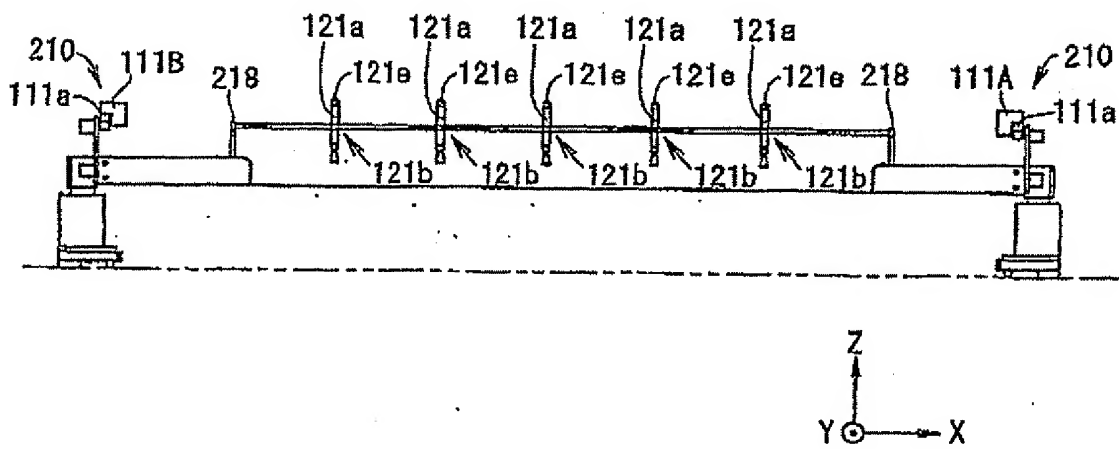


FIG.45

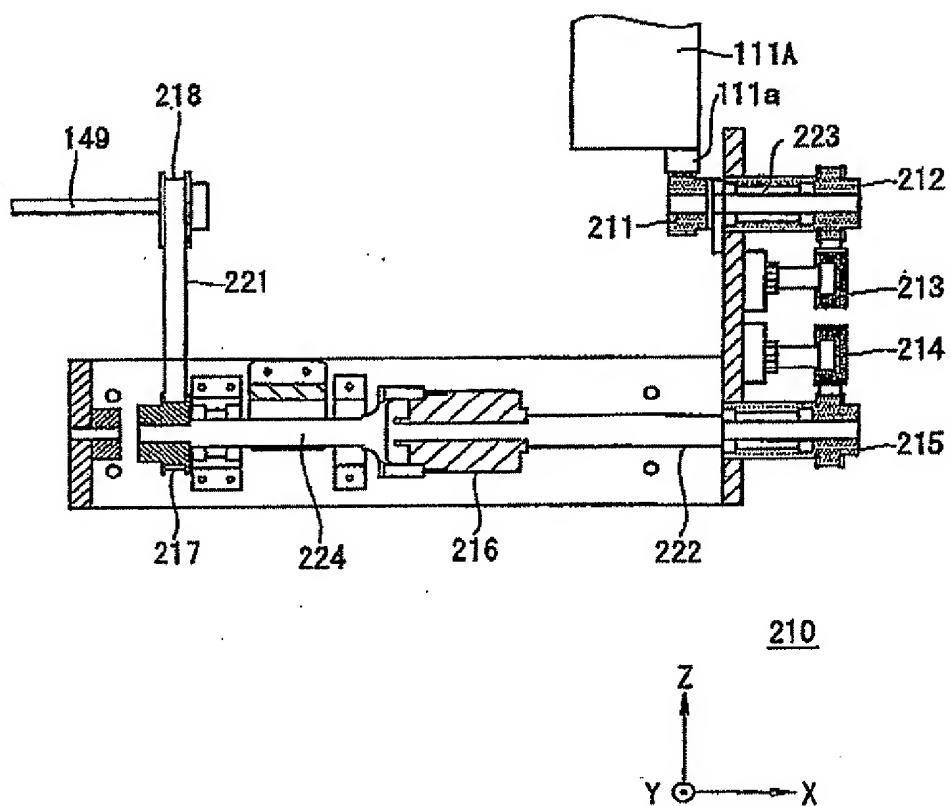
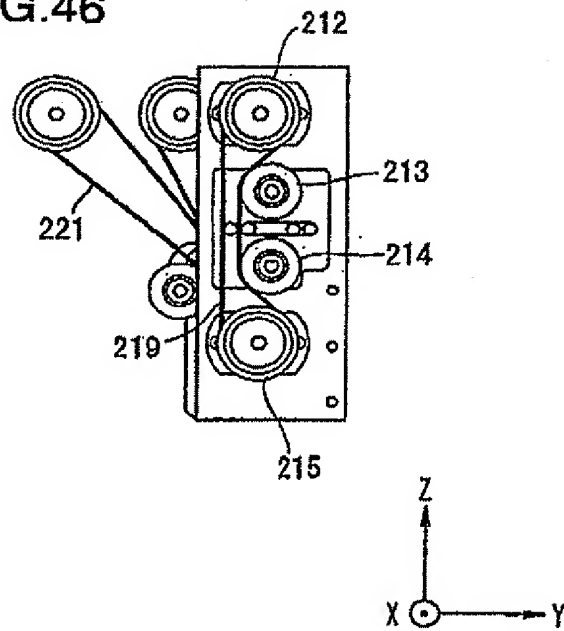


FIG.46



260  
FIG.47

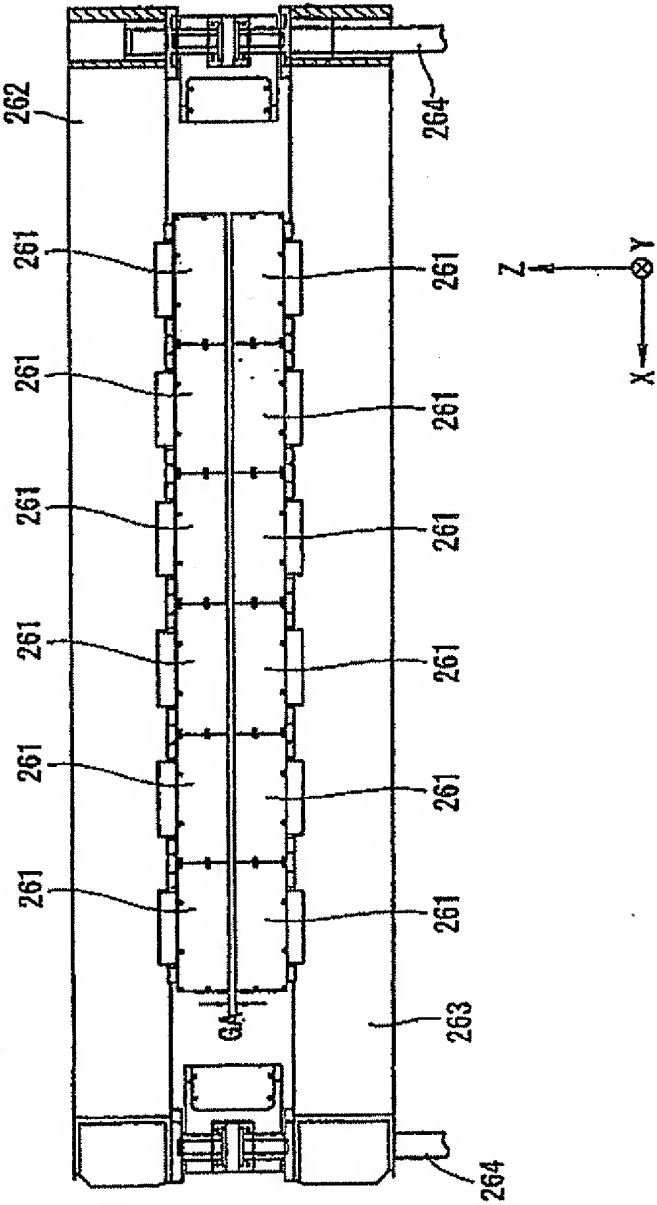
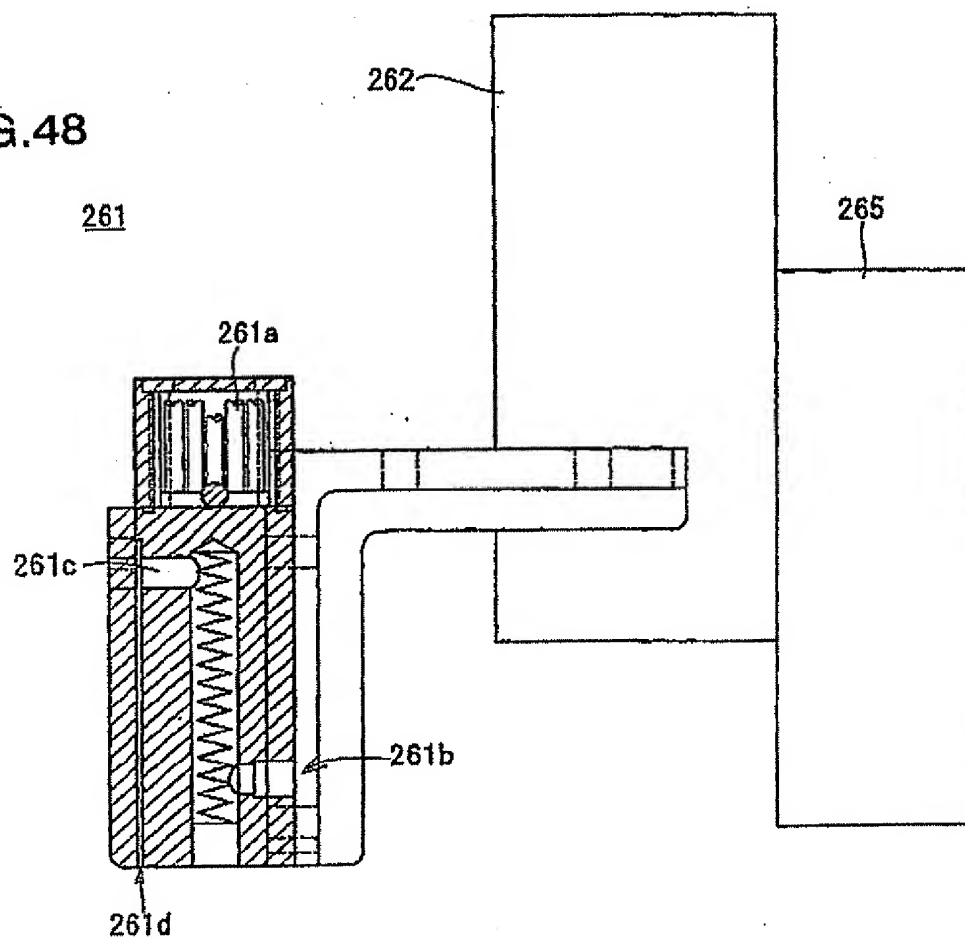
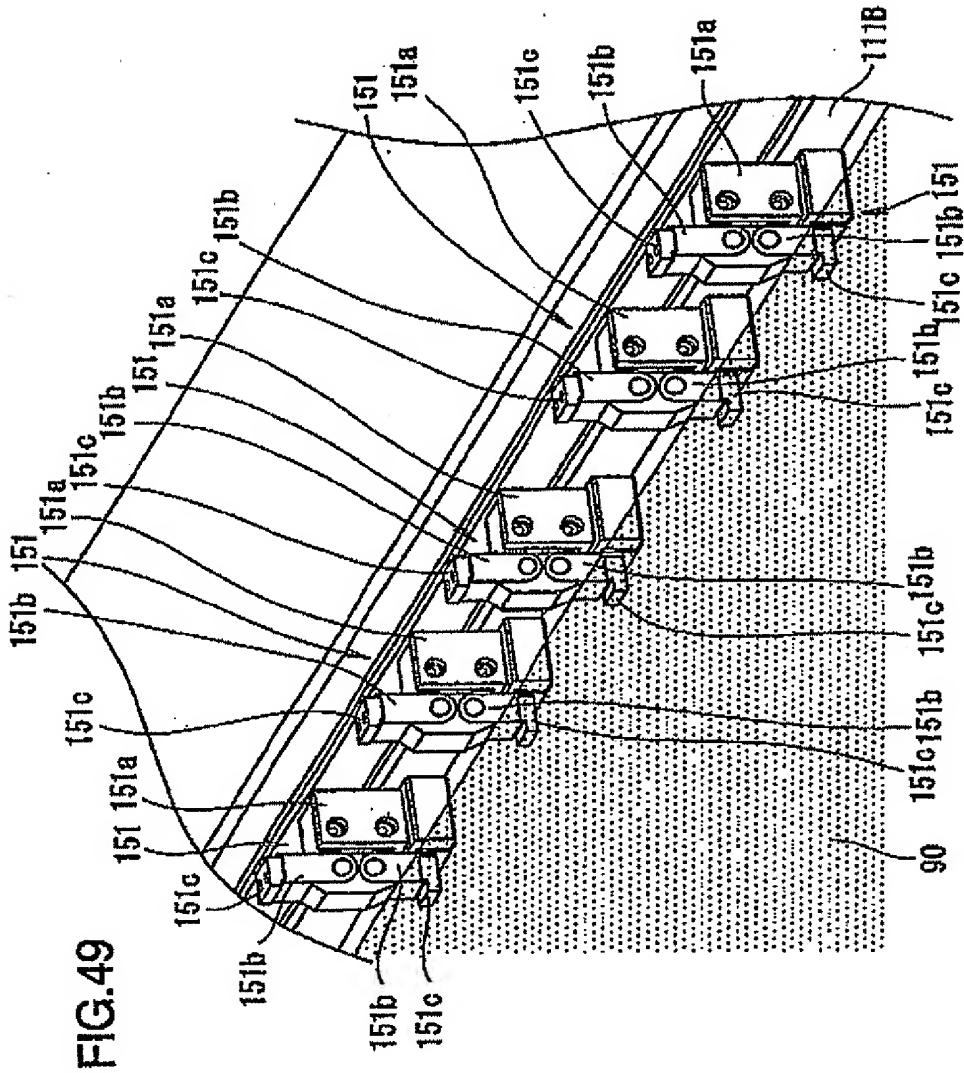




FIG.48





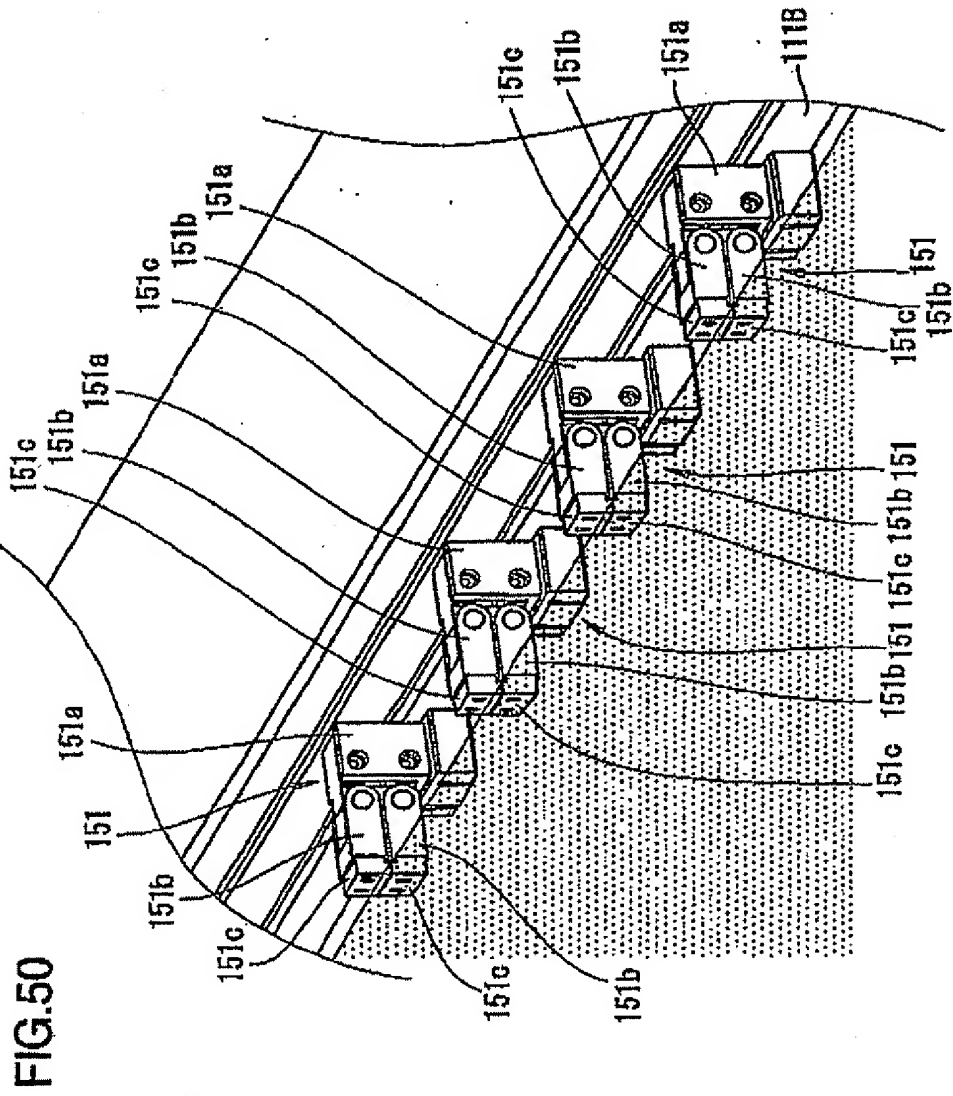


FIG.51

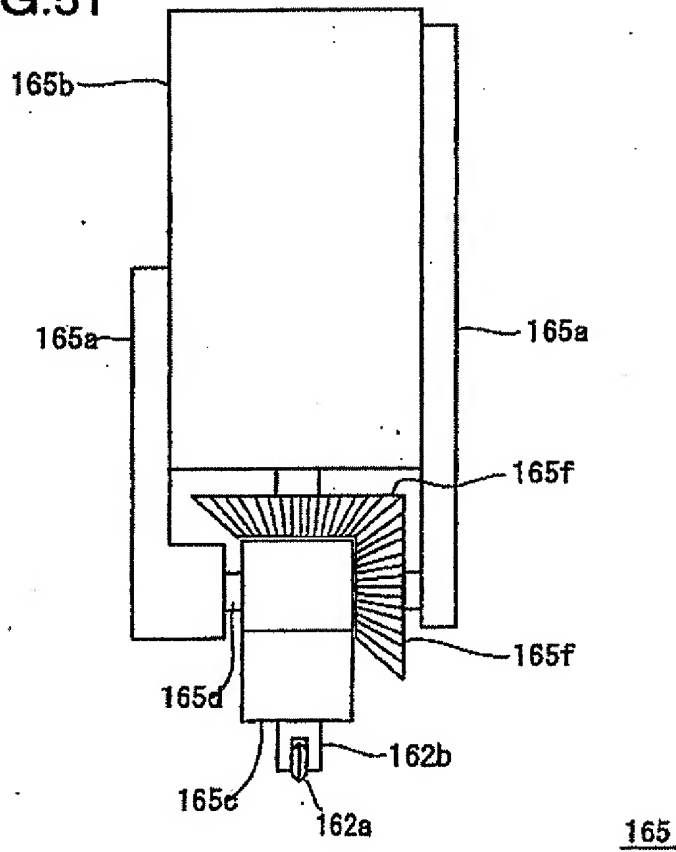


FIG.52

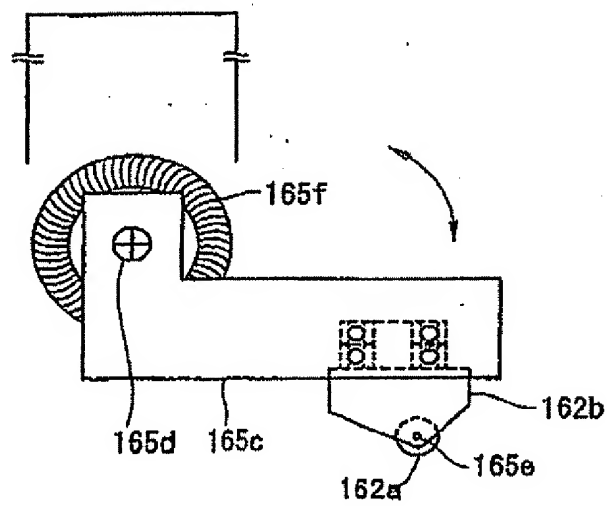
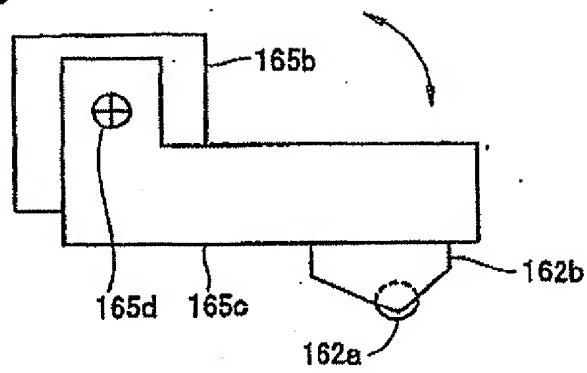
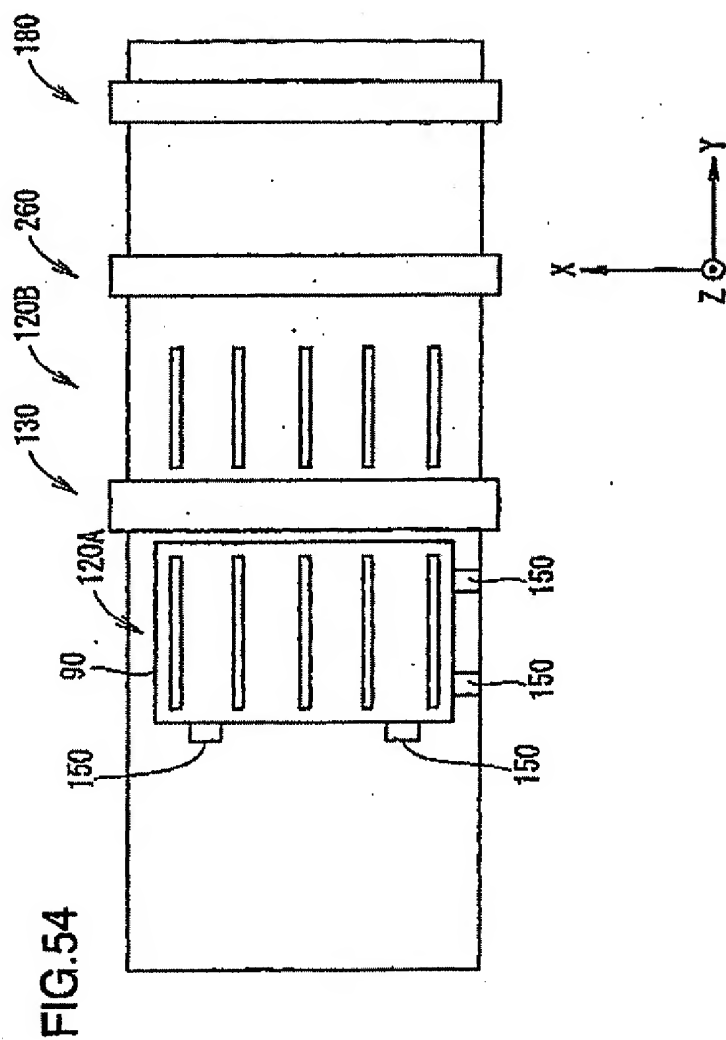


FIG.53





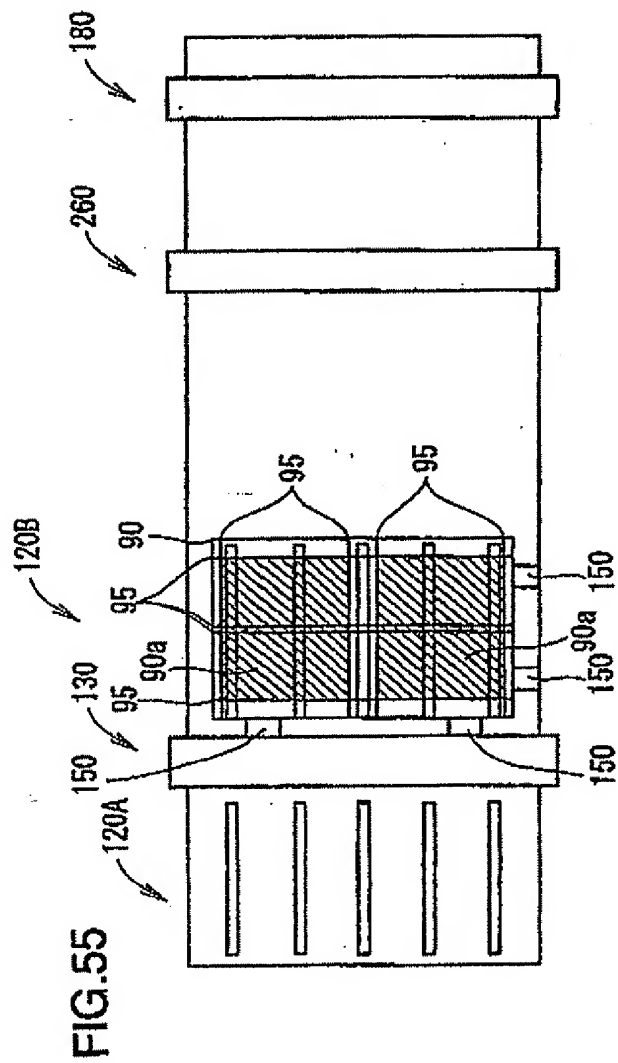


FIG.56

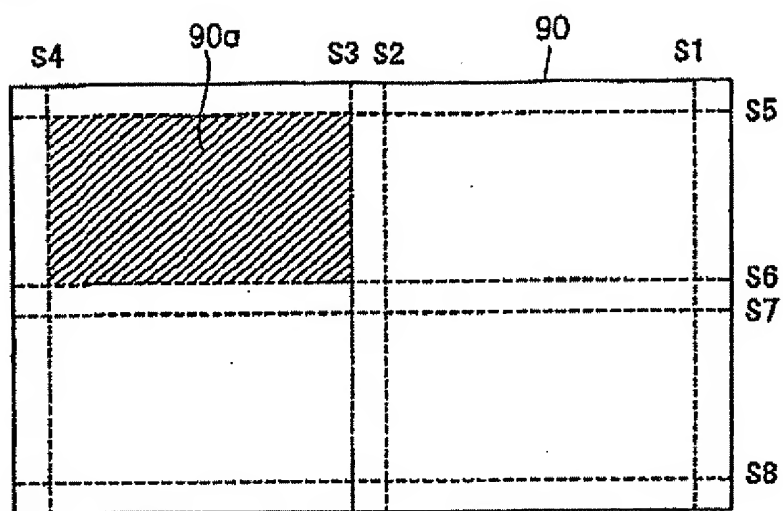




FIG.57

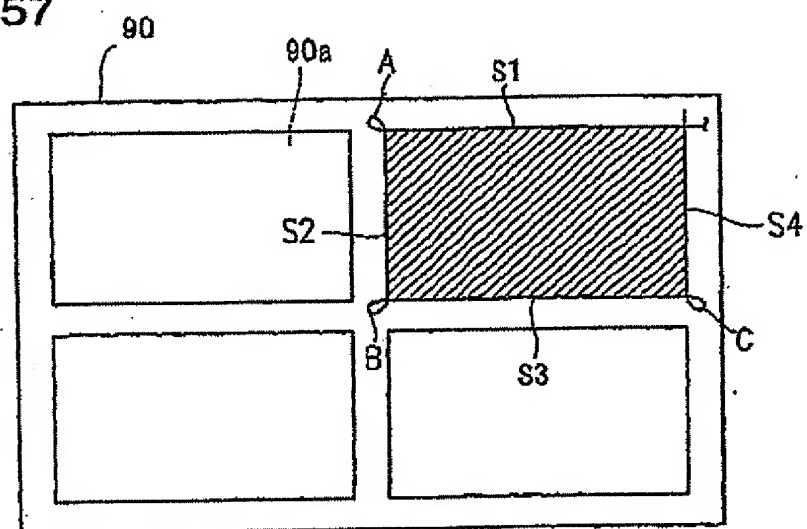
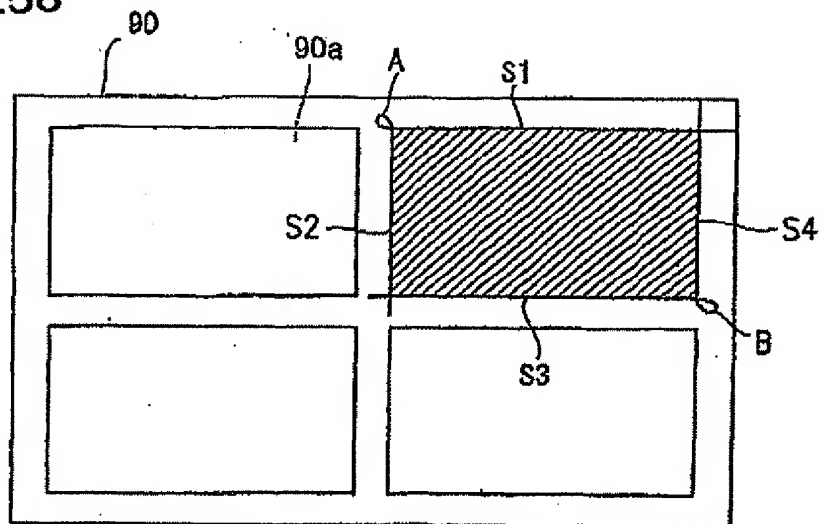
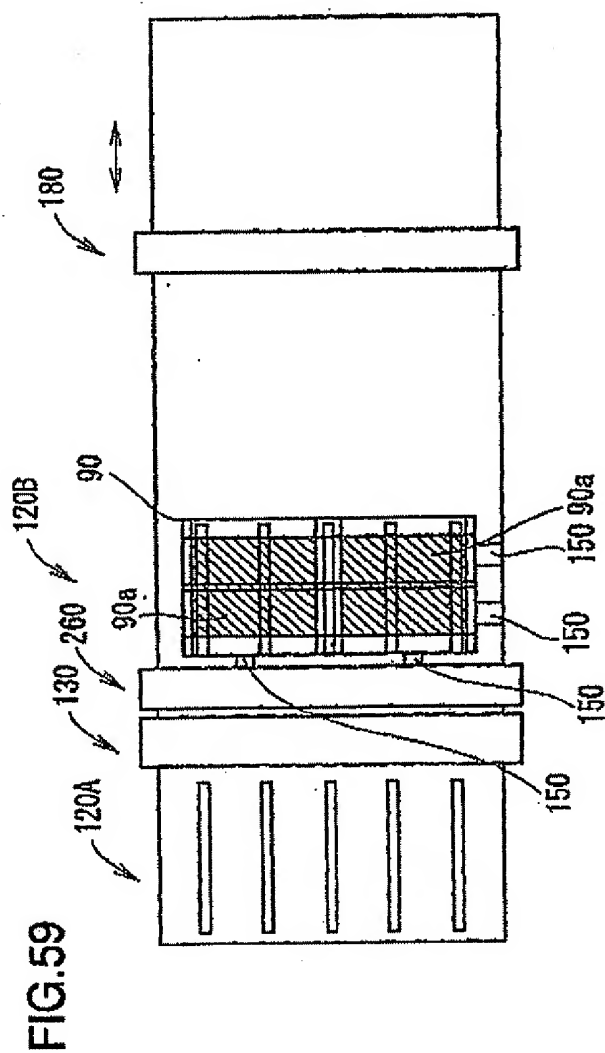


FIG.58





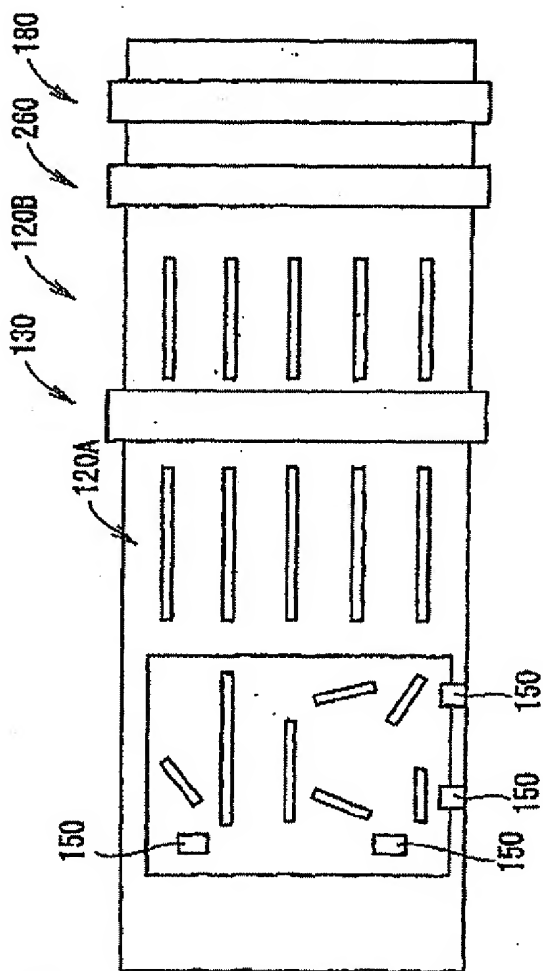


FIG. 60

FIG.61

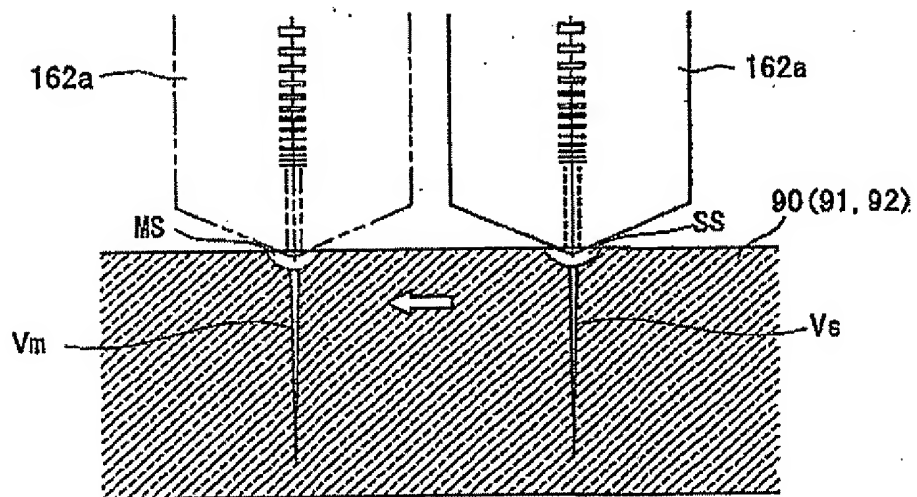


FIG.62

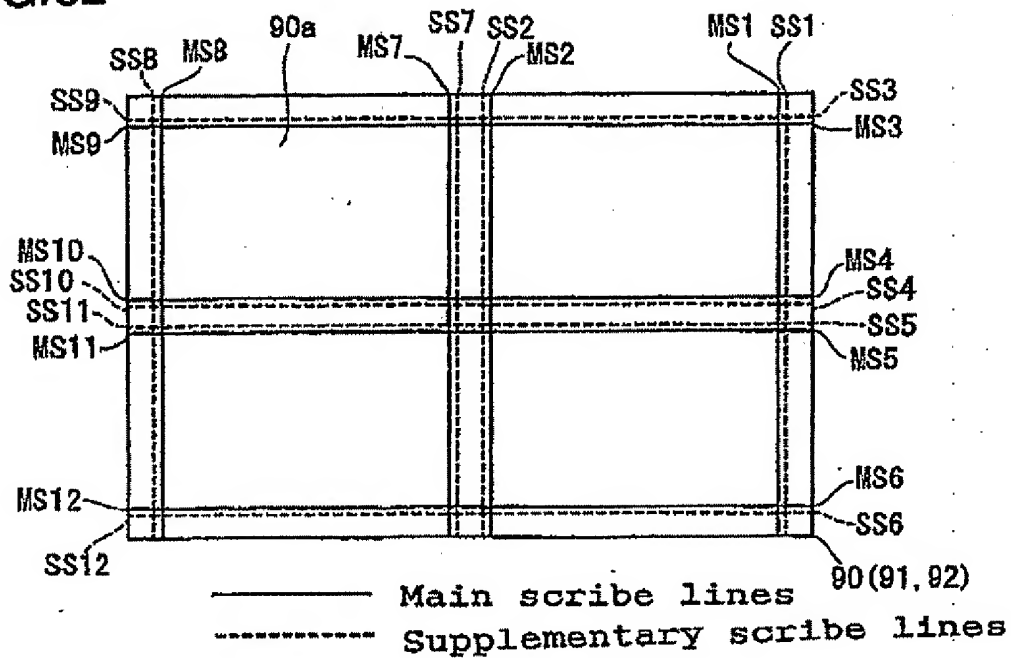


FIG.63

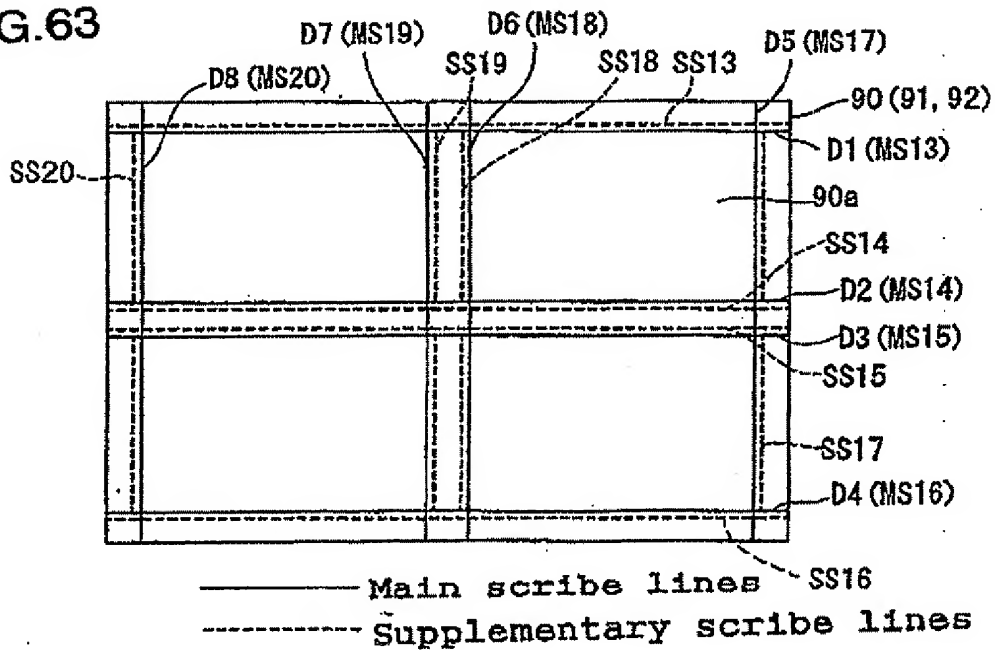


FIG.64

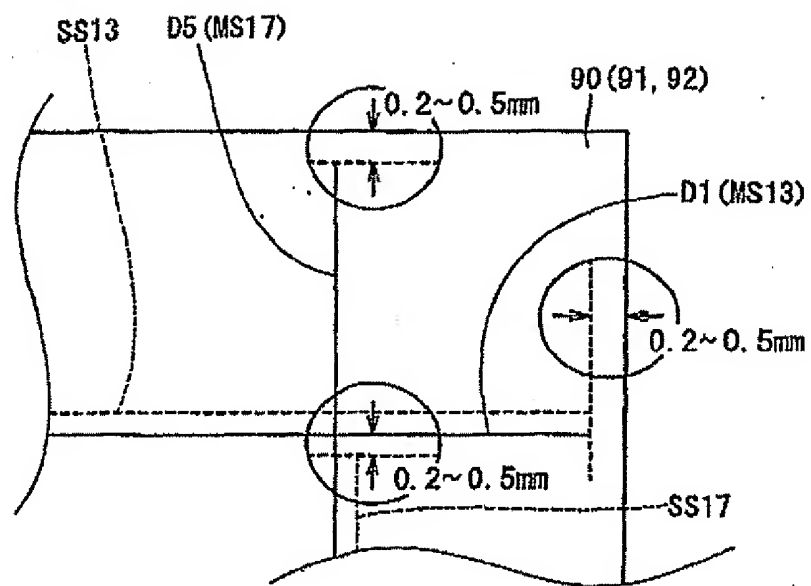


FIG. 65

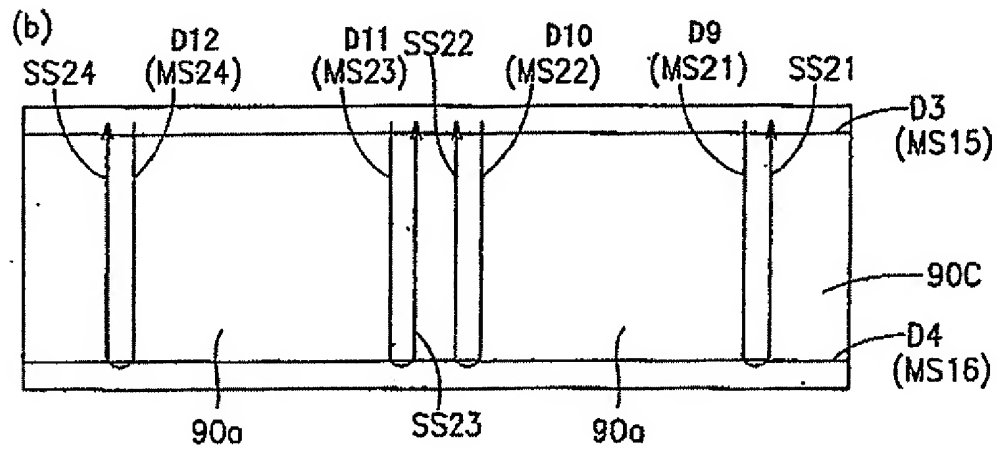
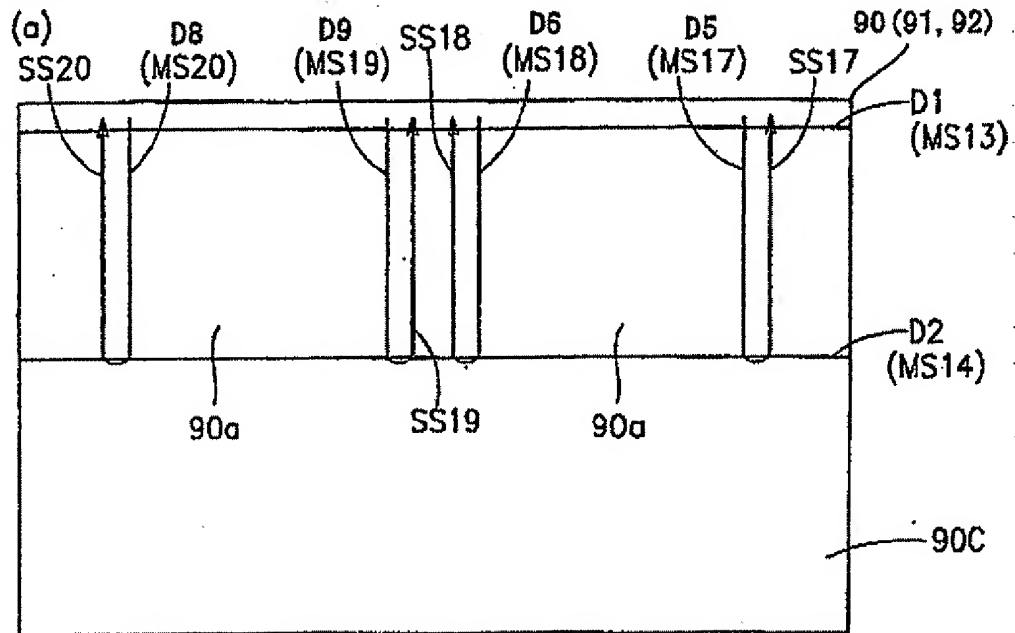




FIG.66

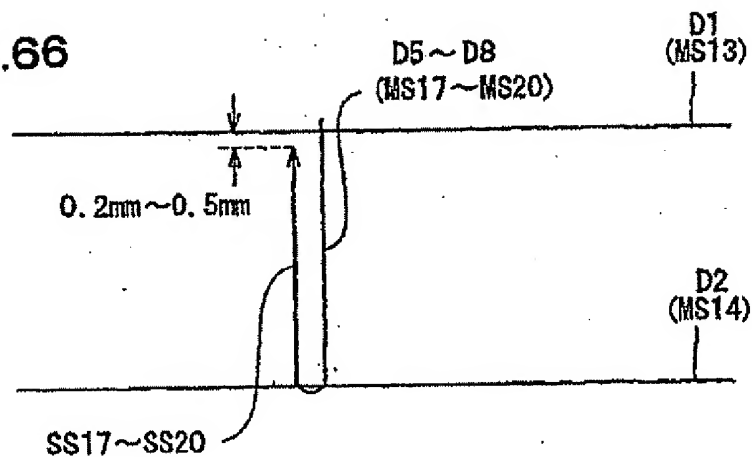


FIG.67

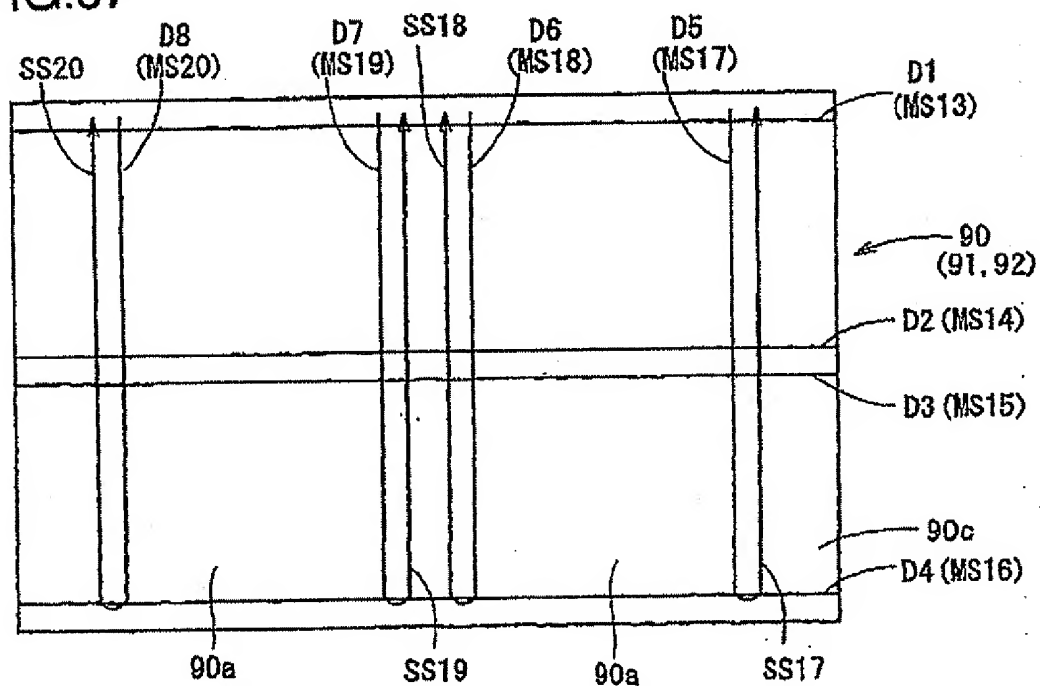


FIG.68

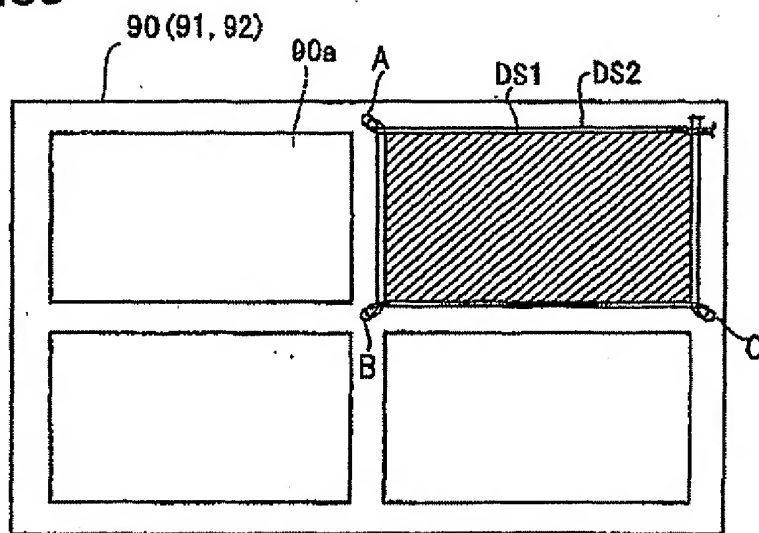


FIG.69

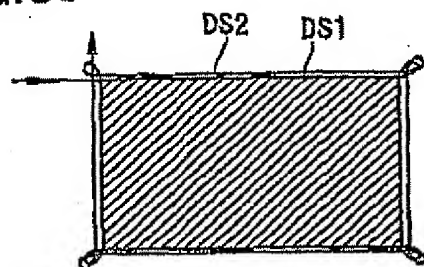
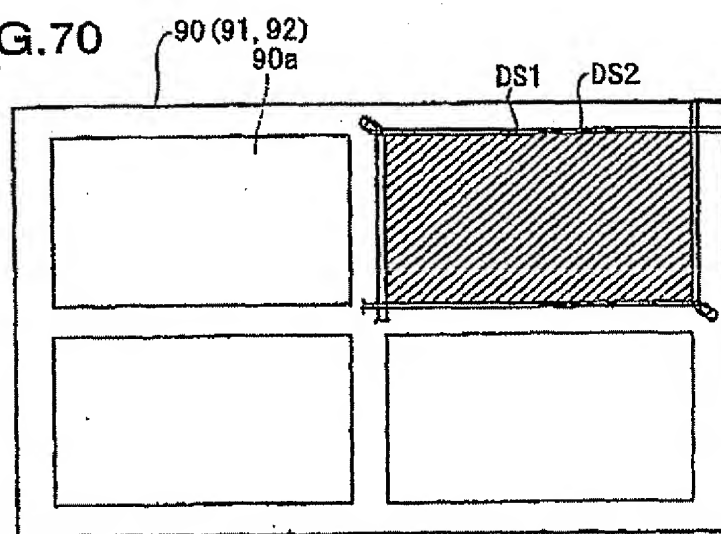
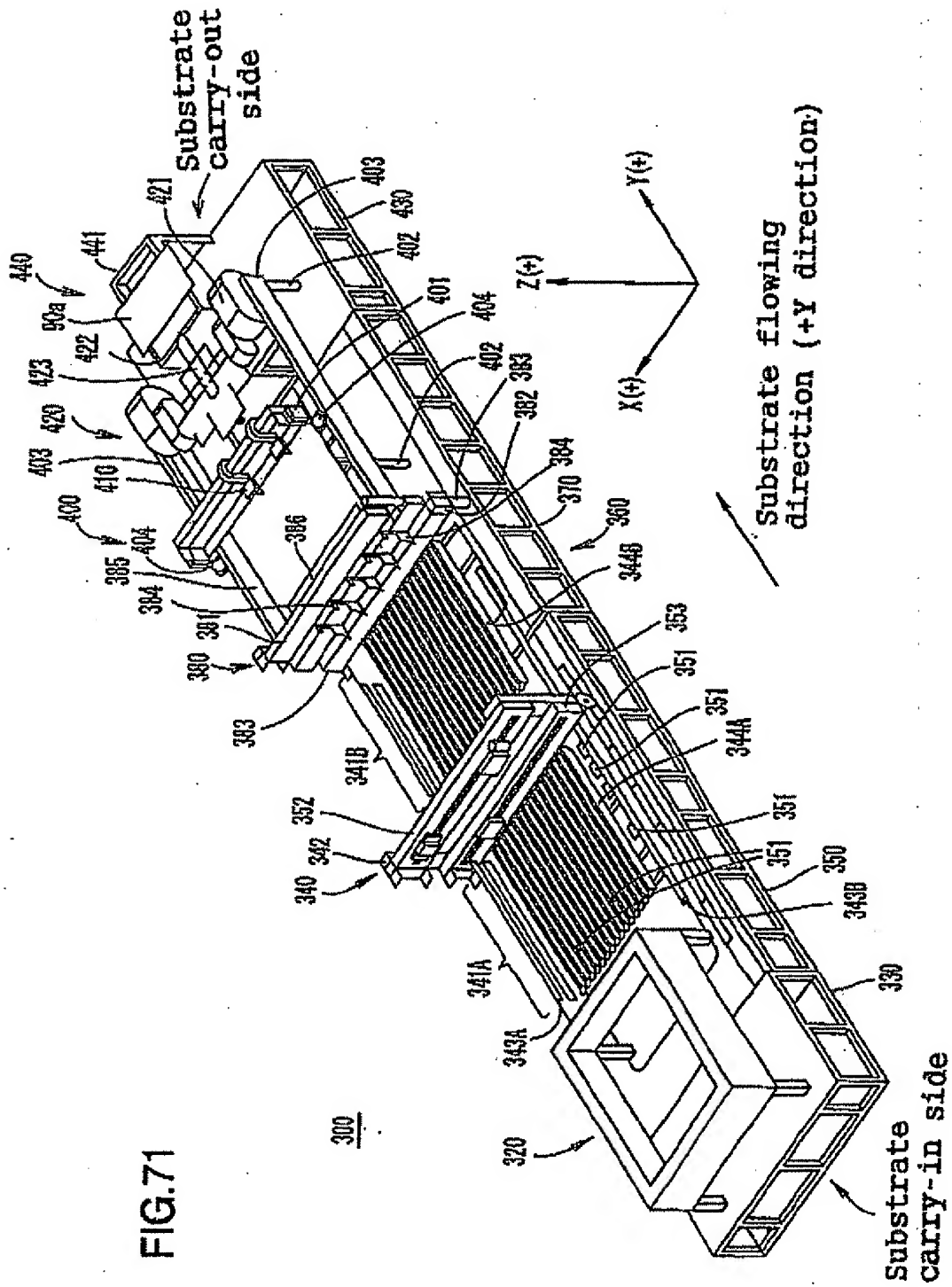
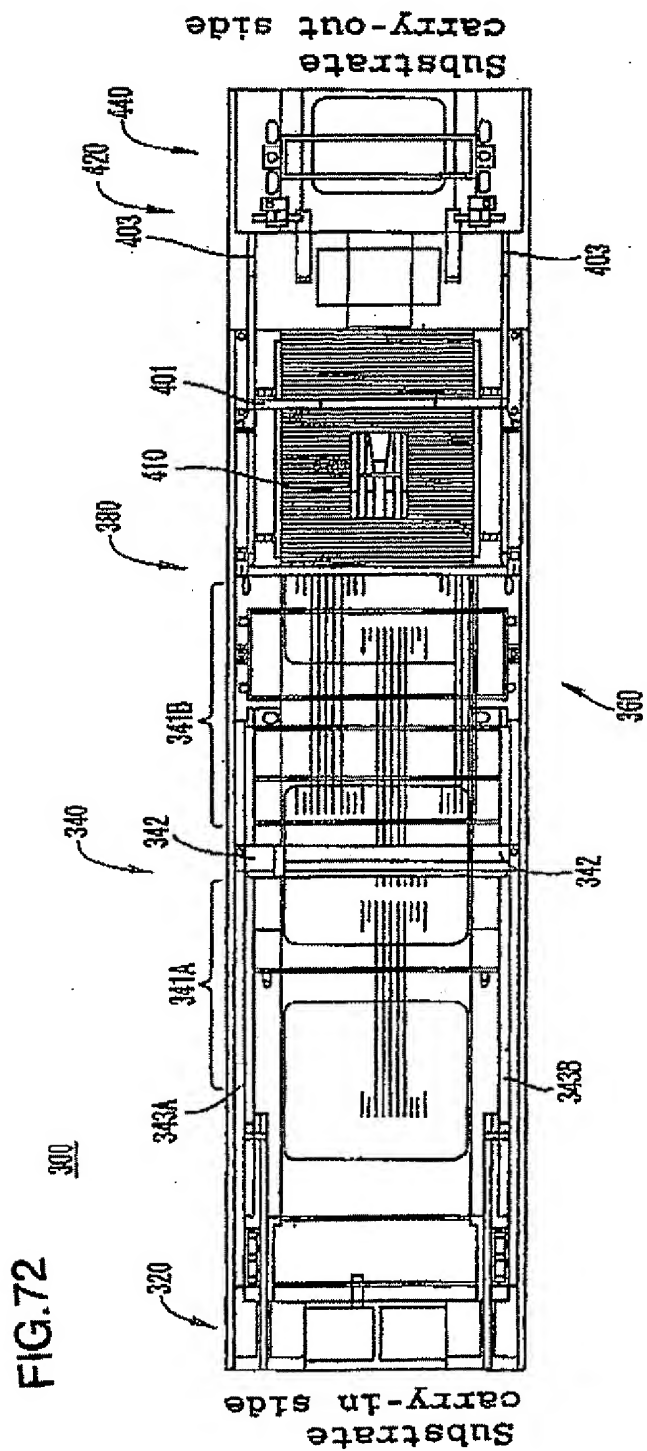
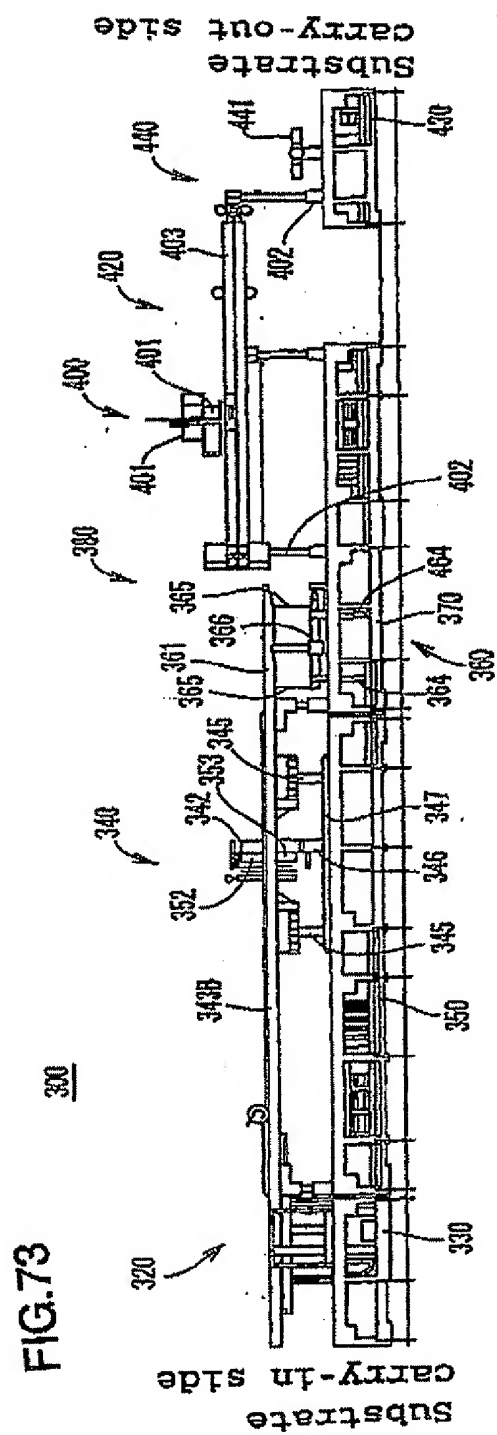


FIG.70









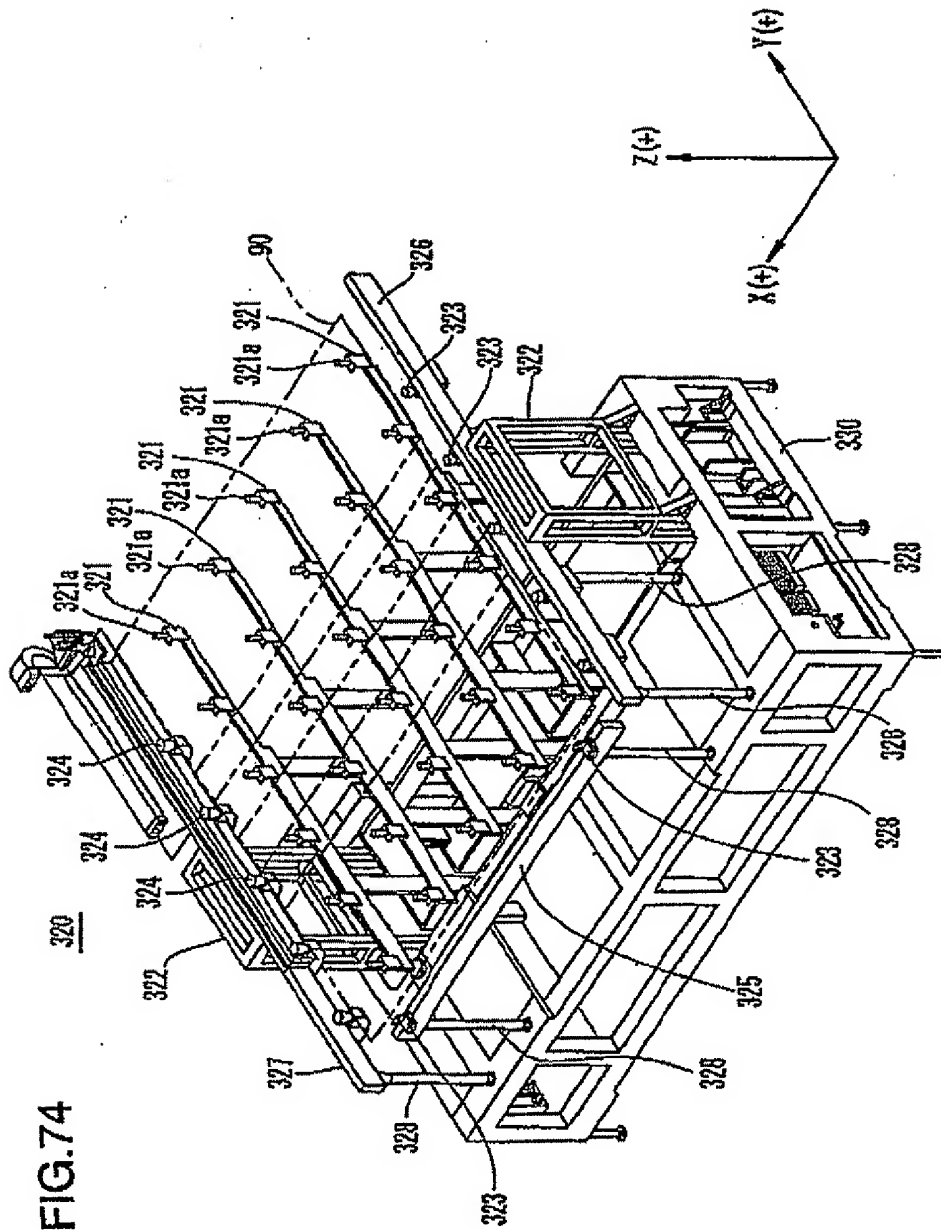


FIG.75

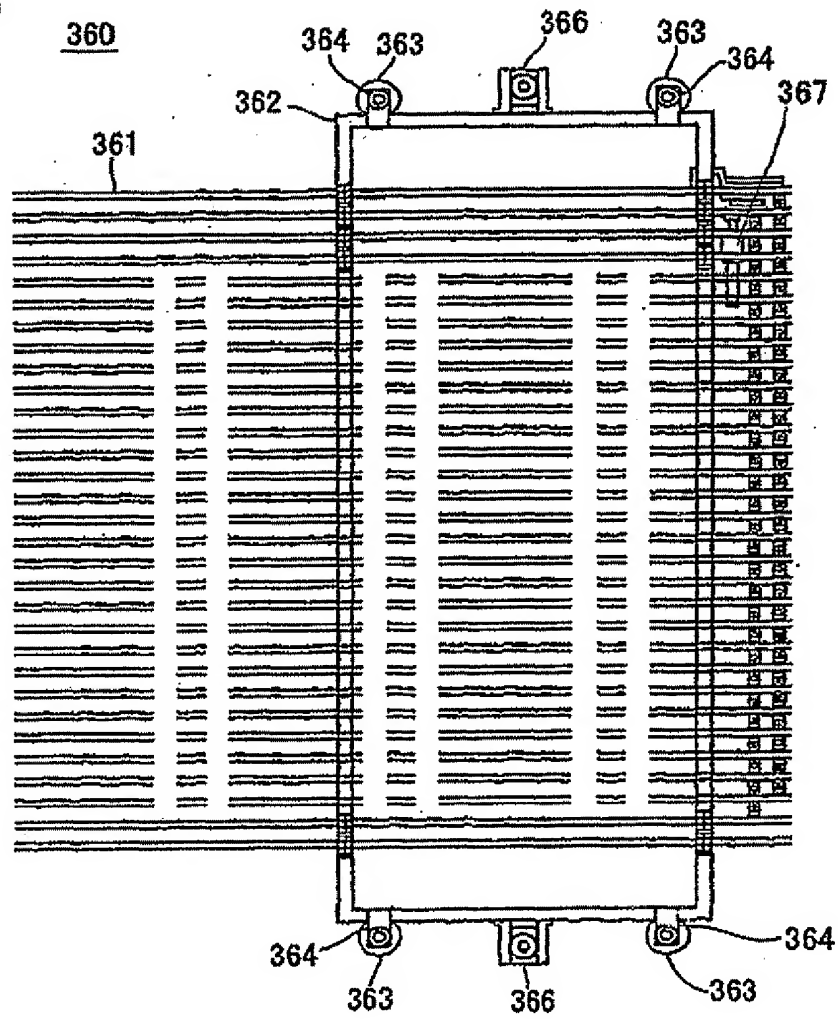




FIG. 76

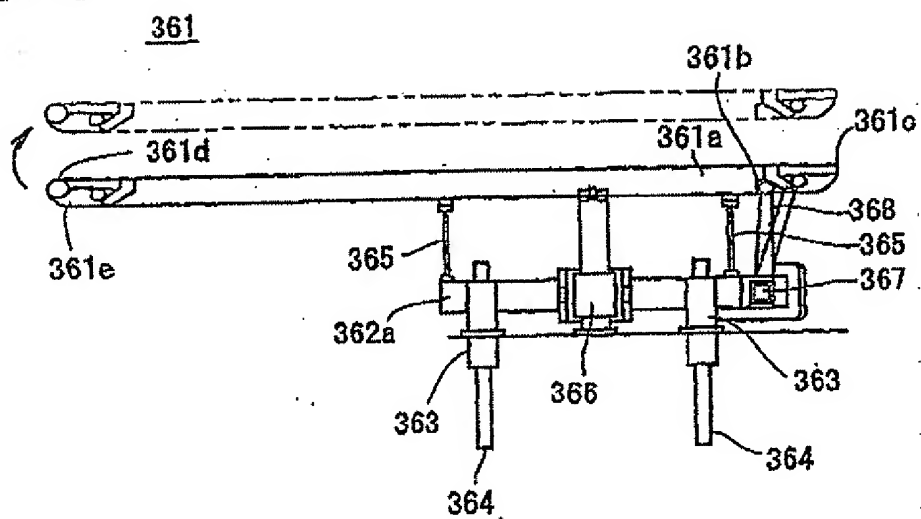


FIG.77

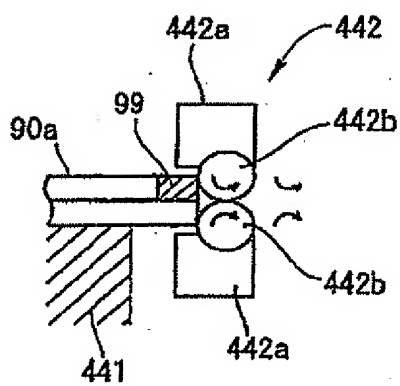


FIG.78

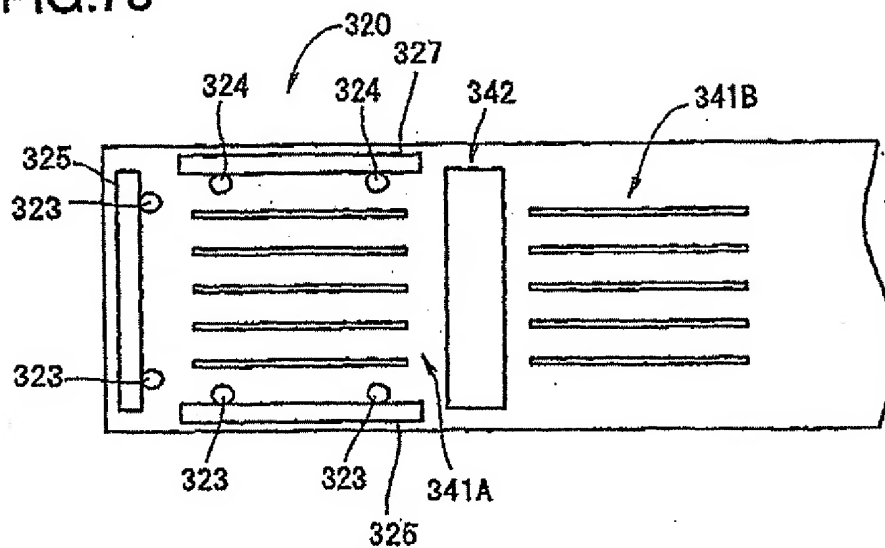


FIG.79

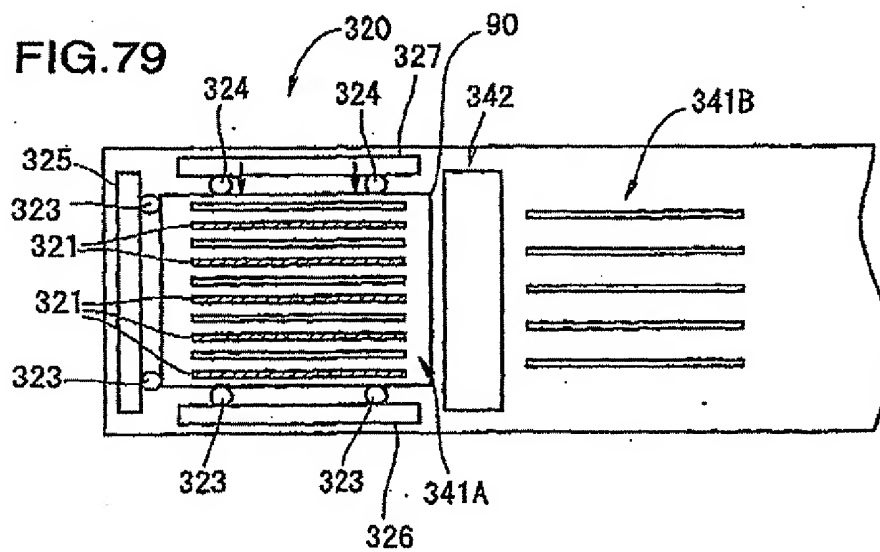


FIG.80

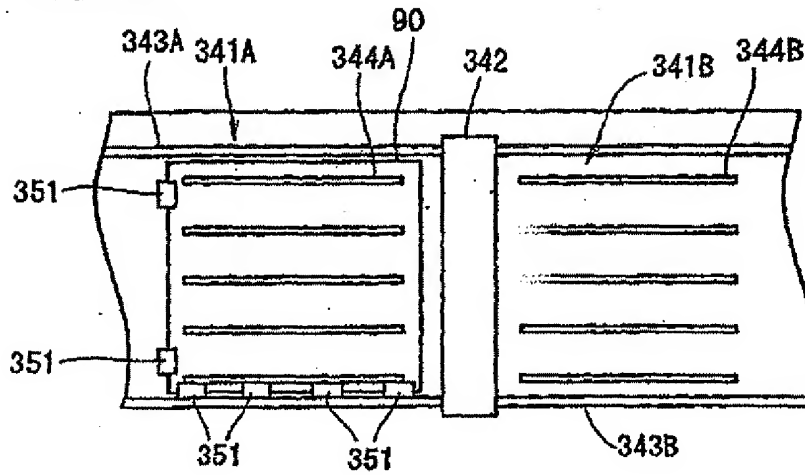


FIG.81

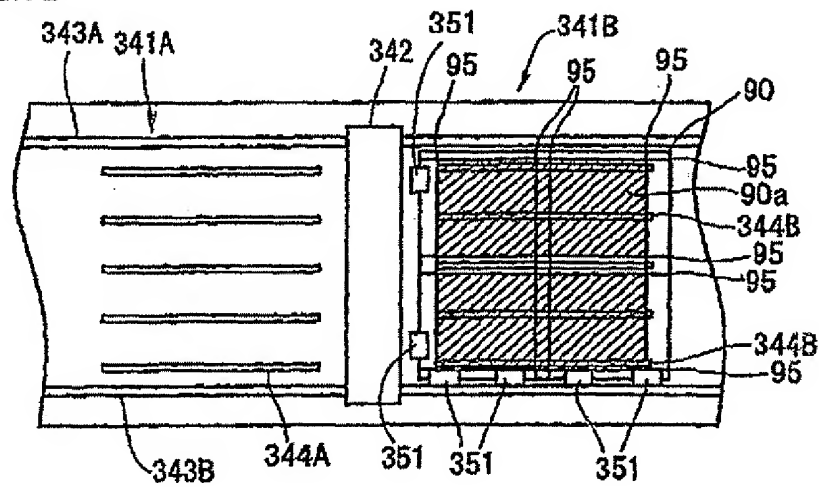


FIG.82

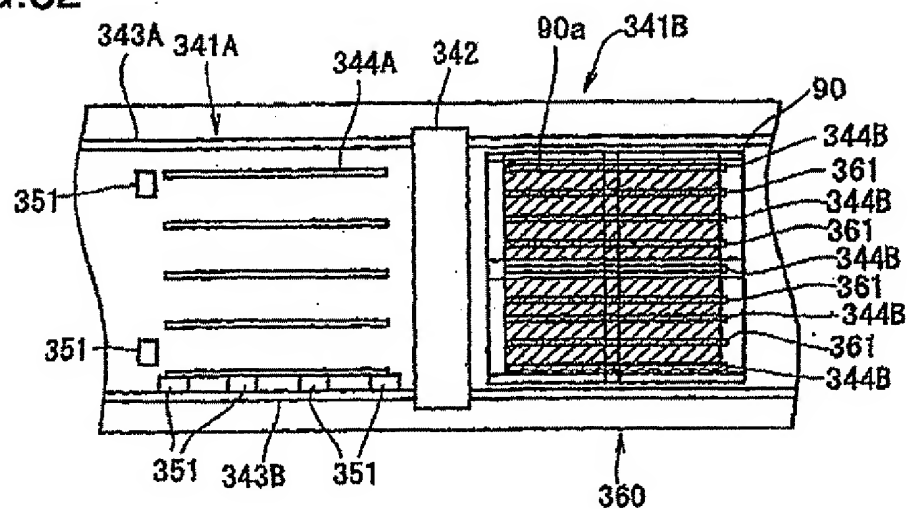
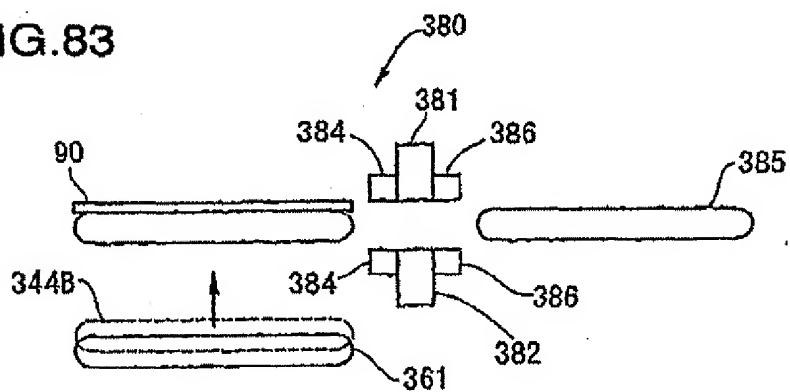


FIG.83



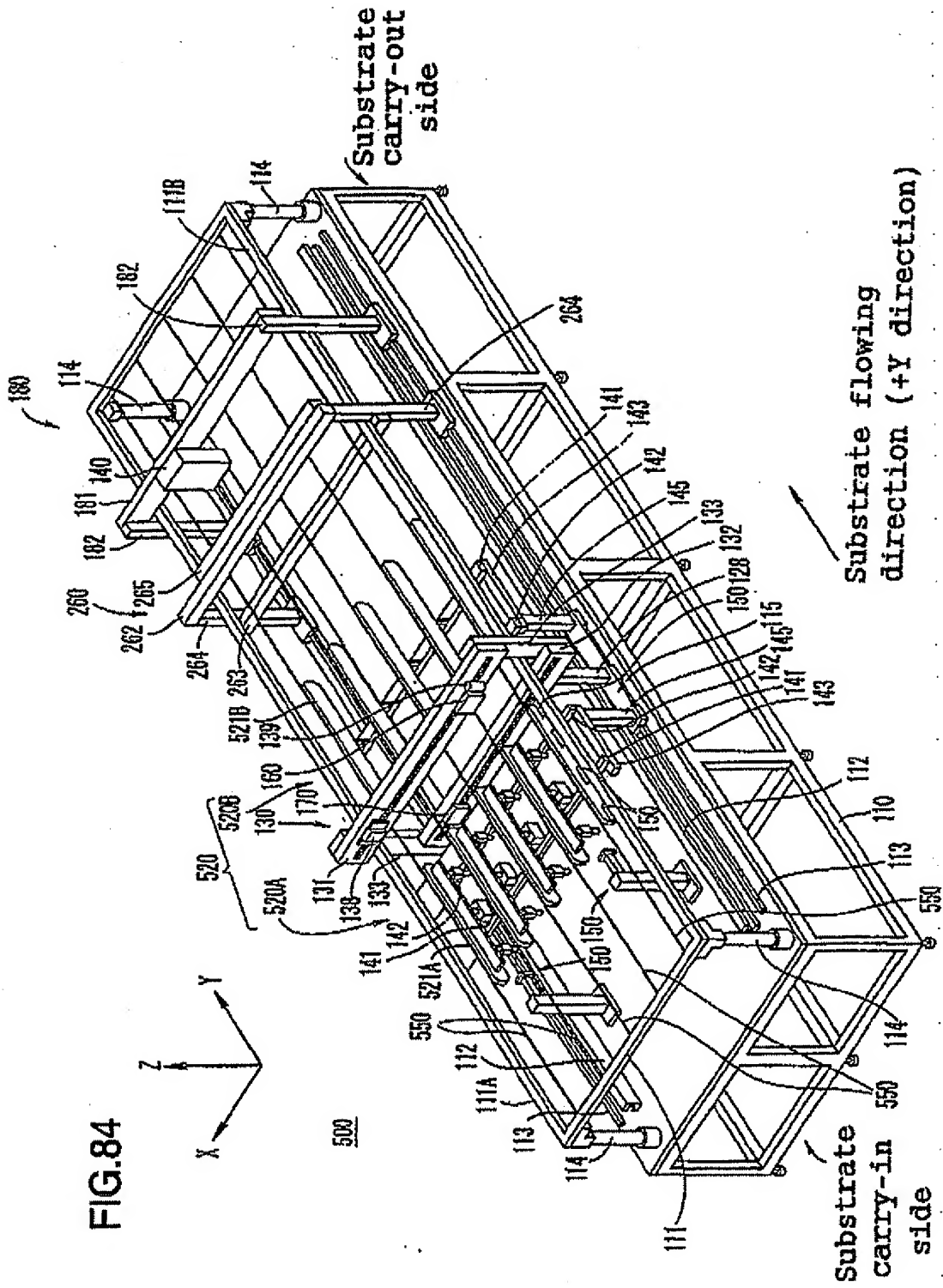


FIG.85

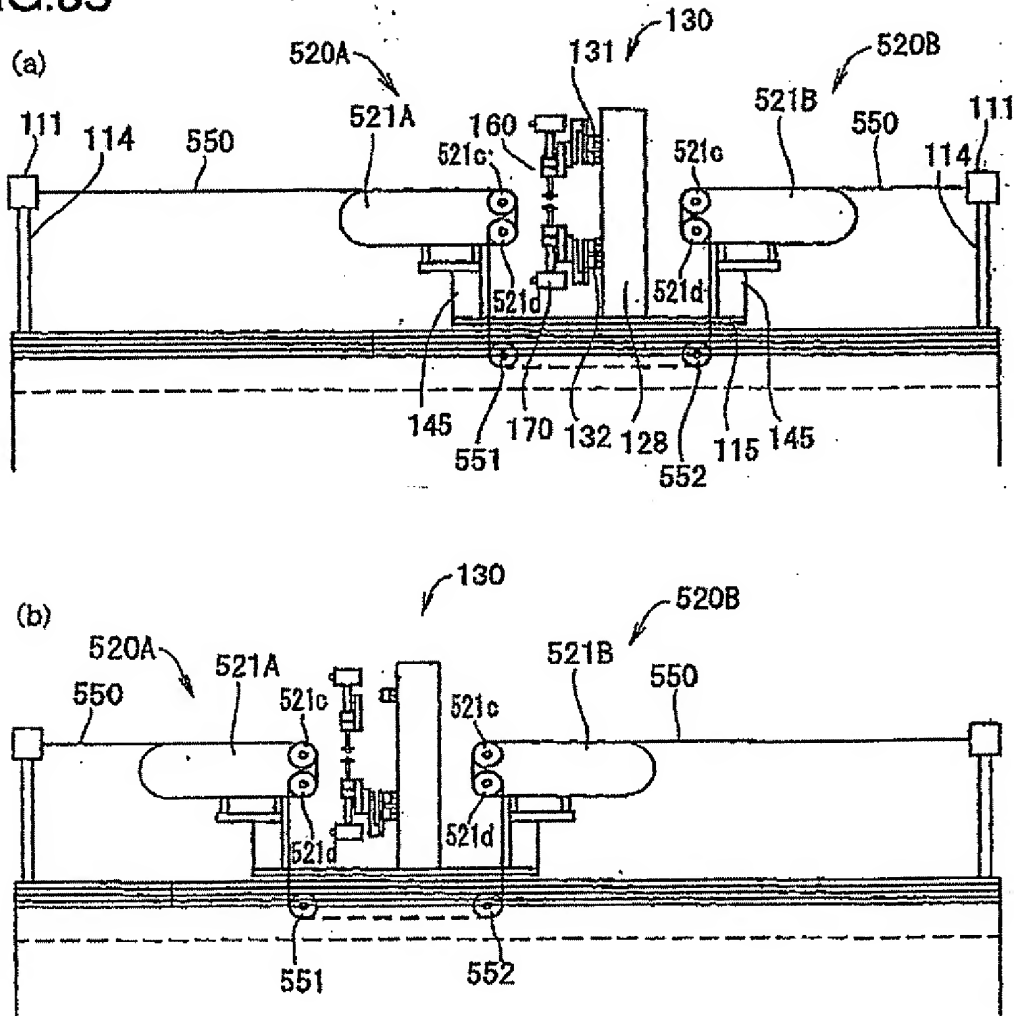
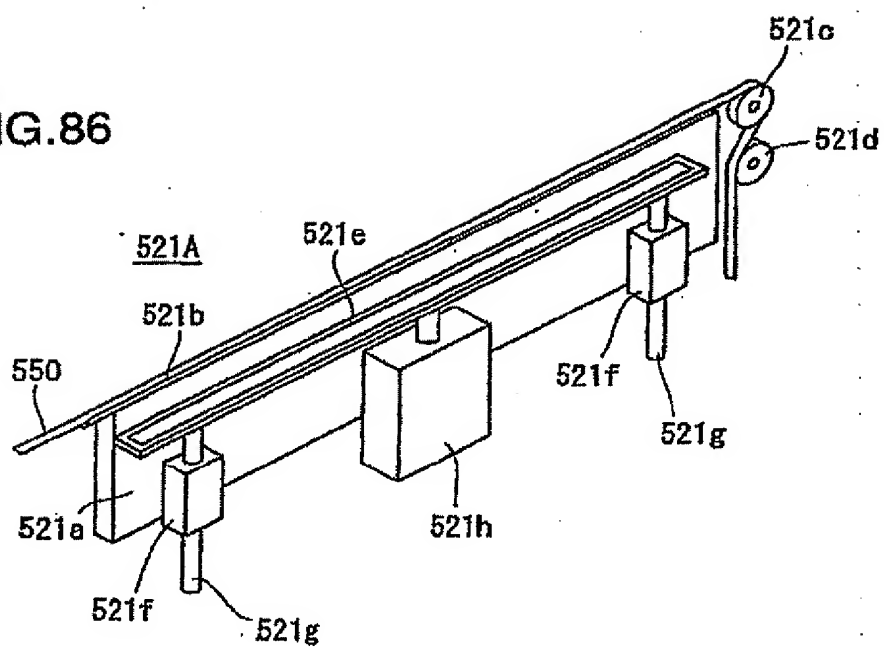
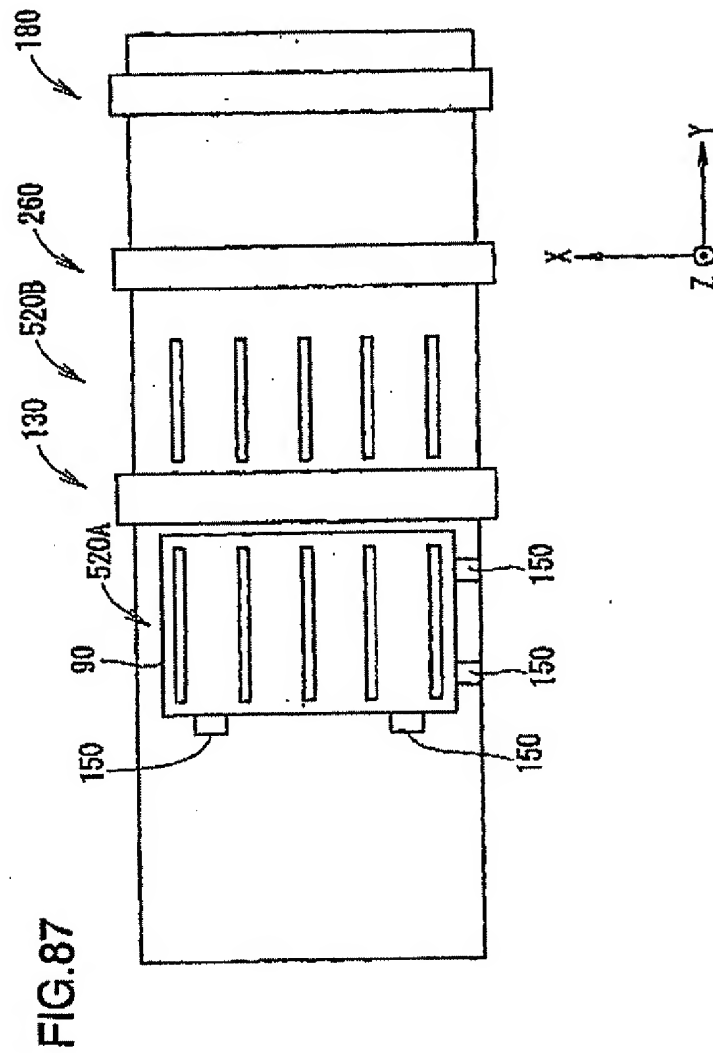


FIG. 86







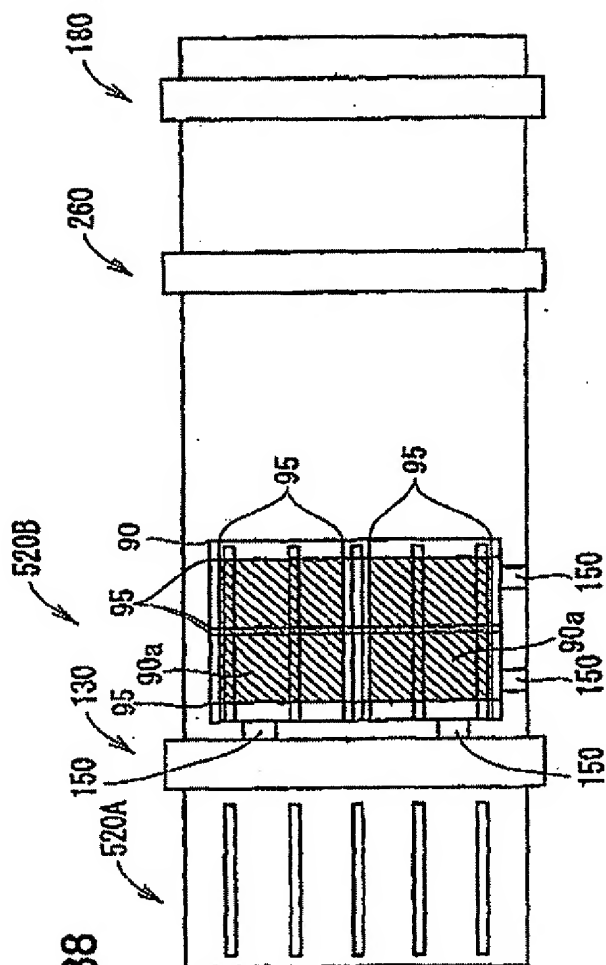
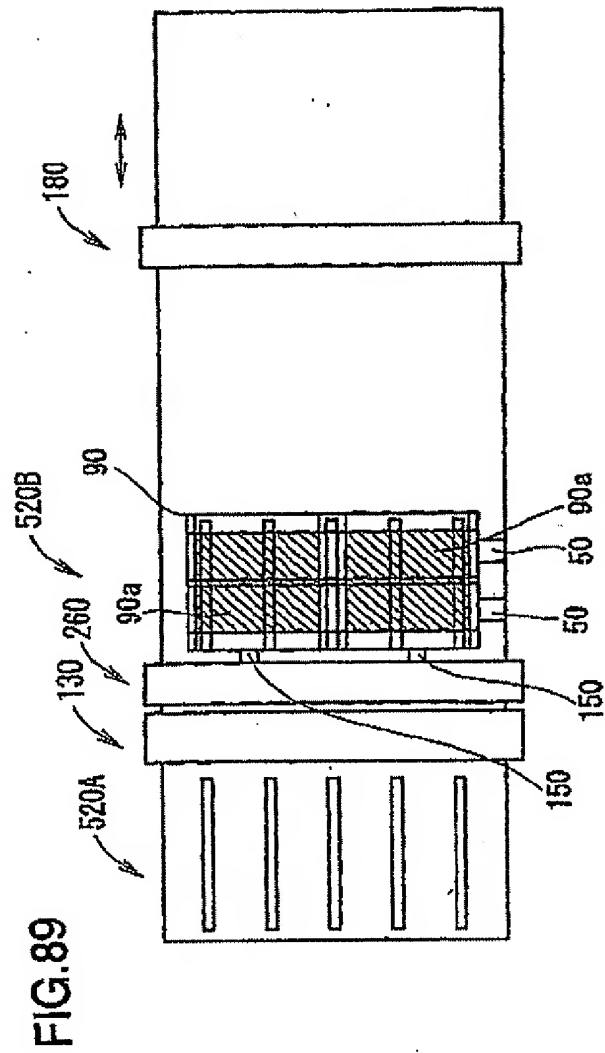
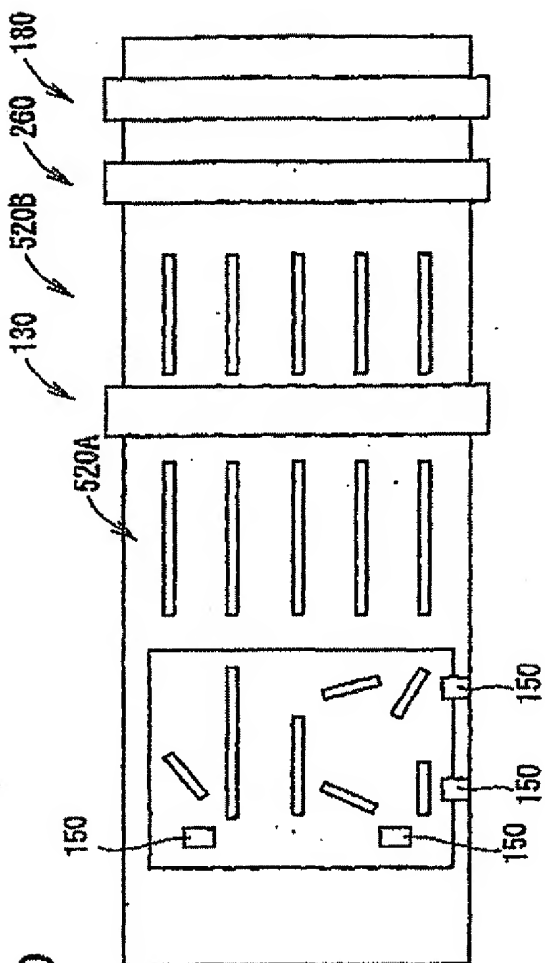
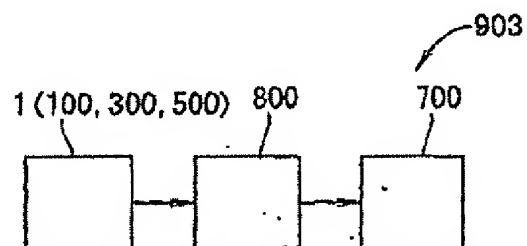
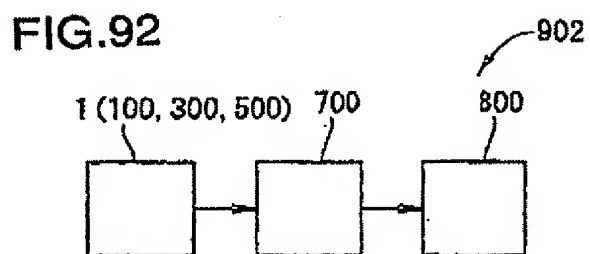
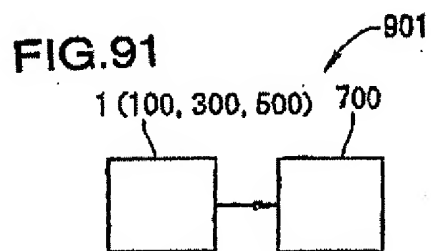
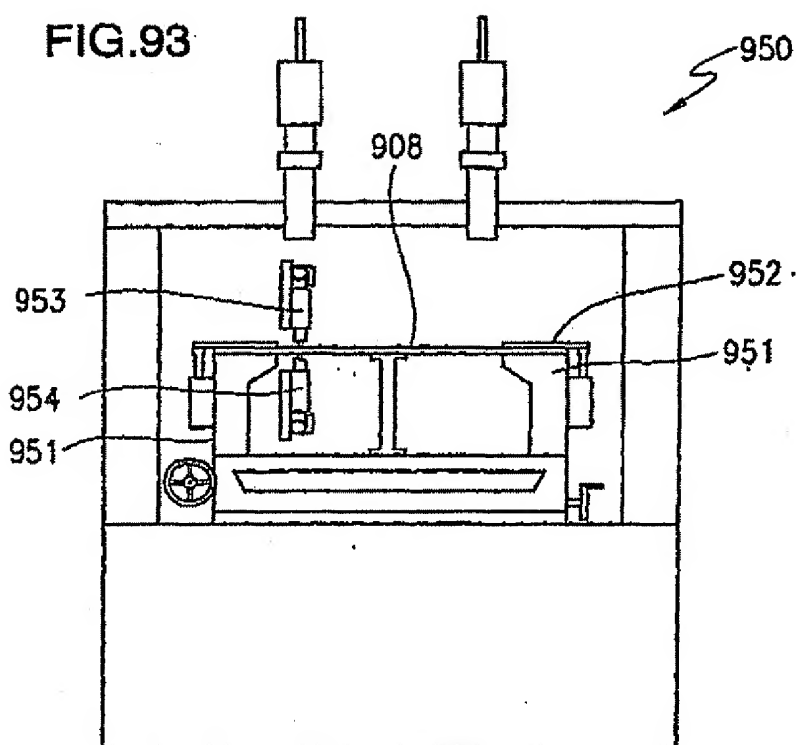


FIG. 88









## INTERNATIONAL SEARCH REPORT

 International application No.  
PCT/JP03/12182

<b>A. CLASSIFICATION OF SUBJECT MATTER</b> Int.Cl <sup>7</sup> B28D5/00, C03B33/03, C03B33/023		
According to International Patent Classification (IPC) or to both national classification and IPC		
<b>B. FIELDS SEARCHED</b> Minimum documentation searched (classification system followed by classification symbols) Int.Cl <sup>7</sup> B28D5/00-5/04, C03B33/00-33/14		
Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched Jitsuyo Shinan Koho 1922-1996 Toroku Jitsuyo Shinan Koho 1994-2003 Kokai Jitsuyo Shinan Koho 1971-2003 Jitsuyo Shinan Toroku Koho 1996-2003		
Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)		
<b>C. DOCUMENTS CONSIDERED TO BE RELEVANT</b>		
Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y	WO 02/057192 A1 (Mitsuboshi Diamond Industrial Co., Ltd.), 25 July, 2002 (25.07.02), Page 10, line 3 to page 14, line 7; page 16, lines 4 to 7; page 17, lines 24 to 26 (Family: none)	1-3, 18, 24, 26, 29-31, 33-49 4-17, 19-23, 25, 27, 28, 32
A		
Y	JP 2001-206727 A (Asahi Glass Co., Ltd.), 31 July, 2001 (31.07.01), Claim 1; Par. Nos. [0015], [0030]; Figs. 1, 7, 8 (Family: none)	1-3, 18, 24, 26, 29-31, 33-48
Y	JP 2000-247669 A (Asahi Glass Co., Ltd.), 12 September, 2000 (12.09.00), Par. No. [0013] (Family: none)	33, 38
<input checked="" type="checkbox"/> Further documents are listed in the continuation of Box C. <input type="checkbox"/> See patent family annex.		
* Special categories of cited documents: "A" document defining the general state of the art which is not considered to be of particular relevance "E" earlier document but published on or after the international filing date "L" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified) "O" document referring to an oral disclosure, use, exhibition or other means "P" document published prior to the international filing date but later than the priority date claimed "T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention "X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone "Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art "&" document member of the same patent family		
Date of the actual completion of the international search 22 December, 2003 (22.12.03)		Date of mailing of the international search report 20 January, 2004 (20.01.04)
Name and mailing address of the ISA/ Japanese Patent Office		Authorized officer
Facsimile No.		Telephone No.

Form PCT/ISA/210 (second sheet) (July 1998)

## INTERNATIONAL SEARCH REPORT

International application No.

PCT/JP03/12182

C (Continuation). DOCUMENTS CONSIDERED TO BE RELEVANT		
Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y	JP 9-188534 A (Mitsuboshi Diamond Industrial Co., Ltd.), 22 July, 1997 (22.07.97), Claim 1 & EP 0773194 A1	37, 46
Y	JP 2001-240421 A (Bando Kiko Co., Ltd.), 04 September, 2001 (04.09.01), Par. No. [0002] (Family: none)	38, 42-48
Y	JP 2002-47024 A (Hitachi, Ltd.), 12 February, 2002 (12.02.02), Claim 7 & US 2002/0001059 A1	49
Y	JP 2002-224872 A (Seiko Epson Corp.), 13 August, 2002 (13.08.02), Page 3, left column, line 44 to right column, line 8 (Family: none)	49
A	JP 2001-176820 A (Hitachi Cable, Ltd.), 29 June, 2001 (29.06.01), Par. No. [0053] (Family: none)	19-23, 25

Form PCT/ISA/210 (continuation of second sheet) (July 1998)